

**INSTITUT TEKNOLOGI NASIONAL MALANG  
FAKULTAS TEKNOLOGI INDUSTRI  
JURUSAN TEKNIK ELEKTRO S-1  
KONSENTRASI TEKNIK ELEKTRONIKA**



**SKRIPSI**

**PERANCANGAN DAN PEMBUATAN ALAT  
PENYIRAMAN AIR OTOMATIS PADA KEDELAI  
MENGUNAKAN MIKROKONTROLER AT89S8252**

*Disusun Oleh :*  
**ACHMAD EBIT SUGIANTO**  
**NIM. 00.17.138**

**MARET 2006**

**LEMBAR PERSETUJUAN**

**PERANCANGAN DAN PEMBUATAN ALAT PENYIRAM AIR  
OTOMATIS PADA KEDELAI MENGGUNAKAN  
MIKROKONTROLLER AT89S8252**

**SKRIPSI**

*Disusun dan Diajukan Untuk Melengkapi dan Memenuhi Syarat  
Guna Mencapai Gelar Sarjana Teknik*

Disusun oleh :


**ACHMAD EBIT SUGIANTO**

**00.17138**

Malang, Maret 2006

Disetujui  
Dosen Pembimbing

  
Mengetahui  
Ketua Jurusan Teknik Elektro S-1  
Ir. F. Yudi Limpraptono, MT  
NIP. Y. 1039500274

  
Ir. Teguh Herbasuki, MT  
NIP. Y. 1038900209

**JURUSAN TEKNIK ELEKTRO S-1  
KONSENTRASI TEKNIK ELEKTRONIKA  
FAKULTAS TEKNOLOGI INDUSTRI  
INSTITUT TEKNOLOGI NASIONAL MALANG  
2006**





INSTITUT TEKNOLOGI NASIONAL MALANG  
FAKULTAS TEKNOLOGI INDUSTRI  
JURUSAN TEKNIK ELEKTRO S-1  
KONSENTRASI TEKNIK ELEKTRONIKA

**BERITA ACARA UJIAN SKRIPSI  
FAKULTAS TEKNOLOGI INDUSTRI**

Nama Mahasiswa : ACHMAD EBIT SUGIANTO  
NIM : 00 17 138  
Jurusan : Teknik Elektro S-1  
Konsentrasi : Teknik Elektronika  
Judul Skripsi :

“PERANCANGAN DAN PEMBUATAN ALAT PENYIRAMAN AIR  
OTOMATIS PADA KEDELAI MENGGUNAKAN MIKROKONTROLLER  
AT89S8252”

Dipertahankan Dihadapan Team Penguji Skripsi Jenjang Strata Satu ( S-1), pada :

Hari : Rabu  
Tanggal : 22 Maret 2006  
Dengan nilai : 79,6 (B+) *sm*



Ketua

( Ir. Mochtar Asroni, MSME )  
NIP.Y. 1018100036

Panitia Ujian Skripsi:

Sekretaris

( Ir.F.Yudi Limpraptono, MT )  
NIP.Y 1039500274

Anggota Penguji:

Penguji I

( Ir.Widodo Pudji M, MT )

Penguji II

( Sotyo Hadi, ST )

3/4 06



FAKULTAS TEKNOLOGI INDUSTRI  
BERITA ACARA UJIAN SKRIPSI

Nama Mahasiswa : AHMAD EBIT SUGIANTO  
NIM : 0017138  
Jurusan : Teknik Elektro 2-1  
Konsentrasi : Teknik Elektronika  
Judul Skripsi :

"PERANCANGAN DAN PEMBUATAN ALAT PENYIRAMAN AIR  
OTOMATIS PADA KEDELAI MENGGUNAKAN MIKROKONTROLER  
AT89C8252"

Diperhatikan dan Disiapkan Tim Pengji Skripsi jenjang Sarjana pada :

Hari : Rabu  
Tanggal : 25 Maret 2009  
Dengan nilai : 79,9 (B+)

Panitia Ujian Skripsi:

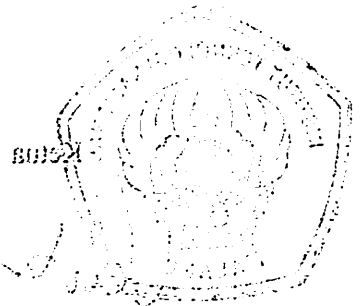
Sebelum

(Dr. Yudi Himmawono, MT)  
NIP. Y. 103920024

Anggota Pengji:

Pengji II

(Solihudin, ST)



(Dr. Mochamad Azoni, MSiE)  
NIP. Y. 1018100026

Pengji I

(Widodo Budhi M. MT)

## KATA PENGANTAR



Puji dan Syukur Alhamdulillah penulis panjatkan kepada Allah SWT karena berkat Rahmat dan karunia-Nya disertai segala cobaan dan rintangan serta keterbatasan waktu, yang semua itu penulis menganggap sebagai tantangan dan rintangan yang harus terjawab akhirnya penulis dapat menyelesaikan skripsi ini yang berjudul :

***“PERANCANGAN DAN PEMBUATAN ALAT PENYIRAMAN AIR OTOMATIS  
PADA KEDELAI MENGGUNAKAN MIKROKONTROLLER AT89S8252 “***

Tujuan penulisan Skripsi ini antara lain untuk memenuhi persyaratan mencapai gelar Sarjana Teknik pada Jurusan Teknik Elektro S1, Konsentrasi Teknik Elektronika, di Institut Teknologi Nasional Malang.

Sehubungan dengan itu penulis menyampaikan ucapan terima kasih yang sebesar-besarnya kepada :

1. Bapak Dr. Ir. Abraham Lomi, MSME. selaku Rektor Institut Teknologi Nasional Malang.
2. Bapak Ir. Mochtar Asroni, MSME. selaku Dekan Fakultas Teknologi Industri Institut Teknologi Nasional Malang.
3. Bapak Ir. F.Yudi Limpraptono, MT. selaku Ketua Jurusan Teknik Elektro Institut Teknologi Nasional Malang.
4. Ibu Ir. Mimien Mustikawati selaku Sekretaris Jurusan Teknik Elektro S-1 Program Studi Teknik Elektronika Institut Teknologi Nasional Malang.

5. Bapak Ir. Teguh Herbasuki, MT. selaku Dosen Pembimbing yang telah banyak meluangkan waktu, arahan dan juga tuntunan yang progresif dalam penyusunan skripsi ini sampai selesai.
6. Bapak dan Ibu dosen yang telah memberikan bekal ilmu selama penulis kuliah di ITN Malang.
7. Teman-teman seperjuangan “angkatan 2000 Elka 3-4” yang telah memberikan masukan-masukan dan saran-saran serta semangat belajar yang tidak dapat disebutkan satu persatu juga untuk semua pihak yang telah banyak membantu dalam menyelesaikan Skripsi ini.

Secara khusus, kebanggaan disertai kasih yang tulus, penulis tujukan kepada Bapak dan Ibu yang telah bersusah payah memberikan kesempatan biaya kepada penulis untuk mengikuti dan menyelesaikan studi ini.

Akhir kata penulis mohon maaf sebesar-besarnya bila ada kata-kata atau kesalahan dalam penulisan laporan ini tentunya tanpa ada unsur kesengajaan dari penulis. Penulis mengharapkan saran dan kritik yang membangun dari pembaca dan harapan saya semoga laporan Tugas Akhir ini dapat bermanfaat bagi kita semua .  
“Amin”.

Malang, Maret 2006

Penulis

## ABSTARKSI

Achmad Ebit Sugianto, November-2005, *Perancangan Dan Pembuatan Alat Penyiram air Otomatis Pada Kedelai Menggunakan Mikrokontroller AT89S8252*. Skripsi Jurusan Teknik Elektronika Fakultas Teknologi Industri Institut Teknologi Nasional Malang. Pembimbing : Ir. Teguh Herbasuki, MT

Teknologi di bidang elektronika mempengaruhi perubahan pola kehidupan masyarakat yang dulunya memanfaatkan tenaga murni/konvensional kini berubah menggunakan suatu alat yang dapat bekerja sendiri (otomatis) yang hanya membutuhkan sedikit sentuhan tenaga manusia.

Pada era globalisasi banyak petani disibukkan dengan berbagai aktifitas dalam bidang pertanian. Seperti halnya yang dilakukan oleh petani dalam penyiraman pada kedelai secara konvensional, yakni harus disiram 3 jam sekali sampai 2 hari dari waktu persemaian. Dengan adanya alat penyiraman otomatis pada kedelai ini, diharapkan petani tidak lagi melakukan aktifitas tersebut lebih-lebih jika memiliki lahan yang luas dan dilakukan berhari-hari. Alat penyiraman otomatis ini dalam bekerjanya tidak lagi berdasarkan satuan waktu penyiraman dalam sehari sekian kali secara mutlak, tetapi lebih didasarkan pada kelembaban tanah terhadap umur tanaman kedelai tersebut. Dalam skripsi ini akan dibuat suatu alat penyiram otomatis dengan sistem pemrograman berbasis mikrokontroler AT89S8252.

## DAFTAR ISI

	<b>Halaman</b>
LEMBAR PENGESAHAN .....	i
LEMBAR BERITA ACARA.....	ii
KATA PENGANTAR .....	iii
ABSTRAKSI.....	v
DAFTAR ISI.....	vi
DAFTAR GAMBAR.....	x
DAFTAR TABEL .....	xii
<b>BAB I PENDAHULUAN.....</b>	<b>1</b>
1.1. Latar Belakang .....	1
1.2. Rumusan Masalah.....	2
1.3. Tujuan .....	2
1.4. Batasan Masalah.....	3
1.5. Metodologi .....	3
1.6. Sistematika Penulisan .....	4
<b>BAB II TINJAUAN PUSTAKA .....</b>	<b>5</b>
2.1. Curah Hujan Dan Kelembaban Tanah.....	5
2.1.1. Hubungan Tanah-Air-Tanaman .....	6
2.2. Mikrokontroller AT89S8252.....	7

2.2.1.	Pendahuluan.....	7
2.2.2.	Perangkat Keras Mikrokontroller AT89S8252.....	8
2.2.3.	Arsitektur AT89S8252 .....	9
2.2.4.	Konfigurasi Pin Mikrokontroller AT89S8252 .....	10
2.2.5.	Organisasi Memori .....	12
2.2.5.1.	Internal Program Memori .....	12
2.2.5.2.	<i>Random Access Memory</i> (RAM).....	12
2.2.5.3.	<i>Special Function Register</i> (SFR).....	13
2.2.5.3.1.	<i>Program Status Word</i> (PSW).....	13
2.2.5.3.2.	<i>Power Control</i> (PCON).....	14
2.2.5.4.	Sistem Interupsi .....	14
2.2.5.5.	<i>Timer / Counter</i> .....	15
2.2.5.6.	Metode Pengalamatan.....	17
2.3.	Sensor Air.....	17
2.4.	<i>Solenoid</i> .....	19
2.5.	Transistor.....	20
2.6.	<i>Keypad</i> .....	22
2.7.	Penguat Operasional.....	24
2.7.1.	Penguat Penbalik .....	24
2.7.2.	Penguat Tak Membalik .....	24
2.8.	<i>Analog to Digital Converter</i> (ADC) .....	25
2.8.1	<i>Successive Approximation</i> .....	27
2.8.2.	<i>Analog to Digital Converter 0809</i> .....	28

2.9. RTC ( <i>Real Time Clock</i> ) IC DS 12C887 .....	30
2.10. LCD ( <i>Liquid Crystal Display</i> ) M 1632.....	35
BAB III PERENCANAAN DAN PEMBUATAN ALAT .....	38
3.1. Pendahuluan.....	38
3.2. Perencanaan Perangkat Keras ( <i>Hardware</i> ).....	38
3.2.1. Sensor Kelembaban Tanah .....	39
3.2.2. Rangkaian Penguat Tegangan Membalik ( <i>Inverting</i> )	42
3.2.3. Rangkaian <i>Keypad</i> 4 x 4.....	43
3.2.4. Rangkaian <i>Converter Analog to Digital</i> (ADC 0809)	45
3.2.5. Rangkaian <i>Timer</i> RTC DS C887.....	46
3.2.6. Rangkaian Sistem Kontrol Utama (Mikrokonroller AT89S8252) .....	48
3.2.7. Rangkaian <i>Driver Solenoid Valve</i> .....	48
3.2.8. Rangkaian <i>Display</i> LCD (M1632) .....	50
3.3. Perencanaan Perangkat Lunak ( <i>Software</i> ) .....	51
3.3.1. <i>Flowchart</i> .....	52
BAB IV PENGUJIAN ALAT .....	53
4.1. Pengujian Sensor Kelembaban Tanah dan Rangkaian Penguat	53
4.2. Pengujian Rangkaian ADC 0809 .....	55
4.3. Pengujian Rangkaian <i>Driver Solenoid</i> .....	57
4.4. Pengujian <i>Timer</i> RTC DS 12C887,LCD & <i>Keypad</i> .....	58

BAB V PENUTUP.....	61
5.1. Kesimpulan.....	61
5.2. Saran-saran.....	61
DAFTAR PUSTAKA.....	62
LAMPIRAN.....	63

## DAFTAR GAMBAR

Gambar 2.1.	Hubungan Antara Kadar Air Tanah Dengan Tekstur Tanah..	5
Gambar 2.2.	Blok Diagram Mikrokontroller AT89S8252.....	8
Gambar 2.3.	Diagram Pin Mikrokontroller AT89S8252 .....	10
Gambar 2.4.	Ukuran Dan Bentuk Fisik Sensor Kelembaban Tanah.....	18
Gambar 2.5.	<i>Solenoid Valve</i> .....	20
Gambar 2.6.	Transistor Sebagai Saklar.....	21
Gambar 2.7.	Titik Potong Antera Garis Beban dan Arus Basis.....	22
Gambar 2.8.	<i>Keypad Matrik 4 x 4</i> .....	23
Gambar 2.9.	Polaritas Tegangan Untuk Penguat Pembalik .....	24
Gambar 2.10.	Polaritas Tegangan Untuk Penguat Tak Membalik.....	25
Gambar 2.11.	Struktur Pin IC ADC 0809.....	29
Gambar 2.12.	Konfigurasi Pin IC DS 12 C 887.....	31
Gambar 2.13.	Peta Alamat RAM <i>Internal Real Time Clock</i> DS 12C887.....	35
Gambar 2.14.	Deskripsi Pin Pada LCD Tipe M1632.....	37
Gambar 3.1.	Blok Sistem Penyiraman Otomatis Pada Tanaman Kedelai ..	39
Gambar 3.2.	Rangkaian Elektrik Sensor Kelembaban Tanah.....	41
Gambar 3.3.	Rangkaian Penguat Tegangan Membalik.....	43
Gambar 3.4.	Rangkaian <i>Keypad Matrik 4 x 4</i> .....	44
Gambar 3.5.	Rangkaian ADC 0809 .....	46
Gambar 3.6.	Rangkaian <i>Timer</i> dengan IC RTC DS 12C887 .....	47
Gambar 3.7.	Rangkaian Sistem Kontrol AT 89S8252.....	48

Gambar 3.8. Rangkaian <i>Driver Selenoid Model Darlington</i> .....	50
Gambar 3.9. Rangkaian LCD Dengan Jalur Data dan Pin Kontrol .....	51
Gambar 3.10. <i>Flowchart</i> Program Penyiram Otomatis .....	52
Gambar 4.1. Pengujian Sensor Kelembaban Tanah Sekaligus Rangkaian Penguat Tegangan .....	49
Gambar 4.2. Pengujian Rangkaian ADC 0809 .....	55
Gambar 4.3. Pengujian <i>Driver Selenoid Valve</i> .....	57
Gambar 4.4. Blok Cara Pengujian Rangkaian RTC Dengan LCD dan Mikrokontroller AT 89S8252.....	58
Gambar 4.5. <i>Flowchart</i> Penulisan dan Pengambilan Data RTC & LCD....	59

## DAFTAR TABEL

Tabel 2.1. Pengaturan RS 0 – RS 1 <i>Bank Register</i> .....	13
Tabel 2.2. Pengaturan RS0-RS1 <i>Bank Register</i> .....	14
Tabel 2.3. Skema Medefinisikan PCON .....	14
Tabel 2.4. Alamat Sumber Interupsi.....	15
Tabel 2.5. Kegunaan <i>Interrupt Enable Register</i> .....	16
Tabel 2.6. <i>Register TMOD</i> .....	16
Tabel 2.7. <i>Timer/Counter Mode Control Register</i> .....	17
Tabel 2.8. Mode Operasi <i>Timer/Counter</i> .....	30
Tabel 2.9. Keterangan Pin IC ADC 0809.....	30
Tabel 2.10. Periode Interrupt dan Frekuensi keluaran SQW.....	34
Tabel 2.11. Pemilihan <i>Register</i> Pada LCD M1632.....	36
Tabel 4.1. Data Hasil Pengukuran Sensor Kelembaban Tanah.....	54
Tabel 4.2. Data Hasil Pengukuran Rangkaian Konversi ADC 0809.....	56
Tabel 4.3. Data Hasil Pengamatan <i>Timer</i> RTC Pada LCD .....	59

# **BAB I**

## **PENDAHULUAN**

### **1.1 Latar Belakang**

Perkembangan ilmu di bidang teknologi khususnya teknologi elektronika merupakan suatu kenyataan yang menunjukkan bahwa manusia banyak melakukan aktivitasnya. Sesuai dengan tuntutan jaman yang bermacam-macam tentang kebutuhan masyarakat akan sebuah hiburan ataupun alat kerja, hal ini telah membawa ide ke arah teknologi yang lebih maju, lebih bermanfaat serta memiliki nilai ekonomis.

Oleh karena itu berbagai macam sebab perkembangan teknologi khususnya bidang elektronika mempengaruhi perubahan pola kehidupan masyarakat yang dulunya memanfaatkan tenaga murni/konvensional kini berubah menggunakan suatu alat yang dapat bekerja sendiri (otomatis) yang hanya membutuhkan sedikit sentuhan tenaga manusia.

Seperti halnya yang dilakukan oleh petani dalam penyiraman pada kedelai secara konvensional, yakni harus disiram 3 jam sekali sampai 2 hari dari waktu persemaian. Dengan adanya alat penyiraman otomatis pada kedelai ini, diharapkan petani tidak lagi melakukan aktifitas tersebut lebih-lebih jika memiliki lahan yang luas dan dilakukan sehari-hari. Alat penyiraman otomatis ini dalam bekerjanya tidak lagi berdasarkan satuan waktu penyiraman dalam sehari sekian kali secara mutlak, tetapi lebih didasarkan pada kelembaban tanah terhadap umur tanaman kedelai tersebut.

Dimana alat yang menggunakan *Real Time Clock* (RTC) sebagai kontrol waktu, keypad sebagai inputan yang mempermudah dalam memasukkan waktu penyiraman atau umur tanaman dan mikrokontroler sebagai basis system pemrogramannya.

## **1.2 Rumusan Masalah**

Permasalahan yang dihadapi dalam merencanakan dan membuat suatu alat penyiram air otomatis pada tanaman kedelai, dapat dirumuskan sebagai berikut:

1. Bagaimana membuat sensor yang mampu mendeteksi kelembaban tanah.
2. Bagaimana membuat suatu rangkaian driver yang dapat membuka kran air secara elektrik.
3. Bagaimana mengendalikan IC RTC dan menggunakannya sebagai referensi terhadap waktu yang presisi.
4. Bagaimana merangkai software yang dapat membaca sensor dan memperhitungkannya sehingga mengeluarkan data sebagai kontrol kran air otomatis.

## **1.3 Tujuan**

Adapun tujuan pada pembuatan alat ini adalah:

Untuk mengaplikasikan sistem pemrograman dengan berbasis mikrokontroller sebagai kontrol penyiraman pada tanaman kedelai dengan referensi kelembaban tanah

## **1.4 Batasan Masalah**

Agar permasalahan yang dibahas tidak meluas, maka penulis membatasi pembahasan hanya pada hal-hal berikut ini:

- Pengontrol utama terprogram menggunakan mikrokontroler AT 89S8252.
- Menggunakan RTC DS12C887 sebagai pengontrol waktu.
- Tidak membahas secara detail system mekanik penyiraman (debit air).
- Pembahasan aplikasi hanya ditujukan untuk tanaman kedelai.
- Tidak membahas secara detail mengenai system catu daya.

## **1.5 Metodologi**

Untuk mendapatkan hasil yang diharapkan, maka di dalam penyusunan laporan tugas akhir ini, penulis menggunakan metode sebagai berikut :

### **1. Studi literatur:**

Studi literatur disini untuk mempelajari hal-hal dasar mengenai teori tiap-tiap komponen yang digunakan sebagai berikut :

### **2. Perencanaan alat:**

- ✓ Melakukan perencanaan untuk tiap-tiap blok diagram yang mendukung.
- ✓ Mempersiapkan dan memilih komponen berdasarkan fungsi dan karakteristik komponen, kemudian tersedianya dipasaran.

### **3. Pembuatan sekaligus pengujian alat:**

Dalam pembuatan alat disini meliputi perencanaan tata letak komponen, pembuatan layer pada PCB, pengeboran dan penyolderan, serta perakitan tiap-

tiap blok menjadi suatu rangkaian yang lengkap yang selanjutnya diuji tiap blok maupun keseluruhan.

#### 4. Kesimpulan dan saran:

Setelah melakukan beberapa pengujian, maka mengambil kesimpulan dan memberi saran yang diperlukan untuk pengembangan alat selanjutnya.

### 1.6 Sistematika Penulisan

Sistematika penulisan dalam skripsi ini terdiri dari lima (5) bab, yaitu:

#### BAB I : PENDAHULUAN

Berisi latar belakang masalah, perumusan masalah, batasan masalah, tujuan penulisan, metodologi dan sistematika penulisan.

#### BAB II : TINJAUAN PUSTAKA

Membahas tentang teori-teori dasar yang berhubungan dengan alat.

#### BAB III : PERENCANAAN PEMBUATAN ALAT

Membahas tentang perencanaan dan pembuatan alat penyiraman air otomatis pada kedelai

#### BAB IV : PENGUJIAN ALAT

Membahas mengenai pengujian dan analisis hasil pengujian.

#### BAB V : PENUTUP

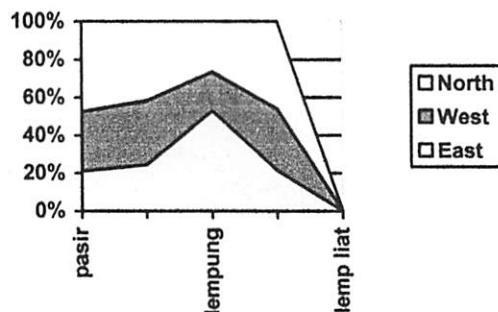
Merupakan kesimpulan hasil uji alat secara keseluruhan dan saran – saran yang memungkinkan untuk pengembangan alat lebih lanjut.

## BAB II

### TINJAUAN PUSTAKA

#### 2.1. Curah Hujan dan Kelembaban Tanah

Indikator kelembaban tanah adalah kadar air tanah yang dinyatakan dalam persen berat atau persen volume, mm air setiap m kedalaman tanah, dan tegangan air tanah (atm atau bar). Dalam praktek dikenal tiga tingkat kadar air tanah, yaitu jenuh air, kapasitas lapang, dan titik layu. Kadar air tanah pada batas antara kapasitas lapang dan titik layu disebut air tersedia bagi tanaman. Akan tetapi karena kemampuan tanah memegang air tergantung pada tekstur tanah, maka kadar air tanah pada kapasitas lapang dan titik layu berbeda menurut tekstur tanah dan demikian pula air tersedia. Hubungan antara status air tanah dan tekstur tanah diilustrasikan dalam gambar 2.1. Tingkat ketersediaan air tanah tertinggi diberikan oleh tanah bertekstur halus, terutama tanah lempung debu. Makin tinggi tegangan air tanah makin rendah air tersedia pada semua tekstur tanah. Pada tegangan 15 atm (titik layu), air tanah tidak tersedia lagi bagi tanaman.



Gambar 2.1. Hubungan Antara Kadar Air Tanah Dengan Tekstur Tanah

\*Sumber : Sadikin Somaatmadja, *Kedelai*, Bogor, 1995.

### 2.1.1. Hubungan Tanah-Air-Tanaman

Teori continuum menganggap tanaman sebagai suatu kapiler tempat air lewat, mulai dari tanah, akar, batang dan selanjutnya menguap ke udara di permukaan daun (transpirasi). Dengan teori ini Slatyer (30) memformulasikan factor-faktor yang menentukan besarnya transpirasi (T) dalam persamaan :

$$T = \frac{\Delta C}{\sum r} \approx (0,622 \rho u d/P \times \frac{\Delta e}{\sum r}) \quad (2-1)$$

Di mana:

$\Delta C$  = selisih konsentrasi uap air di udara dan di daun;

$\sum r$  = jumlah tahanan terhadap difusi uap air dari daun ke udara;

$\Delta e$  = selisih tekanan uap air di udara dan daun;

$0,622 \rho u d/P$  = factor konversi dari  $\Delta C$  ke  $\Delta e$ ;

$\rho u d$  = kerapatan udara;

$P$  = tekanan udara.

Dalam keadaan kering,  $\Delta e$  menjadi besar dan transpirasi meningkat sampai batas dimana laju transmisi air tanah ke akar tidak dapat menandingi laju transpirasi.

Dalam keadaan demikian stomata tertutup,  $r$  menjadi besar dan T akan terhambat.

Di lapangan tanaman tumbuh dalam suatu komunitas yang saling mempengaruhi.

Kehilangan air terjadi karena ada transpirasi dan evaporasi langsung dari permukaan tanah (evapotranspirasi). Dimana, subskripsi int berarti jalur difusi uap air dari komunitas tanaman. Dalam keadaan tanahnya basah sampai permukaan,  $C_{int}$  atau  $e_{int}$  berturut-turut adalah sama dengan  $C$  atau  $e$  di permukaan tanah;  $r_{int}$  dianggap sangat kecil, sebab itu diabaikan. Dalam keadaan

kering yang berkepanjangan, bidang penguapan (evaporation surface) secara lambat laun turun ke lapisan-lapisan daun (leaf canopy) di bawah, dan bila stomata daun tertutup karena sangat kering, bidang penguapan berada dibawah permukaan tanah dan evapotranspirasi menjadi terhambat pula.

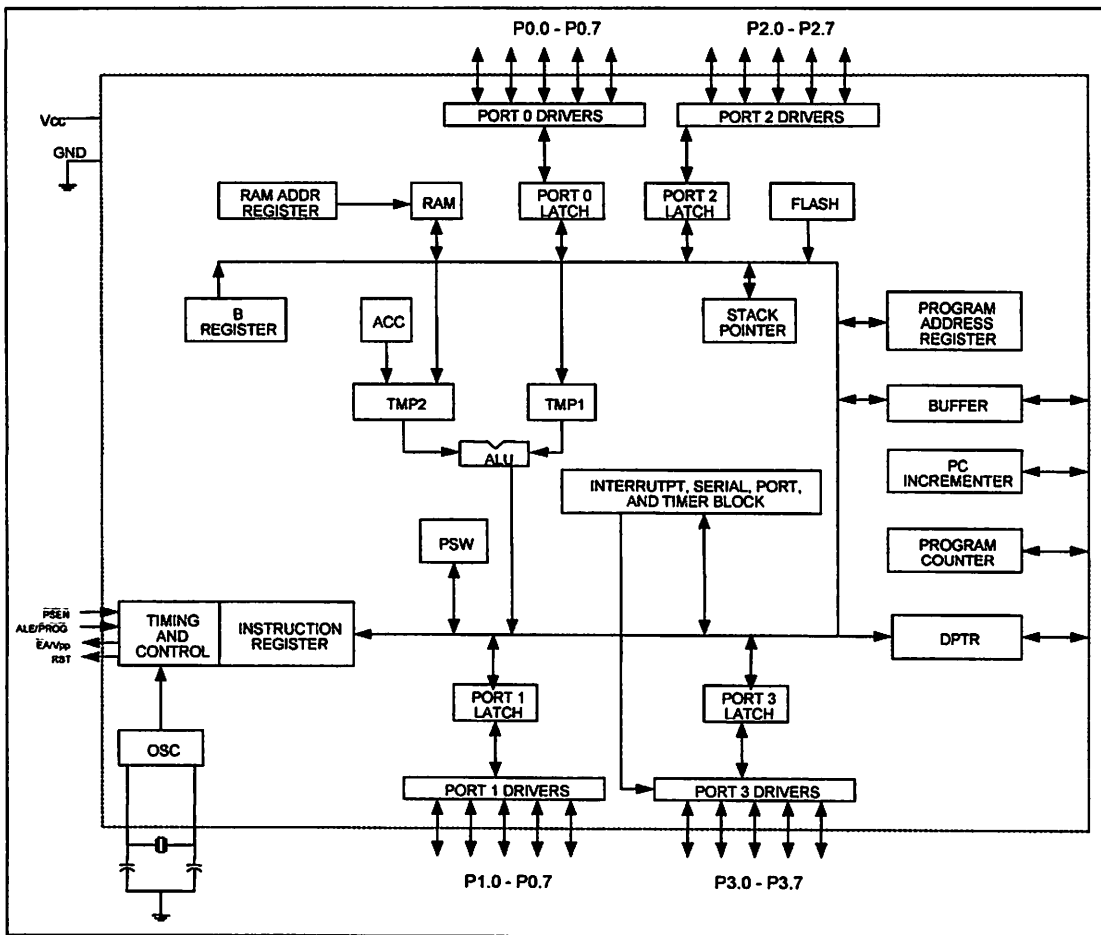
## **2.2. Mikrokontroler AT89S8252**

### **2.2.1. Pendahuluan**

Perbedaan mendasar antara mikrokontroler dan mikroprosesor adalah jika mikrokontroler selain memiliki CPU (*Central Processing Unit*) juga dilengkapi dengan memori dan I/O (*Input/Output*). Maka mikrokontroler dapat dikatakan sebagai *microcomputer* dalam keping tunggal (*single chip microcomputer*) yang dapat berdiri sendiri.

Mikrokontroler AT89S8252 adalah mikrokontroler keluarga MCS-51 yang membutuhkan daya rendah, memiliki kemampuan yang tinggi, dan merupakan mikrokomputer 8 bit yang dilengkapi 8K *byte Flash PEROM* (*Programmable and Erasable Read Only Memory*) yaitu ROM yang dapat ditulis ulang atau dihapus menggunakan sebuah perangkat *programmer*. *Flash PEROM* dalam AT89S8252 menggunakan *Atmel's High-Density Non Volatile Technology* yang mempunyai kemampuan untuk ditulis ulang hingga 1000 kali dan berisikan perintah *standard* MCS-51. Selain itu juga dilengkapi RAM *internal* sebesar 256 *byte*. Dalam sistem Mikrokontroler terdapat dua hal yang mendasar, yaitu: perangkat keras dan perangkat lunak yang keduanya saling terkait dan mendukung

## 2.2.2. Perangkat Keras Mikrokontroler AT89S8252



Gambar 2.2. Blok Diagram Mikrokontroler AT89S8252

\*Sumber : Paulus, 2003 : 2

Mikrokontroler AT89S8252 secara umum memiliki:

- CPU 8 bit
- 8Kbyte FLASH PEROM
- 2 Kbyte EEPROM *internal*
- *Memory* 256 x 8 bit *Internal* RAM
- 32 Port I/O *Lines*
- 3 *Timer* dan *Counter* 16 bit
- 9 Sumber Interupsi
- SPI serial *interface*

- *Oscillator dan clock 12 - 24 MHz*
- *Programmable Watchdog Timer*
- *Programmable UART Serial Chanel*
- *Dual Data Pointer*
- *Power-Off Flag*

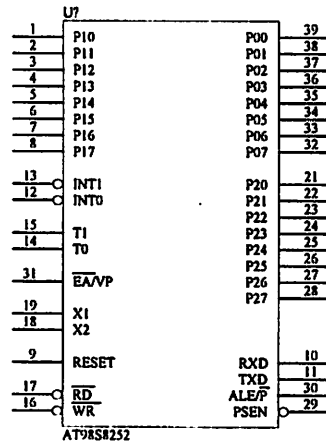
### 2.2.3. Arsitektur AT89S8252

Arsitektur Mikrokontroler AT89S8252 adalah sebagai berikut:

- 1). CPU (*Central Processing Unit*) 8 bit dengan *register A (Accumulator) & B*.
- 2). 16-bit *Program Counter (PC)* dan (*Data Pointer*) DTPR.
- 3). 8-bit *Program Status Word (PSW)*.
- 4). 8-bit *Stack Pointer (SP)*.
- 5). 8 Kbyte Flash PEROM *internal*.
- 6). 256 byte *internal RAM*.
  - 4 *bank register*, masing-masing berisi 8 *register*
  - 16 *byte* yang dapat dialamati pada bit level
  - 208 *byte general purpose memory data*
- 7). 32 pin *input-output* tersusun atas P0-P3. masing-masing 8-bit.
- 8). 3 buah *timer (T0 & T1)* dengan masing-masing 16-bit *timer/ counter*.
- 9). *Receiver/transmitter data* secara *serial full duplex: Serial buffer (SBUF)*.
- 10). *Control register* : (TCON, TMOD, SCON, PCON, IP & IE)
- 11). 9 buah *sumber* interupsi (2 buah sumber interupsi *external* dan 3 buah sumber interupsi *internal* ).
- 12). *Oscillator dan clock internal*.

### 2.2.4. Konfigurasi Pin Mikrokontroler AT89S8252

Konfigurasi kaki-kaki mikrokontroler terdiri dari 40 pena, seperti terlihat pada gambar 2.3:



Gambar 2.3. Diagram Pin Mikrokontroler AT89S8252

\*Sumber : Paulus, 2003 : 2

Fungsi dari tiap-tiap pena adalah sebagai berikut:

- **Pin\_40: Vcc** (sumber tegangan).
- **Pin\_20: GND** (*Ground*).
- **Pin\_32-39: Port\_0:**

Merupakan port *input-output* dua arah multipleks dan dua *bus* alamat rendah (A0-A7) serta data selama pengaksesan program dan data memori *external*.

- **Pin\_1-8: Port\_1:**

Merupakan port *input-output* dua arah dengan *internal pull-up*.

- **Pin\_21-28: Port\_2:**

Merupakan port *input-output* dengan *internal pull-up*. Mengeluarkan *address* tinggi selama pengambilan (*fetching*) *program memory external*. Selama pengaksesan ke *external data memory*, port 2 mengeluarkan isi P2 SFR

(*Special Function Register*). Menerima *address* dan beberapa sinyal kontrol selama pemrograman dan verifikasi.

➤ **Pin\_10-17: Port\_3:**

Merupakan port *input-output* dengan *internal pull-up*. Port 3 juga memiliki fungsi khusus, yaitu:

- RXD (P3.0) : Port *serial input*.
- TXD (P3.1) : Port *serial output*.
- INT0 (P3.2) : *external interrupt 0*.
- INT1 (P3.3) : *external interrupt 1*.
- T0 (P3.4) : *Input external timer 0*.
- T1 (P3.5) : *Input external timer 1*.
- WR (P3.6) : *Strobe tulis data memori external*.
- RD (P3.7) : *Strobe baca data memori external*.

➤ **Pin\_9: RST (Reset):**

*Input Reset* berfungsi me-*reset* CPU saat sumber tegangan dihidupkan.

➤ **Pin\_30: ALE/PROG (Address Latch Enable)/Programming:**

Pulsa output ALE digunakan untuk proses '*latching*' *byte address* rendah (A0-A7) selama pengaksesan ke memori *external*. Pin ini juga digunakan untuk memasukkan pulsa program selama pemrograman.

➤ **Pin\_29: PSEN (Program Store Enable):**

Merupakan *strobe* baca ke program memori *external*.

➤ **Pin\_31: EA/VPP (External Address):**

EA *low* jika mengakses memori *external*. Untuk mengakses memori *internal* maka EA dihubungkan ke-Vcc (+5V).

➤ **Pin\_18-19: XTAL1 dan XTAL2:**

Kaki ini dihubungkan dengan kristal bila menggunakan *Oscillator internal*. XTAL1 merupakan *input inverting Oscillator amplifier* sedangkan XTAL2 merupakan *output inverting Oscillator amplifier*.

### 2.2.5. Organisasi Memori

Dalam mikrokontroler AT89S8252 ruang alamat telah dibedakan untuk program memori dan data memori.

#### 2.2.5.1. Internal Program Memory

Mikrokontroler AT89S8252 memiliki program memori *internal* sebesar 4Kbyte dengan ruang alamat 0000H-0FA0H. Jika alamat-alamat program lebih tinggi dari pada 0FA0H dimana melebihi kapasitas ROM *internal*, menyebabkan AT89S8252 secara otomatis mengambil kode byte dari program memori *external*. Kode *byte* juga dapat diambil hanya dari memori *external* dengan alamat 0000H-FFFFH dengan cara menghubungkan pin EA ke *ground*.

#### 2.2.5.2. Random Access Memory (RAM)

Ruangan alamat memory data *internal* (RAM) dengan kapasitas 256 *byte* yaitu: 00H-FFH yang terbagi atas 3 daerah, yaitu:

1. Empat *bank register*

Setiap *bank* terdiri dari 8 *register* (R0-R7) sehingga jumlah *register* untuk ke-empat *bank register* menjadi 32 buah *register* yang menempati ruang alamat 00H-1FH. Mengaktifkan salah satu *bank register* dapat dilakukan dengan mengatur RS0-RS1 pada *Program Status Word* (PSW).

## 2. Bit Addressable

Terdiri dari *16 byte* yang berada pada alamat 20H-2FH. Masing-masing bit dalam 128 bit yang lokasinya dapat dialamatasi secara langsung.

## 3. RAM Keperluan Umum

Terdiri atas *208 byte* yang menempati alamat 30H-FFH, dan dapat dialamatasi secara langsung maupun tak langsung dalam penggunaan untuk keperluan umum (*general purpose*).

Tabel 2.1  
Pengaturan RS0-RS1 *Bank Register*

RS1	RS0	<i>Register Bank Select Bits</i>
0	0	<i>Bank 0</i>
0	1	<i>Bank 1</i>
1	0	<i>Bank 2</i>
1	1	<i>Bank 3</i>

\*Sumber : Paulus, 2003 : 3

### 2.2.5.3.SFR (*Special Function Register*)

Untuk operasi AT89S8252 yang menggunakan alamat internal RAM (00H-7FH). Beberapa dari *register-register* ini juga mampu dengan pengalamatan bit sehingga dapat dioperasikan serpetri yang ada pada RAM.

#### 2.2.5.3.1. PSW (*Program Status Word*)

*Register* ini terletak di alamat D0H. Cara mendefenisikannya ditunjukkan pada tabel 2.2. berikut ini :

**Tabel 2.2**  
**Pengaturan RS0-RS1 Bank Register**

Alamat	Data	Simbol	Posisi	Fungsi /Arti
<b>D0H</b>	D0	P	PSW.0	<i>Parity flag</i>
	D1	-	PSW.1	<i>Flag didefinisikan oleh pemakai.</i>
	D2	OV	PSW.2	<i>OverflowFlag</i>
	D3	RS0	PSW.3	<i>Bit pemilih bank register.</i>
	D4	RS1	PSW.4	<i>Bit pemilih bank register.</i>
	D5	F0	PSW.5	<i>Flag 0</i>
	D6	AC	PSW.6	<i>Auxiliary CarryFlag</i>
	D7	CY	PSW.7	<i>Carry Flag</i>

\*Sumber : Paulus, 2003 : 12

#### 2.2.5.3.2. PCON (*Power Control*)

*Register* ini terletak pada alamat 87H. Cara mendefenisikannya ditunjukkan pada tabel 2.3 berikut ini :

**Tabel 2.3**  
**Skema Medefinisikan PCON**

Alamat	Data	Simbol	Fungsi /Arti
<b>87H</b>	D0	IDL	<i>Idle mode bit</i>
	D1	PD	<i>Power Down bit</i>
	D2	GF0	<i>Bit flag serbaguna.</i>
	D3	GF1	<i>Bit flag serbaguna.</i>
	D4	-	Tidak dipakai.
	D5	-	Tidak dipakai.
	D6	-	Tidak dipakai.
	D7	SMOD	Digunakan untuk menghasilkan <i>baudrate</i> dan SMOD_1, maka <i>baudrate</i> akan <i>double</i> baik mode 0,1,2 atau 3.

\*Sumber : Paulus, 2003 : 17

#### 2.2.5.4.Sistem Interupsi

Mikrokontroler AT89S8252 mempunyai 9 buah sumber interupsi yang dapat mengakibatkan permintaan interupsi, yaitu: INT0, INT1, T0, T1 port serial dan beberapa port lainnya. Saat terjadi interupsi mikrokontroler secara otomatis akan menuju ke *subrutin* pada alamat tersebut. Setelah interupsi *service* selesai dikerjakan, Mikrokontroler akan mengerjakan program semula. Sumber interupsi

*external* adalah INT0, INT1, dimana kedua interupsi *external* ini akan aktif pada transisi rendah selain itu juga ada *Timer/Counter 0*, *Timer/Counter 0* dan interupsi dari port serial (*receiver*). Interupsi serial dibangkitkan dengan melakukan operasi OR pada R1 dan T1. Tiap-tiap sumber interupsi dapat di-*enable* atau di-*disable* secara *software*. Tingkat prioritas semua sumber interupsi dapat diprogram sendiri-sendiri dengan *set* atau *clear* bit pada SFRS IP (*Interrupt Priority*).

Tabel 2.4  
Alamat Sumber Interupsi

Sumber Interupsi	Alamat Awal
<i>Power On Reset</i>	0000h
<i>Interrupt luar 0 (INT 0)</i>	0003h
<i>Pewaktu/ pencacah 0 (T0)</i>	000Bh
<i>Interrupt luar 1 (INT 1)</i>	0013h
<i>Pewaktu/ pencacah 1 (T1)</i>	001Bh
<i>Port I/O Serial</i>	0023h

\*Sumber : Paulus, 2003 : 53

*Register* yang berperan dalam mengatur aktif tidaknya interupsi adalah *interrupt enable register*, susunan dari bit-bit beserta kegunaannya adalah:

Tabel 2.5  
Kegunaan *Interrupt Enable Register*

Alamat	Data	Simbol	Posisi	Fungsi /Arti
A8H	D0	EX0	IE.0	Diatur secara <i>software</i> untuk interupsi dari INT1.
	D1	ET0	IE.1	Diatur secara <i>software</i> untuk interupsi dari <i>timer/counter 1</i> .
	D2	EX1	IE.2	Diatur secara <i>software</i> untuk interupsi dari INT1.
	D3	ET1	IE.3	Diatur secara <i>software</i> untuk interupsi dari <i>timer/counter 1</i> .
	D4	ES	IE.4	Untuk mengatur <i>enable</i> atau <i>disables</i> uatu interupsi R1/T1.
	D5	-	IE.5	Kosong
	D6	-	IE.6	Kosong
D7	EA	IE.7	Jika diatur 0 maka semua interupsi di- <i>disable</i> , jika diatur 1 maka interupsi diatur di- <i>disable</i> atau di- <i>enable</i> menurut masing-masing bit.	

\*Sumber : Paulus, 2003 : 51

### 2.2.5.5. *Timer/Counter*

Pengendalian kerja dari *timer/counter* dilakukan dengan pengaturan register yang berhubungan dengan kerja dari *timer/counter* yaitu melalui sebuah

*timer/counter mode control*. Untuk mengaktifkan *timer/counter* yang meliputi penentuan fungsi sebagai *timer* atau sebagai *counter* serta pemilihan *mode* operasi dapat diatur melalui TMOD yang beralamat pada 89H. Konfigurasi dari *register* TMOD seperti yang ditunjukkan pada Tabel 2.6. berikut ini :

Tabel 2.6  
Register TMOD

Alamat	Data	Simbol	Posisi	Fungsi /Arti
88H	D0	IT0	TCON.0	<i>Interrupt 0 type control bit.</i>
	D1	IE0	TCON.1	<i>External interrupt 0 edge flag.</i>
	D2	IT1	TCON.2	<i>Interrupt type 1 control bit.</i> Diatur oleh <i>software</i> untuk menentukan aktif <i>low</i> atau <i>high trigger</i> dari <i>external</i> .
	D3	IE1	TCON.3	<i>External interrupt 1 edge flag.</i> Diatur oleh <i>hardware</i> ketika <i>external interrupt</i> terdeteksi dan nol-kan melalui <i>software</i> ketika <i>interrupt</i> diproses.
	D4	TR0	TCON.4	<i>Timer 0 control bit.</i> Diatur oleh <i>software</i> ketika <i>timer/counter 0</i> .
	D5	TF0	TCON.5	<i>Timer 0 overflow flag control bit.</i> Diatur oleh <i>software</i> ketika <i>timer/counter 0</i> <i>oferflow</i> .
	D6	TR1	TCON.6	<i>Timer 1 control bit.</i> Diatur oleh <i>software</i> ketika <i>timer/counter 0</i> .
	D7	TF1	TCON.7	<i>Timer 1 overflow flag control bit.</i> Diatur oleh <i>software</i> ketika <i>timer/counter 0</i> <i>oferflow</i> .

\*Sumber : Paulus, 2003 : 33

Tabel 2.7  
Timer/Counter Mode Control Register

Alamat	Data	Simbol	Fungsi /Arti
89H	D0	<i>Timer 0; M0 (0)</i>	Untuk memilih mode <i>timer</i> .
	D1	<i>Timer 0; M1 (0)</i>	Untuk memilih mode <i>timer</i> .
	D2	<i>Timer 0; C/T (0)</i>	1 = <i>Counter</i> & 0 = <i>Timer</i>
	D3	<i>Timer 0; GATE (0)</i>	<i>Timer</i> akan berjalan jika bit di <i>set</i> dan INT0 (untuk <i>Timer 0</i> ) atau INT1 (untuk <i>Timer 1</i> )
	D4	<i>Timer 1; M0 (1)</i>	Untuk memilih mode <i>timer</i> .
	D5	<i>Timer 1; M1 (1)</i>	Untuk memilih mode <i>timer</i> .
	D6	<i>Timer 1; C/T (0)</i>	1 = <i>Counter</i> & 0 = <i>Timer</i>
	D7	<i>Timer 1; GATE (1)</i>	<i>Timer</i> akan berjalan jika bit di <i>set</i> dan INT0 (untuk <i>Timer 0</i> ) atau INT1 (untuk <i>Timer 1</i> )

\*Sumber : Paulus, 2003 : 32

Tabel 2.8  
Mode Operasi *Timer/Counter*

M1	M0	Operating Mode
0	0	<i>Timer</i> 13 bit
0	1	<i>Timer/Counter</i> 16 bit
1	0	8 bit <i>Auto reload Timer /Counter</i>
1	1	TL0 dari <i>Timer</i> adalah 8 Bit <i>Timer/Counter</i> dikendalikan oleh kontrol bit <i>Timer</i> 0. TH0 adalah 8 bit yang dikendalikan oleh <i>Timer</i> 1 control bit.

\*Sumber : Paulus, 2003 : 33

### 2.2.5.6. Metode Pengalamatan

#### 1. Pengalamatan bit (*Direct Bit Addressing*) :

Pengalamatan langsung tiap bit ini hanya dilakukan pada lokasi RAM *internal* yaitu 20H-2FH, dan sebagian SFR yaitu: port 0, port 1, port 2, port 3, TCON register, SCON register, IE register, PSW register, ACC dan B register.

#### 2. Pengalamatan tak langsung (*Indirect Bit Addressing*):

Pada *pengalamatan* tak langsung, instruksi menunjukkan suatu *register* yang isinya adalah alamat dari *operand*, *eksternal* dan *internal* RAM dapat dialamati secara tidak langsung. *Register* alamat untuk data dengan lebar 8 bit dapat berupa R0 dan R1 yang digunakan untuk memilih angka *register* atau *stack pointer*. *Register* alamat untuk data, dengan lebar 16 bit digunakan *Data Pointer* (DPTR).

#### 3. Pengalamatan ber-indeks :

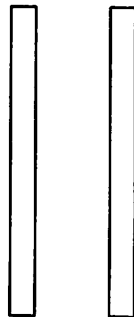
Yang dapat diakses dengan pengalamatan berindeks hanya *memory program*. Mode ini dimaksudkan untuk membaca *look-up table program*.

#### 4. Konstanta *immediat* :

Pengalamatan langsung dilakukan dengan memberikan nilai ke *register* secara langsung, dilakukan dengan menggunakan tanda #, Contoh: Mov A, #100

### 2.3. Sensor Air (Probe)

Sensor ini berfungsi untuk mendeteksi ada tidaknya air tanah yang mengenai sensor. Sensor ini berupa probe yang diletakkan pada posisi yang berbeda dan digunakan sebagai referensi bagi input rangkaian untuk menggerakkan motor menutup atap. Besarnya resistansi probe ketika ada air adalah sekitar  $10\text{ K}\Omega$ , dan ketika tidak ada air yang mengenainya (kering) maka besar resistansinya sangat besar. Sensor air dibentuk (disusun) dari dua logam baja stenles steel dengan masing-masing memiliki ukuran panjang 5 cm, lebar 1 cm, tebal 1mm, jarak kedua logam 1,5cm dan didesain sedemikian rupa sehingga jika ada air tanah diantara kedua logam ini, maka akan menyebabkan perbedaan resistansi antar kedua logam baja tersebut. Perbedaan resistansi ini akan dikondisikan dengan rangkaian pengkondisi sinyal sehingga akan dapat digunakan untuk mendeteksi tingkat kelembaban air tanah. Gambar 2.4 dibawah ini merupakan gambar bentuk fisik sensor tersebut.



**Gambar 2.4**  
**Ukuran dan Bentuk Fisik Sensor Kelembaban Tanah**  
\*Sumber : Perancangan

Untuk merancang sensor ini dapat dengan mudah digunakan rangkaian penguat level tegangan *output* mendeteksi objek. Rangkaian dapat dibentuk dari rangkaian (Op-Amp) dengan pengutan yang dapat diatur.

#### 2.4. Solenoid

Prinsip dasar dari solenoid adalah adalah kumparan bentuk melingkar yang dialiri arus listrik, dimana bila kumparan tersebut dialiri arus  $I$  dengan jumlah lilitan  $n$  dan dengan tegangan sebesar  $V$  akan menimbulkan medan listrik di dalam kumparan tersebut. Arah gerak medan magnet tersebut ditentukan dengan kaidah tangan kiri yang berbunyi dimana arah arus listrik  $I$  tegak lurus terhadap medan listrik. Kuat medan magnet dapat ditunjukkan pada rumus :

$$H = \frac{N \cdot i}{\ell} \quad (2-2)$$

Dimana :

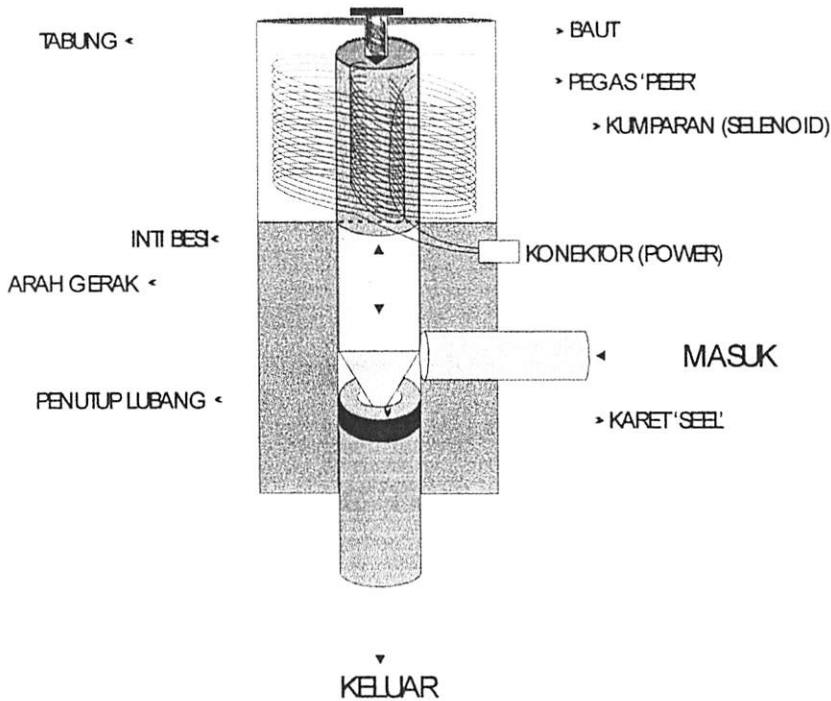
$H$  : Kuat medan (Ampere/meter)

$i$  : Arus listrik (A)

$\ell$  : Panjang jalur (m)

$N$  : Jumlah lilitan

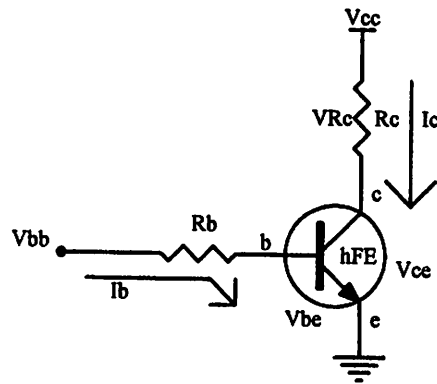
Gambar selenoid valve ditunjukkan pada gambar dibawah ini:



Gambar 2.5. Selenoid Valve

## 2.5. Transistor

Transistor merupakan salah satu dari komponen aktif yang sering sekali digunakan dalam setiap rangkaian elektronika. Beberapa fungsi transistor yaitu dapat digunakan sebagai rangkaian *driver* ataupun sebagai saklar. Rangkaian *driver* merupakan suatu rangkaian yang digunakan untuk menggerakkan suatu peralatan lain yang membutuhkan arus atau tegangan yang lebih besar. Dalam rangkaian *driver* ini kaki basis transistor dikontrol dengan memberi pulsa rendah dan pulsa tinggi. Rangkaian *driver* ditunjukkan dalam gambar 2.6:



Gambar 2.6. Transistor Sebagai Saklar  
 Sumber : Wasito S, *Vademekum*, 1984 : 91

Dalam gambar terlihat  $V_{bb}$  akan memberi tegangan maju kepada dioda emitor melalui resistor  $R_b$ . Untuk sebuah transistor *silikon* memiliki tegangan hambat pada  $V_{be}$  sebesar 0,6 Volt, sedangkan transistor *germanium*  $V_{be}$  0,7 Volt.

Arus basis dan kolektor ditentukan dengan persamaan:

$$I_c = \frac{V_{cc} - V_{ce}}{R_c} \text{ (Ampere)} \quad (2-3)$$

$$I_b = \frac{V_{bb} - V_{be}}{R_b} = \frac{I_c}{h_{fe}} \text{ (Ampere)} \quad (2-4)$$

Dimana:

$V_{bb}$  : Tegangan bias basis (Volt)

$V_{be}$  : Tegangan basis emitor (Volt)

$V_{ce}$  : Tegangan kolektor emitor (Volt)

$V_{cc}$  : Tegangan sumber (Volt)

$R_c$  : Resistor pada kolektor (Ohm)

$R_b$  : Resistor pada basis (Ohm)

$I_c$  : Arus pada kolektor (Ampere)

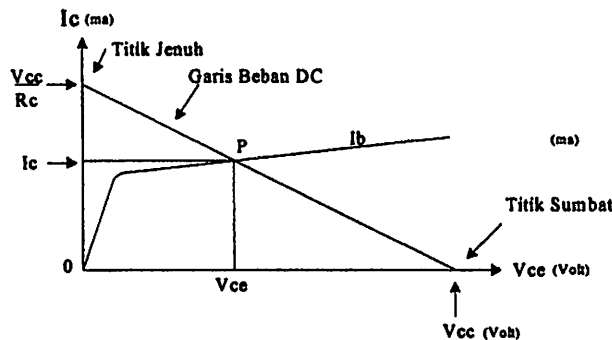
$I_b$  : Arus pada basis (Ampere)

$h_{fe}$  : Penguatan (kali/perkelipatan)

Arus kolektor yang mengalir pada resistor-nya akan menimbulkan tegangan sebesar  $I_c \times R_c$ . Karena itu tegangan emitor kolektor menjadi:

$$V_{ce} = V_{cc} - I_c \cdot R_c \text{ (Volt)} \quad (2-5)$$

Hubungan antara  $I_c$  dan  $V_{ce}$  pada garis beban DC dari transistor pada hambatan beban tertentu ditunjukkan pada gambar 2.7:



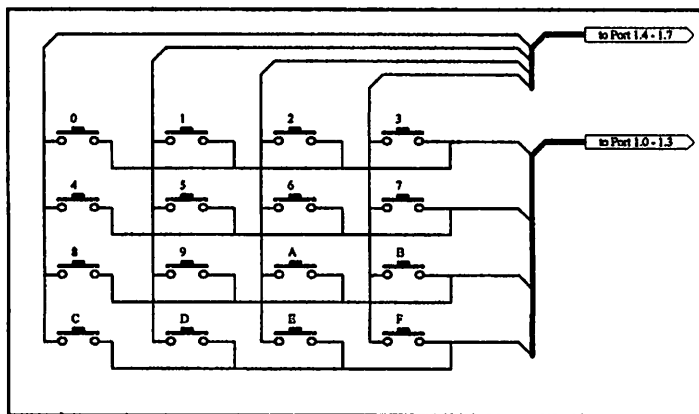
Gambar 2.7. Titik Potong Antara Garis Beban dan Arus Basis  
Sumber : Wasito S, *Vademekum*, 1984 : 96

Garis beban DC tersebut mempunyai titik potong dengan sumbu tegak pada  $I_c$  di titik  $V_{cc} / R_c$  dan memotong sumbu  $V_{ce}$  pada titik  $V_{cc}$ . Titik P merupakan titik potong antara garis beban dan arus beban. Pada gambar diatas tampak bahwa titik potong antara garis beban DC dan kurva  $I_B$  pada daerah 0 atau pada sumbu  $V_{ce}$  dikenal sebagai titik *cut off* (sumbat), pada keadaan ini  $V_{ce}=V_{cc}$ . Sedangkan untuk titik jenuh adalah titik potong kurva  $I_B$  pada ujung teratas pada garis beban DC pada  $V_{ce} = 0$  atau pada sumbu  $I_c$ .

## 2.6. Keypad

Teknik paling populer yang digunakan dalam perancangan *keypad* heksadesimal adalah teknik multiplexer, yaitu: pergantian atau pergeseran suatu

nilai bit dari bit tinggi menuju bit rendah atau sebaliknya dari bit rendah menuju bit tinggi, dengan empat buah jalur baris dan empat jalur kolom. Bila baris dan kolom ini disilangkan, maka akan terbentuk titik potong yang membentuk matrik 4 x 4, seperti ditunjukkan dalam gambar 2.8 berikut ini :



Gambar 2.8. *Keypad* Matrik 4 x 4  
 \*Sumber : Paulus, 2003 : 132

Rangkaian ini dapat dianalogikan dengan tiga buah kabel terbuka dengan empat buah kabel lainnya. Bila pada suatu titik kabel yang bersilangan itu disentuhkan, maka diasumsikan bahwa tombol *keypad* pada posisi yang bersilangan tersebut ditekan. Penekanan *keypad* tersebut akan membentuk koordinat (x,y) dalam dua dimensi. Informasi posisi yang diperlukan adalah informasi tentang nilai x dan y, dalam pemrograman, nilai 'x dan y' ini dapat diperoleh melalui *scanning*. Rangkaian *keypad* ini terdiri dari 16 buah saklar *push button* yang dirangkai dalam bentuk matriks (kolom dan baris). Jalur kolom dan baris dari *keypad* tersebut nantinya akan dihubungkan pada port mikrokontroler.

## 2.7. Penguat Operasional

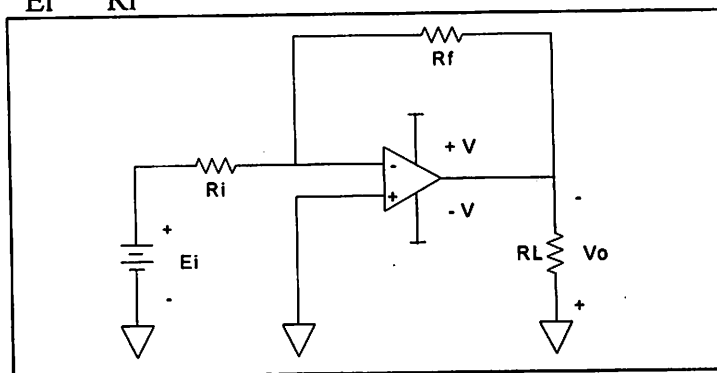
### 2.7.1. Penguat Pembalik

Penguat pembalik (*inverting*) adalah sebuah penguat yang tegangan keluaranya ( $V_o$ ) mempunyai keluarannya yang tidak sama seperti tegangan masukan  $E_i$ , yang diperlihatkan pada gambar 2.9. Persamaan tegangan keluaran dari penguat membalik adalah sebagai berikut :

$$V_o = - \frac{R_f}{R_i} \cdot E_i \text{ Volt} \dots\dots\dots (2.6)$$

Sehingga diperoleh persamaan *gain* tegangannya:

$$A_{cl} = \frac{V_o}{E_i} = \frac{R_f}{R_i} \text{ kali} \dots\dots\dots (2.7)$$



Gambar 2.9. Polaritas Tegangan Untuk Penguat Pembalik  
\*Sumber : Robert Collinc, 1998 : 102

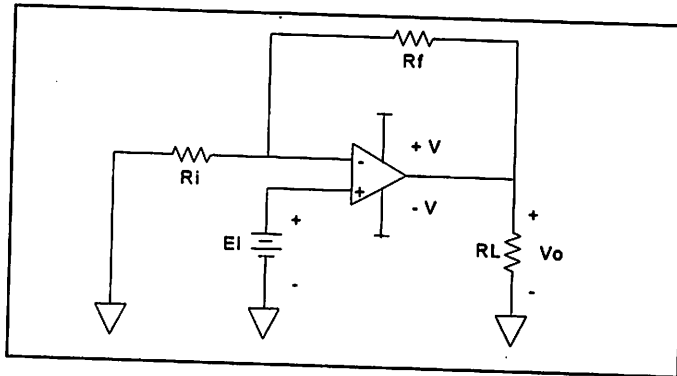
### 2.7.2. Penguat Tak Membalik

Penguat tak membalik (*Non Inverting*) adalah penguat yang tegangan keluaran  $V_o$  mempunyai polaritas yang sama seperti tegangan masukannya  $E_i$ , yang diperlihatkan gambar 2.10. Persamaan tegangan keluaran dari penguat tak membalik adalah sebagai berikut :

$$\left[ 1 + \frac{R_f}{R_i} \right] \cdot E_i = V_o \dots\dots\dots (2.8)$$

Sehinga dapat di peroleh persamaan *gain* tegangannya :

$$A_{cl} = \frac{V_o}{E_i} \dots\dots\dots (2.9)$$



Gambar 2.10. Polaritas Tegangan Untuk Penguat Tak Membalik

\*Sumber : Robert Collinc, 1998 :103

### 2.8. Analog to Digital Converter (ADC)

Sistem kontrol hanya dapat mengolah atau memproses data dalam bentuk *biner* atau lebih disebut digital saja, oleh sebab itu data *analog* yang akan diproses oleh harus diubah terlebih dahulu ke dalam bentuk kode-kode *biner (digital)*. Jadi untuk menghubungkan sistem *analog* yang ada di luar sistem ke dalam kontrol, dibutuhkan suatu pengubah atau *analog to digital converter*.

Fungsi dasar dari pengubah *analog* ke *digital* adalah pengubah tegangan *analog* kedalam bentuk kode-kode *biner (digital)* sehingga dapat diproses oleh kontrol. Tegangan analog yang merupakan masukan dari ADC berasal dari pengkondisi arus, rangkaian ini mempunyai range tertentu dan disebut *analog*. Kode *biner* hasil konversi ini dipakai sebagai data untuk diolah kontrol yang kemudian ditampilkan melalui LCD.

Pengubah *analog* ke *digital* merupakan jantung dari sistem data akuisisi yang berfungsi mengubah data dalam bentuk kontinyu ke dalam *digital* yang diskrit, sehingga cocok untuk diproses oleh mikrokontroler. ADC lebih banyak variasi bentuknya bila dibandingkan dengan DAC. Karena ADC karakteristik yang dibutuhkan jauh lebih banyak. Adapun jenis ADC antara lain :

- *Single Ramp Integrating.*
- *Dual Slope Integrating .*
- *Tracking (Counter Comparator ).*
- *Single Counter.*
- *Successive Approximations.*
- *Multi Comparator (Flash).*

Ada beberapa faktor yang perlu diperhatikan dalam pemilihan komponen ADC, antara lain :

- *Resolution*

Merupakan spesifikasi terpenting untuk ADC, yaitu jumlah langkah dari sinyal skala penuh yang dibagi dan juga ukuran dan langkah-langkah. Boleh juga dinyatakan dalam bit yang ada dalam satu *word*. Ukuran LSB (langkah terkecil) sebagai persen dari skala penuh atau dapat juga LSB dalam mV (untuk skala penuh yang diberikan).

- *Accuracy (Ketelitian)*

Adalah jumlah dari semua kesalahan, misalnya kesalahan *nonlinier*, skala penuh, skala nol dan lain-lain. Dapat juga menyatakan perbedaan antara tegangan *input analog* secara teoritis yang dibutuhkan untuk

menghasilkan suatu kode *biner* tertentu terhadap tegangan *input* nyata yang menghasilkan tegangan kode *biner* tersebut.

- Waktu Konversi

Waktu yang dibutuhkan untuk mengkonversikan *analog* ke *digital* setiap sampel atau waktu yang diperlukan untuk menyelesaikan suatu konversi.

Disini tidak akan dijelaskan keseluruhan dari jenis ADC, tetapi hanya dititik-beratkan pada ADC jenis *successive approximation*, karena dalam perencanaan pembuatan alat digunakan ADC jenis ini. *Successive approximation* merupakan golongan ADC medium. ADC tipe ini dapat dikatakan merupakan perpaduan yang baik antara kecepatan (kecepatan menengah) dan tingkat kerumitan rangkaian (menengah). Waktu Konversi ADC ini selalu tetap, tidak tergantung pada besarnya sinyal analog (*input*), tetapnya waktu konversi ini merupakan salah satu keuntungan penggunaan ADC tipe ini.

### 2.8.1. *Successive Approximation*

ADC jenis ini dibentuk dari beberapa komponen DAC (*Digital to Analog Converter*), *Comparator* dan beberapa *register* serta rangkaian kontrol. Teknik konversi yang dipakai adalah dengan melakukan perbandingan antara tegangan *input* yang tidak diketahui dengan tegangan *input* yang dihasilkan oleh DAC. DAC diatur oleh *shift register* dan rangkaian logika untuk kontrol dan hasil konversi dapat diambil dari *register* keluaran. Konversi dimulai dengan memberikan sinyal *input start conversion*.

Dengan sinyal *start conversion* tersebut mengakibatkan *input* DAC akan dibuat aktif sehingga MSB sama dengan 1 dan bit yang lain berharga 0. *Output*

DAC akan terjadi setengah *full scale* dibanding dengan *input analog* yang dikonversi. Dari *output comparator* dapat diketahui mana yang lebih besar, bila tegangan *output DAC* lebih besar maka bit MSB tetap, sedang bila *output DAC* lebih kecil maka MSB berubah menjadi 0. Kemudian bit berikutnya (bit lebih rendah dari MSB) dibuat sama dengan 1 dengan keadaan MSB tetap seperti proses perbandingan pertama tadi.

Dari keadaan *input digital* ini akan dihasilkan *output analog* (dari DAC) yang juga akan dibandingkan lagi dengan tegangan *input* untuk menentukan apakah keadaan bit kedua akan diubah atau tidak. Proses diatas berlangsung sampai kondisi LSB, sehingga diperoleh *output* dari DAC yang terakhir. Proses pergeseran bit dari MSB sampai LSB dilakukan oleh *shift register* yang waktunya diatur oleh pulsa *clock*. Jika proses konversi tersebut telah selesai dari setiap input, maka *output* status bit pada pin 7 tersebut akan memberitahukan melalui “*End of Conversion*” yang menyatakan bahwa *output digital* ADC dapat diambil sebagai besaran *digital* yang mewakili *input analog* yang dikonversikan

### **2.8.2. Analog To Digital Converter 0809**

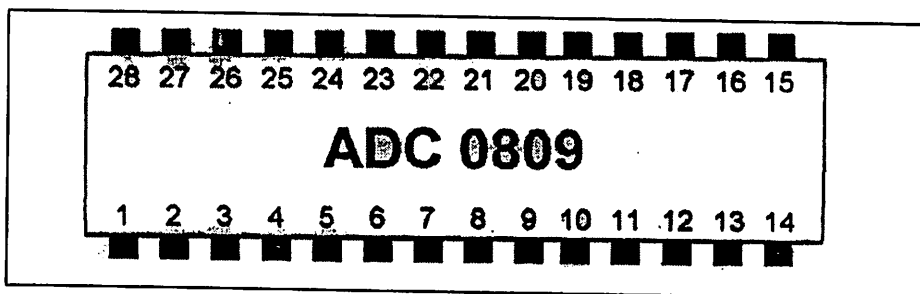
*Analog To Digital Conversion* 0809 dikemas dalam IC *monolitik*, ADC ini menggunakan metode pengubah berturut-turut (*successive Approximation*) dengan 8 saluran *input analog* dan dilengkapi dengan beberapa kontrol logika yang sesuai dengan *standart microprocessor*. Blok diagram ADC 0809 memperlihatkan bahwa ADC 0809 terdiri dari 3 (tiga) bagian utama yaitu :

- MUX *Analog 8 Channel*.
- *Analog to Digital Converter* ADC 8 bit.

- *Three – State Latch Buffer* (penyangga terkunci 3 kanal).

*Multiplexer analog 8 chanel* berfungsi untuk mengolah 8 *input* data *analog* secara bergantian. Untuk memilih *input* mana yang dikehendaki pada *output multiplexer* disediakan 3 bit kontrol pemilih saluran *input* tersedia. *Analog to Digital Converter* (ADC) merupakan *successive approximation register* 8 bit yang terdiri dari komparator, SAR, dan *Clock Three – State Latch Buffer* berfungsi untuk menampung keluaran ADC 8 bit.

ADC ini merupakan *level* terbatas untuk sinyal *input*-nya yang tergantung pada *input* referensi yang digunakan. Dalam hal ini yang membatasi adalah tegangan referensi *positif*  $V_{ref}$  (+) dan tegangan *negatif*  $V_{ref}$  (-). Jika *input* referensi diberi tegangan *negatif* dan *input* referensi *positif* diberi tegangan *positif* sehingga tegangan *input analog* dapat berharga diantara kedua tegangan referensi tadi dan ini disebut *bipolar*, artinya kedua *input*-nya mempunyai polaritas *positif* dan *negatif*. Jika *input* referensi *positif* diberi tegangan *positif* dan referensi *negatif* diberi tegangan 0 Volt, maka dapat disebut *unipolar* karena *analog*-nya berada diatas 0 Volt (berharga *positif* saja). ADC yang dipakai dalam sistem ini dirancang untuk jenis *unipolar*. Gambar struktur pin ADC 0809 sebagai berikut:



Gambar 2.11. Struktur Pin IC ADC 0809  
 \*Sumber : *Anonimous, National Data Sheet, 1995 : 2/56*

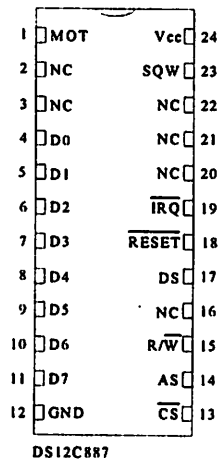
Tabel 2.9  
Keterangan Pin IC ADC 0809

Pin	Nama	Keterangan
1	IN <sub>3</sub>	Masukan 3
2	IN <sub>4</sub>	Masukan 4
3	IN <sub>5</sub>	Masukan 5
4	IN <sub>6</sub>	Masukan 6
5	IN <sub>7</sub>	Masukan 7
6	Start	Mulai Konversi
7	EOC	End of Conversion
8	2 <sup>-5</sup>	Output 5
9	Output Enable	Menghidupkan Output
10	Clock	Clock
11	Vcc	Supply tegangan
12	Vref (+)	Tegangan referensi (+)
13	GND	Ground
14	2 <sup>-7</sup>	Output 7
15	2 <sup>-6</sup>	Output 6
16	Vref (-)	Tegangan referensi (-)
17	2 <sup>-8</sup> <sub>LSB</sub>	Output 0
18	2 <sup>-4</sup>	Output 4
19	2 <sup>-3</sup>	Output 3
20	2 <sup>-2</sup>	Output 2
21	2 <sup>-1</sup> <sub>MSB</sub>	Output 1
22	ALE	Address Latch Enable
23	ADD C	Control A
24	ADD B	Control B
25	ADD A	Control C
26	IN <sub>0</sub>	Masukan 0
27	IN <sub>1</sub>	Masukan 1
28	IN <sub>2</sub>	Masukan 2

\*Sumber : Anonimous, NATIONAL DATA SHEET, 1995 : 2/56

## 2.9.RTC (Real Time Clock) IC DS 12C887

DS 12C887 adalah serpih yang dipakai sebagai basis pewaktuan buatan *dallas Semiconductor*. Terdiri atas 24 pin dengan konfigurasi penyemat seperti ditunjukkan dalam gambar 2.12 berikut ini :



Gambar 2.12. Konfigurasi Pin IC DS 12C887

\*Sumber : Paulus, 2003 : 142

Arsitektur dari IC RTC tipe DS 12C887 antara lain adalah:

- *Oscillator internal* dan *time base internal*.
- Menghitung detik, menit, jam dalam hari.
- Menghitung hari dalam setiap minggu, tanggal, bulan dan tahun.
- Seratus tahun kalender (1 abad) samapai tahun 2100.
- Mempunyai catu daya *back-up*.
- Dapat beroperasi lebih dari 10 tahun tanpa kehadiran catu daya eksternal
- RAM internal sebesar 64 byte, terdiri atas 14 byte untuk *clock* dan *register* kontrol, sedangkan 50 *byte* lainnya dapat digunakan oleh pemakai (umum).

Fungsi tiap-tiap pin IC RTC DS 12C887 adalah sebagai berikut :

➤ **Pin\_1: MOT (*Motel*):**

Digunakan sebagai saklar pemilih mode. Apabila dihubungkan dengan Vcc, pewaktuan *Motorola* yang dipakai, jika dihubungkan dengan GND (*Ground*) berarti sistem diagram pewaktuan *Intel* yang dipakai.

➤ **Pin\_2-3: NC (*No Conec*):**

Tidak terhubung.

- **Pin\_3-11: AD0-AD7 (*Multiplexed Bidirectional Address/Data Bus*):**  
Merupakan *bus* alamat dan data dua arah yang termultipleks.
- **Pin\_12: GND (*Ground*):**  
Merupakan penyemat catu daya yang dihubungkan dengan *ground*.
- **Pin\_13:  $\overline{CS}$  (*Chip Select Input*):**  
Merupakan masukan untuk mengaktifkan periferan RTC. Sinyal CS didapat dari dekoder alamat dengan alamat tertentu.
- **Pin\_14: AS (*Address Strobe Input*):**  
Merupakan masukan bagi sinyal yang digunakan untuk memisahkan *bus* data dan *bus* alamat.
- **Pin\_15:  $R/\overline{W}$  (*Read/Write Input*):**  
Penyemat  $R/\overline{W}$  dapat diartikan sama seperti sinyal *Write Enable* (WE) yang dipakai dalam proses penulisan data memori jenis RAM.
- **Pin\_16: NC (*No Conec*):**  
Tidak terhubung.
- **Pin\_17:  $\overline{DS}$  (*Data Strobe or Read Input*):**  
Pin DS diartikan sama seperti sinyal *Output Enable* (OE) dalam komponen memori untuk melakukan proses membaca data RAM internal RTC.
- **Pin\_18: RESET (*Reset Input*):**  
Sinyal RESET diberikan dengan memberikan logika rendah selama waktu yang di spesifikasikan.

➤ **Pin\_19: IRQ (*Interrupt Request Output*):**

Sinyal IRQ merupakan sinyal aktif rendah, yang dapat digunakan untuk menginterupsi sistem kontrol. Saat tidak terdapat interupsi, pin ini dalam kondisi impedansi tinggi (*high-impedance*).

➤ **Pin\_20-22: NC (*No Conec*):**

Tidak terhubung.

➤ **Pin\_23:  $SQ\bar{W}$  (*Square Wave Output*):**

Merupakan pin yang dapat dipilih untuk mengeluarkan satu dari 13 frekuensi keluaran yang tersedia. Besar frekuensi keluaran  $SQ\bar{W}$  dapat diubah melalui pengaturan pada *register* "A". Untuk mengaktifkan dan me-nonaktifkan sinyal  $SQ\bar{W}$  dipilih lewat bit  $SQ\bar{W}E$  dalam *register* "B". Tabel 2.1 menunjukkan cara mengatur *register* "A" agar dihasilkan frekuensi dalam pin  $SQ\bar{W}$ .

➤ **Pin\_24: Vcc:**

Merupakan pin catu daya yang dihubungkan dengan sumber sebesar 5Volt.

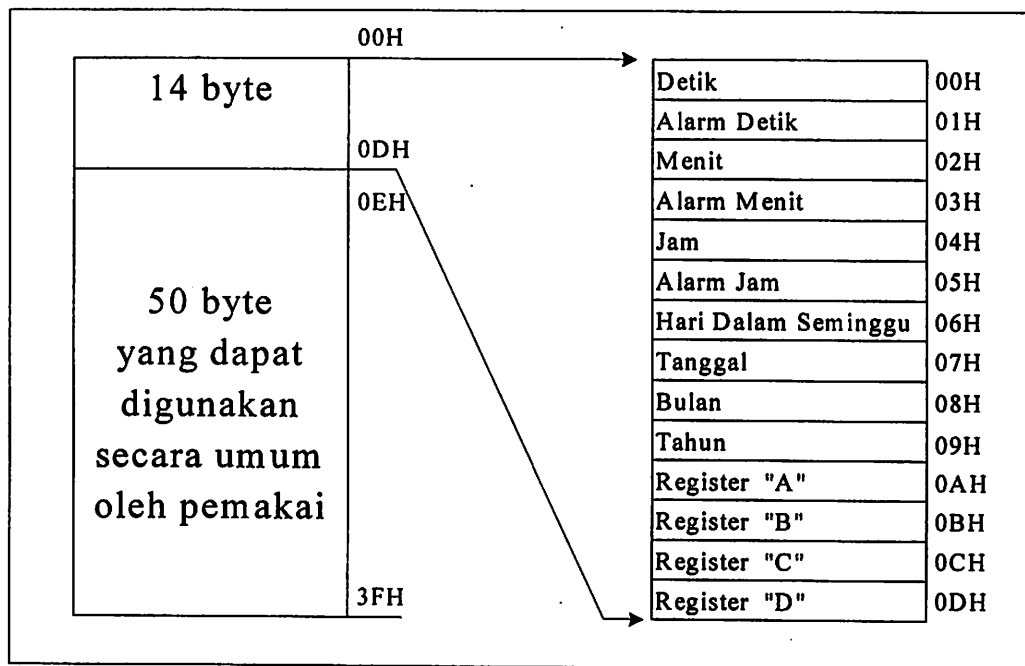
Tabel 2.10  
 Periode *Interrupt* dan Frekuensi Keluaran  $SQ\bar{W}$

SELECT BIT REGISTER A				T <sub>pi</sub> PERIODIC INTERRUPT RATE	SQW OUTPUT FREQUENCY
RS3	RS2	RS1	RS0		
0	0	0	0	None	None
0	0	0	1	30,0517 us	32.768 Hz
0	0	1	0	61,0352 us	16.384 Hz
0	0	1	1	122,070 us	8.129 Hz
0	1	0	0	244,141 us	4.096 Hz
0	1	0	1	488,2813 us	2.048 Hz
0	1	1	0	976,5625 us	1.024 Hz
0	1	1	1	1,953125 ms	512 Hz
1	0	0	0	3,90625 ms	256 Hz
1	0	0	1	7,8125 ms	128 Hz
1	0	1	0	15,625 ms	64 Hz
1	0	1	1	31,25 ms	32 Hz
1	1	0	0	62,5 ms	16 Hz
1	1	0	1	125 ms	8 Hz
1	1	1	0	250 ms	4 Hz
1	1	1	1	500 ms	2 Hz

\*Sumber : Paulus, 2003 : 144

Untuk menginisialisasi IC RTC, yaitu mengatur beberapa *register* yang ada di dalam RAM IC RTC saat kali pertama diaktifkan. Sinyal WR (*write*) sistem kontrol dihubungkan dengan penyemat R/W IC RTC, setelah data yang diinginkan dalam alamat dianggap sesuai. Sedangkan untuk membaca data RAM *internal* IC RTC, digunakan sinyal RD (*read*) pada sistem kontrol yang dihubungkan dengan pin DS (*data strobe*) pada IC RTC. Operasi pembacaan dan penulisan RAM *internal* IC RTC, sama seperti operasi baca dan tulis saat menggunakan komponen memori jenis RAM umumnya.

Peta alamat RAM *internal* IC RTC tipe DS 12C887 ditunjukkan dalam gambar 2.13 berikut ini :



Gambar 2.13 Peta Alamat RAM *Internal Real Time Clock* DS 12C887  
 \*Sumber : Paulus, 2003 : 143

## 2.10. LCD (*Liquid Crystal Display*) M1632

LCD (*Liquid Cristal Display*) adalah suatu jenis piranti *output* yang menggunakan daya rendah dengan pengontrol kontras dan kecerahan. Pengontrol utamanya dan karakter ada pada ROM (*Read Only Memory*) *generator* dan *display* data RAM (*Random Access Memory*) yang akan menghasilkan *extended key codes* (kode tombol/*keyboard* standart *international* dalam Hexsa) jika padanya diberikan inputan. Untuk dapat memfungsikan dengan baik maka perlu diperhatikan proses inialisasi yang telah ditentukan oleh pabrik pembuatnya. *Timing* penginisialisasian sangat perlu dipertimbangkan, karena jika meleset sampai orde *mili secon*, maka dapat dipastikan LCD itu tidak dapat berfungsi.

Ada dua jenis *register* yang terdapat dalam LCD M1632 ini, yaitu *data register* dan *instruction register*. Dengan menggunakan pin RS (*Register Select*)

pada LCD, pemakaian kedua *register* dapat dipilih. Pemilihan *register* pada LCD ditunjukkan pada Tabel 2.9. berikut ini :

Tabel 2.11  
Pemilihan *Register* Pada LCD M1632

Nama Sinyal	No. Terminal	I/O	Tujuan	Keterangan Sinyal
RS	4	Input	MPU	0 : <i>Instruction register</i> 1 : <i>Data register</i>

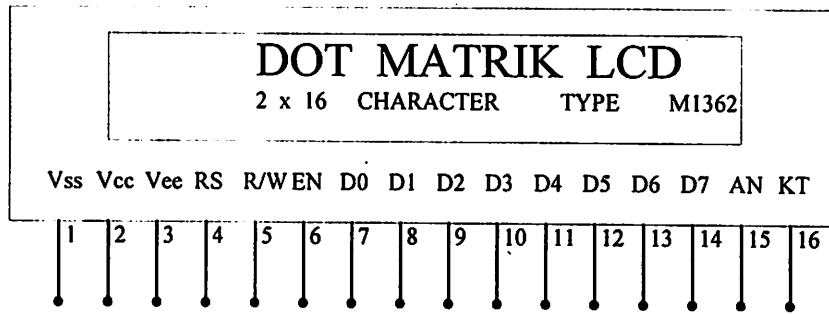
\*Sumber : Seiko Data Sheet, 1987 : 2

Jika bagian yang dipilih adalah *instruction register* maka output yang dihasilkan adalah meliputi operasional dari LCD, misalnya fungsi *display clear*, *cursor home*, *entry mode set*, *display on/off*, *cursor shift* dan sejenisnya. Sebaliknya jika bagian yang dipilih adalah *data register*, output yang dihasilkan adalah meliputi karakter yang tabelnya terdapat pada lampiran.

Karakteristik LCD M1632 adalah :

- 16 karakter 2 baris dalam bentuk *dot matrik* 5 x 7 dan kursor.
- *Duty ratio* 1/16.
- Memiliki ROM pembangkit karakter untuk 192 jenis karakter.
- RAM untuk data *display* sebanyak 80 x 8 bit (80 karakter maksimum).
- Dapat dirangkai dengan MPU (*Microprocesor Unit*) 8 bit atau 4 bit.
- RAM data *display* dan RAM pembangkit karakter dibaca oleh MPU.
- Memiliki fungsi instruksi : *display ON/OFF*, *cursor ON/OFF*, *display character blink*, *cursor shift* dan *display shift*.
- Memiliki rangkaian *oscillator* sendiri.
- Sumber tegangan tunggal +5 Volt.
- Memiliki rangkaian *reset* otomatis pada saat catu daya dihidupkan.
- Temperatur operasi 0° – 50°.

Deskripsi pin LCD ditunjukkan dalam gambar 2.14 berikut ini :



Gambar 2.14 Deskripsi Pin Pada LCD Tipe M1632

\*Sumber : Seiko Data Sheet, 1987 : 2

## BAB III

### PERENCANAAN DAN PEMBUATAN ALAT

#### 3.1. Pendahuluan

Perancangan dan pembuatan alat ini berdasarkan beberapa teori penunjang yang telah dijelaskan pada BAB II sebelumnya. Rangkaian yang akan dibahas meliputi rangkaian sensor kelembaban tanah, rangkaian penguat tegangan, rangkaian konverter *analog* ke *digital* (ADC), rangkaian *display* (LCD), rangkaian kontrol utama dengan mikrokontroler AT89S8252 dan beberapa driver solenoid sebagai pembuka kran air secara elektrik. Disamping itu juga dibahas perencanaan perangkat lunak dengan bahasa pemrograman assembler.

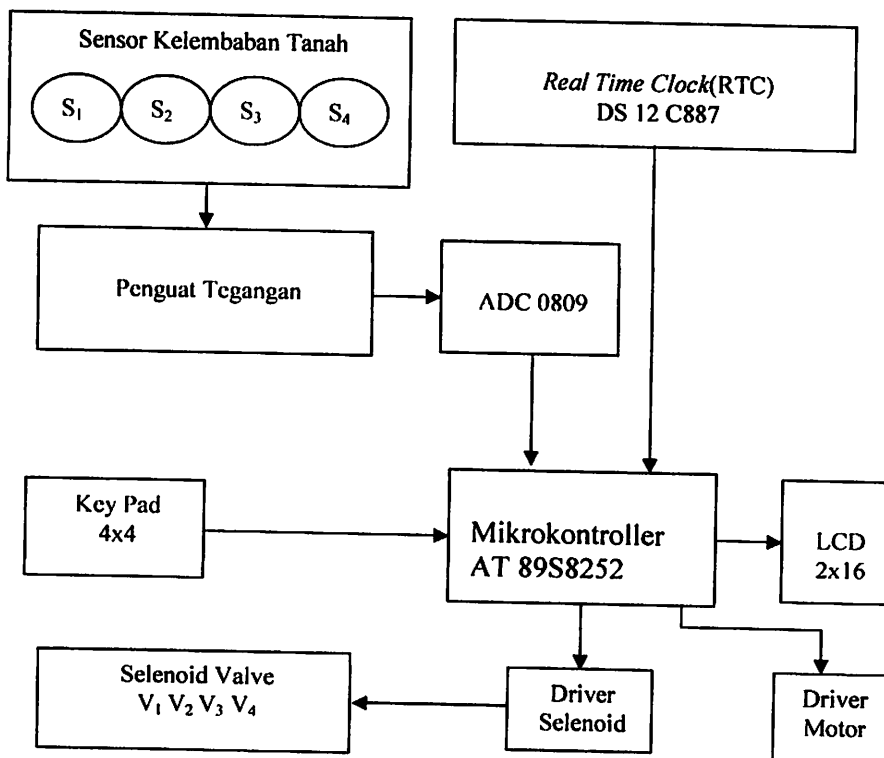
#### 3.2. Perencanaan Perangkat Keras (*Hardware*)

Sebelum melakukan perancangan beberapa hardware, terlebih dahulu perlu adanya penyusunan blok diagram seperti ditunjukkan pada gambar 3.1. Untuk perancangan penyiraman otomatis pada tanaman kedelai berdasarkan kelembaban tanah ada beberapa fungsi dari setiap blok diagram yang ada pada gambar, antara lain:

- Sensor kelembaban tanah sebagai pendeteksi dari kelembaban tanah dengan satuan persentase dari kering hingga basah ( 0% - 99%).
- Rangkaian penguat tegangan yang difungsikan untuk menguatkan tegangan keluaran sensor agar dapat dibaca oleh rangkaian ADC dengan akurat.
- *Analog to Digital Converter* (ADC) sebagai pengubah besaran *analog* dari sensor menjadi besaran *digital* agar dapat diolah oleh sistem kontrol.

- Blok *Real Time Clock* (RTC) sebagai generator pembangkit waktu yang akurat, sehingga dapat menunjukkan waktu penyiraman yang aman dan tidak berbahaya bagi daun tanaman kedelai.
- Blok kontrol yakni, yang mengendalikan hidup dan matinya kran penyiraman berdasarkan data yang diolah secara digital dari sensor kelembaban.
- Rangkaian *driver selenoid* sebagai pembuka kran air pada penyiraman tanaman kedelai secara otomatis (elektrik).
- *Display* LCD sebagai penampil data persentase dari kelembaban baik dari keypad maupun dari ADC (sensor) serta penampil data waktu dari IC RTC.

Berikut adalah gambar blok diagram sistem secara keseluruhan dari penyiraman otomatis pada tanaman kedelai.



Gambar 3.1. Blok Sistem Penyiraman Otomatis Pada Tanaman Kedelai  
\*Sumber : Perencanaan

### 3.2.1. Sensor Kelembaban Tanah

Sensor ini berfungsi untuk mendeteksi konsentrasi air dalam tanah yang menyatakan kelembaban dari suatu bidang tanah. Sensor berupa probe yang ditanam pada kedalaman tertentu (10cm-20cm). Sensor dalam perencanaan ini dibuat sebanyak empat buah, dan digunakan sebagai pengukur kondisi air tanah (kelembaban) untuk rangkaian kontrol dalam menggerakkan buka-tutup *solenoid valve* (kran listrik air).

Probe yang ditanam dalam tanah, saat mendeteksi konsentrasi kelembaban tanah tinggi memiliki resistansi sekitar  $\pm 500 \Omega$ , dan ketika tidak ada air (kering) maka besar resistansinya sangat besar (tak terhingga). Sensor ini dibentuk (disusun) dari dua lempeng baja yang tipis:

Data sensor :

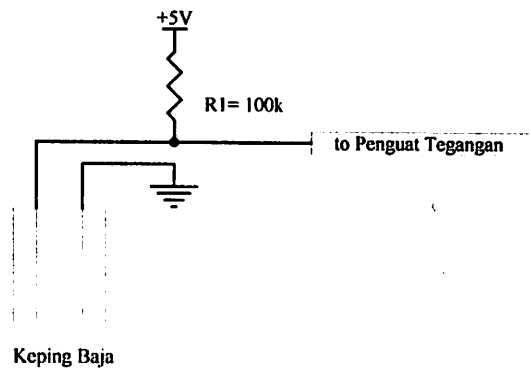
Panjang = 5cm

Lebar = 1cm

Tebal = 1mm

Jarak (*track*) = 1cm

Jika ada air tanah mengenai probe (sensor), maka akan menyebabkan turunnya nilai resistansi antara *track* (lempeng baja). *Output* dari sensor dimasukkan pada suatu rangkaian penguat tegangan, hal ini untuk menghasilkan tegangan keluaran yang sesuai dengan harga maksimal *input* ADC. Gambar 3.2 dibawah ini merupakan gambar elektrik sensor air dalam tanah (kelembaban tanah).



Gambar 3.2. Rangkaian Elektrik Sensor Kelembaban Tanah  
 \*Sumber : Perencanaan

Rangkaian penedeteksi air tanah ini tidak berdiri sendiri tetapi masih dilengkapi resistor *pull-up* sebagai pengangkat tegangan saat tidak ada kelembaban. Besar nilai resistor *pull-up* ( $R_1$ ) ditentukan berdasarkan besar nilai arus maksimal yang mengalir, yaitu 0,05mA, dengan tegangan *output* maksimal 5Volt, maka  $R_1$  adalah:

$$\begin{aligned}
 R_1 &= \frac{V_{cc}}{I_{mak}} & (3.1) \\
 &= \frac{5V}{0,5mA} \\
 &= 100k\Omega
 \end{aligned}$$

Sedangkan pada saat sensor mendeteksi kelembaban tinggi, resistansi berkisar  $500\Omega$  dengan  $R_1$  yang terpasang  $100k\Omega$ . Sehingga arus maksimal dan tegangan output maksimal dapat dicari sebagai berikut:

$$\begin{aligned}
 I_{mak} &= \frac{V_{cc}}{R_{up} + R_{ph}} & (3.2) \\
 &= \frac{5V}{100k + 0,5k} \\
 &= 0,049mA
 \end{aligned}$$

Untuk  $V_{out}$  minimal:

$$\begin{aligned} V_{out} &= \frac{R_{pb}}{R_{pb} + R_1} \times V_{CC} \\ &= \frac{0,5k}{0,5k + 100k} \times 5V = 0,024V \end{aligned} \quad (3.3)$$

Dari perhitungan diatas didapat nilai  $V_{out} = 0,024V$  saat sensor mendeteksi kelembaban tinggi.

### 3.2.2. Rangkaian Penguat Tegangan Membalik (*Inverting*)

Dari *output* rangkaian sensor memberi pengertian terbalik, dengan kondisi dimana sesungguhnya jika kelembaban naik, maka prosentase akan naik demikian juga tegangan keluaran akan naik, namun tidak demikian untuk sensor diatas. Untuk menyeimbangkan pengertian diatas, maka keluaran tegangan sensor terlebih dahulu diumpankan pada rangkaian penguat membalik dengan penguatan ( $A=1$ ) kali menggunakan IC Op-Amp tipe LM324. Dengan menentukan  $R_i = 100k\Omega$ , maka dapat ditentukan nilai  $R_f$  sebagai berikut:

$$\begin{aligned} A &= -\frac{R_f}{R_i} \\ -R_f &= 1 \times 100k \\ &= 100k\Omega \end{aligned} \quad (3.4)$$

Sedangkan untuk membalik tegangan keluaran, dengan mengeser trimpot  $50k\Omega$  sampai pada tegangan ( $V_{ref}$ ). Untuk menentukan nilai  $V_{ref}$  harus sebanding dengan besar nilai *output* sensor saat kelembaban rendah (kering), yaitu =  $5Volt$ . Sehingga didapat  $V_{out}$  Op-Amp saat kelembaban kering adalah:

$$V_{out} = \Delta V \times A \quad (3.5)$$

$$\Delta V = V^+ - V^- \quad (3.6)$$

$$= 5V - 5V$$

$$= 0V$$

$$V_{out} = 0V \times 1$$

$$= 0V$$

Saat Kelembaban tinggi (tanah basah) adalah:

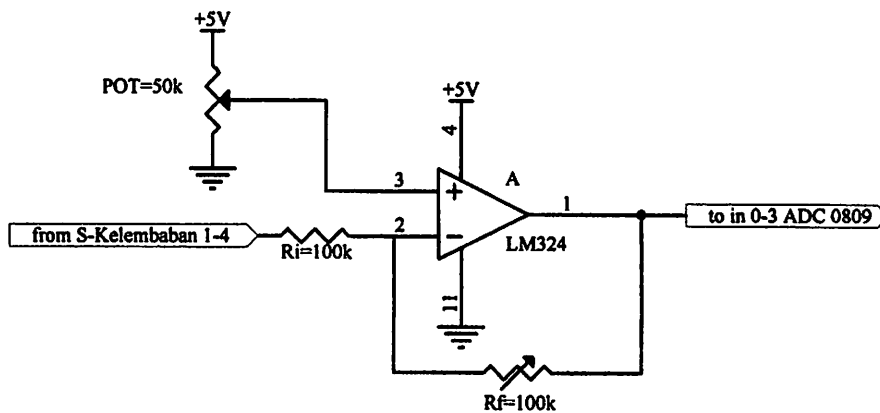
$$= 5V - 0,024V$$

$$= 4,976V$$

$$V_{out} = 4,976V \times 1$$

$$= 4,976V$$

Rangkaian penguat pembalik tegangan dari sensor kelembaban ditunjukkan pada gambar 3.3 dibawah ini:



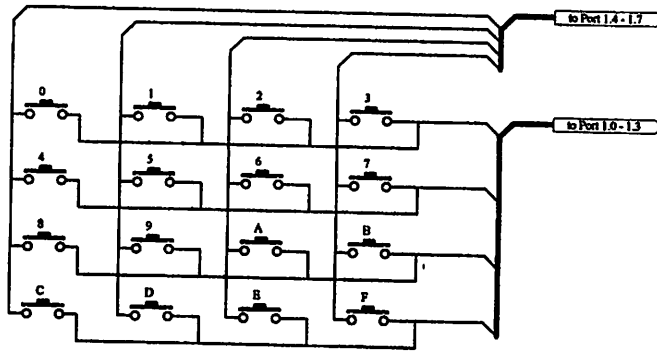
Gambar 3.3. Rangkaian Penguat Tegangan Membalik

\*Sumber : Perencanaan

### 3.2.3. Rangkaian Keypad 4x4

Rangkaian keypad dalam perancangan menggunakan keypad 4 x 4 push button. Dari 12 tombol tersebut akan terbentuk karakter angka dan simbol (0-9 dan A-F). Teknik pembacaan pada keypad ini, yaitu model scanning 4 jalur baris

dan 4 jalur kolom. Bila baris dan kolom ini disilangkan maka akan terbentuk titik-titik potong yang membentuk matrik 4 x 4 seperti ditunjukkan pada gambar 3.4:



Gambar 3.4. Rangkaian *Keypad* Matrik 4 x 4  
\*Sumber : Perencanaan

Proses pembacaan *keypad* 4 x 4 model *scanning* sebagai berikut :

- a) Menentukan urutan data karakter permanen *keypad* pada saat pembuatan *software*, misal (3-2-1-0-7-6-5-4-B-A-9-8-F-E-D-C). Dimana “3” yang pertama dan seterusnya “C” yang terakhir.
- b) Kemudian menentukan data (*output*) untuk kolom dan baris, misal secara berurutan dari kolom teratas sampai baris paling bawah yaitu (111-1110).
- c) Selanjutnya menentukan data pembanding yang ke-n, misal (0111-1110).
- d) Setelah menentukan data pembanding yang ke-n, maka siap membaca data (*input*) dari penekanan tombol pada *keypad* untuk *scan* yang ke-n. Jika data *input* dan *output* sama, maka proses *scanning* dihentikan. Perlu diingat proses dihentikan pada saat *scan* yang ke-n, maka data karakter yang diambil juga yang ke-n, misal nilai ‘n =1’ karakternya yaitu “3”.
- e) Bila proses *scanning* dihentikan atau sudah melakukan *scanning* sebanyak 16 kali, maka program keluar dari proses *scanning* menuju program selanjutnya

dalam *software*. Sebaliknya bila proses tidak dihentikan dikarenakan data *input* dan *output* tidak sama atau *scanning* belum 16 kali, maka proses menuju poin (6).

- f) Jika pencocokkan antara data *input* dan *output* tidak sama, maka proses diteruskan dengan menentukan data pembanding yang ke-( $n + 1$ ), yaitu dengan cara menggeser ke kanan satu kali *logic* '0' pada kolom dan menetapkan data pada barisnya. Proses kembali pada poin (4).
- g) Jika kolom sudah digeser 4 kali, maka diganti dengan menggeser satu kali ke kiri *logic* '0' pada baris dan mengembalikan data kolom pada posisi awal yaitu seperti poin 3 (0111). Sedangkan data pembanding dilanjutkan yang ke-( $n + 1$ ) dan proses kembali pada poin 4.

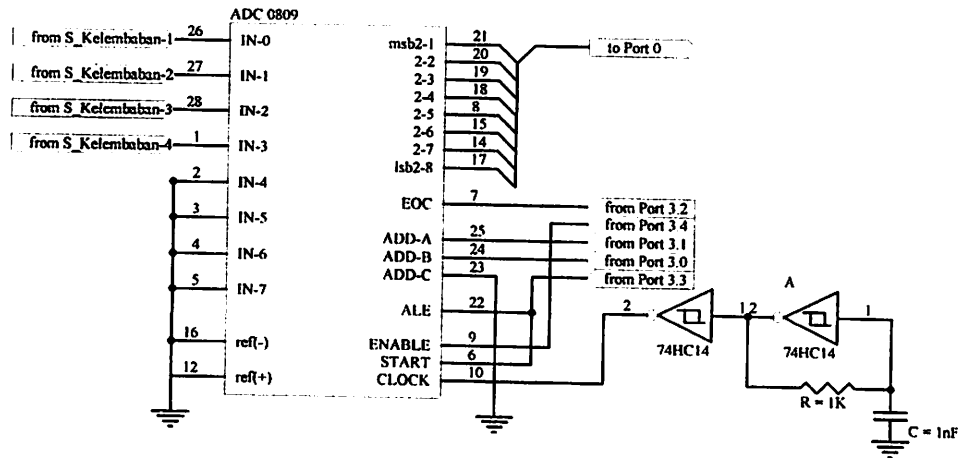
#### **3.2.4. Rangkaian *Converter Analog to Digital* (ADC 0809)**

Penggunaan rangkaian ADC 0809 yang merupakan ADC dengan sistem *Successive Approximation*. ADC 0809 ini memiliki 8 buah *input*, tetapi dalam perancangan ini hanya menggunakan empat buah inputan yaitu D0-D3. Untuk menyeleksi empat inputannya terdapat tiga bit address yang ada pada ADC 0809 (A0, A1 & A2) dimana pin ini akan dihubungkan dengan mikrokontroler AT89S8252 untuk pengontrolannya.

Dikarenakan tegangan yang di inputkan 0-5 *Volt*, maka tingkat resolusi dari ADC 0809 diharapkan cukup kecil juga, sehingga penulis menggunakan  $V_{ref} = 5\text{Volt}$ . Untuk membuat ADC 0809 dapat bekerja, maka perlu sebuah sumber

pulsa frekuensi sebesar 900Hz, yang dihasilkan dari rangkaian tangki pulsa (C & R). Rangkaian dan besar nilai “C & R” dapat di cari sebagai berikut:

$$\begin{aligned}
 F &= 1/1,1 RC \\
 900\text{Hz} &= 1/(1,1 \times 1000 \times C) \\
 C &= 10^{-9} \text{ F} = 1\text{nF}
 \end{aligned}
 \tag{3.7}$$



Gambar 3.5. Rangkaian ADC 0809  
\*Sumber : Perencanaan

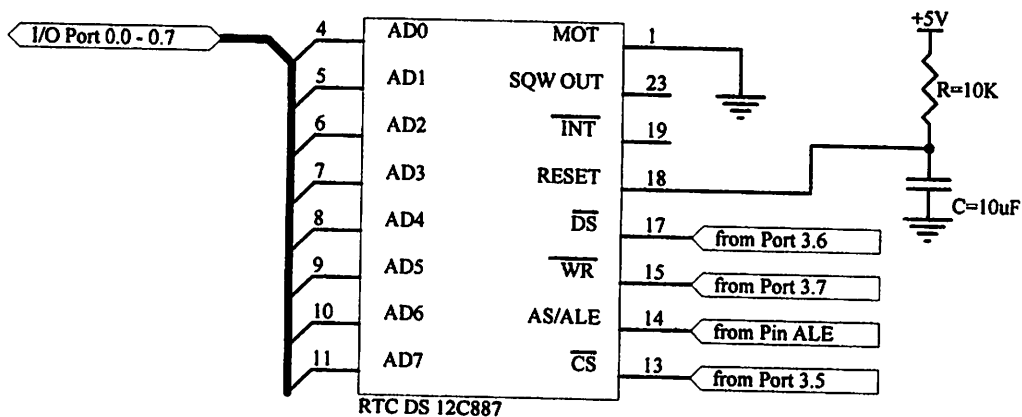
### 3.2.5. Rangkaian *Timer* RTC DS12C887

Seperti telah dijelaskan dalam sebelumnya (tinjauan pustaka), bahwa untuk mengoperasikan IC *timer* ini diperlukan beberapa langkah, yaitu menentukan *register* A, B dan *register* C pada IC. Sedangkan untuk mengambil data dari hasil operasi *timer* RTC, dengan cara pembacaan *interrupt* pada bit “IUP” yang terletak pada *register* C. Pengaturan *interrupt* IUP langsung dikontrol oleh *register* B. Sedangkan pembacaan IUP ditentukan oleh *frekuensi counter* pada RTC, dimana *frekuensi* ini diatur pada *register* A.

Besarnya *frekuensi counter* yang dihasilkan dapat dilihat pada pin SQW, dengan *duty cycle* 50%. Sama seperti halnya IUP, SQW juga diatur oleh *register*

B untuk mengaktifkannya. Setelah bit IUP memiliki *carry flag* “1”, data waktu dapat diambil. Selanjutnya sebelum ditampilkan pada layar *display* LCD, terlebih dahulu data (jam, menit, tanggal, bulan dan tahunnya) akan dicocokkan dengan data masa aktif dari masing-masing agenda yang tersimpan pada memori.

Hubungan tatap muka antara IC *timer* RTC DS 12C887 dengan sistem kontrol ditentukan oleh pin MOT pada pin 1. Bila berhubungan dengan sistem kontrol MOTOROLA maka pin MOT dihubungkan dengan Vcc, sebaliknya bila dengan sistem kontrol INTEL (mikrokontroler) pin MOT dihubungkan dengan *ground*. Rangkaian *timer* RTC nilai komponen penunjang, dicuplik dari “*Aplication Data Sheet Dallas Semiconductor*”. Sedangkan untuk jalur pin data-alamat serta pin kontrol disesuaikan dengan perencanaan sistem seperti ditunjukkan pada gambar 3.6:

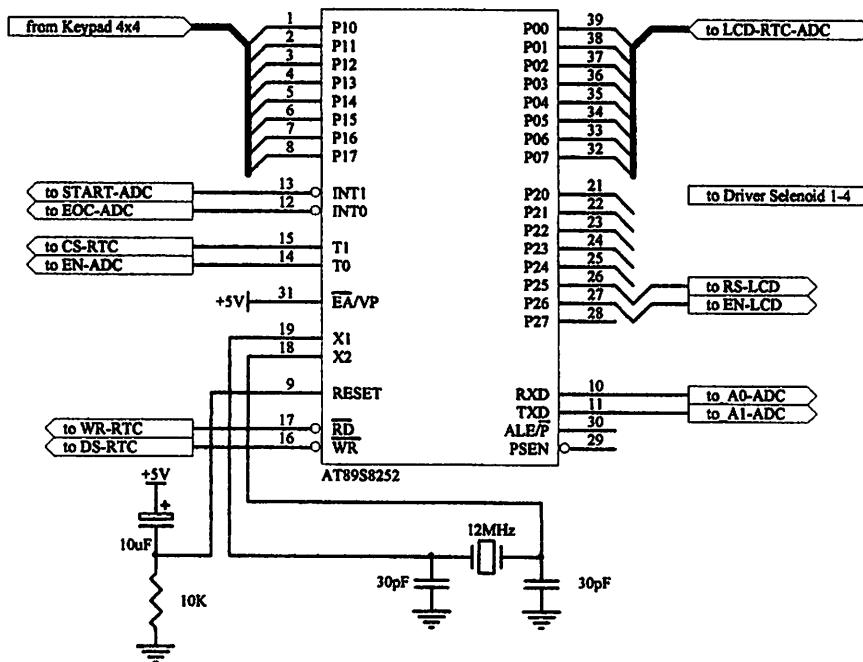


Gambar 3.6. Rangkaian *Timer* dengan IC RTC DS 12C887  
\*Sumber : Perencanaan

### 3.2.6. Rangkaian Sistem Kontrol Utama (Mikrokontroler AT89S8252)

Dalam perancangan perangkat keras mikrokontroler AT89S8252 sebagai kontrol utama untuk menjalankan sistem, akan dibantu dengan rangkaian penunjang lainnya. Penggunaan rangkaian karena sistem kontrol beroperasi dalam sistem *digital*, sedangkan objek yang dibaca maupun yang dikontrol merupakan sistem *analog* murni. Mikrokontroler memiliki memori mpenyimpan program (Flash EPROM) dan penyimpan data dengan (EEPROM), yang sifatnya *non volatile* (tidak menguap) meskipun power dimatikan.

Pada mikrokontroler tersebut menggunakan sistem *clock* eksternal dengan frekuensi 12MHz. *Clock* ini akan disusun dari kristal 12MHz dan 2 kapasitor keramik 30pF. Gambar minimum sistem dari IC kontrol mikrokontroler AT89S8252 beserta jalur data dan kontrol ditunjukkan pada gambar 3.7 berikut:



Gambar 3.7. Rangkaian Sistem Kontrol AT89S8252

\*Sumber : Perencanaan

### 3.2.7. Rangkaian Driver Selenoid Valve

Untuk menghubungkan pengontrol utama mikrokontroler dengan alat yang dikontrol, dibutuhkan suatu rangkaian penyesuai tegangan antara tegangan

pengontrol utama mikrokontroler dengan tegangan alat yang dikontrol. Penyesuaian tegangan ini yang disebut rangkaian *driver*.

*Solenoid* pada perencanaan ini berfungsi sebagai buka-tutup kran air penyiraman. Komponen yang digunakan adalah 2 buah transistor NPN FCS 9013 dengan  $H_{fe}$  120 dan TIP 41  $H_{fe}$  40. Sebuah solenoid 12V dan 1 buah diode sebagai penghantar arus diri pada kumparan *solenoid*. Dimana kedua komponen tersebut disusun dengan *driver model darlington* guna menghasilkan penguatan arus yang besar, sehingga sesuai dengan kebutuhan beban. Karena memiliki penguatan arus yang sangat besar, maka diperlukan pembatas arus dengan resistor basis ( $R_b$ ) pada basis transistor utama, agar transistor beban tidak berkerja terlalu jenuh akibat kelebihan arus basis.

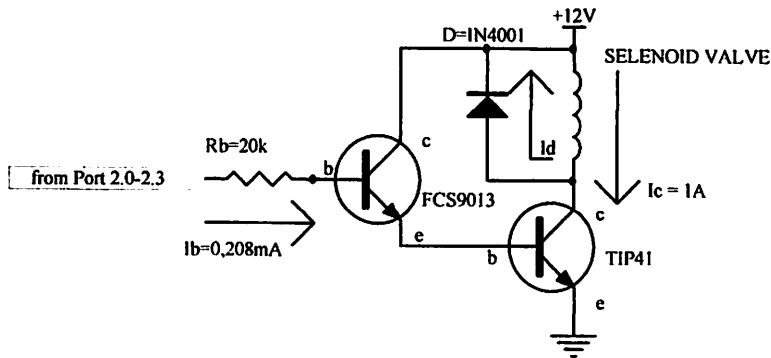
$$I_b = \frac{I_C}{h_{fe-1} \times h_{fe-2}} \quad (3.8)$$

$$= \frac{1A}{120 \times 40} = 0,208mA$$

$$R_b = \frac{V_{BB} - 2 \times V_{BE}}{I_B} \quad (3.9)$$

$$= \frac{5V - 2 \times 0,6}{0,208mA} = 18,269k\Omega$$

Untuk pemasangan  $R_b$  yang mendekati maka dipasang nilai 20  $K\Omega$ . Gambar dari *driver solenoide* terdapat pada gambar 3.8.



Gambar 3.8. Rangkaian *Driver Solenoid Model Darlington*  
Sumber : Perencanaan

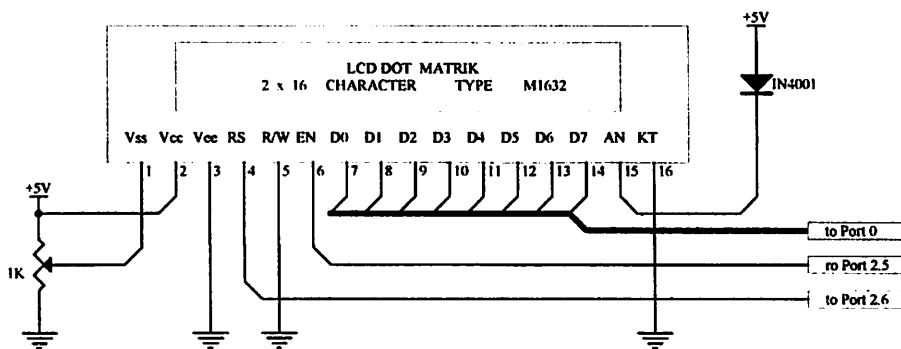
### 3.2.8. Rangkaian *Display LCD (M1632)*

Rangkaian LCD dot matrik 2 x 16 karakter ini adalah komponen *display* yang paling umum digunakan saat ini. *Display LCD* 2 x 16 karakter ini memiliki ROM sebagai penyimpan karakter sebanyak 192 buah. Sebelum mengoperasikan LCD sebagai penampil karakter, terlebih dahulu ditentukan format penulisan LCD. Dalam format penulisan LCD ada beberapa aturan yang diberikan oleh pabrik pembuatnya (*data sheet*) yaitu:

1. Menentukan jalur bit data yang akan digunakan (4bit atau 8bit).
2. Membersihkan layar *display* dari karakter *blank*.
3. Menentukan alamat baris pertama dan baris kedua.
4. **Dalam penulisan karakter menggunakan *cursor* atau tidak.**

Jika penginisialisasian telah selesai, langkah selanjutnya menulis karakter yang diinginkan, misal tampilan yang diinginkan "123", maka format data yang ditransferkan ke jalur data adalah format data BCD angka 123 yang masing-masing disertai data posisi baris. Data yang dikirim ke LCD cukup satu kali,

selanjutnya data akan terus ditampilkan berulang-ulang oleh LCD itu sendiri selama tidak ada intruksi membersihkan layar *display*. Hubungan pin data dan pin kontrol LCD dengan mikrokontroler ditunjukkan dalam gambar 3.9 di bawah ini:



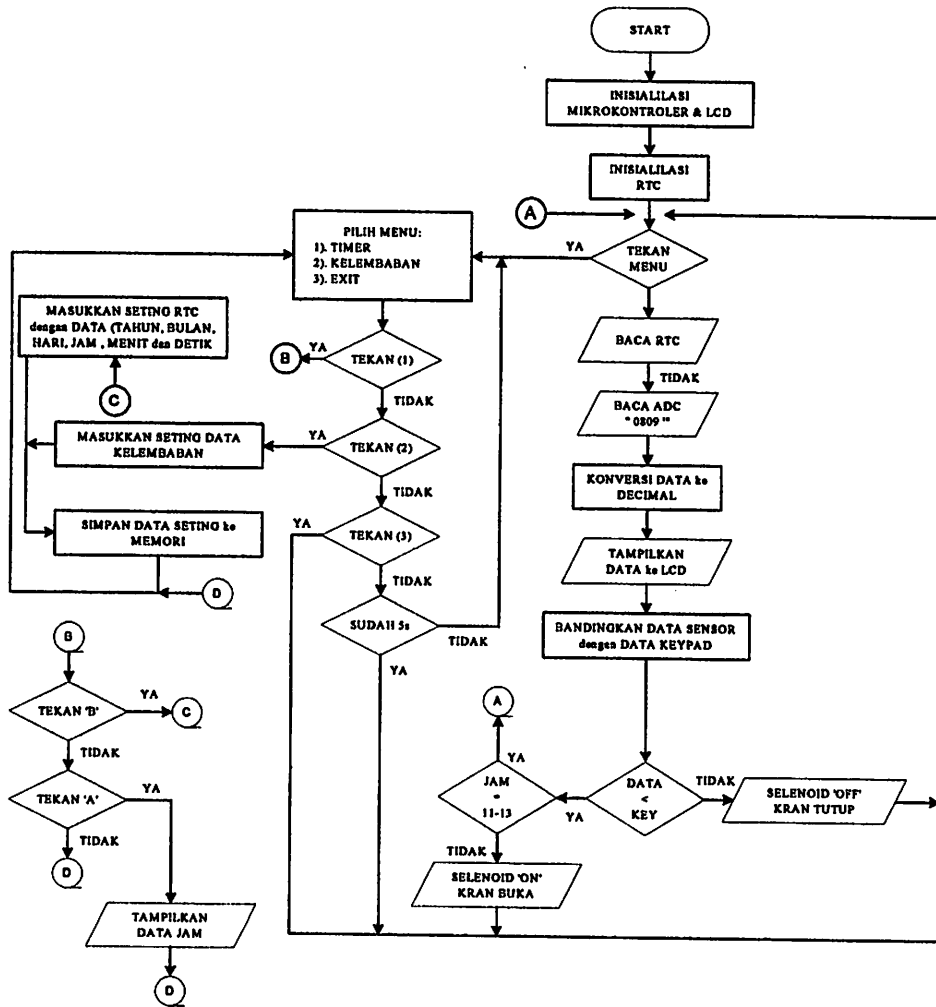
Gambar 3.9. Rangkaian LCD dengan Jalur Data dan Pin Kontrol  
\*Sumber : Perancangan

### 3.3. Perencanaan Perangkat Lunak (*Software*)

Pada sub-bab ini dibahas juga perancangan perangkat lunak secara diagram alir. Untuk pemakaian sistem kontrol digital terprogram, perlu direncanakan perangkat lunak yang dapat mengatur sistem tersebut. Perangkat lunak disini adalah susunan perintah-perintah (program) di dalam memori yang harus dilaksanakan oleh mikrokontroler.

Di dalam suatu mikrokontroler terdapat memori (Flash EPROM)) merupakan fasilitas utama untuk penyimpanan intruksi, karena disinilah disimpan perintah-perintah yang harus dikerjakan. Perencanaan perangkat lunak (*software*) didasarkan perencanaan perangkat keras yang telah dibuat sebelumnya, untuk mendapatkan sistem kerja yang diharapkan. *Software* dari alat tersebut terdapat di bagian lampiran dan diagram alir (*flow chart*).

### 3.3.1. Flowchart



Gambar 3.10. Flowchart Program Penyiraman Otomatis  
\*Sumber : Perencanaan

## **BAB IV**

### **PENGUJIAN ALAT**

Untuk mengetahui sistem penyiraman otomatis pada tanaman kedelai secara terprogram ini dapat bekerja seperti yang diharapkan, maka diperlukan pengujian-pengujian terhadap sistem. Dalam rangka pengujian tersebut, pada bab ini diuraikan sejumlah pengukuran dan percobaan yang dilakukan untuk mengetahui sistem kerja alat secara keseluruhan. Ada beberapa cara dalam pengujian yaitu pengujian perangkat keras (*hardware*) per-blok dan alat secara keseluruhan (*hardware* dan *software*). Berikut ini prosedur pengujian perblok dan hasil pengamatan terhadap pengujian.

#### **4.1. Pengujian Sensor Kelembaban Tanah dan Rangkaian Penguat**

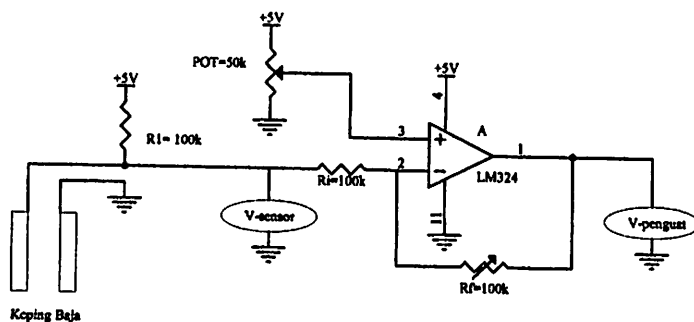
a. Tujuan:

Pada pengujian ini bertujuan untuk mengetahui kepekaan sensor kelembaban dalam mendeteksi tingkat intensitas kadar air dalam tanah dengan jenis dan kedalaman tanah yang berbeda.

b. Alat dan bahan:

- Catu daya +5Volt DC
- Voltmeter *digital*
- Media tanah dan air
- Rangkaian pengujian

c. Blok gambar cara pengujian:



Gambar 4.1. Pengujian Sensor Kelembaban Tanah  
Sekaligus Rangkaian Penguat Tegangan  
\*Sumber : Rangkaian pengujian

d. Data hasil pengukuran alat:

Tabel 4.1  
Data Hasil Pengukuran Rangkaian Sensor Kelembaban Tanah

No	Jenis Tanah	Kelembaban	Tegangan Output Sensor (Volt)	Penguatan (kali)	Tegangan Output Op-Amp (Volt)
1	Liat	Kering	4,35	1	4,83
2	Liat	Lembab	2,78	1	2,55
3	Liat	Basah	0,43	1	0,62
4	Pasir	Kering	4,21	1	4,24
5	Pasir	Lembab	2,32	1	2,97
6	Pasir	Basah	0,22	1	0,31

\*Sumber : Data hasil pengukuran

e. Analisis:

Setelah melakukan pengujian dan melihat data dari hasil beberapa pengukuran kelembaban tanah, di dapat analisis yaitu, sensor kelembaban dapat mendeteksi adanya air dalam tanah dan sensor memiliki tingkat resistansi yang berbeda untuk tiap struktur tanah yang berbeda.



d. Data hasil pengukuran alat:

Tabel 4.2  
Data Hasil Pengukuran Rangkaian Konversi ADC 0809

Vin_0 (Volt)	Keluaran ADC						
	Perhitungan				Pengukuran		
	D7-D4	D3-D0	Des	Hex	D7-D4	D3-D0	Des
5,09	1111	1111	255	FFH	1111	1111	255
4,76	1110	1110	238	EEH	1110	1111	239
4,40	1101	1100	220	DCH	1101	1100	220
4,00	1100	1000	200	C8H	1100	1011	203
3,76	1011	1100	188	BCH	1011	1110	190
3,24	1010	0010	162	A2H	1010	0000	160
3,08	1001	1010	154	9AH	1001	1011	155
2,84	1000	1110	142	8EH	1000	1110	142
2,52	0111	1110	126	7EH	0111	1110	126
2,20	0110	1110	110	6EH	0110	1110	110
1,88	0101	1110	94	5EH	0101	1110	94
1,54	0100	1101	77	4DH	0100	0000	64
1,24	0011	1110	62	3EH	0011	0000	48
0,92	0010	1110	46	2EH	0010	0000	32
0,62	0001	1111	31	1FH	0001	1111	31
0,28	0000	1110	14	0EH	0000	1111	15
0,00	0000	0000	0	00H	0000	0000	0

\*Sumber : Data pengukuran

Keterangan:

Vin = Tegangan input ADC

"1" = LED ON

"0" = LED OFF

D7-D4 = Keluaran D7, D6, D5, D4 (MSB)

D3-D0 = Keluaran D3, D2, D1, D0 (LSB)

Des = Keluaran dalam bentuk desimal

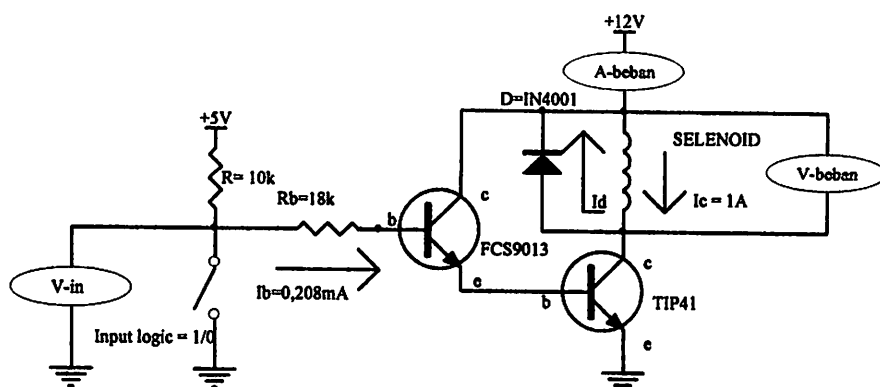
e. Analisis:

Pada percobaan ini kesalahan (*error*) masih dapat diabaikan, jika kesalahan tersebut berada pada keluaran D<sub>0</sub>-D<sub>1</sub>, karena bobot nilai dari rumus (2<sup>n</sup>) pada keluaran ini sangat rendah, yakni antara (0 – 3 desimal) saja.

### 4.3. Pengujian Rangkaian *Driver Selenoid*

Pengujian *driver selenoid* sebagai simulasi penggerak buka tutup kranair secara elektrik, dengan cara menghubungkan catu daya yang sesuai (+12 V) terlebih dahulu, kemudian memberi masukan pada *input logic* (1 / 0) pada basis transistor *driver*.

Dengan pengujian cara ini dapat diketahui pada saat *input* diberi masukan logika “1” maka transistor pertama (9013) akan mengalirkan arus kolektor yang lebih besar dan sebanding dari hasil kali arus basis dengan penguatan arusnya ( $H_{fe}$ ). Kemudian arus kolektor yang mengalir menuju emitor akan diumpankan pada basis transistor terakhir, dengan demikian maka, arus kolektor pada transistor (TIP 41) akan mengalir melalui selenoid. Pada kondisi ini selenoid akan membangkitkan medan listrik yang akan membuka katup penutup aliran air (sebagai kran). Kondisi sebaliknya jika *input* basis transistor pertama diberi logikia *low* ‘0’, maka arus kolektor pada kedua transistor akan tersumbat dan menyebabkan selenoid tidak melepaskan katup penutup kran, dengan demikian kran air akan tertutup kembali.

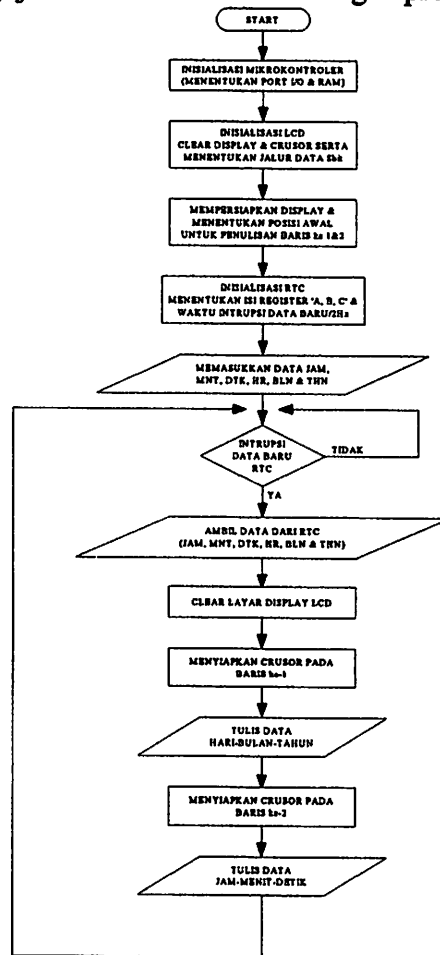


Gambar 4.3. Pengujian *Driver Selenoid Valve*

\*Sumber : Rangkaian pengujian



d. *Flowchart* pengujian IC RTC dan LCD dengan program assembler:



Gambar 4.5. *Flowchart* Penulisan dan Pengambilan Data RTC & LCD

\*Sumber : Pengujian

e. Data hasil pengujian :

Tabel 4.3

*Data Hasil Pengamatan Timer RTC Pada LCD*

No	Baris LCD	Tampilan LCD	Keterangan
1	Pertama	Minggu –Oktober – 2005	Pergantian Hari/Jam 00:00:00
2	Kedua	20 : 45 : 05	Timer-Up/Detik

\*Sumber : Pengujian

f. Analisis :

Pada pengujian blok ini tidak dapat dilakukan seperti pengujian rangkaian lainnya, karena pada blok ini masih membutuhkan perangkat lunak untuk

mengatur dan membaca data RTC tersebut. Pengujian RTC ini didukung rangkaian kontrol dan *display* LCD, karena pengujian rangkaian RTC tidak dapat berdiri sendiri. Melihat dari tabel hasil pengamatan pada pengujian RTC dan LCD, menunjukkan bahwa program penulisan dan pembacaan sekaligus menampilkan data waktu pada layar *display* LCD, berjalan sesuai yang diharapkan.

## **BAB V**

### **PENUTUP**

#### **5.1. Kesimpulan**

Dari hasil perancangan, pengujian dan analisis alat didapat beberapa kesimpulan sebagai berikut :

1. Sistem hanya dilengkapi empat sensor dan empat *solenoid* pembuka kran air.
2. Waktu penyiraman dapat dilakukan sewaktu-waktu, kecuali pada jam-jam khusus jika terjadi kekeringan, sistem kontrol akan menahan pembuka kran air tetap tertutup, yakni dari jam 11 – 1 siang.
3. Penyiram akan dilakukan, jika sensor terbaca lebih kecil dari harga data pada keypad, dan selama itu kran air akan membuka.
4. Penggunaan IC RTC DS12C887 dapat memberikan pewaktuan yang tepat saat pada jam-jam khusus untuk tidak menyiram, hal ini untuk menghindari terbakarnya daun akibat dari terik sinar matahari.

#### **5.2. Saran-Saran**

1. Diperlukan penyesuaian alat (mekanik) jika untuk penggunaan yang sesungguhnya (kran air dan banyaknya sensor).
2. Sistem dapat dikembangkan dengan memberikan data kelembaban sampai pada akhir tanaman (panen).
3. Penyesuaian sensor kelembaban dapat dikembangkan menjadi model tongkat yang diberi satuan centimeter untuk mengukur kedalaman sensor.
4. Sensor dapat diperbanyak dengan cara dipararelkan.

## DAFTAR PUSTAKA

- Agfianto Eko Putra, *Belajar Mikrokontroler AT89S51/52 (Teori dan Aplikasi)*, edisi ketiga, Yogyakarta: Gava Media, 2004.
- Anonimous, 2001, SS9013, TIP41 Fairchild.  
<http://www.dzjs.com/file/9000/SS9013.pdf#search=TRANSISTOR%209013.html>  
12/03/2005.
- Coughlin, Robert F. and Frederick F. Driscoll (1982), *Penguat Operasional dan Rangkaian Terpadu Linear*, Terjemahan: Ir. Herman Widodo S., Erlangga, Jakarta, 1982.
- Edminister, Joseph A., M.S.E., *Elektromagnetika*, Erlangga, Jakarta, 1997.
- Hayt, William H. (1979), *Elektromagnetika Teknologi*, Terjemahan: Murjono N.Sc, Erlangga, Jakarta, 1989.
- Malik, Mch. Ibnu, dan Anistradi, *Bereksperimen Dengan Mikrokontroler 8031*, PT. Elex Media Komputindo, Jakarta, 1997.
- Malvino, *Elektronik Principle*, 3<sup>rd</sup> edition, Mc Graw Hill Inc., New York, (1984).
- National Semikonduktor Coporation, Inc., Dta Acquisition, *Operational Amplifier*, National semi konduktor, Santa clara, California, (1995).
- Paulus Andi Nalwan, 2003, *Teknik Antar Muka dan Pemrograman Mikrokontroler AT89C51*, Jakarta: PT. Elex Media Komputindo.
- Rusdianto, Eduard, S.T., *Penerapan Konsep Dasar Listrik dan Elektronika*, Kanisius, Yogyakarta, 1999.
- Somaatmaja, Sadikin, *Kedelai*, Badan Penelitian Dan Pengembangan Pertanian, Pusat Penelitian Dan Pengembangan Tanaman Pangan, Bogor.
- Wasito, S., *Vademekum Elektronika*, PT Multimedia, Jakarta, 1985.

# ***LAMPIRAN***



## FORMULIR BIMBINGAN SKRIPSI

Nama : Ahmad Ebit S.  
Nim : 0017138  
Masa Bimbingan : 19-Jul-2005 s/d 19-Jan-2006  
Judul Skripsi : Perancangan dan pembuatan alat penyiram air otomatis pada kedelai menggunakan Mikrokontroler AT89S8252

NO	Tanggal	Uraian	Paraf Pembimbing
1.	21/07 05	Konsultasi pemb. alat	
2.	07/08 05	Konsultasi lap. skripsi	
3.	02/09 05	Konsultasi bab I, II	
4.	16/09 05	Konsultasi bab III	
5.	02/10 05	Konsultasi bab IV & V	
6.	29/10 05	Percobaan Alat	
7.	11/11 05	Revisi Alat	
8.	17/10 05	Acc Ujian	
9.			
10.			

Malang, 2005  
Dosen Pembimbing

Ir. Teguh Herbasuki, MT



```

;
;
;=====  

;          KONSTANTA PORT  

;=====  

LCD          EQU  P0    ;DISPLAY  

RTC          EQU  P0    ;TIMER  

ADC          EQU  P0    ;ADC0809  

KEY          EQU  P1    ;KEYPAD  

;  

SEL_1        BIT   P2.0 ;  

SEL_2        BIT   P2.1 ;  

SEL_3        BIT   P2.2 ;  

SEL_4        BIT   P2.3 ;  

MTR          BIT   P2.4 ;  

RS           BIT   P2.5  

EN           BIT   P2.6  

CON_A        BIT   P3.0  

CON_B        BIT   P3.1  

START        BIT   P3.2  

EOC          BIT   P3.3  

CS_T         BIT   P3.4  

BACA         BIT   P3.5  

;=====  

;          RAM  

;=====  

BARIS        EQU  3BH  

DATA_4       EQU  3CH  

PER_BARIS    EQU  3DH  

BAN_P1       EQU  3EH  

COMMON       EQU  3FH  

BOUNC        EQU  35H  

DAT          EQU  36H  

DATA_KEY     EQU  37H  

;  

REG_A        EQU  0AH  

REG_B        EQU  0BH  

REG_C        EQU  0CH  

REG_D        EQU  0DH  

;  

RTC_DETIK    EQU  00H  

RTC_MENIT    EQU  02H  

RTC_JAM      EQU  04H  

RTC_HARI     EQU  06H  

RTC_TANGGAL  EQU  07H  

RTC_BULAN    EQU  08H  

RTC_TAHUN    EQU  09H  

RTC_CENTURY  EQU  32H  

;  

PULUHAN      EQU  40H  

SATUAN       EQU  41H  

;

```

PUL_TAHUN	EQU	42H
SAT_TAHUN	EQU	43H
PUL_BULAN	EQU	44H
SAT_BULAN	EQU	45H
PUL_TANGGAL	EQU	46H
SAT_TANGGAL	EQU	47H
PUL_HARI	EQU	48H
SAT_HARI	EQU	49H
PUL_JAM	EQU	4AH
SAT_JAM	EQU	4BH
PUL_MENIT	EQU	4CH
SAT_MENIT	EQU	4DH
PUL_DETIK	EQU	4EH
SAT_DETIK	EQU	4FH
;		
DAT_TANGGAL	EQU	50H
DAT_HARI	EQU	51H
DAT_BULAN	EQU	52H
DAT_TAHUN	EQU	53H
;		
DAT_JAM	EQU	54H
DAT_MENIT	EQU	55H
DAT_DETIK	EQU	56H
;		
DAT_UPP	EQU	57H
DAT_DWN	EQU	58H
DAT_ERR	EQU	59H
DAT_BUF	EQU	5AH
BUF_HARI	EQU	5BH
BUF_BULAN	EQU	5CH
DAT_KON	EQU	5DH
DAT_KONVIC	EQU	5EH
;		
LEMB_1	EQU	60H
LEMB_2	EQU	61H
LEMB_3	EQU	62H
LEMB_4	EQU	63H
;		
BUF_1	EQU	64H
BUF_2	EQU	65H
BUF_3	EQU	66H
BUF_4	EQU	67H
;		
EROR_1	EQU	68H
EROR_2	EQU	69H
EROR_3	EQU	6AH
EROR_4	EQU	6BH
;		
CAD_1	EQU	6CH
CODE_1	EQU	6DH

CODE\_2 EQU 6EH  
VALUE EQU 6FH

---

---

PROG\_AWAL

---

---

ORG 00H  
SETB CS\_T  
SETB SEL\_1  
SETB SEL\_2  
SETB SEL\_3  
SETB SEL\_4  
SETB MTR  
SETB EN  
CLR BACA  
CLR RS

-----  
LCALL INIT\_LCD  
LCALL HEADO\_1  
LCALL PLEASED

-----  
START\_1:

LCALL AMBIL\_PERSEN  
LCALL BACA\_ADC  
LCALL TAMPIL  
LCALL BANDING

LCALL SIRAM

LCALL KEY\_SCAN  
MOV A,DAT  
CJNE A,#1,START\_2  
MOV DAT,#0  
MOV A,DATA\_KEY  
CJNE A,#0FH,START\_2  
LJMP MENU

START\_2:

LCALL TUNDA  
LJMP START\_1

---

---

PRO\_AMBIL PERSEN

---

---

AMBIL\_PERSEN:

MOV R0,#60H  
MOV R1,#10H  
MOV R7,#4  
CLR CS\_T

PERSEN:

LCALL DELAY  
MOVX A,@R1  
LCALL DELAY

```

MOV @R0,A
INC R0
INC R1
DJNZ R7,PERSEN
SETB CS_T
RET

```

---



---

```

;
; PRO_BACA_ADC
;

```

---



---

```

BACA_ADC:

```

```

MOV R0,#64H
MOV R7,#4
MOV CAD_1,#0
CLR CON_A
CLR CON_B
LCALL DELAY

```

```

BACA_Y:

```

```

LCALL TULISEN
LCALL DELAY
LCALL DELAY
; JNB EOC,$
LCALL GUN_1
SETB BACA
LCALL DELAY

```

```

;-----

```

```

MOV A,ADC
CLR C
MOV B,#25
SUBB A,B
MOV B,#24
DIV AB
MOV CODE_1,A
MOV A,B
MOV B,#10
MUL AB
MOV B,#26
DIV AB
MOV CODE_2,A

```

```

;

```

```

MOV A,CODE_1
SWAP A
ORL A,CODE_2

```

```

;-----

```

```

MOV @R0,A
INC R0
INC CAD_1
CLR BACA
DJNZ R7,BACA_1
RET

```

```

BACA_1:

```

```

MOV      A,CAD_1
CJNE    A,#1,BACA_2
SETB    CON_A
CLR     CON_B
LJMP    BACA_Y
BACA_2:
CJNE    A,#2,BACA_3
CLR     CON_A
SETB    CON_B
LJMP    BACA_Y
BACA_3:
SETB    CON_A
SETB    CON_B
LJMP    BACA_Y
;*****"START"*****
TULISEN:
SETB    START
LCALL   DELAY
LCALL   DELAY
CLR     START
LCALL   DELAY
RET

=====
;
; PRO_TAMPIL
;
=====
TAMPIL:
MOV      R1,#60H
MOV      R7,#4
LCALL   CLEAR_TAMPILAN
LCALL   ROW_1
MOV      DPTR,#MAS_3
LCALL   WRITE
TAMPIL_3:
MOV      A,@R1
ANL     A,#0F0H
SWAP    A
CJNE    A,#0,TAMPIL_1
LCALL   SPASI
SJMP    TAMPIL_2
TAMPIL_1:
LCALL   TULIS
TAMPIL_2:
MOV      A,@R1
ANL     A,#0FH
LCALL   TULIS
LCALL   STRIP
INC     R1
DJNZ    R7,TAMPIL_3
;-----
MOV      R1,#64H

```

```

MOV      R7,#4
LCALL   ROW_2
MOV      DPTR,#MAS_4
LCALL   WRITE
TIMPIL_3:
MOV      A,@R1
ANL     A,#0F0H
SWAP    A
CJNE    A,#0,TIMPIL_1
LCALL   SPASI
SJMP    TIMPIL_2
TIMPIL_1:
LCALL   TULIS
TIMPIL_2:
MOV      A,@R1
ANL     A,#0FH
LCALL   TULIS
LCALL   STRIP
INC     R1
DJNZ    R7,TIMPIL_3
RET

;=====
; PRO_BANDING
;=====
BANDING:
MOV      DAT_UPP,#60H    ;LEMB
MOV      DAT_DWN,#64H   ;BUF
MOV      R0,#68H
MOV      R7,#4
BAND_1:
MOV      A,DAT_UPP
MOV      R1,A
MOV      A,@R1
MOV      B,A
MOV      A,DAT_DWN
MOV      R1,A
MOV      A,@R1
CLR      C
CJNE    A,B,BAND_2 ;BUF/LEMB
BAND_4:
MOV      A,#0
BAND_3:
MOV      @R0,A
INC     R0
INC     DAT_UPP
INC     DAT_DWN
DJNZ    R7,BAND_1
RET
BAND_2:
JNC     BAND_4

```

```
MOV    A,#1
SJMP   BAND_3
```

---

```
;
; PRO_PUTAR
```

---

```
SIRAM:
```

```
CLR    CS_T
LCALL  DELAY
LCALL  CEK_UIP
LCALL  DELAY
```

```
;
MOV    R0,#RTC_JAM
LCALL  DELAY
MOVX   A,@R0
LCALL  KONVERSI
MOV    PUL_JAM,PULUHAN
MOV    SAT_JAM,SATUAN
LCALL  AS_BIN
MOV    DAT_JAM,A ;UTK_PEMBANDING
SETB   CS_T
LCALL  DELAY
```

```
;
MOV    A,DAT_JAM
CJNE   A,#0BH,TARA_1
MOV    VALUE,#1
SJMP   TARA_3
```

```
TARA_1:
CJNE   A,#0CH,TARA_2
MOV    VALUE,#1
SJMP   TARA_3
```

```
TARA_2:
MOV    VALUE,#0
```

```
TARA_3:
MOV    R1,#68H
MOV    DAT,#0
```

```
;
MOV    A,@R1
CJNE   A,#0,TAR_1
```

```
TER_1:
SETB   SEL_1
INC    R1
SJMP   TAR_2
```

```
TAR_1:
MOV    A,VALUE
CJNE   A,#0,TER_1
CLR    SEL_1
MOV    DAT,#1
INC    R1
```

```
TAR_2:
MOV    A,@R1
```

```

        CJNE      A,#0,TAR_3
TER_2:  SETB      SEL_2
        INC      R1
        SJMP     TAR_4
TAR_3:  MOV      A,VALUE
        CJNE     A,#0,TER_2
        CLR      SEL_2
        MOV      DAT,#1
        INC      R1
TAR_4:  MOV      A,@R1
        CJNE     A,#0,TAR_5
TER_3:  SETB      SEL_3
        INC      R1
        SJMP     TAR_6
TAR_5:  MOV      A,VALUE
        CJNE     A,#0,TER_3
        CLR      SEL_3
        MOV      DAT,#1
        INC      R1
TAR_6:  MOV      A,@R1
        CJNE     A,#0,TAR_7
TER_4:  SETB      SEL_4
        INC      R1
        SJMP     TAR_8
TAR_7:  MOV      A,VALUE
        CJNE     A,#0,TER_4
        CLR      SEL_4
        MOV      DAT,#1
        INC      R1
TAR_8:  MOV      A,DAT
        CJNE     A,#0,TAR_9
TAR_A:  SETB      MTR
        RET
TAR_9:  MOV      A,VALUE
        CJNE     A,#0,TAR_A
        CLR      MTR

```

RET

---

---

PRO\_SETTING\_MENU

---

---

MENU:

LCALL SETT\_1  
MOV CODE\_1,#40

LIEP\_1:  
MOV CODE\_2,#250

LIEP\_6:  
LCALL KEY\_SCAN  
MOV A,DAT  
CJNE A,#1,LIEP\_3  
MOV DAT,#0  
SJMP LIEP\_4

LIEP\_3:  
DJNZ CODE\_2,LIEP\_6  
DJNZ CODE\_1,LIEP\_1  
LJMP START\_1

LIEP\_4:  
MOV A,DATA\_KEY  
CJNE A,#01H,LIEP\_5  
LJMP CEK\_TIMER ;CEK\_RTC

LIEP\_5:  
CJNE A,#02H,LIEP\_7 ;SET\_LEMBAB  
LCALL LEMBAB  
LCALL DELAY  
LJMP MENU

LIEP\_7:  
CJNE A,#03H,LIEP\_3 ;EXIT  
LCALL DELAY  
LJMP START\_1

-----  
LEMBAB:

MOV BUF\_1,#5  
MOV BUF\_2,#0AAH  
MOV BUF\_3,#2  
LCALL NO\_MEN

NUM\_1:  
LCALL KEY\_SCAN  
MOV A,DAT  
CJNE A,#1,NUM\_1  
MOV DAT,#0  
MOV A,DATA\_KEY  
MOV BUF\_1,A

; CJNE A,#0CH,NUM\_2  
RET

NUM\_2:  
CLR C

```

        CJNE     A,#05H,NUM_22
        SJMP     NUM_1
NUM_22:
        JNC     NUM_1
        CJNE     A,#0,NUM_3
        SJMP     NUM_1
NUM_3:
        LCALL    NO_MEN
NUM_33:
        LCALL    KEY_SCAN
        MOV     A,DAT
        CJNE     A,#1,NUM_33
        MOV     DAT,#0
        MOV     A,DATA_KEY
        CJNE     A,#0EH,NUM_33
        LCALL    WAKTU
NUM_4:
        LCALL    KEY_SCAN
        MOV     A,DAT
        CJNE     A,#1,NUM_4
        MOV     DAT,#0
        MOV     A,DATA_KEY
;
        CJNE     A,#0CH,NUM_5
        RET
NUM_5:
        CLR     C
        CJNE     A,#0AH,NUM_55
        SJMP     NUM_4
NUM_55:
        JNC     NUM_6
        MOV     A,BUF_2
        SWAP    A
        ANL     A,#0F0H
        ORL     A,DATA_KEY
        MOV     BUF_2,A
        LCALL    NO_MEN
        DJNZ    BUF_3,NUM_4
NUM_7:
        LCALL    KEY_SCAN
        MOV     A,DAT
        CJNE     A,#1,NUM_7
        MOV     DAT,#0
        MOV     A,DATA_KEY
        CJNE     A,#0EH,NUM_7
        SJMP     NUM_8
NUM_6:
        CJNE     A,#0EH,NUM_4
NUM_8:
        LCALL    WAKTU

```

```

    LCALL    TUNGGU_1
;
    MOV     A,BUF_1
    MOV     B,#0FH
    ADD    A,B
    MOV     R0,A
;
    CLR     CS_T
    MOV     A,BUF_2
    LCALL   DELAY
    MOV     x @R0,A
    LCALL   DELAY
    SETB    CS_T
    RET
;-----
TULIS:
    ORL     A,#30H
    MOV     LCD,A
    LCALL   LCD_CONTROL
    RET
;=====
;
;   PRO_CEK TIMER
;=====
CEK_TIMER:
    LCALL   TUNGGU_2
LIOP_1:
    LCALL   KEY_SCAN
    MOV     A,DAT
    CJNE    A,#1,LIOP_1
    MOV     DAT,#0
    MOV     A,DATA_KEY
;
    CJNE    A,#0AH,LIOP_2    ;LIHAT TIMER
    LJMP    LIHAT_RTC
LIOP_2:
    CJNE    A,#0BH,LIOP_3    ;GANTI TIMER
    LJMP    SETING_RTC
LIOP_3:
    CJNE    A,#0CH,LIOP_1    ;GANTI TIMER
    LCALL   DELAY
    RET
;=====
;
;   PRO_LIHAT TIMER
;=====
LIHAT_RTC:
    MOV     R6,#10
SEEP_1:
    LCALL   AMBIL_DATA        ;AMBIL DATA RTC
    LCALL   AMBIL_HARIAN     ;AMBIL HARI RTC
    LCALL   TAMPIL_RTC       ;TAMPIL DATA RTC

```



```

        CJNE     A,B,UPPER_1
        LJMP     YES_1
UPPER_1:
        LCALL    SET_TIMER ;DISPLAY
        LCALL    SET_TAHUN ;DISPLAY
        INC      DAT_TAHUN
        LCALL    RIBU
        LJMP     YES_1
YEX_1:
        CJNE     A,#6,YEX_2
        MOV      A,DAT_BULAN
        MOV      B,DAT_UPP
        CJNE     A,B,UPPER_2
        LJMP     YES_1
UPPER_2:
        LCALL    SET_TIMER ;DISPLAY
        LCALL    SET_BULAN ;DISPLAY
        INC      DAT_BULAN
        LCALL    BUL_UPDW
        LJMP     YES_1
YEX_2:
        CJNE     A,#5,YEX_3
        MOV      A,DAT_HARI
        MOV      B,DAT_UPP
        CJNE     A,B,UPPER_3
        LJMP     YES_1
UPPER_3:
        LCALL    SET_TIMER ;DISPLAY
        LCALL    SET_HARI ;DISPLAY
        INC      DAT_HARI
        LCALL    HAR_UPDW
        LJMP     YES_1
YEX_3:
        CJNE     A,#4,YEX_4
        MOV      A,DAT_TANGGAL
        MOV      B,DAT_UPP
        CJNE     A,B,UPPER_4
        LJMP     YES_1
UPPER_4:
        LCALL    SET_TIMER ;DISPLAY
        LCALL    SET_TANGGAL ;DISPLAY
        INC      DAT_TANGGAL
        MOV      A,DAT_TANGGAL
        LCALL    BAGI
        LJMP     YES_1
YEX_4:
        CJNE     A,#3,YEX_5
        MOV      A,DAT_JAM
        MOV      B,DAT_UPP
        CJNE     A,B,UPPER_5

```

```

    LJMP        YES_1
UPPER_5:
    LCALL       SET_TIMER ;DISPLAY
    LCALL       SET_JAM   ;DISPLAY
    INC        DAT_JAM
    MOV        A,DAT_JAM
    LCALL       BAGI
    LJMP        YES_1
YEX_5:
    CJNE       A,#2,YEX_6
    MOV        A,DAT_MENIT
    MOV        B,DAT_UPP
    CJNE       A,B,UPPER_6
    LJMP        YES_1
UPPER_6:
    LCALL       SET_TIMER ;DISPLAY
    LCALL       SET_MENIT ;DISPLAY
    INC        DAT_MENIT
    MOV        A,DAT_MENIT
    LCALL       BAGI
    LJMP        YES_1
YEX_6:
    MOV        A,DAT_DETIK
    MOV        B,DAT_UPP
    CJNE       A,B,UPPER_7
    LJMP        YES_1
UPPER_7:
    LCALL       SET_TIMER ;DISPLAY
    LCALL       SET_DETIK ;DISPLAY
    INC        DAT_DETIK
    MOV        A,DAT_DETIK
    LCALL       BAGI
    LJMP        YES_1
=====
YES_Y:
    MOV        A,DAT_BUF
    CJNE       A,#7,XEY_1
    MOV        A,DAT_TAHUN
    MOV        B,DAT_DWN
    CJNE       A,B,DOWER_1
    LJMP        YES_1
DOWER_1:
    LCALL       SET_TIMER ;DIPLAY
    LCALL       SET_TAHUN ;DISPLAY
    DEC        DAT_TAHUN
    LCALL       RIBU
    LJMP        YES_1
XEY_1:
    CJNE       A,#6,XEY_2
    MOV        A,DAT_BULAN

```

```

MOV      B,DAT_DWN
CJNE    A,B,DOWER_2
LJMP    YES_1
DOWER_2:
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_BULAN ;DISPLAY
DEC     DAT_BULAN
LCALL   BUL_UPDW
LJMP    YES_1
XEY_2:
CJNE    A,#5,XEY_3
MOV     A,DAT_HARI
MOV     B,DAT_DWN
CJNE    A,B,DOWER_3
LJMP    YES_1
DOWER_3:
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_HARI ;DISPLAY
DEC     DAT_HARI
LCALL   HAR_UPDW
LJMP    YES_1
XEY_3:
CJNE    A,#4,XEY_4
MOV     A,DAT_TANGGAL
MOV     B,DAT_DWN
CJNE    A,B,DOWER_4
LJMP    YES_1
DOWER_4:
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_TANGGAL ;DISPLAY
DEC     DAT_TANGGAL
MOV     A,DAT_TANGGAL
LCALL   BAGI
LJMP    YES_1
XEY_4:
CJNE    A,#3,XEY_5
MOV     A,DAT_JAM
MOV     B,DAT_DWN
CJNE    A,B,DOWER_5
LJMP    YES_1
DOWER_5:
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_JAM ;DISPLAY
DEC     DAT_JAM
MOV     A,DAT_JAM
LCALL   BAGI
LJMP    YES_1
XEY_5:
CJNE    A,#2,XEY_6
MOV     A,DAT_MENIT

```

```

MOV      B,DAT_DWN
CJNE    A,B,DOWER_6
LJMP    YES_1
DOWER_6:
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_MENIT ;DIPLAY
DEC     DAT_MENIT
MOV     A,DAT_MENIT
LCALL   BAGI
LJMP    YES_1
KEY_6:
MOV     A,DAT_DETIK
MOV     B,DAT_DWN
CJNE    A,B,DOWER_7
LJMP    YES_1
DOWER_7:
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_DETIK ;DISPLAY
DEC     DAT_DETIK
MOV     A,DAT_DETIK
LCALL   BAGI
LJMP    YES_1
=====
YES_4:
MOV     A,DAT_BUF
CJNE    A,#6,YES_5
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_BULAN ;DISPLAY
MOV     DAT_DWN,#1
MOV     DAT_UPP,#12
MOV     DAT_BULAN,#1
LCALL   BUL_UPDW
LJMP    YES_1
YES_5:
CJNE    A,#5,YES_6
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_HARI ;DISPLAY
MOV     DAT_DWN,#1
MOV     DAT_UPP,#7
MOV     DAT_HARI,#1
LCALL   HAR_UPDW
LJMP    YES_1
YES_6:
CJNE    A,#4,YES_7
LCALL   SET_TIMER ;DISPLAY
LCALL   SET_TANGGAL ;DISPLAY
MOV     DAT_DWN,#1
MOV     DAT_UPP,#31
MOV     DAT_TANGGAL,#1
MOV     A,DAT_TANGGAL

```

```

        LCALL    BAGI
        LJMP    YES_1
YES_7:
        CJNE    A,#3,YES_8
        LCALL    SET_TIMER    ;DISPLAY
        LCALL    SET_JAM      ;DISPLAY
        MOV     DAT_DWN,#0
        MOV     DAT_UPP,#23
        MOV     DAT_JAM,#0
        MOV     A,DAT_JAM
        LCALL    BAGI
        LJMP    YES_1
YES_8:
        CJNE    A,#2,YES_9
        LCALL    SET_TIMER    ;DISPLAY
        LCALL    SET_MENIT   ;DISPLAY
        MOV     DAT_DWN,#0
        MOV     DAT_UPP,#59
        MOV     DAT_MENIT,#0
        MOV     A,DAT_MENIT
        LCALL    BAGI
        LJMP    YES_1
YES_9:
        LCALL    SET_TIMER    ;DISPLAY
        LCALL    SET_DETIK   ;DISPLAY
        MOV     DAT_DWN,#0
        MOV     DAT_UPP,#59
        MOV     DAT_DETIK,#0
        MOV     A,DAT_DETIK
        LCALL    BAGI
        LJMP    YES_1

```

---

```

;
;   PRO_SIMPAN_JAM
;

```

```

SIMPAN_RTC:

```

```

;   CLR     EA
;   LCALL   TUNGGU_1
;
;   CLR     CS_T    ;>>
;   LCALL   DOLAY
;   LCALL   INIT_RTC_DS
;   LCALL   RTC_SAVE_DS
;   LCALL   DOLAY
;   SETB    CS_T    ;>>
;   LCALL   DELAY_TAMPILAN
;   SETB    EA
;   LJMP   MENU

```

---

```

;
;   Inisialisasi RTC_DS
;

```

```

INIT_RTC_DS:
    LCALL    DELAY
    MOV     R1,#REG_A
    MOV     A,#2FH
    LCALL    DELAY
    MOVX    @R1,A
    LCALL    DELAY
;
    MOV     R1,#REG_B
    MOV     A,#1AH
    LCALL    DELAY
    MOVX    @R1,A
    LCALL    DELAY
;
    MOV     R1,#RTC_CENTURY
    MOV     A,#20H
    LCALL    DELAY
    MOVX    @R1,A
    LCALL    DELAY
    RET
;
=====
;
;   PRO_SIMPAN_MENU_MAKANAN_DS
;
=====

```

```

RTC_SAVE_DS:
    MOV     R1,#RTC_TAHUN
    MOV     A,DAT_TAHUN
    LCALL    SEIKO
;
    MOV     R1,#RTC_BULAN
    MOV     A,DAT_BULAN
    LCALL    SEIKO
;
    MOV     R1,#RTC_TANGGAL
    MOV     A,DAT_TANGGAL
    LCALL    SEIKO
;
    MOV     R1,#RTC_HARI
    MOV     A,DAT_HARI
    LCALL    SEIKO
;
    MOV     R1,#RTC_JAM
    MOV     A,DAT_JAM
    LCALL    SEIKO
;
    MOV     R1,#RTC_MINIT
    MOV     A,DAT_MINIT
    LCALL    SEIKO
;
    MOV     R1,#RTC_DETİK
    MOV     A,DAT_DETİK

```

```
LCALL SEIKO
RET
```

---

```
;
; PRO_AMBIL_DATA_RTC
;
```

```
AMBIL_DATA:
```

```
CLR CS_T
LCALL DELAY
LCALL CEK_UIP
LCALL DELAY
```

```
;
MOV R0,#RTC_TAHUN
LCALL DELAY
MOVB A,@R0
LCALL KONVERSI
MOV PUL_TAHUN,PULUHAN
MOV SAT_TAHUN,SATUAN
LCALL DELAY
```

```
;
MOV R0,#RTC_BULAN
LCALL DELAY
MOVB A,@R0
LCALL KONVERSI
MOV PUL_BULAN,PULUHAN
MOV SAT_BULAN,SATUAN
LCALL DELAY
```

```
;
MOV R0,#RTC_TANGGAL
LCALL DELAY
MOVB A,@R0
LCALL KONVERSI
MOV PUL_TANGGAL,PULUHAN
MOV SAT_TANGGAL,SATUAN
LCALL DELAY
```

```
;
MOV R0,#RTC_HARI
LCALL DELAY
MOVB A,@R0
LCALL KONVERSI
MOV PUL_HARI,PULUHAN
MOV SAT_HARI,SATUAN
LCALL DELAY
```

```
;
MOV R0,#RTC_JAM
LCALL DELAY
MOVB A,@R0
LCALL KONVERSI
MOV PUL_JAM,PULUHAN
MOV SAT_JAM,SATUAN
LCALL AS_BIN
```

```

MOV     DAT_JAM,A ;UTK_PEMBANDING
LCALL  DELAY
;
MOV     R0,#RTC_MENIT
LCALL  DELAY
MOVX   A,@R0
LCALL  KONVERSI
MOV    PUL_MENIT,PULUHAN
MOV    SAT_MENIT,SATUAN
LCALL  AS_BIN
MOV    DAT_MENIT,A      ;UTK_PEMBANDING
LCALL  DELAY
;
MOV     R0,#RTC_DETİK
LCALL  DELAY
MOVX   A,@R0
LCALL  KONVERSI
MOV    PUL_DETİK,PULUHAN
MOV    SAT_DETİK,SATUAN
LCALL  AS_BIN
MOV    DAT_DETİK,A      ;UTK_PEMBANDING
SETB   CS_T
LCALL  DELAY
RET

```

```

;=====
;  PROG_AMBIL_HARI
;=====

```

AMBIL\_HARIAN:

```

MOV     A,SAT_HARI
CJNE   A,#31H,BA_SENIN
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#MINGGU
LCALL  WRITE
RET

```

BA\_SENIN:

```

CJNE   A,#32H,BA_SELASA
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#SENIN
LCALL  WRITE
RET

```

BA\_SELASA:

```

CJNE   A,#33H,BA_RABU
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#SELASA
LCALL  WRITE
RET

```

BA\_RABU:

```

    CJNE    A,#34H,BA_KAMIS
    LCALL   CLEAR_TAMPILAN
    LCALL   ROW_1
    MOV     DPTR,#RABU
    LCALL   WRITE
    RET

BA_KAMIS:
    CJNE    A,#35H,BA_JUMAT
    LCALL   CLEAR_TAMPILAN
    LCALL   ROW_1
    MOV     DPTR,#KAMIS
    LCALL   WRITE
    RET

BA_JUMAT:
    CJNE    A,#36H,BA_SABTU
    LCALL   CLEAR_TAMPILAN
    LCALL   ROW_1
    MOV     DPTR,#JUMAT
    LCALL   WRITE
    RET

BA_SABTU:
    LCALL   CLEAR_TAMPILAN
    LCALL   ROW_1
    MOV     DPTR,#SABTU
    LCALL   WRITE
    RET

```

---



---

```

;
; PRO_TAMPILAN_RTC
;

```

---



---

```

TAMPIL_RTC:
    LCALL   KOMA
;
    MOV     LCD,PUL_TANGGAL
    LCALL   LCD_CONTROL
    MOV     LCD,SAT_TANGGAL
    LCALL   LCD_CONTROL
;
    LCALL   STRIP
;
    MOV     LCD,PUL_BULAN
    LCALL   LCD_CONTROL
    MOV     LCD,SAT_BULAN
    LCALL   LCD_CONTROL
;
    LCALL   STRIP
;
    MOV     LCD,PUL_TAHUN
    LCALL   LCD_CONTROL
    MOV     LCD,SAT_TAHUN
    LCALL   LCD_CONTROL

```

```

;
    LCALL    ROW_2
    LCALL    DELAY
;
    SETB     RS
    LCALL    WIB
    LCALL    KOMA
;
    MOV      LCD,PUL_JAM
    LCALL    LCD_CONTROL
    MOV      LCD,SAT_JAM
    LCALL    LCD_CONTROL
;
    LCALL    TITIK
;
    MOV      LCD,PUL_MENIT
    LCALL    LCD_CONTROL
    MOV      LCD,SAT_MENIT
    LCALL    LCD_CONTROL
;
    LCALL    TITIK
;
    MOV      LCD,PUL_DETIK
    LCALL    LCD_CONTROL
    MOV      LCD,SAT_DETIK
    LCALL    LCD_CONTROL
    RET

```

---



---

```

;
;   PRO_KONVERSI_BCD_ASCII
;

```

```

KONVERSI:

```

```

    LCALL    DELAY
    MOV      DAT_KONVIC,A
    ANL     A,#0F0H
    SWAP    A
    ORL     A,#30H
    MOV     PULUHAN,A
    MOV     A,DAT_KONVIC
    ANL     A,#0FH
    ORL     A,#30H
    MOV     SATUAN,A
    RET

```

---



---

```

;
;   PRO_KONVERSI_ASCII_BINER/DESIMAL
;

```

```

AS_BIN:

```

```

    MOV     A,PULUHAN
    ANL     A,#0FH
    MOV     B,#10
    MUL    AB

```

```
MOV     PULUHAN,A
MOV     A,SATUAN
ANL     A,#0FH
MOV     B,PULUHAN
ADD     A,B
LCALL   DELAY
RET
```

```
;  
;  
; PRO_KONVERSI_BCD_BINER  
;  
;
```

BC\_BIN:

```
MOV     SATUAN,A
ANL     A,#0F0H
SWAP    A
MOV     B,#10
MUL     AB
MOV     PULUHAN,A
MOV     A,SATUAN
ANL     A,#0FH
MOV     B,PULUHAN
ADD     A,B
LCALL   DELAY
RET
```

```
;  
;  
; PRO_KONVERSI_BINER_BCD_DG_CLOK  
;  
;
```

SEIKO:

```
MOV     B,#10
DIV     AB
SWAP    A
ADD     A,B
```

GUCI\_1:

```
LCALL   DELAY
MOVX    @R1,A
LCALL   DELAY
RET
```

```
;  
;  
; PRO_CEK_'IRQF/UIP'  
;  
;
```

CEK\_UIP:

```
MOV     R0,#REG_C
MOV     A,R0
MOV     R1,A
```

SIBUK:

```
LCALL   DELAY
MOVX    A,@R0
LCALL   DELAY
ANL     A,#80H
JNB     ACC.7,SIBUK
CLR     ACC.7
```

```
MOV    @R1,A
LCALL  DELAY
RET
```

---

```
;
; PRO_DIS_AWAL
```

---

```
HEADO_1:
```

```
MOV    7CH,#1
MOV    7DH,#150
```

```
HEADO_2:
```

```
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#HEADER_1
LCALL  WRITE
LCALL  ROW_2
MOV    DPTR,#HEADER_2
LCALL  ISI_DATA
LCALL  DISPLAY
INC    7CH
LCALL  TUNDA
LCALL  TUNDA
DJNZ   7DH,HEADO_2
LCALL  DELAY
LCALL  DELAY
RET
```

```
SETT_1:
```

```
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#MENO_3
LCALL  WRITE
LCALL  ROW_2
MOV    DPTR,#MENO_4
LCALL  WRITE
RET
```

```
;-----
```

```
PLEASED:
```

```
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#PLS_1
LCALL  WRITE
LCALL  ROW_2
MOV    DPTR,#PLS_2
LCALL  WRITE
LCALL  DELAY_TAMPILAN
LCALL  DELAY_TAMPILAN
RET
```

```
TUNGGU_1:
```

```
LCALL  CLEAR_TAMPILAN
LCALL  ROW_1
MOV    DPTR,#PLS_3
```

```

        LCALL    WRITE
        LCALL    ROW_2
        MOV     DPTR,#PLS_4      ;SIMPAN PROG
        LCALL    WRITE
        LCALL    DELAY_TAMPILAN
        RET
TUNGGU_2:
        LCALL    CLEAR_TAMPILAN
        LCALL    ROW_1
        MOV     DPTR,#PLS_5      ;LIHAT TIMER
        LCALL    WRITE
        LCALL    ROW_2
        MOV     DPTR,#PLS_6      ;GANTI TIMER
        LCALL    WRITE
        RET
NO_MEN:
        LCALL    CLEAR_TAMPILAN
        LCALL    ROW_1
        MOV     DPTR,#MAS_1
        LCALL    WRITE
        MOV     A,BUF_1
        CJNE   A,#05H,MOM_1
        SJMP   MOM_2
MOM_1:
        LCALL    TULIS
MOM_2:
        LCALL    ROW_2
        MOV     DPTR,#MAS_2
        LCALL    WRITE
        MOV     A,BUF_2
        SWAP   A
        ANL    A,#0FH
        CJNE   A,#0AH,MAM_1
        MOV     A,BUF_2
        ANL    A,#0FH
        CJNE   A,#0AH,MAM_3
        SJMP   MAM_2
MAM_1:
        LCALL    TULIS
        MOV     A,BUF_2
        ANL    A,#0FH
MAM_3:
        LCALL    TULIS
MAM_2:
        RET
;-----
SET_TIMER:
        LCALL    CLEAR_TAMPILAN
        LCALL    ROW_1
        MOV     DPTR,#JAM_1

```

```

        LCALL    WRITE
        RET
SET_JAM:
        LCALL    ROW_2
        MOV      DPTR,#JAM_2
        LCALL    WRITE
        RET
SET_MENIT:
        LCALL    ROW_2
        MOV      DPTR,#JAM_3
        LCALL    WRITE
        RET
SET_DETIK:
        LCALL    ROW_2
        MOV      DPTR,#JAM_4
        LCALL    WRITE
        RET
SET_HARI:
        LCALL    ROW_2
        MOV      DPTR,#JAM_5
        LCALL    WRITE
        RET
SET_BULAN:
        LCALL    ROW_2
        MOV      DPTR,#JAM_6
        LCALL    WRITE
        RET
SET_TANGGAL:
        LCALL    ROW_2
        MOV      DPTR,#JAM_7
        LCALL    WRITE
        RET
SET_TAHUN:
        LCALL    ROW_2
        MOV      DPTR,#JAM_8
        LCALL    WRITE
        RET
KALI:
        MOV      A,#'H'
        MOV      LCD,A
        LCALL    LCD_CONTROL
        MOV      A,#'a'
        MOV      LCD,A
        LCALL    LCD_CONTROL
        MOV      A,#'r'
        MOV      LCD,A
        LCALL    LCD_CONTROL
        MOV      A,#'i'
        MOV      LCD,A
        LCALL    LCD_CONTROL

```

```

RET
WIB:
MOV     A,#'W'
MOV     LCD,A
LCALL   LCD_CONTROL
MOV     A,#'I'
MOV     LCD,A
LCALL   LCD_CONTROL
MOV     A,#'B'
MOV     LCD,A
LCALL   LCD_CONTROL
LCALL   SPASI
LCALL   SPASI
LCALL   SPASI
LCALL   SPASI
RET

;=====
VIU:
ORL     A,#30H
MOV     LCD,A
LCALL   LCD_CONTROL
RET

;
;=====
BAGI:
MOV     B,#10
DIV     AB
ORL     A,#30H
MOV     LCD,A
LCALL   LCD_CONTROL
ORL     B,#30H
MOV     LCD,B
LCALL   LCD_CONTROL
RET

;=====
HAR_UPDW:
MOV     A,DAT_HARI
MOV     B,#6
MUL     AB
MOV     BUF_HARI,A
MOV     DAT_KON,#6
MOV     DPTR,#HEAD_1
HAR_2:
MOV     A,BUF_HARI
MOVC   A,@A+DPTR
MOV     LCD,A
LCALL   LCD_CONTROL
DJNZ   DAT_KON,HAR_1
RET
HAR_1:

```

```

        INC        DPTR
        SJMP       HAR_2
;=====
BUL_UPDW:
        MOV        A,DAT_BULAN
        MOV        B,#9
        MUL        AB
        MOV        BUF_BULAN,A
        MOV        DAT_KON,#9
        MOV        DPTR,#HEAD_2
BUL_2:
        MOV        A,BUF_BULAN
        MOVC       A,@A+DPTR
        MOV        LCD,A
        LCALL      LCD_CONTROL
        DJNZ       DAT_KON,BUL_1
        RET
BUL_1:
        INC        DPTR
        SJMP       BUL_2
;=====
RIBU:
        MOV        LCD,#00110010B    ;'2'
        LCALL      LCD_CONTROL
        MOV        LCD,#00110000B    ;'0'
        LCALL      LCD_CONTROL
        MOV        A,DAT_TAHUN
        MOV        B,#10
        DIV        AB
        ORL        A,#30H
        MOV        LCD,A
        LCALL      LCD_CONTROL
        ORL        B,#30H
        MOV        LCD,B
        LCALL      LCD_CONTROL
        RET
;=====
SPASI:
        MOV        A,#' '
        MOV        LCD,A
        LCALL      LCD_CONTROL
        RET
STRIP:
        MOV        A,#-' '
        MOV        LCD,A
        LCALL      LCD_CONTROL
        RET
TITIK:
        MOV        A,#':'
        MOV        LCD,A

```

```

        LCALL    LCD_CONTROL
        RET
KOMA:
        MOV     A,#';'
        MOV     LCD,A
        LCALL   LCD_CONTROL
        RET

```

```

;-----
;
;   Baca Keypad
;-----
;

```

```

KEY_SCAN:
        LCALL   BACA_TOMBOL
        MOV     A,DAT
        CJNE   A,#1,KEMBALI
LOMPAT:
        MOV     BOUNC,#5
LOMPAT1:
        MOV     P1,COMMON
        MOV     A,P1
        ORL    A,#0FH
        CJNE   A,#0FFH,LOMPAT
        DJNZ   BOUNC,LOMPAT1
KEMBALI:
        RET

```

```

;+++++
;Baca Tombol Keypad 4X4
;Jumlah baris:4 (P1.0 - P1.3)
;Jumlah kolom:4 (P1.4 - P1.7)
;+++++

```

```

BACA_TOMBOL:
        MOV    BARIS,#4
        MOV    COMMON,#11111110B    ;DATA BARIS
        MOV    DATA_4,#0
        MOV    DPTR,#ANGKA
BACA_TOMBOL1:
        MOV    BAN_P1,#01111111B    ;DATA KOLOM
        MOV    PER_BARIS,#0
BACA_TOMBOL2:
        MOV    P1,COMMON
        MOV    A,P1
        ORL    A,#0FH
        CJNE   A,BAN_P1,BACA_TOMBOL3
        MOV    A,PER_BARIS
        ADD    A,DATA_4
        MOVC   A,@A+DPTR
        MOV    DATA_KEY,A
        MOV    DAT,#1
        RET
BACA_TOMBOL3:
        INC    PER_BARIS

```

```
MOV    A,BAN_P1
RR     A
MOV    BAN_P1,A
MOV    A,PER_BARIS
CJNE   A,#4,BACA_TOMBOL2
```

nextscan:

```
MOV    A,DATA_4
ADD    A,#4
MOV    DATA_4,A
MOV    A,COMMON
RL     A
MOV    COMMON,A
DJNZ   BARIS,BACA_TOMBOL1
MOV    P1,#0FFh
MOV    DAT,#0
RET
```

---

---

PROG\_ISI DATA RAM

---

---

ISI\_DATA:

```
MOV    R1,#60H
MOV    R3,#16
```

ISI\_DATA1:

```
MOV    A,7CH
MOVC   A,@A+DPTR
MOV    @R1,A
INC    DPTR
INC    R1
DJNZ   R3,ISI_DATA1
RET
```

---

---

PROG\_DISPLAY

---

---

DISPLAY:

```
MOV    R0,#60H
MOV    R3,#16
SETB   RS
```

DISPLAY1:

```
MOV    A,@R0
MOV    LCD,A
LCALL  LCD_CONTROL
INC    R0
DJNZ   R3,DISPLAY1
RET
```

---

---

Inisialisasi LCD

---

---

INIT\_LCD:

```
CLR    RS
MOV    LCD,#3FH
```

```
LCALL LCD_CONTROL
LCALL LCD_CONTROL
LCALL DELAY
MOV LCD,#0EH
LCALL LCD_CONTROL
LCALL DELAY
MOV LCD,#06H
LCALL LCD_CONTROL
LCALL DELAY
MOV LCD,#01H
LCALL LCD_CONTROL
LCALL DELAY
MOV LCD,#0CH
LCALL LCD_CONTROL
LCALL DELAY
RET
```

;-----

LCD\_CONTROL:

```
LCALL DELAY
SETB EN
CLR EN
LCALL DELAY
LCALL DELAY
RET
```

---

;
; Hapus Tampilan
;

CLEAR\_TAMPILAN:

```
CLR EA
CLR RS
MOV LCD,#01H
LCALL LCD_CONTROL
LCALL DELAY
RET
```

---

;
; Baris Pertama
;

ROW\_1:

```
CLR RS
MOV LCD,#10H
LCALL LCD_CONTROL
LCALL DELAY
RET
```

---

;
; Baris Kedua
;

ROW\_2:

```
CLR RS
MOV LCD,#11000000B
LCALL LCD_CONTROL
```

```
LCALL    DELAY
RET
```

```
;  
;  
;   Prosedur Pengiriman Data  
;   ke LCD  
;
```

```
WRITE:
```

```
    SETB    RS
```

```
TULIS_1:
```

```
    CLR     A  
    MOVC   A,@A+DPTR  
    CJNE  A,#$,TULIS_2  
    SETB   EA  
    NOP  
    RET
```

```
TULIS_2:
```

```
    MOV    LCD,A  
    LCALL  LCD_CONTROL  
    INC    DPTR  
    LCALL  DELAY  
    LJMP   TULIS_1
```

```
;  
;  
;   PROG_TIMER KRISTAL 12MHz  
;
```

```
DOLAY:
```

```
    PUSH B  
    PUSH PSW  
    PUSH 02H  
    PUSH 03H  
    MOV R2,#200
```

```
DOLAY_1:
```

```
    MOV R3,#0FFH  
    DJNZ R3,$  
    DJNZ R2,DOLAY_1  
    POP 03H  
    POP 02H  
    POP PSW  
    POP B  
    RET
```

```
DELAY:
```

```
    PUSH B  
    PUSH PSW  
    PUSH 02H  
    PUSH 03H  
    MOV R2,#9
```

```
DELAY_1:
```

```
    MOV R3,#10  
    DJNZ R3,$  
    DJNZ R2,DELAY_1  
    POP 03H
```

```

    POP 02H
    POP PSW
    POP B
    RET
DELAY_TAMPILAN:
    PUSH B
    PUSH PSW
    PUSH 02H
    PUSH 03H
    PUSH 04H
    MOV R2,#10
DELAY_TAMPILAN1:
    MOV R3,#0FFH
DELAY_TAMPILAN2:
    MOV R4,#0FFH
    DJNZ R4,$
    DJNZ R3,DELAY_TAMPILAN2
    DJNZ R2,DELAY_TAMPILAN1
    POP 04H
    POP 03H
    POP 02H
    POP PSW
    POP B
    RET
TUNDA:
    PUSH B
    PUSH PSW
    PUSH 03H
    PUSH 04H
    MOV R4,#125
LDEL_1:
    MOV R3,#0FFH
    DJNZ R3,$
    DJNZ R4,LDEL_1
    POP 04H
    POP 03H
    POP PSW
    POP B
    RET
WAKTU:                                ; 0.5_s
    PUSH B
    PUSH PSW
    PUSH 02H
WAKTU_2:
    MOV R2,#25
WAKTU_3:
    LCALL GAP_1
    DJNZ R2,WAKTU_3
    POP 02H
    POP PSW

```

```

    POP B
    RET
GAPA_1:                                ; 1_s
    PUSH B
    PUSH PSW
    PUSH 02H
    MOV R2,#100
GAPA_2:
    LCALL    GAP_1
    DJNZ     R2,GAPA_2
    POP      02H
    POP      PSW
    POP      B
    RET
GAP_1:                                ;"65.535 - 10000 = 55535_Dec = D8EF_Hex"
    MOV TMOD,#1                        ;(t= 0,000.100s) = 0,0001s
    MOV TH0,#0D8H
    MOV TL0,#0EFH
    SETB TR0
GAP_2:
    NOP
    JBC TF0,GAP_3
    SJMP GAP_2
GAP_3:
    RET
GUN_1:                                ;"65.535 - XXX = 65435_Dec = FF9B_Hex"
    MOV TMOD,#1                        ;(t= 0,000.100s) = 0,0001s
    MOV TH0,#0FFH
    MOV TL0,#9BH
    SETB TR0
GUN_2:
    NOP
    JBC TF0,GUN_3
    SJMP GUN_2
GUN_3:
    RET
;=====
; DATA_MEMORY
;=====
ANGKA:
    DB
    03H,02H,01H,00H,07H,06,05H,04H,0BH,0AH,09H,08H,0FH,0EH,0DH,0CH
HEADER_1:
    DB "'TAMPILAN UTAMA'$"
HEADER_2:
    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB '* PENYIRAMAN OTOMATIS PADA TANAMAN KEDELAI * - Oleh:
ACHMAT EBIT - NIM: 00.107138 - '
    DB 'Fak/Jur: TEK. ELEKTRO/ELEKTRONIKA - * ITN MALANG *'

```

```

    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB 20H,20H,20H,20H,20H,20H,20H,20H
    DB 20H,20H,20H,20H,20H,20H,20H,20H
DAT_SP:
    DB 'HARI: $'
MINGGU:
    DB 'Minggu $'
SENIN:
    DB 'Senin $'
SELASA:
    DB 'Selasa $'
RABU:
    DB 'Rabu $'
KAMIS:
    DB 'Kamis $'
JUMAT:
    DB 'Jum"at $'
SABTU:
    DB 'Sabtu $'
HEAD_1:
    DB ' MingguSenin SelasaRabu Kamis Jum"atSabtu '
HEAD_2:
    DB ' Januari Februari Maret April Mei Juni Juli Agustus
SeptemberOktober Nopember Desember '
PLS_1:
    DB ' * Masuk Menu * $'
PLS_2:
    DB '-- Tekan: "F" --$'
PLS_3:
    DB 'TUNGGU!!! Sedang$'
PLS_4:
    DB ' Simpan Program $'
PLS_5:
    DB 'Lihat Timer: "A"$'
PLS_6:
    DB 'Ganti Timer: "B"$'
MENO_3:
    DB 'MENU SET: 1.JAM $'
MENO_4:
    DB '2.LEMBAB 3.EXIT$'
MAS_1:
    DB 'Nomor Sensor: $'
MAS_2:
    DB 'Kelembaban : $'
MAS_3:
    DB 'KEY: $'

```

```
MAS_4:
  DB 'ADC: $'
JAM_1:
  DB 'SET TIMER "24HR"$'
JAM_2:
  DB 'JAM: $'
JAM_3:
  DB 'MENIT: $'
JAM_4:
  DB 'DETIK: $'
JAM_5:
  DB 'HARI: $'
JAM_6:
  DB 'BULAN: $'
JAM_7:
  DB 'TANGGAL: $'
JAM_8:
  DB 'TAHUN: $'
  END
```

## Features

- Compatible with MCS<sup>®</sup>51 Products
- 8K Bytes of In-System Reprogrammable Downloadable Flash Memory
  - SPI Serial Interface for Program Downloading
  - Endurance: 1,000 Write/Erase Cycles
- 2K Bytes EEPROM
  - Endurance: 100,000 Write/Erase Cycles
- 4V to 6V Operating Range
- Fully Static Operation: 0 Hz to 24 MHz
- Three-level Program Memory Lock
- 256 x 8-bit Internal RAM
- 32 Programmable I/O Lines
- Three 16-bit Timer/Counters
- Nine Interrupt Sources
- Programmable UART Serial Channel
- SPI Serial Interface
- Low-power Idle and Power-down Modes
- Interrupt Recovery from Power-down
- Programmable Watchdog Timer
- Dual Data Pointer
- Power-off Flag

## Description

The AT89S8252 is a low-power, high-performance CMOS 8-bit microcontroller with 8K bytes of downloadable Flash programmable and erasable read-only memory and 2K bytes of EEPROM. The device is manufactured using Atmel's high-density nonvolatile memory technology and is compatible with the industry-standard 80C51 instruction set and pinout. The on-chip downloadable Flash allows the program memory to be reprogrammed In-System through an SPI serial interface or by a conventional nonvolatile memory programmer. By combining a versatile 8-bit CPU with downloadable Flash on a monolithic chip, the Atmel AT89S8252 is a powerful microcontroller, which provides a highly-flexible and cost-effective solution to many embedded control applications.

The AT89S8252 provides the following standard features: 8K bytes of downloadable Flash, 2K bytes of EEPROM, 256 bytes of RAM, 32 I/O lines, programmable watchdog timer, two data pointers, three 16-bit timer/counters, a six-vector two-level interrupt architecture, a full duplex serial port, on-chip oscillator, and clock circuitry. In addition, the AT89S8252 is designed with static logic for operation down to zero frequency and supports two software selectable power saving modes. The Idle Mode stops the CPU while allowing the RAM, timer/counters, serial port, and interrupt system to continue functioning. The Power-down mode saves the RAM contents but freezes the oscillator, disabling all other chip functions until the next external interrupt or hardware reset.

The downloadable Flash can be changed a single byte at a time and is accessible through the SPI serial interface. Holding RESET active forces the SPI bus into a serial programming interface and allows the program memory to be written to or read from unless lock bits have been activated.



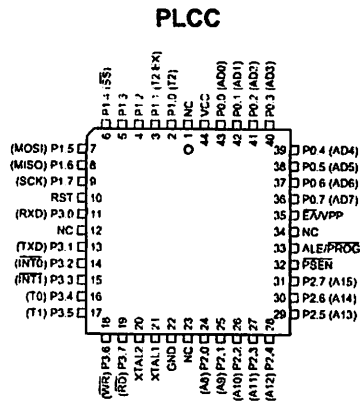
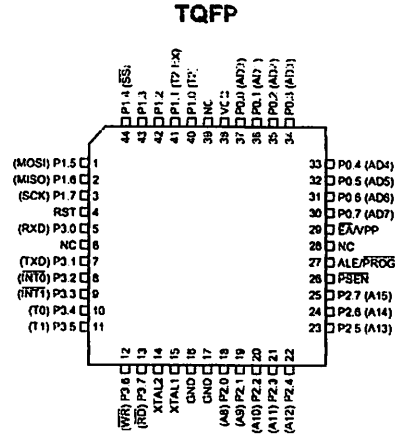
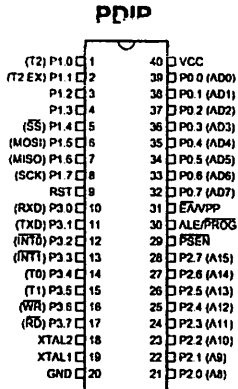
## 8-bit Microcontroller with 8K Bytes Flash

**AT89S8252**





## Pin Configurations



## Pin Description

**VCC** Supply voltage.

**GND** Ground.

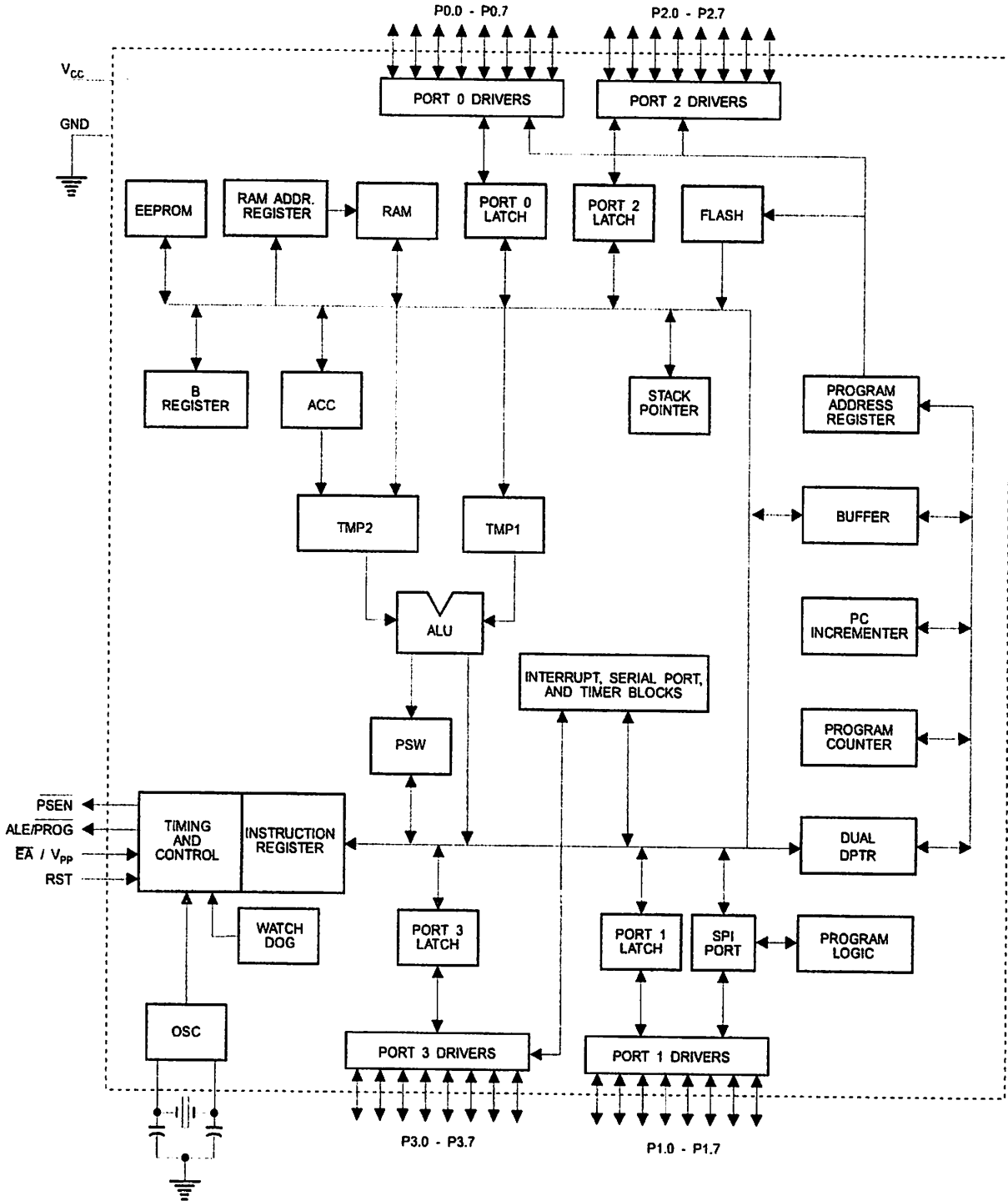
**Port 0** Port 0 is an 8-bit open drain bi-directional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. External pull-ups are required during program verification.

**Port 1** Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current ( $I_{IL}$ ) because of the internal pull-ups.

Block Diagram





Some Port 1 pins provide additional functions. P1.0 and P1.1 can be configured to be the timer/counter 2 external count input (P1.0/T2) and the timer/counter 2 trigger input (P1.1/T2EX), respectively.

Furthermore, P1.4, P1.5, P1.6, and P1.7 can be configured as the SPI slave port select, data input/output and shift clock input/output pins as shown in the following table.

Port Pin	Alternate Functions
P1.0	T2 (external count input to Timer/Counter 2), clock-out
P1.1	T2EX (Timer/Counter 2 capture/reload trigger and direction control)
P1.4	$\overline{SS}$ (Slave port select input)
P1.5	MOSI (Master data output, slave data input pin for SPI channel)
P1.6	MISO (Master data input, slave data output pin for SPI channel)
P1.7	SCK (Master clock output, slave clock input pin for SPI channel)

Port 1 also receives the low-order address bytes during Flash programming and verification.

## Port 2

Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current ( $I_{IL}$ ) because of the internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

## Port 3

Port 3 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current ( $I_{IL}$ ) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89S8252, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{\text{INT0}}$ (external interrupt 0)
P3.3	$\overline{\text{INT1}}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{\text{WR}}$ (external data memory write strobe)
P3.7	$\overline{\text{RD}}$ (external data memory read strobe)

## RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

## ALE/ $\overline{\text{PROG}}$

Address Latch Enable is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input ( $\overline{\text{PROG}}$ ) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

## $\overline{\text{PSEN}}$

Program Store Enable is the read strobe to external program memory.

When the AT89S8252 is executing code from external program memory,  $\overline{\text{PSEN}}$  is activated twice each machine cycle, except that two  $\overline{\text{PSEN}}$  activations are skipped during each access to external data memory.

## $\overline{\text{EA}}$ / $\overline{\text{VPP}}$

External Access Enable.  $\overline{\text{EA}}$  must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed,  $\overline{\text{EA}}$  will be internally latched on reset.

$\overline{\text{EA}}$  should be strapped to  $V_{CC}$  for internal program executions. This pin also receives the 12-volt programming enable voltage ( $V_{PP}$ ) during Flash programming when 12-volt programming is selected.

## XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

## XTAL2

Output from the inverting oscillator amplifier.



## Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

**Timer 2 Registers** Control and status bits are contained in registers T2CON (shown in Table 2) and T2MOD (shown in Table 9) for Timer 2. The register pair (RCAP2H, RCAP2L) are the Capture/Reload registers for Timer 2 in 16-bit capture mode or 16-bit auto-reload mode.

**Table 1. AT89S8252 SFR Map and Reset Values**

0F8H									0FFH
0F0H	B 00000000								0F7H
0E8H									0EFH
0E0H	ACC 00000000								0E7H
0D8H									0DFH
0D0H	PSW 00000000					SPCR 000001XX			0D7H
0C8H	T2CON 00000000	T2MOD XXXXXX00	RCAP2L 00000000	RCAP2H 00000000	TL2 00000000	TH2 00000000			0CFH
0C0H									0C7H
0B8H	IP XX000000								0BFH
0B0H	P3 11111111								0B7H
0A8H	IE 0X000000		SPSR 00XXXXXX						0AFH
0A0H	P2 11111111								0A7H
98H	SCON 00000000	SBUF XXXXXXXX							9FH
90H	P1 11111111						WMCON 00000010		97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000			8FH
80H	P0 11111111	SP 00000111	DP0L 00000000	DP0H 00000000	DP1L 00000000	DP1H 00000000	SPDR XXXXXXXX	PCON 0XXX0000	87H

**Table 2. T2CON – Timer/Counter 2 Control Register**

T2CON Address = 0C8H				Reset Value = 0000 0000B				
Bit Addressable								
	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	$C/\overline{T2}$	$CP/\overline{RL2}$
Bit	7	6	5	4	3	2	1	0

Symbol	Function
TF2	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK = 1 or TCLK = 1.
EXF2	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	Receive clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in serial port Modes 1 and 3. RCLK = 0 causes Timer 1 overflows to be used for the receive clock.
TCLK	Transmit clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in serial port Modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	Timer 2 external enable. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	Start/Stop control for Timer 2. TR2 = 1 starts the timer.
$C/\overline{T2}$	Timer or counter select for Timer 2. $C/\overline{T2}$ = 0 for timer function. $C/\overline{T2}$ = 1 for external event counter (falling edge triggered).
$CP/\overline{RL2}$	Capture/Reload select. $CP/\overline{RL2}$ = 1 causes captures to occur on negative transitions at T2EX if EXEN2 = 1. $CP/\overline{RL2}$ = 0 causes automatic reloads to occur when Timer 2 overflows or negative transitions occur at T2EX when EXEN2 = 1. When either RCLK or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.



**Watchdog and Memory Control Register** The WMCON register contains control bits for the Watchdog Timer (shown in Table 3). The EEMEN and EEMWE bits are used to select the 2K bytes on-chip EEPROM, and to enable byte-write. The DPS bit selects one of two DPTR registers available.

**Table 3. WMCON—Watchdog and Memory Control Register**

WMCON Address = 96H				Reset Value = 0000 0010B				
Bit	PS2	PS1	PS0	EEMWE	EEMEN	DPS	WDTRST	WDTEN
	7	6	5	4	3	2	1	0

Symbol	Function
PS2 PS1 PS0	Prescaler Bits for the Watchdog Timer. When all three bits are set to "0", the watchdog timer has a nominal period of 16 ms. When all three bits are set to "1", the nominal period is 2048 ms.
EEMWE	EEPROM Data Memory Write Enable Bit. Set this bit to "1" before initiating byte write to on-chip EEPROM with the MOVX instruction. User software should set this bit to "0" after EEPROM write is completed.
EEMEN	Internal EEPROM Access Enable. When EEMEN = 1, the MOVX instruction with DPTR will access on-chip EEPROM instead of external data memory. When EEMEN = 0, MOVX with DPTR accesses external data memory.
DPS	Data Pointer Register Select. DPS = 0 selects the first bank of Data Pointer Register, DP0, and DPS = 1 selects the second bank, DP1
WDTRST RDY/BSY	Watchdog Timer Reset and EEPROM Ready/Busy Flag. Each time this bit is set to "1" by user software, a pulse is generated to reset the watchdog timer. The WDTRST bit is then automatically reset to "0" in the next instruction cycle. The WDTRST bit is Write-Only. This bit also serves as the RDY/BSY flag in a Read-Only mode during EEPROM write. RDY/BSY = 1 means that the EEPROM is ready to be programmed. While programming operations are being executed, the RDY/BSY bit equals "0" and is automatically reset to "1" when programming is completed.
WDTEN	Watchdog Timer Enable Bit. WDTEN = 1 enables the watchdog timer and WDTEN = 0 disables the watchdog timer.

**SPI Registers** Control and status bits for the Serial Peripheral Interface are contained in registers SPCR (shown in Table 4) and SPSR (shown in Table 5). The SPI data bits are contained in the SPDR register. Writing the SPI data register during serial data transfer sets the Write Collision bit, WCOL, in the SPSR register. The SPDR is double buffered for writing and the values in SPDR are not changed by Reset.

**Interrupt Registers** The global interrupt enable bit and the individual interrupt enable bits are in the IE register. In addition, the individual interrupt enable bit for the SPI is in the SPCR register. Two priorities can be set for each of the six interrupt sources in the IP register.

**Dual Data Pointer Registers** To facilitate accessing both internal EEPROM and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR WMCON selects DP0 and DPS = 1 selects DP1. The user should **ALWAYS** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

**Power Off Flag** The Power Off Flag (POF) is located at bit\_4 (PCON.4) in the PCON SFR. POF is set to "1" during power up. It can be set and reset under software control and is not affected by RESET.

**Table 4. SPCR – SPI Control Register**

SPCR Address = D5H								Reset Value = 0000 01XXB															
Bit	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0															
	7	6	5	4	3	2	1	0															
Symbol	Function																						
SPIE	SPI Interrupt Enable. This bit, in conjunction with the ES bit in the IE register, enables SPI interrupts: SPIE = 1 and ES = 1 enable SPI interrupts. SPIE = 0 disables SPI interrupts.																						
SPE	SPI Enable. SPI = 1 enables the SPI channel and connects $\overline{SS}$ , MOSI, MISO and SCK to pins P1.4, P1.5, P1.6, and P1.7. SPI = 0 disables the SPI channel.																						
DORD	Data Order. DORD = 1 selects LSB first data transmission. DORD = 0 selects MSB first data transmission.																						
MSTR	Master/Slave Select. MSTR = 1 selects Master SPI mode. MSTR = 0 selects Slave SPI mode.																						
CPOL	Clock Polarity. When CPOL = 1, SCK is high when Idle. When CPOL = 0, SCK of the master device is low when not transmitting. Please refer to figure on SPI Clock Phase and Polarity Control.																						
CPHA	Clock Phase. The CPHA bit together with the CPOL bit controls the clock and data relationship between master and slave. Please refer to figure on SPI Clock Phase and Polarity Control.																						
SPR0 SPR1	SPI Clock Rate Select. These two bits control the SCK rate of the device configured as master. SPR1 and SPR0 have no effect on the slave. The relationship between SCK and the oscillator frequency, $F_{osc}$ , is as follows: <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>SPR1</th> <th>SPR0</th> <th>SCK = <math>F_{osc}</math> divided by</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>4</td> </tr> <tr> <td>0</td> <td>1</td> <td>16</td> </tr> <tr> <td>1</td> <td>0</td> <td>64</td> </tr> <tr> <td>1</td> <td>1</td> <td>128</td> </tr> </tbody> </table>								SPR1	SPR0	SCK = $F_{osc}$ divided by	0	0	4	0	1	16	1	0	64	1	1	128
SPR1	SPR0	SCK = $F_{osc}$ divided by																					
0	0	4																					
0	1	16																					
1	0	64																					
1	1	128																					



**Table 5. SPSR – SPI Status Register**

SPSR Address = AAH				Reset Value = 00XX XXXXB			
	SPIF	WCOL	–	–	–	–	–
Bit	7	6	5	4	3	2	1
0							

Symbol	Function
SPIF	SPI Interrupt Flag. When a serial transfer is complete, the SPIF bit is set and an interrupt is generated if SPIE = 1 and ES = 1. The SPIF bit is cleared by reading the SPI status register with SPIF and WCOL bits set, and then reading/writing the SPI data register.
WCOL	Write Collision Flag. The WCOL bit is set if the SPI data register is written during a data transfer. During data transfer, the result of reading the SPDR register may be incorrect, and writing to it has no effect. The WCOL bit (and the SPIF bit) are cleared by reading the SPI status register with SPIF and WCOL set, and then accessing the SPI data register.

**Table 6. SPDR – SPI Data Register**

SPDR Address = 86H				Reset Value = unchanged				
	SPD7	SPD6	SPD5	SPD4	SPD3	SPD2	SPD1	SPD0
Bit	7	6	5	4	3	2	1	0

## Data Memory – EEPROM and RAM

The AT89S8252 implements 2K bytes of on-chip EEPROM for data storage and 256 bytes of RAM. The upper 128 bytes of RAM occupy a parallel space to the Special Function Registers. That means the upper 128 bytes have the same addresses as the SFR space but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the address mode used in the instruction specifies whether the CPU accesses the upper 128 bytes of RAM or the SFR space. Instructions that use direct addressing access SFR space.

For example, the following direct addressing instruction accesses the SFR at location 0A0H (which is P2).

```
MOV 0A0H, #data
```

Instructions that use indirect addressing access the upper 128 bytes of RAM. For example, the following indirect addressing instruction, where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

```
MOV @R0, #data
```

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

The on-chip EEPROM data memory is selected by setting the EEMEN bit in the WMCON register at SFR address location 96H. The EEPROM address range is from 000H to 7FFH. The MOVX instructions are used to access the EEPROM. To access off-chip data memory with the MOVX instructions, the EEMEN bit needs to be set to "0".

The EEMWE bit in the WMCON register needs to be set to "1" before any byte location in the EEPROM can be written. User software should reset EEMWE bit to "0" if no further EEPROM write is required. EEPROM write cycles in the serial programming mode are self-timed and typically take 2.5 ms. The progress of EEPROM write can be monitored by reading the RDY/BSY bit (read-only) in SFR WMCON. RDY/BSY = 0 means

programming is still in progress and  $\overline{RDY/BSY} = 1$  means EEPROM write cycle is completed and another write cycle can be initiated.

In addition, during EEPROM programming, an attempted read from the EEPROM will fetch the byte being written with the MSB complemented. Once the write cycle is completed, true data are valid at all bit locations.

**Programmable Watchdog Timer**

The programmable Watchdog Timer (WDT) operates from an independent internal oscillator. The prescaler bits, PS0, PS1 and PS2 in SFR WMCON are used to set the period of the Watchdog Timer from 16 ms to 2048 ms. The available timer periods are shown in the following table and the actual timer periods (at  $V_{CC} = 5V$ ) are within  $\pm 30\%$  of the nominal.

The WDT is disabled by Power-on Reset and during Power-down. It is enabled by setting the WDTEN bit in SFR WMCON (address = 96H). The WDT is reset by setting the WDTRST bit in WMCON. When the WDT times out without being reset or disabled, an internal RST pulse is generated to reset the CPU.

**Table 7. Watchdog Timer Period Selection**

WDT Prescaler Bits			Period (nominal)
PS2	PS1	PS0	
0	0	0	16 ms
0	0	1	32 ms
0	1	0	64 ms
0	1	1	128 ms
1	0	0	256 ms
1	0	1	512 ms
1	1	0	1024 ms
1	1	1	2048 ms

**Timer 0 and 1**

Timer 0 and Timer 1 in the AT89S8252 operate the same way as Timer 0 and Timer 1 in the AT89C51 and AT89C52. For further information on the timers' operation, refer to the Atmel web site (<http://www.atmel.com>). From the home page, select "Products", then "Microcontrollers, then "8051-Architecture". Click on "Documentation", then on "Other Documents". Open the document "AT89 Series Hardware Description".

**Timer 2**

Timer 2 is a 16-bit Timer/Counter that can operate as either a timer or an event counter. The type of operation is selected by bit  $C/\overline{T2}$  in the SFR T2CON (shown in Table 2). Timer 2 has three operating modes: capture, auto-reload (up or down counting), and baud rate generator. The modes are selected by bits in T2CON, as shown in Table 8.

Timer 2 consists of two 8-bit registers, TH2 and TL2. In the Timer function, the TL2 register is incremented every machine cycle. Since a machine cycle consists of 12 oscillator periods, the count rate is 1/12 of the oscillator frequency.

In the Counter function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T2. In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. The new count value appears in the register during S3P1 of the cycle following the one in which the transition was detected.





Since two machine cycles (24 oscillator periods) are required to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. To ensure that a given level is sampled at least once before it changes, the level should be held for at least one full machine cycle.

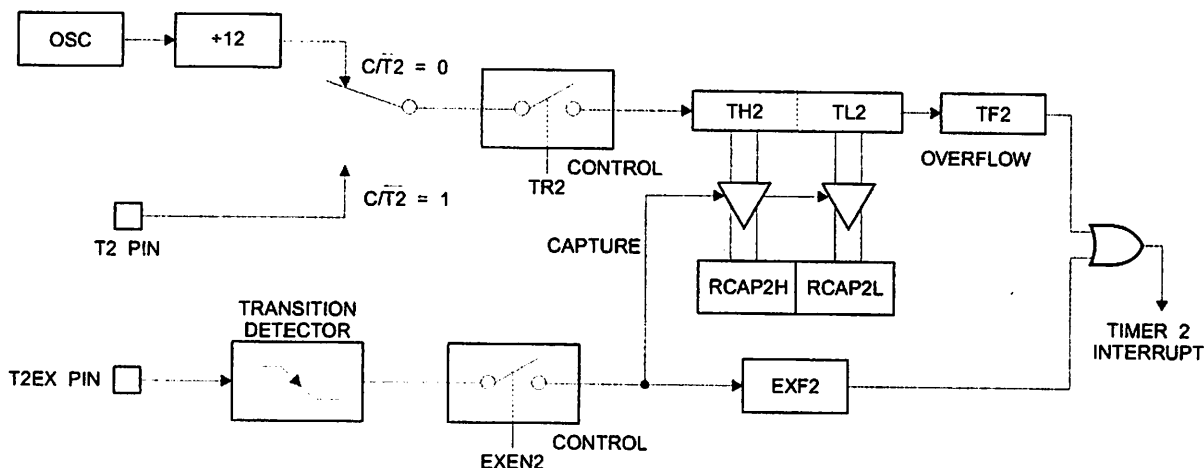
**Table 8. Timer 2 Operating Modes**

RCLK + TCLK	CP/ $\overline{RL2}$	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud Rate Generator
X	X	0	(Off)

### Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16-bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 1.

**Figure 1. Timer 2 in Capture Mode**



**Auto-reload (Up or Down Counter)**

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 9). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

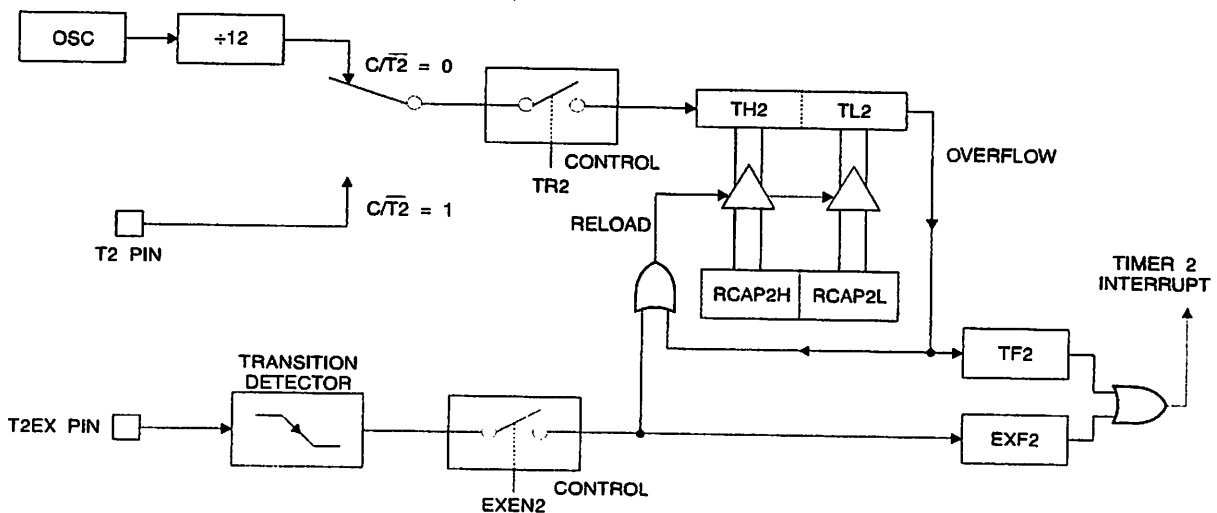
Figure 2 shows Timer 2 automatically counting up when DCEN = 0. In this mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 counts up to 0FFFFH and then sets the TF2 bit upon overflow. The overflow also causes the timer registers to be reloaded with the 16-bit value in RCAP2H and RCAP2L. The values in RCAP2H and RCAP2L are preset by software. If EXEN2 = 1, a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at external input T2EX. This transition also sets the EXF2 bit. Both the TF2 and EXF2 bits can generate an interrupt if enabled.

Setting the DCEN bit enables Timer 2 to count up or down, as shown in Figure 3. In this mode, the T2EX pin controls the direction of the count. A logic 1 at T2EX makes Timer 2 count up. The timer will overflow at 0FFFFH and set the TF2 bit. This overflow also causes the 16-bit value in RCAP2H and RCAP2L to be reloaded into the timer registers, TH2 and TL2, respectively.

A logic 0 at T2EX makes Timer 2 count down. The timer underflows when TH2 and TL2 equal the values stored in RCAP2H and RCAP2L. The underflow sets the TF2 bit and causes 0FFFFH to be reloaded into the timer registers.

The EXF2 bit toggles whenever Timer 2 overflows or underflows and can be used as a 17th bit of resolution. In this operating mode, EXF2 does not flag an interrupt.

**Figure 2. Timer 2 in Auto Reload Mode (DCEN = 0)**





**Table 9. T2MOD – Timer 2 Mode Control Register**

T2MOD Address = 0C9H						Reset Value = XXXX XX00B		
Not Bit Addressable								
Bit	7	6	5	4	3	2	1	0
	-	-	-	-	-	-	T2OE	DCEN

Symbol	Function
-	Not implemented, reserved for future use.
T2OE	Timer 2 Output Enable bit.
DCEN	When set, this bit allows Timer 2 to be configured as an up/down counter.

**Figure 3. Timer 2 Auto Reload Mode (DCEN = 1)**

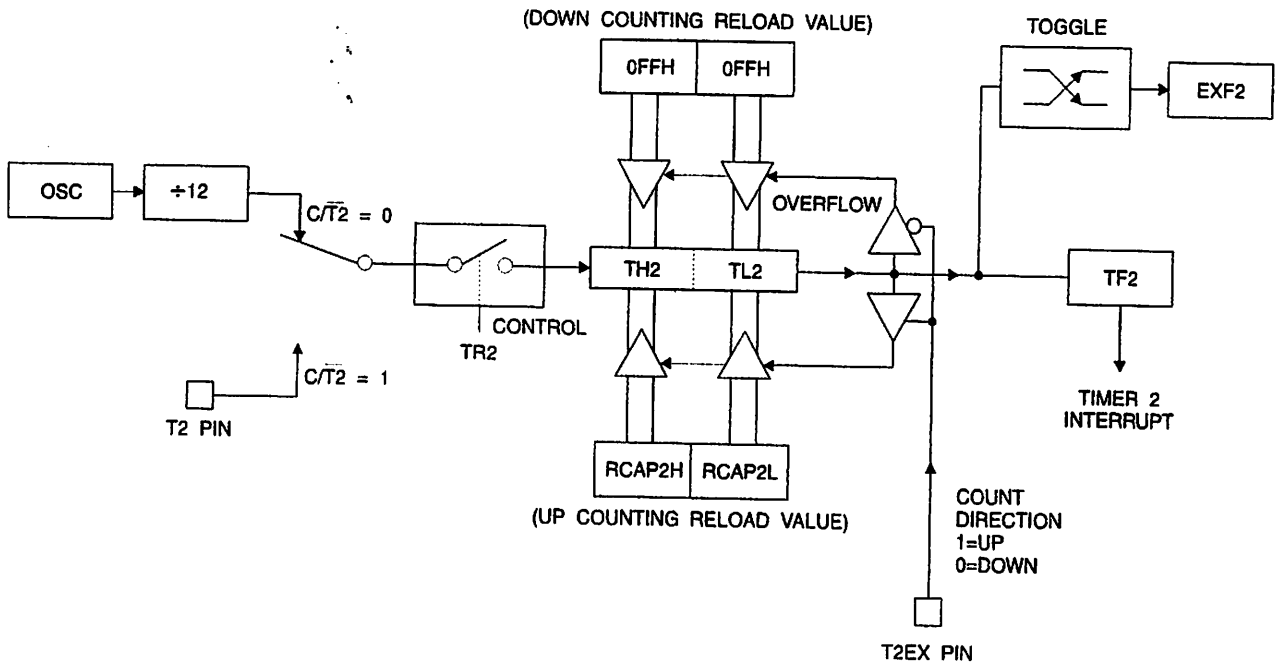
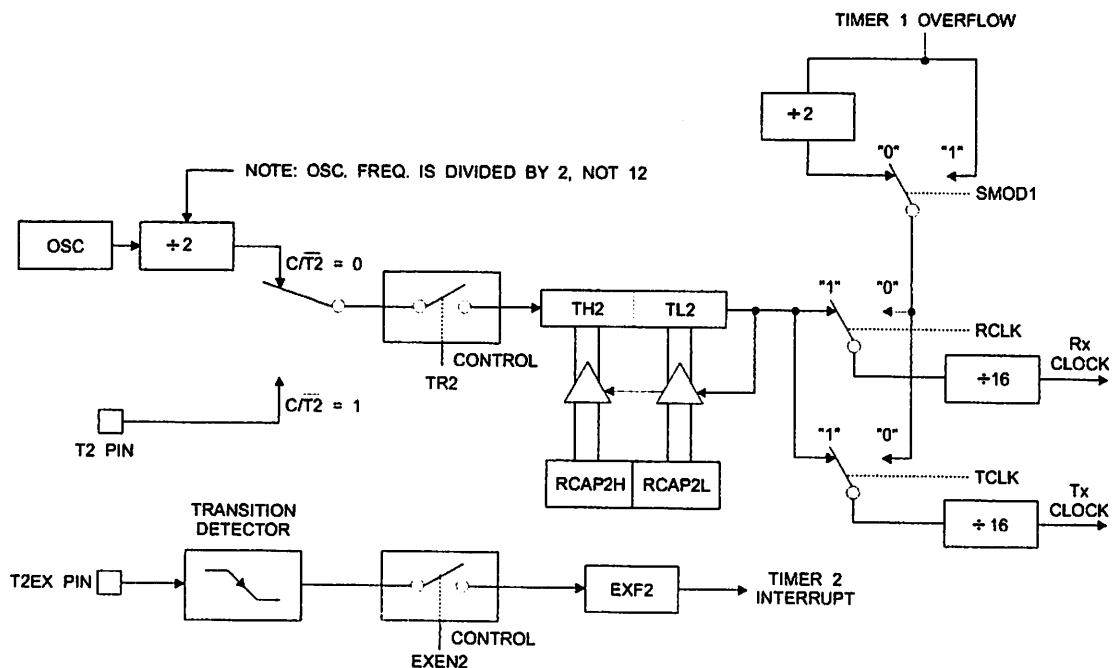


Figure 4. Timer 2 in Baud Rate Generator Mode



**Baud Rate Generator**

Timer 2 is selected as the baud rate generator by setting TCLK and/or RCLK in T2CON (Table 2). Note that the baud rates for transmit and receive can be different if Timer 2 is used for the receiver or transmitter and Timer 1 is used for the other function. Setting RCLK and/or TCLK puts Timer 2 into its baud rate generator mode, as shown in Figure 4.

The baud rate generator mode is similar to the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in Modes 1 and 3 are determined by Timer 2's overflow rate according to the following equation.

$$\text{Modes 1 and 3 Baud Rates} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

The Timer can be configured for either timer or counter operation. In most applications, it is configured for timer operation ( $CP/\overline{T2} = 0$ ). The timer operation is different for Timer 2 when it is used as a baud rate generator. Normally, as a timer, it increments every machine cycle (at 1/12 the oscillator frequency). As a baud rate generator, however, it increments every state time (at 1/2 the oscillator frequency). The baud rate formula is given below.

$$\frac{\text{Modes 1 and 3}}{\text{Baud Rate}} = \frac{\text{Oscillator Frequency}}{32 \times [65536 - (\text{RCAP2H}, \text{RCAP2L})]}$$

where (RCAP2H, RCAP2L) is the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.





Timer 2 as a baud rate generator is shown in Figure 4. This figure is valid only if RCLK or TCLK = 1 in T2CON. Note that a rollover in TH2 does not set TF2 and will not generate an interrupt. Note too, that if EXEN2 is set, a 1-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt.

Note that when Timer 2 is running (TR2 = 1) as a timer in the baud rate generator mode, TH2 or TL2 should not be read from or written to. Under these conditions, the Timer is incremented every state time, and the results of a read or write may not be accurate. The RCAP2 registers may be read but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.

## Programmable Clock Out

A 50% duty cycle clock can be programmed to come out on P1.0, as shown in Figure 5. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed to input the external clock for Timer/Counter 2 or to output a 50% duty cycle clock ranging from 61 Hz to 4 MHz (for a 16-MHz operating frequency).

To configure the Timer/Counter 2 as a clock generator, bit C/T<sub>2</sub> (T2CON.1) must be cleared and bit T2OE (T2MOD.1) must be set. Bit TR2 (T2CON.2) starts and stops the timer.

The clock-out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L), as shown in the following equation.

$$\text{Clock Out Frequency} = \frac{\text{Oscillator Frequency}}{4 \times [65536 - (\text{RCAP2H}, \text{RCAP2L})]}$$

In the clock-out mode, Timer 2 rollovers will not generate an interrupt. This behavior is similar to when Timer 2 is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and clock-out frequencies cannot be determined independently from one another since they both use RCAP2H and RCAP2L.





## UART

The UART in the AT89S8252 operates the same way as the UART in the AT89C51 and AT89C52. For further information on the UART operation, refer to the Atmel web site (<http://www.atmel.com>). From the home page, select "Products", then "Microcontrollers", then "8051-Architecture". Click on "Documentation", then on "Other Documents". Open the document "AT89 Series Hardware Description".

## Serial Peripheral Interface

The serial peripheral interface (SPI) allows high-speed synchronous data transfer between the AT89S8252 and peripheral devices or between several AT89S8252 devices. The AT89S8252 SPI features include the following:

- Full-Duplex, 3-Wire Synchronous Data Transfer
- Master or Slave Operation
- 1.5 MHz Bit Frequency (max.)
- LSB First or MSB First Data Transfer
- Four Programmable Bit Rates
- End of Transmission Interrupt Flag
- Write Collision Flag Protection
- Wakeup from Idle Mode (Slave Mode Only)

The interconnection between master and slave CPUs with SPI is shown in the following figure. The SCK pin is the clock output in the master mode but is the clock input in the slave mode. Writing to the SPI data register of the master CPU starts the SPI clock generator, and the data written shifts out of the MOSI pin and into the MOSI pin of the slave CPU. After shifting one byte, the SPI clock generator stops, setting the end of transmission flag (SPIF). If both the SPI interrupt enable bit (SPIE) and the serial port interrupt enable bit (ES) are set, an interrupt is requested.

The Slave Select input,  $\overline{SS}/P1.4$ , is set low to select an individual SPI device as a slave. When  $\overline{SS}/P1.4$  is set high, the SPI port is deactivated and the MOSI/P1.5 pin can be used as an input.

There are four combinations of SCK phase and polarity with respect to serial data, which are determined by control bits CPHA and CPOL. The SPI data transfer formats are shown in Figure 8 and Figure 9.

Figure 7. SPI Master-slave Interconnection

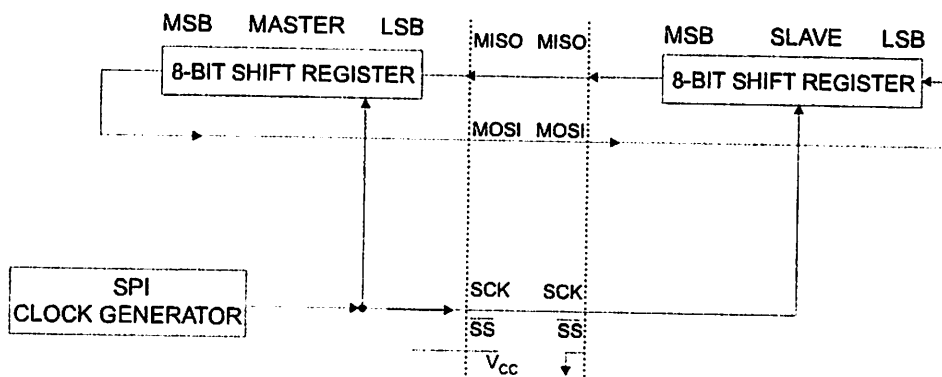
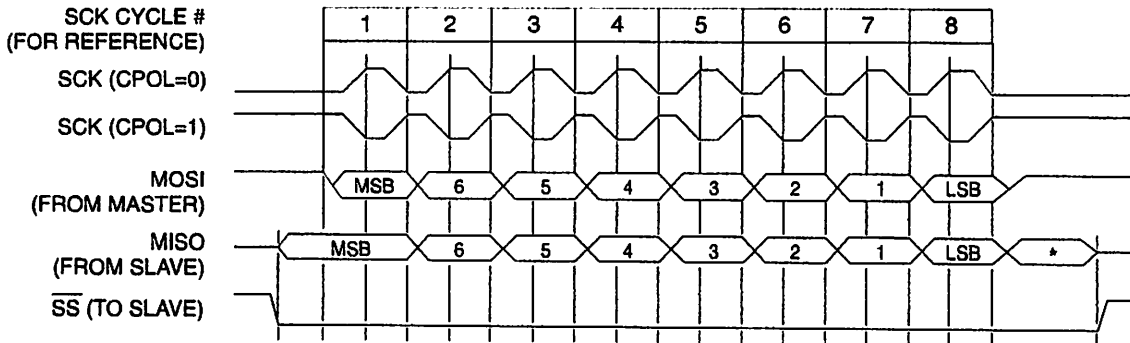
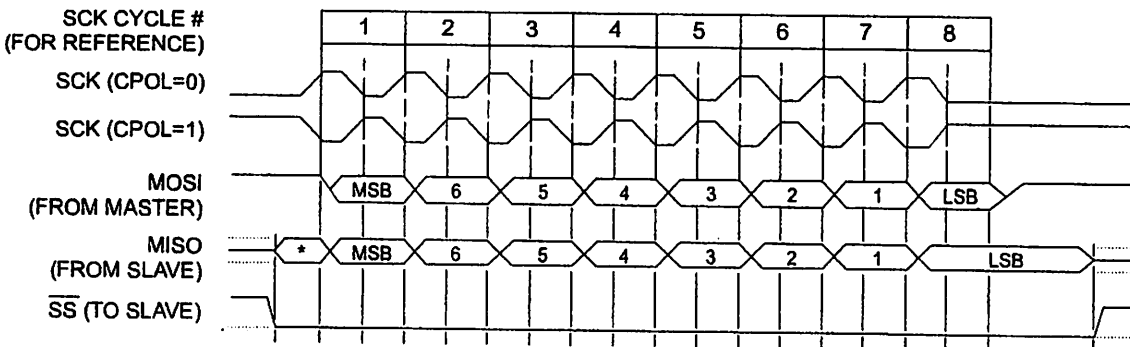


Figure 8. SPI transfer Format with CPHA = 0



Note: \*Not defined but normally MSB of character just received

Figure 9. SPI Transfer Format with CPHA = 1



Note: \*Not defined but normally LSB of previously transmitted character.

## Interrupts

The AT89S8252 has a total of six interrupt vectors: two external interrupts ( $\overline{INT0}$  and  $\overline{INT1}$ ), three timer interrupts (Timers 0, 1, and 2), and the serial port interrupt. These interrupts are all shown in Figure 10.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 10 shows that bit position IE.6 is unimplemented. In the AT89C51, bit position IE.5 is also unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

Timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register T2CON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and that bit will have to be cleared in software.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle. However, the Timer 2 flag, TF2, is set at S2P2 and is polled in the same cycle in which the timer overflows.

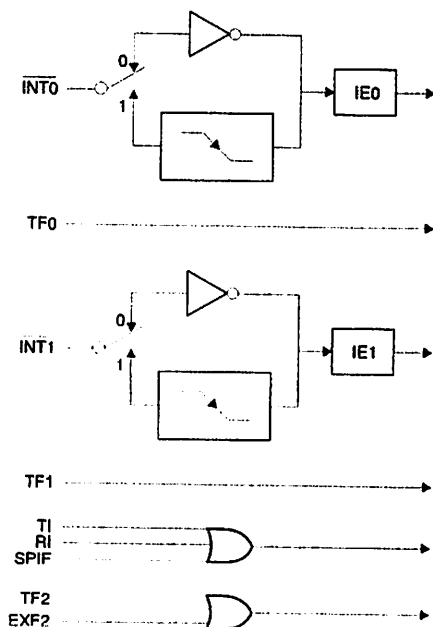




**Table 10. Interrupt Enable (IE) Register**

(MSB)(LSB)							
EA	-	ET2	ES	ET1	EX1	ET0	EX0
Enable Bit = 1 enables the interrupt.							
Enable Bit = 0 disables the interrupt.							
Symbol	Position	Function					
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.					
-	IE.6	Reserved.					
ET2	IE.5	Timer 2 interrupt enable bit.					
ES	IE.4	SPI and UART interrupt enable bit.					
ET1	IE.3	Timer 1 interrupt enable bit.					
EX1	IE.2	External interrupt 1 enable bit.					
ET0	IE.1	Timer 0 interrupt enable bit.					
EX0	IE.0	External interrupt 0 enable bit.					
User software should never write 1s to unimplemented bits, because they may be used in future AT89 products.							

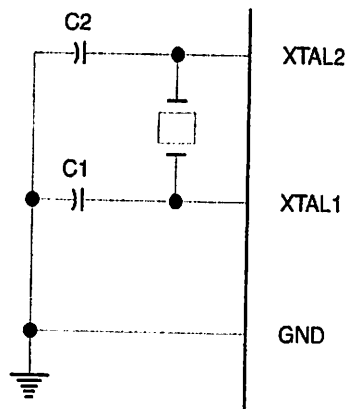
**Figure 10. Interrupt Sources**



## Oscillator Characteristics

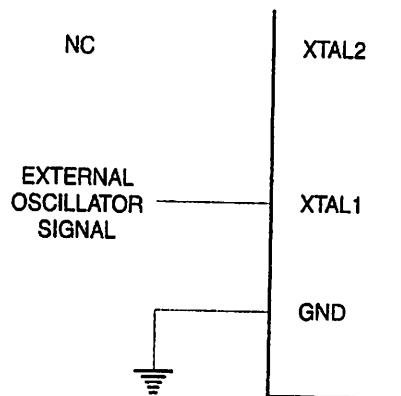
XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 11. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 12. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Figure 11. Oscillator Connections



Note: C1, C2 = 30 pF ± 10 pF for Crystals  
 = 40 pF ± 10 pF for Ceramic Resonators

Figure 12. External Clock Drive Configuration





## Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

### Status of External Pins During Idle and Power-down Modes

Mode	Program Memory	ALE	$\overline{\text{PSEN}}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

## Power-down Mode

In the power-down mode, the oscillator is stopped and the instruction that invokes power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the power-down mode is terminated. Exit from power-down can be initiated either by a hardware reset or by an enabled external interrupt. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before  $V_{CC}$  is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

To exit power-down via an interrupt, the external interrupt must be enabled as level sensitive before entering power-down. The interrupt service routine starts at 16 ms (nominal) after the enabled interrupt pin is activated.

## Program Memory Lock Bits

The AT89S8252 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the following table.

When lock bit 1 is programmed, the logic level at the  $\overline{\text{EA}}$  pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of  $\overline{\text{EA}}$  must agree with the current logic level at that pin in order for the device to function properly.

Once programmed, the lock bits can only be unprogrammed with the Chip Erase operations in either the parallel or serial modes.

## Lock Bit Protection Modes<sup>(1)(2)</sup>

	Program Lock Bits			Protection Type
	LB1	LB2	LB3	
1	U	U	U	No internal memory lock feature.
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory. $\overline{\text{EA}}$ is sampled and latched on reset and further programming of the Flash memory (parallel or serial mode) is disabled.
3	P	P	U	Same as Mode 2, but parallel or serial verify are also disabled.
4	P	P	P	Same as Mode 3, but external execution is also disabled.

Notes: 1. U = Unprogrammed  
2. P = Programmed

## Programming the Flash and EEPROM

Atmel's AT89S8252 Flash Microcontroller offers 8K bytes of in-system reprogrammable Flash Code memory and 2K bytes of EEPROM Data memory.

The AT89S8252 is normally shipped with the on-chip Flash Code and EEPROM Data memory arrays in the erased state (i.e. contents = FFH) and ready to be programmed. This device supports a High-voltage (12-V  $V_{PP}$ ) Parallel programming mode and a Low-voltage (5-V  $V_{CC}$ ) Serial programming mode. The serial programming mode provides a convenient way to reprogram the AT89S8252 inside the user's system. The parallel programming mode is compatible with conventional third party Flash or EPROM programmers.

The Code and Data memory arrays are mapped via separate address spaces in the serial programming mode. In the parallel programming mode, the two arrays occupy one contiguous address space: 0000H to 1FFFH for the Code array and 2000H to 27FFH for the Data array.

The Code and Data memory arrays on the AT89S8252 are programmed byte-by-byte in either programming mode. An auto-erase cycle is provided with the self-timed programming operation in the serial programming mode. There is no need to perform the Chip Erase operation to reprogram any memory location in the serial programming mode unless any of the lock bits have been programmed.

In the parallel programming mode, there is no auto-erase cycle. To reprogram any non-blank byte, the user needs to use the Chip Erase operation first to erase both arrays.

**Parallel Programming Algorithm:** To program and verify the AT89S8252 in the parallel programming mode, the following sequence is recommended:

1. Power-up sequence:
  - Apply power between  $V_{CC}$  and GND pins.
  - Set RST pin to "H".
  - Apply a 3 MHz to 24 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.
2. Set  $\overline{PSEN}$  pin to "L"
  - ALE pin to "H"
  - $\overline{EA}$  pin to "H" and all other pins to "H".
3. Apply the appropriate combination of "H" or "L" logic levels to pins P2.6, P2.7, P3.6, P3.7 to select one of the programming operations shown in the Flash Programming Modes table.
4. Apply the desired byte address to pins P1.0 to P1.7 and P2.0 to P2.5.
  - Apply data to pins P0.0 to P0.7 for Write Code operation.
5. Raise  $\overline{EA}/V_{PP}$  to 12V to enable Flash programming, erase or verification.
6. Pulse ALE/ $\overline{PROG}$  once to program a byte in the Code memory array, the Data memory array or the lock bits. The byte-write cycle is self-timed and typically takes 1.5 ms.
7. To verify the byte just programmed, bring pin P2.7 to "L" and read the programmed data at pins P0.0 to P0.7.
8. Repeat steps 3 through 7 changing the address and data for the entire 2K or 8K bytes array or until the end of the object file is reached.
9. Power-off sequence:
  - Set XTAL1 to "L".
  - Set RST and  $\overline{EA}$  pins to "L".
  - Turn  $V_{CC}$  power off.





In the parallel programming mode, there is no auto-erase cycle and to reprogram any non-blank byte, the user needs to use the Chip Erase operation first to erase both arrays.

**Data Polling:** The AT89S8252 features  $\overline{\text{DATA}}$  Polling to indicate the end of a byte write cycle. During a byte write cycle in the parallel or serial programming mode, an attempted read of the last byte written will result in the complement of the written datum on P0.7 (parallel mode), and on the MSB of the serial output byte on MISO (serial mode). Once the write cycle has been completed, true data are valid on all outputs, and the next cycle may begin.  $\overline{\text{DATA}}$  Polling may begin any time after a write cycle has been initiated.

**Ready/Busy:** The progress of byte programming in the parallel programming mode can also be monitored by the  $\text{RDY}/\overline{\text{BSY}}$  output signal. Pin P3.4 is pulled Low after ALE goes High during programming to indicate  $\overline{\text{BUSY}}$ . P3.4 is pulled High again when programming is done to indicate READY.

**Program Verify:** If lock bits LB1 and LB2 have not been programmed, the programmed Code or Data byte can be read back via the address and data lines for verification. The state of the lock bits can also be verified directly in the parallel programming mode. In the serial programming mode, the state of the lock bits can only be verified indirectly by observing that the lock bit features are enabled.

**Chip Erase:** Both Flash and EEPROM arrays are erased electrically at the same time. In the parallel programming mode, chip erase is initiated by using the proper combination of control signals and by holding  $\text{ALE}/\overline{\text{PROG}}$  low for 10 ms. The Code and Data arrays are written with all "1"s in the Chip Erase operation.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 16 ms.

During chip erase, a serial read from any address location will return 00H at the data outputs.

**Serial Programming Fuse:** A programmable fuse is available to disable Serial Programming if the user needs maximum system security. The Serial Programming Fuse can only be programmed or erased in the Parallel Programming Mode.

*The AT89S8252 is shipped with the Serial Programming Mode enabled.*

**Reading the Signature Bytes:** The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows:

(030H) = 1EH indicates manufactured by Atmel

(031H) = 72H indicates 89S8252

## Programming Interface

Every code byte in the Flash and EEPROM arrays can be written, and the entire array can be erased, by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most worldwide major programming vendors offer support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

## Serial Downloading

Both the Code and Data memory arrays can be programmed using the serial SPI bus while RST is pulled to  $V_{CC}$ . The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before program/erase operations can be executed.

An auto-erase cycle is built into the self-timed programming operation (in the serial mode ONLY) and there is no need to first execute the Chip Erase instruction unless any of the lock bits have been programmed. The Chip Erase operation turns the content of every memory location in both the Code and Data arrays into FFH.

The Code and Data memory arrays have separate address spaces:

0000H to 1FFFH for Code memory and 000H to 7FFH for Data memory.

Either an external system clock is supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/40 of the crystal frequency. With a 24 MHz oscillator clock, the maximum SCK frequency is 600 kHz.

## Serial Programming Algorithm

To program and verify the AT89S8252 in the serial programming mode, the following sequence is recommended:

1. Power-up sequence:
  - Apply power between VCC and GND pins.
  - Set RST pin to "H".
  - If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 24 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.
2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 40.
3. The Code or Data array is programmed one byte at a time by supplying the address and data together with the appropriate Write instruction. The selected memory location is first automatically erased before new data is written. The write cycle is self-timed and typically takes less than 2.5 ms at 5V.
4. Any memory location can be verified by using the Read instruction which returns the content at the selected address at serial output MISO/P1.6.
5. At the end of a programming session, RST can be set low to commence normal operation.
6. Power-off sequence (if needed):
  - Set XTAL1 to "L" (if a crystal is not used).
  - Set RST to "L".
  - Turn  $V_{CC}$  power off.





## Serial Programming Instruction

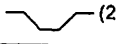

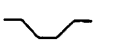
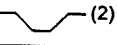
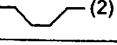
The Instruction Set for Serial Programming follows a 3-byte protocol and is shown in the following table:

### Instruction Set

Instruction	Input Format			Operation
	Byte 1	Byte 2	Byte 3	
Programming Enable	1010 1100	0101 0011	xxxx xxxx	Enable serial programming interface after RST goes high.
Chip Erase	1010 1100	xxxx x100	xxxx xxxx	Chip erase both 8K & 2K memory arrays.
Read Code Memory	aaaa a001	low addr	xxxx xxxx	Read data from Code memory array at the selected address. The 5 MSBs of the first byte are the high order address bits. The low order address bits are in the second byte. Data are available at pin MISO during the third byte.
Write Code Memory	aaaa a010	low addr	data in	Write data to Code memory location at selected address. The address bits are the 5 MSBs of the first byte together with the second byte.
Read Data Memory	00aa a101	low addr	xxxx xxxx	Read data from Data memory array at selected address. Data are available at pin MISO during the third byte.
Write Data Memory	00aa a110	low addr	data in	Write data to Data memory location at selected address.
Write Lock Bits	1010 1100	LB3 LB2 LB1 xxx x111	xxxx xxxx	Write lock bits. Set LB1, LB2 or LB3 = "0" to program lock bits.

- Notes:
1. DATA polling is used to indicate the end of a byte write cycle which typically takes less than 2.5 ms at 5V.
  2. "aaaaa" = high order address.
  3. "x" = don't care.

Flash and EEPROM Parallel Programming Modes

Mode	RST	PSEN	ALE/PROG	EA/V <sub>PP</sub>	P2.6	P2.7	P3.6	P3.7	Data I/O P0.7:0	Address P2.5:0 P1.7:0
Serial Prog. Modes	H	h <sup>(1)</sup>	h <sup>(1)</sup>	x						
Chip Erase	H	L	 (2)	12V	H	L	L	L	X	X
Write (10K bytes) Memory	H	L		12V	L	H	H	H	DIN	ADDR
Read (10K bytes) Memory	H	L	H	12V	L	L	H	H	DOUT	ADDR
Write Lock Bits:	H	L		12V	H	L	H	L	DIN	X
Bit - 1									P0.7 = 0	X
Bit - 2									P0.6 = 0	X
Bit - 3									P0.5 = 0	X
Read Lock Bits:	H	L	H	12V	H	H	L	L	DOUT	X
Bit - 1									@P0.2	X
Bit - 2									@P0.1	X
Bit - 3									@P0.0	X
Read Atmel Code	H	L	H	12V	L	L	L	L	DOUT	30H
Read Device Code	H	L	H	12V	L	L	L	L	DOUT	31H
Serial Prog. Enable	H	L	 (2)	12V	L	H	L	H	P0.0 = 0	X
Serial Prog. Disable	H	L	 (2)	12V	L	H	L	H	P0.0 = 1	X
Read Serial Prog. Fuse	H	L	H	12V	H	H	L	H	@P0.0	X

- Notes:
1. "h" = weakly pulled "High" internally.
  2. Chip Erase and Serial Programming Fuse require a 10 ms  $\overline{\text{PROG}}$  pulse. Chip Erase needs to be performed first before reprogramming any byte with a content other than FFH.
  3. P3.4 is pulled Low during programming to indicate  $\overline{\text{RDY/BSY}}$ .
  4. "X" = don't care

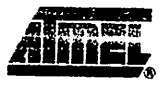




Figure 13. Programming the Flash/EEPROM Memory

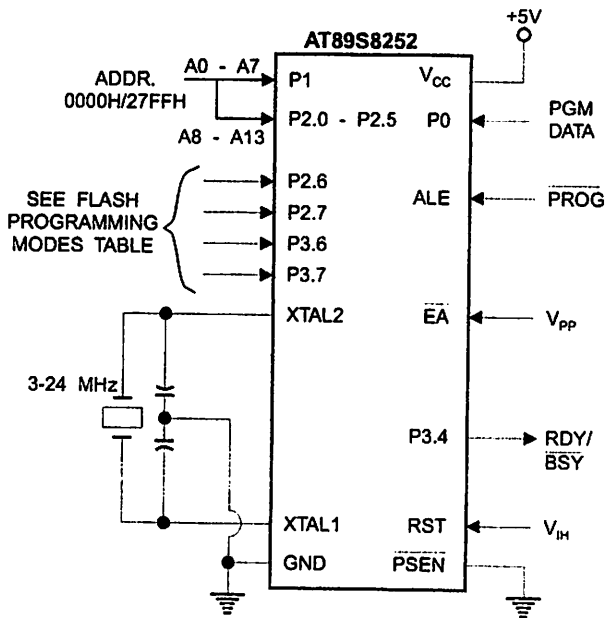


Figure 15. Flash/EEPROM Serial Downloading

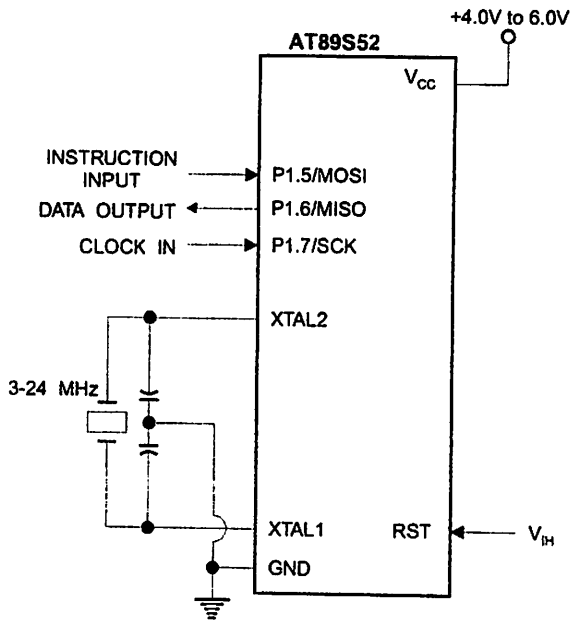
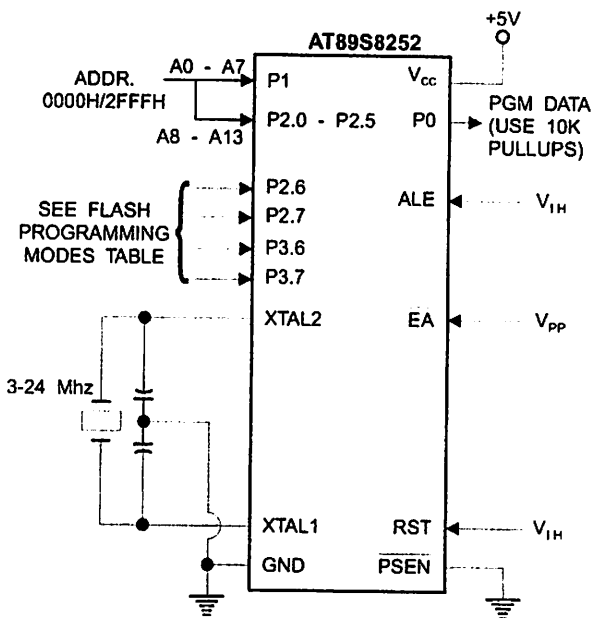


Figure 14. Verifying the Flash/EEPROM Memory

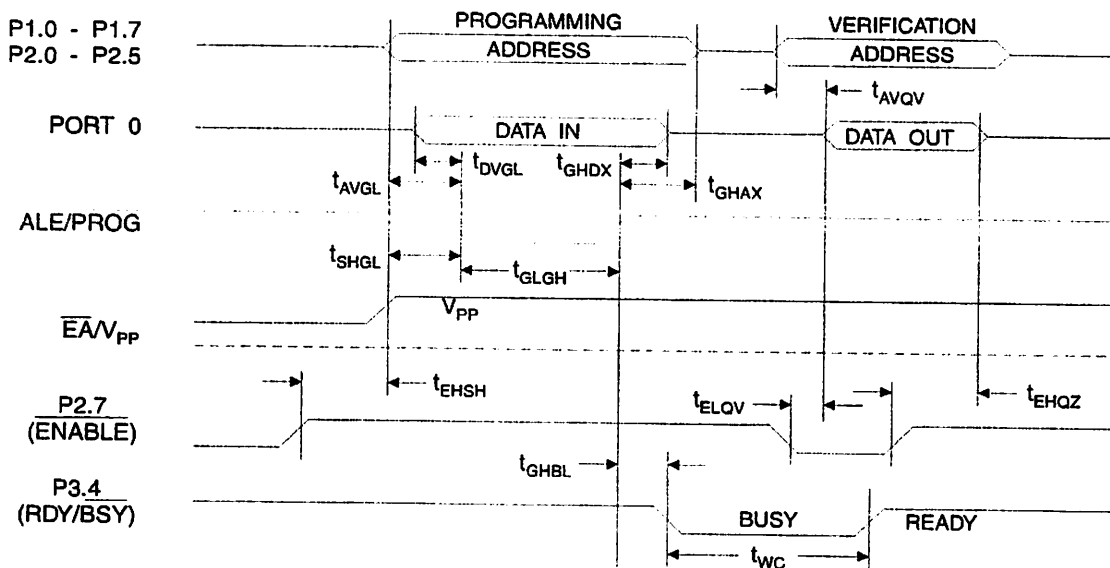


Flash Programming and Verification Characteristics – Parallel Mode

T<sub>A</sub> = 0°C to 70°C, V<sub>CC</sub> = 5.0V ± 10%

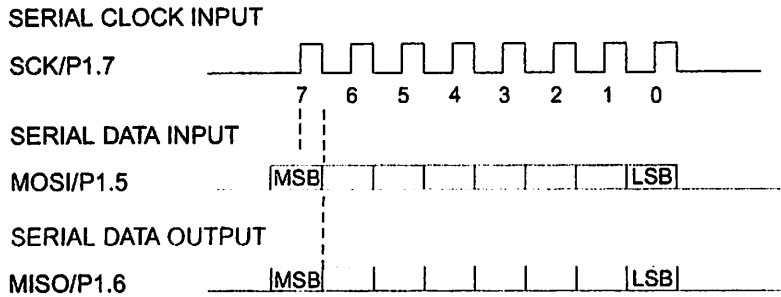
Symbol	Parameter	Min	Max	Units
V <sub>PP</sub>	Programming Enable Voltage	11.5	12.5	V
I <sub>PP</sub>	Programming Enable Current		1.0	mA
1/t <sub>CLCL</sub>	Oscillator Frequency	3	24	MHz
t <sub>AVGL</sub>	Address Setup to $\overline{\text{PROG}}$ Low	48t <sub>CLCL</sub>		
t <sub>GHAX</sub>	Address Hold after $\overline{\text{PROG}}$	48t <sub>CLCL</sub>		
t <sub>DVGL</sub>	Data Setup to $\overline{\text{PROG}}$ Low	48t <sub>CLCL</sub>		
t <sub>GHDX</sub>	Data Hold after $\overline{\text{PROG}}$	48t <sub>CLCL</sub>		
t <sub>ESH</sub>	P2.7 (ENABLE) High to V <sub>PP</sub>	48t <sub>CLCL</sub>		
t <sub>SHGL</sub>	V <sub>PP</sub> Setup to $\overline{\text{PROG}}$ Low	10		μs
t <sub>GLGH</sub>	$\overline{\text{PROG}}$ Width	1	110	μs
t <sub>AVQV</sub>	Address to Data Valid		48t <sub>CLCL</sub>	
t <sub>ELQV</sub>	ENABLE Low to Data Valid		48t <sub>CLCL</sub>	
t <sub>EHQZ</sub>	Data Float after $\overline{\text{ENABLE}}$	0	48t <sub>CLCL</sub>	
t <sub>GHBL</sub>	$\overline{\text{PROG}}$ High to $\overline{\text{BUSY}}$ Low		1.0	μs
t <sub>WC</sub>	Byte Write Cycle Time		2.0	ms

Flash/EEPROM Programming and Verification Waveforms – Parallel Mode





## Serial Downloading Waveforms



## Serial Programming Characteristics

Figure 16. Serial Programming Timing

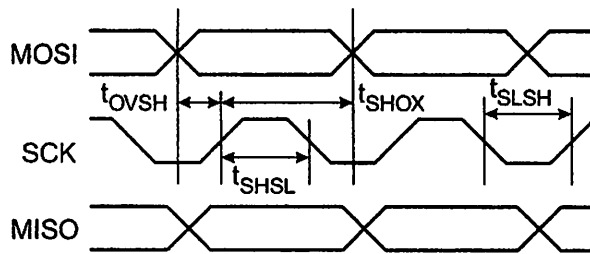


Table 11. Serial Programming Characteristics,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ ,  $V_{CC} = 4.0 - 6.0\text{V}$  (Unless Otherwise Noted)

Symbol	Parameter	Min	Typ	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0		24	MHz
$t_{CLCL}$	Oscillator Period	41.6			ns
$t_{SHSL}$	SCK Pulse Width High	$24 t_{CLCL}$			ns
$t_{SLSH}$	SCK Pulse Width Low	$24 t_{CLCL}$			ns
$t_{OVSH}$	MOSI Setup to SCK High	$t_{CLCL}$			ns
$t_{SHOX}$	MOSI Hold after SCK High	$2 t_{CLCL}$			ns

### Absolute Maximum Ratings\*

Operating Temperature.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
Voltage on Any Pin with Respect to Ground.....	-1.0V to +7.0V
Maximum Operating Voltage.....	6.6V
DC Output Current.....	15.0 mA

**\*NOTICE:** Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### DC Characteristics

The values shown in this table are valid for  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$  and  $V_{CC} = 5.0\text{V} \pm 20\%$ , unless otherwise noted.

Symbol	Parameter	Condition	Min	Max	Units	
$V_{IL}$	Input Low-voltage	(Except $\overline{EA}$ )	-0.5	$0.2 V_{CC} - 0.1$	V	
$V_{IL1}$	Input Low-voltage ( $\overline{EA}$ )		-0.5	$0.2 V_{CC} - 0.3$	V	
$V_{IH}$	Input High-voltage	(Except XTAL1, RST)	$0.2 V_{CC} + 0.9$	$V_{CC} + 0.5$	V	
$V_{IH1}$	Input High-voltage	(XTAL1, RST)	$0.7 V_{CC}$	$V_{CC} + 0.5$	V	
$V_{OL}$	Output Low-voltage <sup>(1)</sup> (Ports 1,2,3)	$I_{OL} = 1.6 \text{ mA}$		0.5	V	
$V_{OL1}$	Output Low-voltage <sup>(1)</sup> (Port 0, ALE, $\overline{PSEN}$ )	$I_{OL} = 3.2 \text{ mA}$		0.5	V	
$V_{OH}$	Output High-voltage (Ports 1,2,3, ALE, $\overline{PSEN}$ )	$I_{OH} = -60 \mu\text{A}, V_{CC} = 5\text{V} \pm 10\%$	2.4		V	
		$I_{OH} = -25 \mu\text{A}$	$0.75 V_{CC}$		V	
		$I_{OH} = -10 \mu\text{A}$	$0.9 V_{CC}$		V	
$V_{OH1}$	Output High-voltage (Port 0 in External Bus Mode)	$I_{OH} = -800 \mu\text{A}, V_{CC} = 5\text{V} \pm 10\%$	2.4		V	
		$I_{OH} = -300 \mu\text{A}$	$0.75 V_{CC}$		V	
		$I_{OH} = -80 \mu\text{A}$	$0.9 V_{CC}$		V	
$I_{IL}$	Logical 0 Input Current (Ports 1,2,3)	$V_{IN} = 0.45\text{V}$		-50	$\mu\text{A}$	
$I_{TL}$	Logical 1 to 0 Transition Current (Ports 1,2,3)	$V_{IN} = 2\text{V}, V_{CC} = 5\text{V} \pm 10\%$		-650	$\mu\text{A}$	
$I_{LI}$	Input Leakage Current (Port 0, $\overline{EA}$ )	$0.45 < V_{IN} < V_{CC}$		$\pm 10$	$\mu\text{A}$	
RRST	Reset Pull-down Resistor		50	300	$\text{K}\Omega$	
$C_{IO}$	Pin Capacitance	Test Freq. = 1 MHz, $T_A = 25^\circ\text{C}$		10	pF	
$I_{CC}$	Power Supply Current	Active Mode, 12 MHz		25	mA	
		Idle Mode, 12 MHz		6.5	mA	
	Power-down Mode <sup>(2)</sup>	$V_{CC} = 6\text{V}$			100	$\mu\text{A}$
		$V_{CC} = 3\text{V}$			40	$\mu\text{A}$

- Notes: 1. Under steady state (non-transient) conditions,  $I_{OL}$  must be externally limited as follows:  
 Maximum  $I_{OL}$  per port pin: 10 mA  
 Maximum  $I_{OL}$  per 8-bit port: Port 0: 26 mA; Ports 1, 2, 3: 15 mA  
 Maximum total  $I_{OL}$  for all output pins: 71 mA  
 If  $I_{OL}$  exceeds the test condition,  $V_{OL}$  may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum  $V_{CC}$  for Power-down is 2V





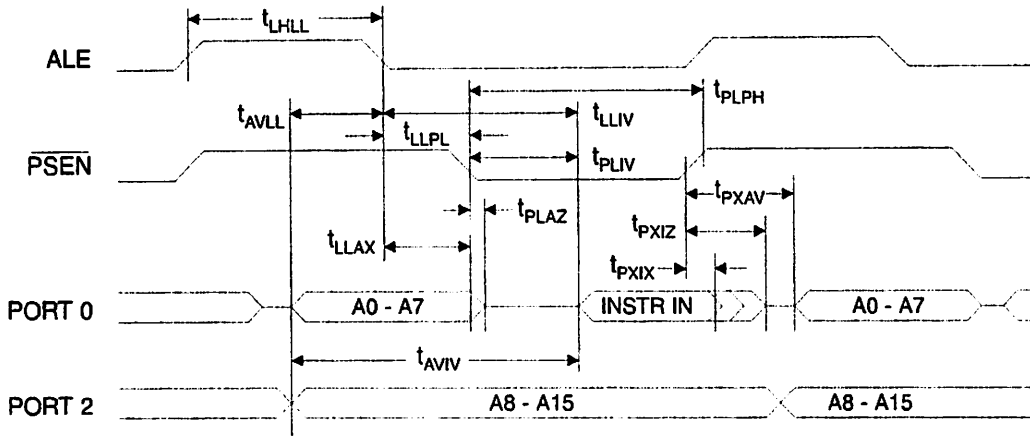
## AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/PROG, and PSEN = 100 pF; load capacitance for all other outputs = 80 pF.

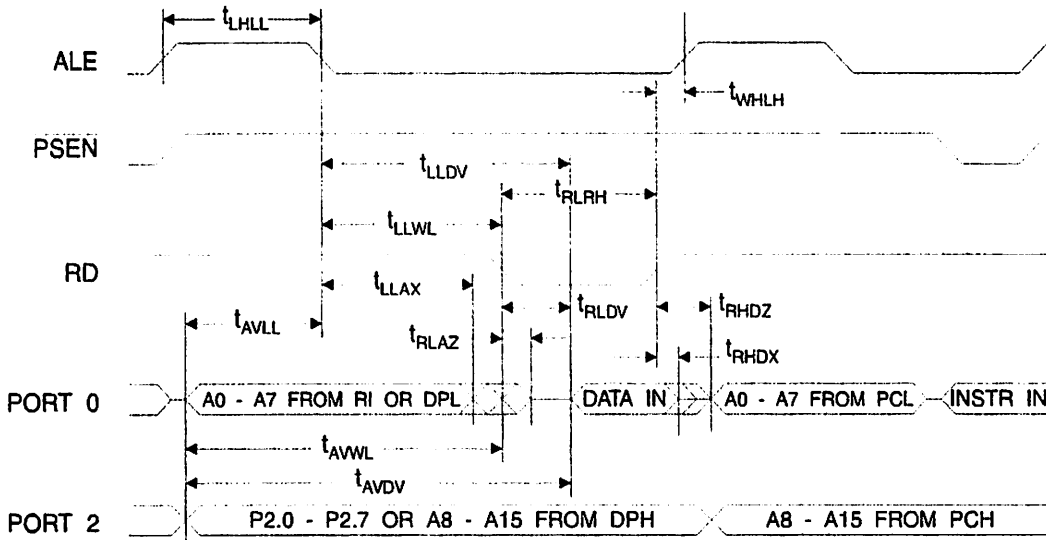
### External Program and Data Memory Characteristics

Symbol	Parameter	Variable Oscillator		Units
		Min	Max	
$1/t_{CLCL}$	Oscillator Frequency	0	24	MHz
$t_{LHLL}$	ALE Pulse Width	$2t_{CLCL} - 40$		ns
$t_{AVLL}$	Address Valid to ALE Low	$t_{CLCL} - 13$		ns
$t_{LLAX}$	Address Hold after ALE Low	$t_{CLCL} - 20$		ns
$t_{LLIV}$	ALE Low to Valid Instruction In		$4t_{CLCL} - 65$	ns
$t_{LLPL}$	ALE Low to PSEN Low	$t_{CLCL} - 13$		ns
$t_{PLPH}$	PSEN Pulse Width	$3t_{CLCL} - 20$		ns
$t_{PLIV}$	PSEN Low to Valid Instruction In		$3t_{CLCL} - 45$	ns
$t_{PXIX}$	Input Instruction Hold after PSEN	0		ns
$t_{PXIZ}$	Input Instruction Float after PSEN		$t_{CLCL} - 10$	ns
$t_{PXAV}$	PSEN to Address Valid	$t_{CLCL} - 8$		ns
$t_{AVIV}$	Address to Valid Instruction In		$5t_{CLCL} - 55$	ns
$t_{PLAZ}$	PSEN Low to Address Float		10	ns
$t_{RLRH}$	RD Pulse Width	$6t_{CLCL} - 100$		ns
$t_{WLWH}$	WR Pulse Width	$6t_{CLCL} - 100$		ns
$t_{RLDV}$	RD Low to Valid Data In		$5t_{CLCL} - 90$	ns
$t_{RHDX}$	Data Hold after RD	0		ns
$t_{RHDZ}$	Data Float after RD		$2t_{CLCL} - 28$	ns
$t_{LLDV}$	ALE Low to Valid Data In		$8t_{CLCL} - 150$	ns
$t_{AVDV}$	Address to Valid Data In		$9t_{CLCL} - 165$	ns
$t_{LLWL}$	ALE Low to RD or WR Low	$3t_{CLCL} - 50$	$3t_{CLCL} + 50$	ns
$t_{AVWL}$	Address to RD or WR Low	$4t_{CLCL} - 75$		ns
$t_{QVWX}$	Data Valid to WR Transition	$t_{CLCL} - 20$		ns
$t_{QVWH}$	Data Valid to WR High	$7t_{CLCL} - 120$		ns
$t_{WHQX}$	Data Hold after WR	$t_{CLCL} - 20$		ns
$t_{RLAZ}$	RD Low to Address Float		0	ns
$t_{WHLH}$	RD or WR High to ALE High	$t_{CLCL} - 20$	$t_{CLCL} + 25$	ns

External Program Memory Read Cycle

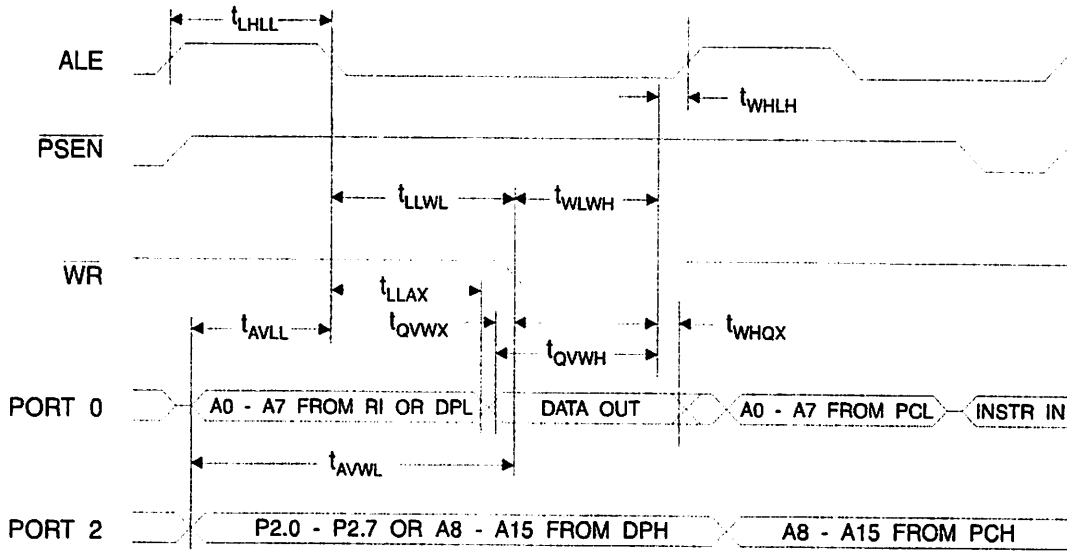


External Data Memory Read Cycle

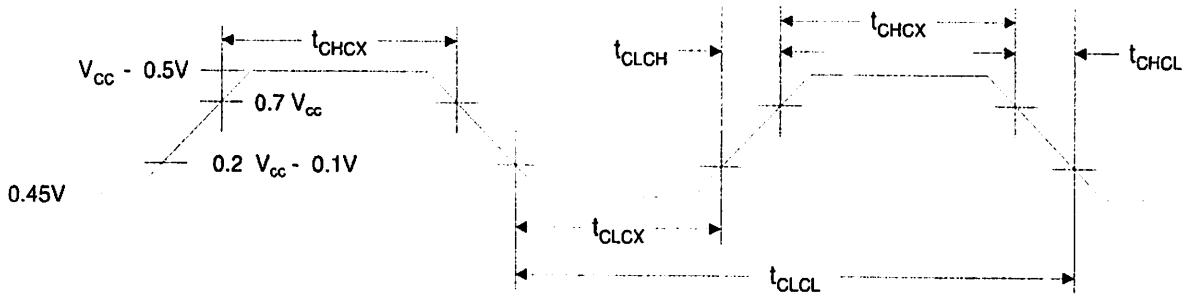




## External Data Memory Write Cycle



## External Clock Drive Waveforms



## External Clock Drive

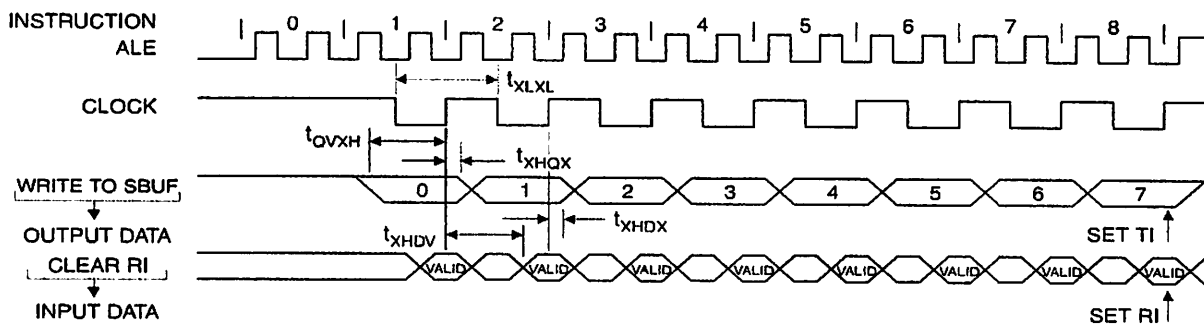
Symbol	Parameter	$V_{CC} = 4.0V \text{ to } 6.0V$		Units
		Min	Max	
$t_{CLCL}$	Oscillator Frequency	0	24	MHz
$t_{LCL}$	Clock Period	41.6		ns
$t_{HCX}$	High Time	15		ns
$t_{LCX}$	Low Time	15		ns
$t_{LCH}$	Rise Time		20	ns
$t_{HCL}$	Fall Time		20	ns

Serial Port Timing: Shift Register Mode Test Conditions

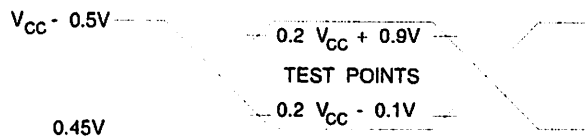
The values in this table are valid for  $V_{CC} = 4.0V$  to  $6V$  and Load Capacitance =  $80\text{ pF}$ .

Symbol	Parameter	Variable Oscillator		Units
		Min	Max	
$t_{CLCL}$	Serial Port Clock Cycle Time	$12t_{CLCL}$		$\mu\text{s}$
$t_{OVXH}$	Output Data Setup to Clock Rising Edge	$10t_{CLCL} - 133$		ns
$t_{HQX}$	Output Data Hold after Clock Rising Edge	$2t_{CLCL} - 117$		ns
$t_{HDX}$	Input Data Hold after Clock Rising Edge	0		ns
$t_{HDV}$	Clock Rising Edge to Input Data Valid		$10t_{CLCL} - 133$	ns

Shift Register Mode Timing Waveforms

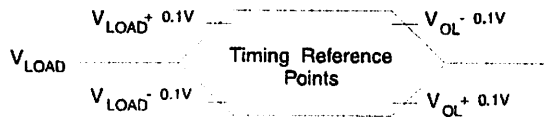


AC Testing Input/Output Waveforms<sup>(1)</sup>



1. AC Inputs during testing are driven at  $V_{CC} - 0.5V$  for a logic 1 and  $0.45V$  for a logic 0. Timing measurements are made at  $V_{IH}$  min. for a logic 1 and  $V_{IL}$  max. for a logic 0.

Load Waveforms<sup>(1)</sup>

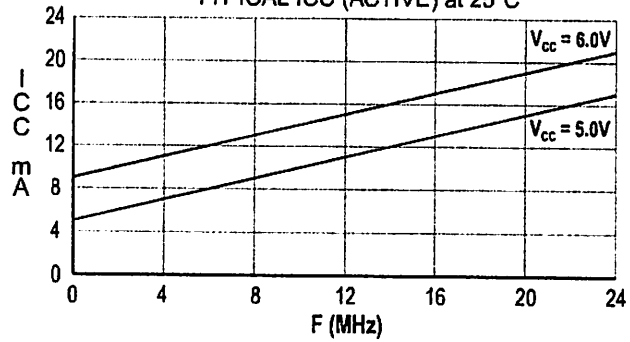


1. For timing purposes, a port pin is no longer floating when a  $100\text{ mV}$  change from load voltage occurs. A port pin begins to float when a  $100\text{ mV}$  change from the loaded  $V_{OH}/V_{OL}$  level occurs.



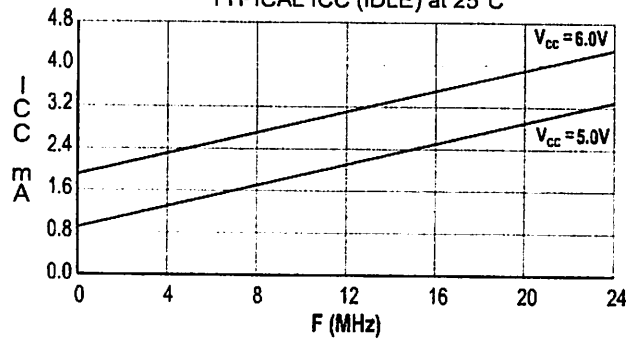
### AT89S8252

TYPICAL ICC (ACTIVE) at 25°C



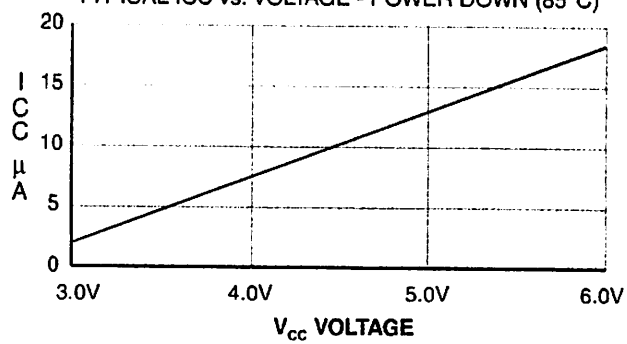
### AT89S8252

TYPICAL ICC (IDLE) at 25°C



### AT89S8252

TYPICAL ICC vs. VOLTAGE - POWER DOWN (85°C)



- Notes:
1. XTAL1 tied to GND for Icc (power-down)
  2. Lock bits programmed

## Ordering Information

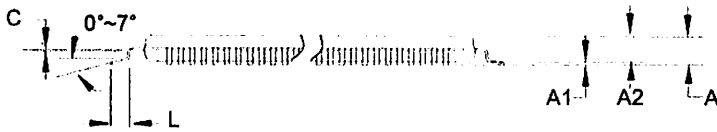
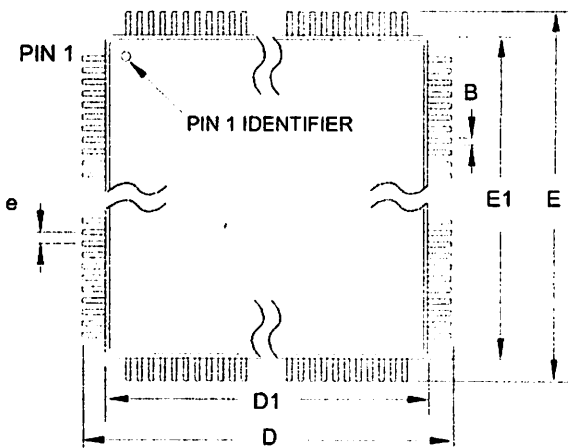
Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
24	4.0V to 6.0V	AT89S8252-24AC	44A	Commercial (0° C to 70° C)
		AT89S8252-24JC	44J	
		AT89S8252-24PC	40P6	
	4.0V to 6.0V	AT89S8252-24AI	44A	Industrial (-40° C to 85° C)
		AT89S8252-24JI	44J	
		AT89S8252-24PI	40P6	

Package Type	
A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
P6	40-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)



# Packaging Information

44A – TQFP



**COMMON DIMENSIONS**  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	1.20	
A1	0.05	-	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	-	0.45	
C	0.09	-	0.20	
L	0.45	-	0.75	
e	0.80 TYP			

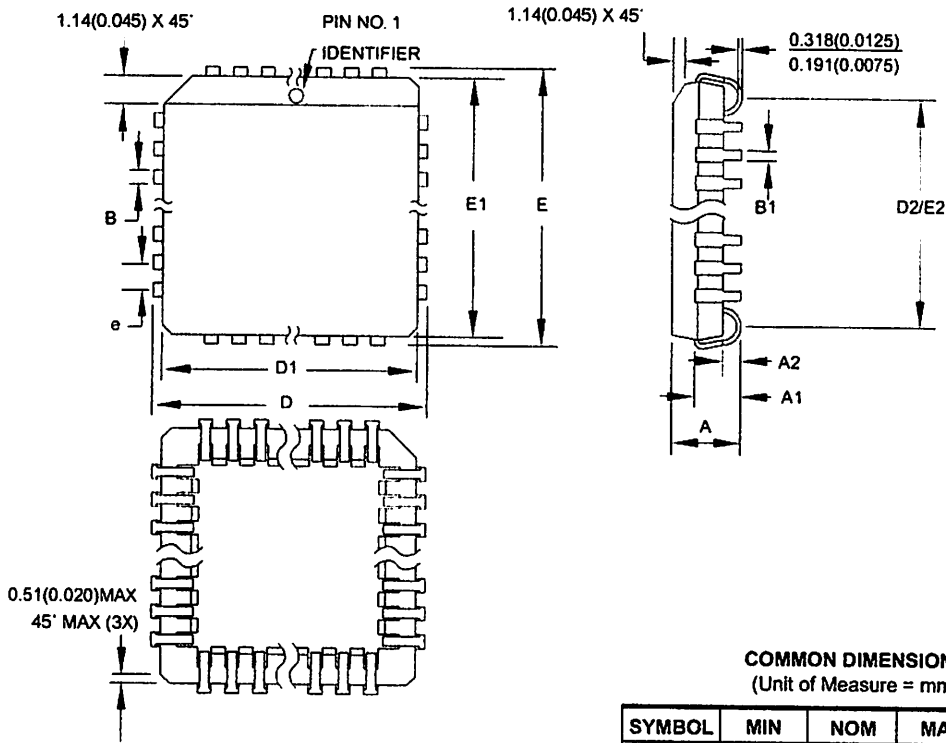
- Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
  2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
  3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

2325 Orchard Parkway San Jose, CA 95131	TITLE	DRAWING NO.	REV.
	44A, 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

**AT89S8252**

J - PLCC




COMMON DIMENSIONS  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	-	4.572	
A1	2.286	-	3.048	
A2	0.508	-	-	
D	17.399	-	17.653	
D1	16.510	-	16.662	Note 2
E	17.399	-	17.653	
E1	16.510	-	16.662	Note 2
D2/E2	14.986	-	16.002	
B	0.660	-	0.813	
B1	0.330	-	0.533	
e	1.270 TYP			

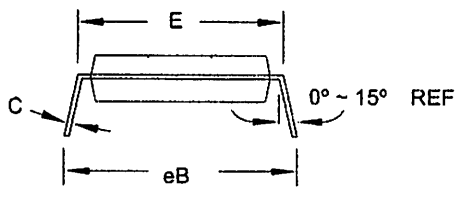
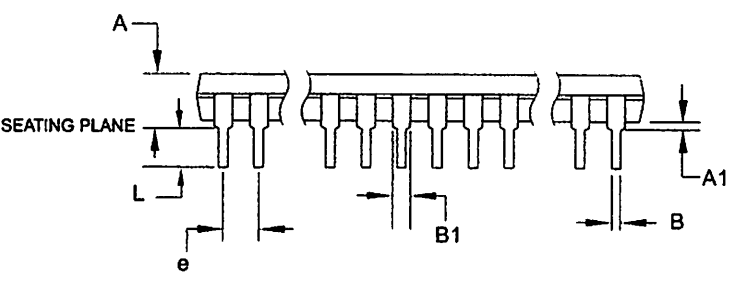
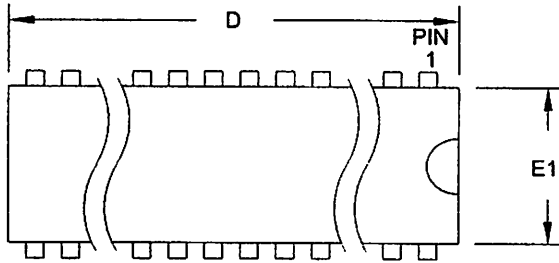
- Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
  2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010" (0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
  3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

 2325 Orchard Parkway San Jose, CA 95131	TITLE	DRAWING NO.	REV.
	44J, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B



P6 – PDIP



**COMMON DIMENSIONS**  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	4.826	
A1	0.381	-	-	
D	52.070	-	52.578	Note 2
E	15.240	-	15.875	
E1	13.462	-	13.970	Note 2
B	0.356	-	0.559	
B1	1.041	-	1.651	
L	3.048	-	3.556	
C	0.203	-	0.381	
eB	15.494	-	17.526	
e	2.540 TYP			

- Notes: 1. This package conforms to JEDEC reference MS-011, Variation AC.  
2. Dimensions D and E1 do not include mold Flash or Protrusion.  
Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

2325 Orchard Parkway San Jose, CA 95131	<b>TITLE</b> <b>40P6, 40-lead (0.600"/15.24 mm Wide) Plastic Dual In-line Package (PDIP)</b>	<b>DRAWING NO.</b>	<b>REV.</b>
		40P6	B



## Atmel Corporation

2325 Orchard Parkway  
San Jose, CA 95131, USA  
Tel: 1(408) 441-0311  
Fax: 1(408) 487-2600

## Regional Headquarters

### Europe

Atmel Sarl  
Route des Arsenalux 41  
Case Postale 80  
CH-1705 Fribourg  
Switzerland  
Tel: (41) 26-426-5555  
Fax: (41) 26-426-5500

### Asia

Room 1219  
Chinachem Golden Plaza  
77 Mody Road Tsimshatsui  
East Kowloon  
Hong Kong  
Tel: (852) 2721-9778  
Fax: (852) 2722-1369

### Japan

9F, Tonetsu Shinkawa Bldg.  
1-24-8 Shinkawa  
Chuo-ku, Tokyo 104-0033  
Japan  
Tel: (81) 3-3523-3551  
Fax: (81) 3-3523-7581

## Atmel Operations

### Memory

2325 Orchard Parkway  
San Jose, CA 95131, USA  
Tel: 1(408) 441-0311  
Fax: 1(408) 436-4314

### Microcontrollers

2325 Orchard Parkway  
San Jose, CA 95131, USA  
Tel: 1(408) 441-0311  
Fax: 1(408) 436-4314

La Chanterrie  
BP 70602  
44306 Nantes Cedex 3, France  
Tel: (33) 2-40-18-18-18  
Fax: (33) 2-40-18-19-60

### ASIC/ASSP/Smart Cards

Zone Industrielle  
13106 Rousset Cedex, France  
Tel: (33) 4-42-53-60-00  
Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd.  
Colorado Springs, CO 80906, USA  
Tel: 1(719) 576-3300  
Fax: 1(719) 540-1759

Scottish Enterprise Technology Park  
Maxwell Building  
East Kilbride G75 0QR, Scotland  
Tel: (44) 1355-803-000  
Fax: (44) 1355-242-743

### RF/Automotive

Theresienstrasse 2  
Postfach 3535  
74025 Heilbronn, Germany  
Tel: (49) 71-31-67-0  
Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd.  
Colorado Springs, CO 80906, USA  
Tel: 1(719) 576-3300  
Fax: 1(719) 540-1759

### Biometrics/Imaging/Hi-Rel MPU/ High Speed Converters/RF Datacom

Avenue de Rochepleine  
BP 123  
38521 Saint-Egreve Cedex, France  
Tel: (33) 4-76-58-30-00  
Fax: (33) 4-76-58-34-80

---

**Literature Requests**  
[www.atmel.com/literature](http://www.atmel.com/literature)

Disclaimer: Atmel Corporation makes no warranty for the use of its products, other than those expressly contained in the Company's standard warranty which is detailed in Atmel's Terms and Conditions located on the Company's web site. The Company assumes no responsibility for any errors which may appear in this document, reserves the right to change devices or specifications detailed herein at any time without notice, and does not make any commitment to update the information contained herein. No licenses to patents or other intellectual property of Atmel are granted by the Company in connection with the sale of Atmel products, expressly or by implication. Atmel's products are not authorized for use in critical components in life support devices or systems.

© Atmel Corporation 2003. All rights reserved. Atmel® and combinations thereof are the registered trademarks of Atmel Corporation or its subsidiaries. MCS® is a registered trademark of Intel Corporation. Other terms and product names may be the trademarks of others.



Printed on recycled paper.

0401F-MICRO-11/03

xM

## FEATURES

- Drop-in replacement for IBM AT computer clock/calendar
- Pin compatible with the MC146818B and DS1287
- Totally nonvolatile with over 10 years of operation in the absence of power
- Self-contained subsystem includes lithium, quartz, and support circuitry.
- Counts seconds, minutes, hours, days, day of the week, date, month, and year with leap year compensation valid up to 2100
- Binary or BCD representation of time, calendar, and alarm
- 12- or 24-hour clock with AM and PM in 12-hour mode
- Daylight Savings Time option
- Selectable between Motorola and Intel bus timing
- Multiplex bus for pin efficiency
- Interfaced with software as 128 RAM locations
  - 15 bytes of clock and control registers
  - 113 bytes of general purpose RAM
- Programmable square wave output signal
- Bus-compatible interrupt signals (IRQ)
- Three interrupts are separately software maskable and testable
  - Time-of-day alarm once/second to once/day
  - Periodic rates from 122 ms to 500 ms
  - End of clock update cycle
- Century register

## DESCRIPTION

The DS12C887 Real Time Clock plus RAM is designed as a direct upgrade replacement for the DS12887 in existing IBM compatible personal computers to add hardware year 2000 compliance. A century byte was added to memory location 50, 32h, as called out by the PC AT specification. A lithium energy source, quartz crystal, and write-protection circuitry are contained within a 24-pin dual in-line package. As such, the DS12C887 is a complete subsystem replacing 16 components in a typical application. The functions include a nonvolatile time-of-day clock, an alarm, a one-hundred-year calendar, programmable interrupt, square wave generator, and 113 bytes of nonvolatile static RAM. The real time clock is distinctive in that time-of-day and memory are maintained even in the absence of power.

## PIN ASSIGNMENT

MOT	1	24	V <sub>CC</sub>
NC	2	23	SQW
NC	3	22	NC
AD0	4	21	NC
AD1	5	20	NC
AD2	6	19	IRQ
AD3	7	18	RESET
AD4	8	17	DS
AD5	9	16	NC
AD6	10	15	R/W
AD7	11	14	AS
GND	12	13	CS

DS12C887 24-Pin  
ENCAPSULATED PACKAGE

## PIN DESCRIPTION

- AD0-AD7 - Multiplexed Address/Data Bus
- NC - No Connect
- MOT - Bus Type Selection
- CS - RTC Chip Select Input
- AS - Address Strobe
- R/W - Read/Write Input
- DS - Data Strobe
- RESET - Reset Input
- IRQ - Interrupt Request Output
- SQW - Square Wave Output
- V<sub>CC</sub> - +5 Volt Main Supply
- GND - Ground

## OPERATION

The block diagram in Figure 1 shows the pin connections with the major internal functions of the DS12C887. The following paragraphs describe the function of each pin.

## SIGNAL DESCRIPTIONS

**V<sub>CC</sub>, V<sub>DD</sub>** - DC power is provided to the device on these pins. V<sub>CC</sub> is the +5 volt input. When 5 volts are applied within normal limits, the device is fully accessible and data can be written and read. When V<sub>CC</sub> is below 4.25 volts typical, reads and writes are inhibited. However, the timekeeping function continues unaffected by the lower input voltage. As V<sub>CC</sub> falls below 3 volts typical, the RAM and timekeeper are switched over to an internal lithium energy source. The timekeeping function maintains an accuracy of  $\pm 1$  minute per month at 25°C regardless of the voltage input on the V<sub>CC</sub> pin.

**MOT (Mode Select)** – The MOT pin offers the flexibility to choose between two bus types. When connected to V<sub>CC</sub>, Motorola bus timing is selected. When connected to GND or left disconnected, Intel bus timing is selected. The pin has an internal pull-down resistance of approximately 20K $\Omega$ .

**SQW (Square Wave Output)** – The SQW pin can output a signal from one of 13 taps provided by the 5 internal divider stages of the Real Time Clock. The frequency of the SQW pin can be changed by programming Register A as shown in Table 1. The SQW signal can be turned on and off using the SQWEN bit in Register B. The SQW signal is not available when V<sub>CC</sub> is less than 4.25 volts typical.

**AD0-AD7 (Multiplexed Bidirectional Address/Data Bus)** – Multiplexed buses save pins because address information and data information time share the same signal paths. The addresses are present during the first portion of the bus cycle and the same pins and signal paths are used for data in the second portion of the cycle. Address/data multiplexing does not slow the access time of the DS12C887 since the bus change from address to data occurs during the internal RAM access time. Addresses must be valid prior to the falling edge of AS/ALE, at which time the DS12C887 latches the address from AD0 to AD6. Valid write data must be present and held stable during the latter portion of the DS or WR pulses. In a read cycle the DS12C887 outputs 8 bits of data during the latter portion of the DS or RD pulses. The read cycle is terminated and the bus returns to a high impedance state as DS transitions low in the case of Motorola timing or as RD transitions high in the case of Intel timing.

**AS (Address Strobe Input)** – A positive going address strobe pulse serves to demultiplex the bus. The falling edge of AS/ALE causes the address to be latched within the DS12C887. The next rising edge that occurs on the AS bus will clear the address regardless of whether  $\overline{CS}$  is asserted. Access commands could be sent in pairs.

**DS (Data Strobe or Read Input)** – The DS/RD pin has two modes of operation depending on the level of the MOT pin. When the MOT pin is connected to V<sub>CC</sub>, Motorola bus timing is selected. In this mode DS is a positive pulse during the latter portion of the bus cycle and is called Data Strobe. During read cycles, DS signifies the time that the DS12C887 is to drive the bidirectional bus. In write cycles the falling edge of DS causes the DS12C887 to latch the written data. When the MOT pin is connected to GND, Intel bus timing is selected. In this mode the DS pin is called Read(RD). RD identifies the time period when the DS12C887 drives the bus with read data. The RD signal is the same definition as the Output Enable (OE) signal on a typical memory.

**$\overline{R/\overline{W}}$  (Read/Write Input)** – The  $\overline{R/\overline{W}}$  pin also has two modes of operation. When the MOT pin is connected to  $V_{CC}$  for Motorola timing, R/W is at a level which indicates whether the current cycle is a read or write. A read cycle is indicated with a high level on R/W while DS is high. A write cycle is indicated when  $\overline{R/\overline{W}}$  is low during DS. When the MOT pin is connected to GND for Intel timing, the  $\overline{R/\overline{W}}$  signal is an active low signal called WR. In this mode the  $\overline{R/\overline{W}}$  pin has the same meaning as the Write Enable signal (WE) on generic RAMs.

**$\overline{CS}$  (Chip Select Input)** – The Chip Select signal must be asserted low for a bus cycle in the DS12C887 to be accessed.  $\overline{CS}$  must be kept in the active state during DS and AS for Motorola timing and during RD and WR for Intel timing. Bus cycles which take place without asserting  $\overline{CS}$  will latch addresses but no access will occur. When  $V_{CC}$  is below 4.25 volts, the DS12C887 internally inhibits access cycles by internally disabling the  $\overline{CS}$  input. This action protects both the real time clock data and RAM data during power outages.

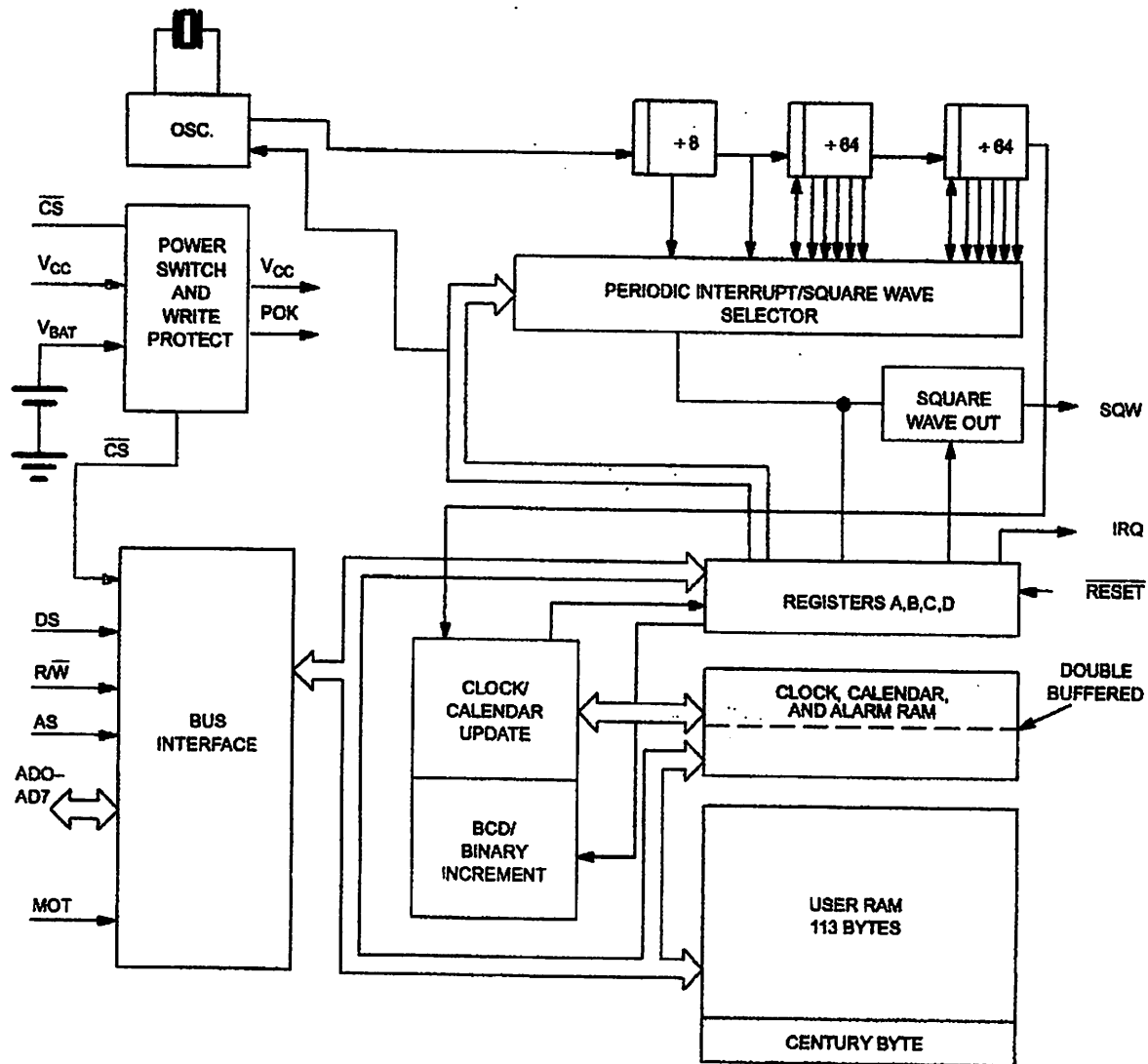
**$\overline{IRQ}$  (Interrupt Request Output)** - The  $\overline{IRQ}$  pin is an active low output of the DS12C887 that can be used as an interrupt input to a processor. The  $\overline{IRQ}$  output remains low as long as the status bit causing the interrupt is present and the corresponding interrupt-enable bit is set. To clear the  $\overline{IRQ}$  pin the processor program normally reads the C register. The RESET pin also clears pending interrupts. When no interrupt conditions are present, the  $\overline{IRQ}$  level is in the high impedance state. Multiple interrupting devices can be connected to an  $\overline{IRQ}$  bus. The  $\overline{IRQ}$  bus is an open drain output and requires an external pull-up resistor.

**$\overline{RESET}$  (Reset Input)** – The  $\overline{RESET}$  pin has no effect on the clock, calendar, or RAM. On power-up the  $\overline{RESET}$  pin can be held low for a time in order to allow the power supply to stabilize. The amount of time that  $\overline{RESET}$  is held low is dependent on the application. However, if  $\overline{RESET}$  is used on power-up, the time  $\overline{RESET}$  is low should exceed 200 ms to make sure that the internal timer that controls the DS12C887 on power-up has timed out. When  $\overline{RESET}$  is low and  $V_{CC}$  is above 4.25 volts, the following occurs:

- A. Periodic Interrupt Enable (PEI) bit is cleared to zero.
- B. Alarm Interrupt Enable (AIE) bit is cleared to zero.
- C. Update Ended Interrupt Flag (UF) bit is cleared to zero.
- D. Interrupt Request Status Flag (IRQF) bit is cleared to zero.
- E. Periodic Interrupt Flag (PF) bit is cleared to zero.
- F. The device is not accessible until  $\overline{RESET}$  is returned high.
- G. Alarm Interrupt Flag (AF) bit is cleared to zero.
- H.  $\overline{IRQ}$  pin is in the high impedance state.
- I. Square Wave Output Enable (SQWE) bit is cleared to zero.
- J. Update Ended Interrupt Enable (UIE) is cleared to zero.

In a typical application  $\overline{RESET}$  can be connected to  $V_{CC}$ . This connection will allow the DS12C887 to go in and out of power fail without affecting any of the control registers.

DS12C887 BLOCK DIAGRAM Figure 1



## POWER-DOWN/POWER-UP CONSIDERATIONS

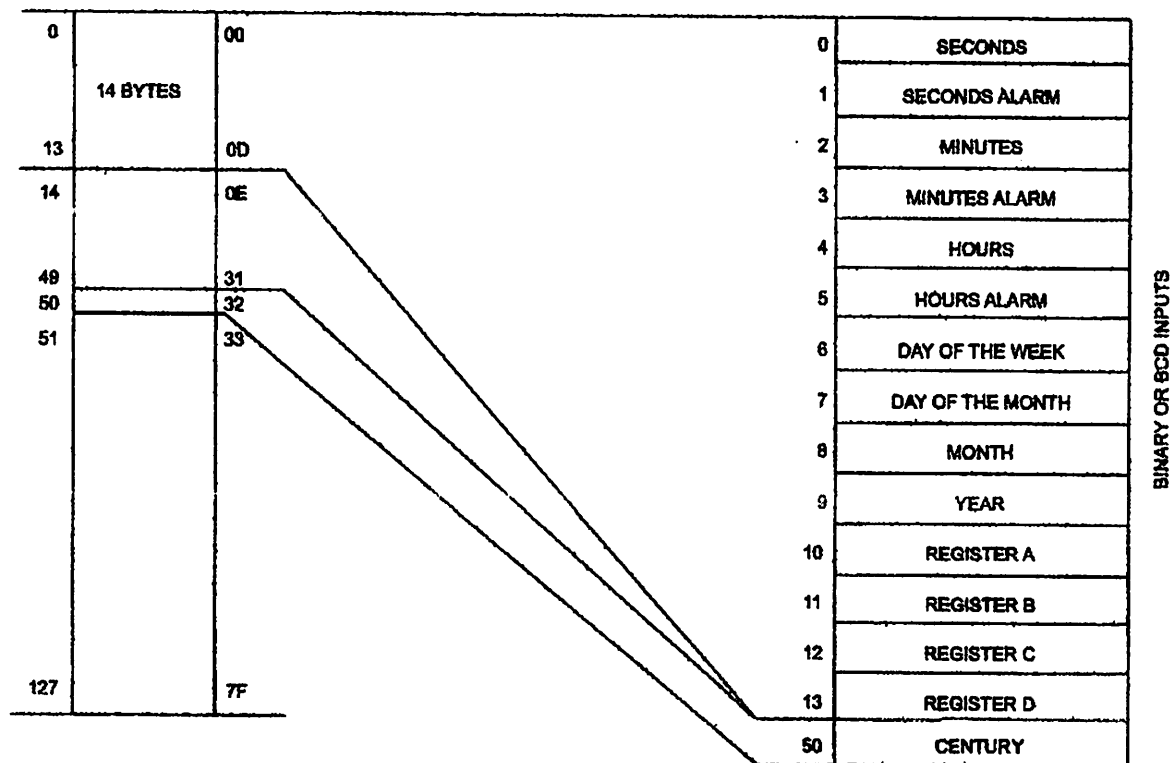
The Real Time Clock function will continue to operate and all of the RAM, time, calendar, and alarm memory locations remain nonvolatile regardless of the level of the  $V_{CC}$  input. When  $V_{CC}$  is applied to the DS12C887 and reaches a level of greater than 4.25 volts, the device becomes accessible after 200 ms, provided that the oscillator is running and the oscillator countdown chain is not in reset (see Register A). This time period allows the system to stabilize after power is applied. When  $V_{CC}$  falls below 4.25 volts, the chip select input is internally forced to an inactive level regardless of the value of  $\overline{CS}$  at the input pin. The DS12C887 is, therefore, write-protected. When the DS12C887 is in a write-protected state, all inputs are ignored and all outputs are in a high impedance state. When  $V_{CC}$  falls below a level of approximately 3 volts, the external  $V_{CC}$  supply is switched off and an internal lithium energy source supplies power to the Real Time Clock and the RAM memory.

## RTC ADDRESS MAP

The address map for the DS12C887 is shown in Figure 2. The address map consists of 113 bytes of user RAM, 11 bytes of RAM that contain the RTC time, calendar, and alarm data, and 4 bytes which are used for control and status. All 128 bytes can be directly written or read except for the following:

1. Registers C and D are read-only.
2. Bit-7 of Register A is read-only.
3. The high order bit of the seconds byte is read-only.

## DS12C887 REAL TIME CLOCK ADDRESS MAP Figure 2



**TIME, CALENDAR AND ALARM LOCATIONS**

The time and calendar information is obtained by reading the appropriate memory bytes. The time, calendar, and alarm are set or initialized by writing the appropriate RAM bytes. The contents of the ten time, calendar, and alarm bytes can be either Binary or Binary-Coded Decimal (BCD) format. Before writing the internal time, calendar, and alarm registers, the SET bit in Register B should be written to a logic one to prevent updates from occurring while access is being attempted. In addition to writing the ten time, calendar, and alarm registers in a selected format (binary or BCD), the data mode bit (DM) of Register B must be set to the appropriate logic level. All ten time, calendar, and alarm bytes must use the same data mode. The set bit in Register B should be cleared after the data mode bit has been written to allow the real time clock to update the time and calendar bytes. Once initialized, the real time clock makes all updates in the selected mode. The data mode cannot be changed without reinitializing the ten data bytes. Table 2 shows the binary and BCD formats of the ten time, calendar, and alarm locations. The 4–12 bit cannot be changed without reinitializing the hour locations. When the 12-hour format is selected, the high order bit of the hours byte represents PM when it is a logic one. The time, calendar, and alarm bytes are always accessible because they are double buffered. Once per second the eleven bytes are advanced by one second and checked for an alarm condition. If a read of the time and calendar data occurs during an update, a problem exists where seconds, minutes, hours, etc. may not correlate. The probability of reading incorrect time and calendar data is low. Several methods of avoiding any possible incorrect time and calendar reads are covered later in this text. The three alarm bytes can be used in two ways. First, when the alarm time is written in the appropriate hours, minutes, and seconds alarm locations, the alarm interrupt is initiated at the specified time each day if the alarm enable bit is high. The second use condition is to insert a “don’t care” state in one or more of the three alarm bytes. The “don’t care” code is any hexadecimal value from C0 to FF. The two most significant bits of each byte set the “don’t care” condition when at logic 1. An alarm will be generated each hour when the “don’t care” bits are set in the hours byte. Similarly, an alarm is generated every minute with “don’t care” codes in the hours and minute alarm bytes. The “don’t care” codes in all three alarm bytes create an interrupt every second.

**TIME, CALENDAR AND ALARM DATA MODES Table 1**

ADDRESS LOCATION	FUNCTION	DECIMAL RANGE	RANGE	
			BINARY DATA MODE	BCD DATA MODE
0	Seconds	0-59	00-3B	00-59
1	Seconds Alarm	0-59	00-3B	00-59
2	Minutes	0-59	00-3B	00-59
3	Minutes Alarm	0-59	00-3B	00-59
4	Hours 12-hr, Mode	1-12	01-0C AM, 81-8C PM	01-12 AM, 81-92 PM
	Hours 24-hr, Mode	0-23	00-17	00-23
5	Hours Alarm 12-hr, Mode	1-12	01-0C AM, 81-8C PM	01-12 AM, 81-92 PM
	Hours Alarm 24-hr, Mode	0-23	00-17	00-23
6	Day of the week Sunday=1	1-7	01-07	01-07
7	Date of Month	1-31	01-1F	01-31
8	Month	1-12	01-0C	01-12
9	Year	0-99	00-63	00-99
50	Century	0-99	NA	19,20

## CONTROL REGISTERS

The DS12C887 has four control registers which are accessible at all times, even during the update cycle.

### REGISTER A

MSB

LSB

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
UIP	DV2	DV1	DV0	RS3	RS2	RS1	RS0

**UIP** - The Update In Progress (UIP) bit is a status flag that can be monitored. When the UIP bit is a 1, the update transfer will soon occur. When UIP is a 0, the update transfer will not occur for at least 244 $\mu$ s. The time, calendar, and alarm information in RAM is fully available for access when the UIP bit is 0. The UIP bit is read-only and is not affected by RESET. Writing the SET bit in Register B to a 1 inhibits any update transfer and clears the UIP status bit.

**DV2, DV1, DV0** - These three bits are used to turn the oscillator on or off and to reset the countdown chain. A pattern of 010 is the only combination of bits that will turn the oscillator on and allow the RTC to keep time. A pattern of 11X will enable the oscillator but holds the countdown chain in reset. The next update will occur at 500 ms after a pattern of 010 is written to DV0, DV1, and DV2.

**RS3, RS2, RS1, RS0** - These four rate-selection bits select one of the 13 taps on the 15-stage divider or disable the divider output. The tap selected can be used to generate an output square wave (SQW pin) and/or a periodic interrupt. The user can do one of the following:

1. Enable the interrupt with the PIE bit;
2. Enable the SQW output pin with the SQWE bit;
3. Enable both at the same time and the same rate; or
4. Enable neither

Table 1 lists the periodic interrupt rates and the square wave frequencies that can be chosen with the RS bits. These four read/write bits are not affected by RESET.

**REGISTER B**

MSB				LSB			
BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
SET	PIE	AIE	UIE	SQWE	DM	24/12	DSE

**SET** - When the SET bit is a 0, the update transfer functions normally by advancing the counts once per second. When the SET bit is written to a 1, any update transfer is inhibited and the program can initialize the time and calendar bytes without an update occurring in the midst of initializing. Read cycles can be executed in a similar manner. SET is a read/write bit and is not affected by  $\overline{\text{RESET}}$  or internal functions of the DS12C887.

**PIE** - The Periodic Interrupt Enable bit is a read/write bit which allows the Periodic Interrupt Flag (PF) bit in Register C to drive the  $\overline{\text{IRQ}}$  pin low. When the PIE bit is set to 1, periodic interrupts are generated by driving the  $\overline{\text{IRQ}}$  pin low at a rate specified by the RS3-RS0 bits of Register A. A 0 in the PIE bit blocks the  $\overline{\text{IRQ}}$  output from being driven by a periodic interrupt, but the Periodic Flag (PF) bit is still set at the periodic rate. PIE is not modified by any internal DS12C887 functions but is cleared to 0 on  $\overline{\text{RESET}}$ .

**AIE** - The Alarm Interrupt Enable (AIE) bit is a read/write bit which, when set to a 1, permits the Alarm Flag (AF) bit in register C to assert  $\overline{\text{IRQ}}$ . An alarm interrupt occurs for each second that the 3 time bytes equal the 3 alarm bytes including a "don't care" alarm code of binary 11XXXXXX. When the AIE bit is set to 0, the AF bit does not initiate the  $\overline{\text{IRQ}}$  signal. The internal functions of the DS12C887 not affect the AIE bit.

**UIE** - The Update Ended Interrupt Enable (UIE) bit is a read/write bit that enables the Update End Flag (UEF) bit in Register C to assert  $\overline{\text{IRQ}}$ . The  $\overline{\text{RESET}}$  pin going low or the SET bit going high clears the UIE bit.

**SQWE** - When the Square Wave Enable (SQWE) bit is set to a 1, a square wave signal at the frequency set by the rate-selection bits RS3 through RS0 is driven out on the SQW pin. When the SQWE bit is set to 0, the SQW pin is held low. SQWE is a read/write bit and is cleared by  $\overline{\text{RESET}}$ . SQWE is set to a 1 when  $V_{CC}$  is powered up.

**DM** - The Data Mode (DM) bit indicates whether time and calendar information is in binary or BCD format. The DM bit is set by the program to the appropriate format and can be read as required. This bit is not modified by internal functions or  $\overline{\text{RESET}}$ . A 1 in DM signifies binary data while a 0 in DM specifies Binary Coded Decimal (BCD) data.

**24/12** - The 24/12 control bit establishes the format of the hours byte. A 1 indicates the 24-hour mode and 0 indicates the 12-hour mode. This bit is read/write and is not affected by internal functions or  $\overline{\text{RESET}}$ .

**DSE** - The Daylight Savings Enable (DSE) bit is a read/write bit which enables two special updates when DSE is set to 1. On the first Sunday in April the time increments from 1:59:59 AM to 3:00:00 AM. On the last Sunday in October when the time first reaches 1:59:59 AM it changes to 1:00:00 AM. These special updates do not occur when the DSE bit is a zero. This bit is not affected by internal functions or  $\overline{\text{RESET}}$ .

**REGISTER C**

MSB							LSB
BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
IRQF	PF	AF	UF	0	0	0	0

**IRQF** - The Interrupt Request Flag (IRQF) bit is set to a 1 when one or more of the following are true:

PF = PIE = 1

AF = AIE = 1

UF = UIE = 1

i.e.,  $IRQF = (PF \bullet PIE) + (AF \bullet AIE) + (UF \bullet UIE)$

Any time the IRQF bit is a 1, the  $\overline{IRQ}$  pin is driven low. Flag bits PF, AF, and UF are cleared after Register C is read by the program or when the  $\overline{RESET}$  pin is low.

**PF** - The Periodic Interrupt Flag (PF) is a read-only bit which is set to a 1 when an edge is detected on the selected tap of the divider chain. The RS3 through RS0 bits establish the periodic rate. PF is set to a 1 independent of the state of the PIE bit. When both PF and PIE are 1's, the  $\overline{IRQ}$  signal is active and will set the IRQF bit. The PF bit is cleared by a software read of Register C or a  $\overline{RESET}$ .

**AF** - A 1 in the Alarm Interrupt Flag (AF) bit indicates that the current time has matched the alarm time. If the AIE bit is also a 1, the  $\overline{IRQ}$  pin will go low and a 1 will appear in the IRQF bit. A  $\overline{RESET}$  or a read of Register C will clear AF.

**UF** - The Update Ended Interrupt Flag (UF) bit is set after each update cycle. When the UIE bit is set to 1, the 1 in UF causes the IRQF bit to be a 1, which will assert the  $\overline{IRQ}$  pin. UF is cleared by reading Register C or a  $\overline{RESET}$ .

**BIT 3 THROUGH BIT 0** - These are unused bits of the status Register C. These bits always read 0 and cannot be written.

**REGISTER D**

MSB							LSB
BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
VRT	0	0	0	0	0	0	0

**VRT** - The Valid RAM and Time (VRT) bit indicates the condition of the battery connected to the  $V_{BAT}$  pin. This bit is not writeable and should always be a 1 when read. If a 0 is ever present, an exhausted internal lithium energy source is indicated and both the contents of the RTC data and RAM data are questionable. This bit is unaffected by  $\overline{RESET}$ .

**BIT 6 THROUGH BIT 0** - The remaining bits of Register D are not usable. They cannot be written and, when read, they will always read 0.

## CENTURY REGISTER

The century register at location 32h, is a BCD register designed to automatically load the BCD value 20 as the year register changes from 99 to 00. The MSB of this register will not be affected when the load of 20 occurs and will remain at the value written by the user.

## NONVOLATILE RAM

The 113 general purpose nonvolatile RAM bytes are not dedicated to any special function within the DS12C887. They can be used by the processor program as nonvolatile memory and are fully available during the update cycle.

## INTERRUPTS

The RTC plus RAM includes three separate, fully automatic sources of interrupt for a processor. The alarm interrupt can be programmed to occur at rates from once per second to once per day. The periodic interrupt can be selected for rates from 500ms to 122 $\mu$ s. The update-ended interrupt can be used to indicate to the program that an update cycle is complete. Each of these independent interrupt conditions is described in greater detail in other sections of this text.

The processor program can select which interrupts, if any, are going to be used. Three bits in Register B enable the interrupts. Writing a logic 1 to an interrupt-enable bit permits that interrupt to be initiated when the event occurs. A zero in an interrupt-enable bit prohibits the  $\overline{\text{IRQ}}$  pin from being asserted from that interrupt condition. If an interrupt flag is already set when an interrupt is enabled,  $\overline{\text{IRQ}}$  is immediately set at an active level, although the interrupt initiating the event may have occurred much earlier. As a result, there are cases where the program should clear such earlier initiated interrupts before first enabling new interrupts.

When an interrupt event occurs, the relating flag bit is set to logic 1 in Register C. These flag bits are set independent of the state of the corresponding enable bit in Register B. The flag bit can be used in a polling mode without enabling the corresponding enable bits. The interrupt flag bit is a status bit which software can interrogate as necessary. When a flag is set, an indication is given to software that an interrupt event has occurred since the flag bit was last read; however, care should be taken when using the flag bits as they are cleared each time Register C is read. Double latching is included with Register C so that bits which are set remain stable throughout the read cycle. All bits which are set (high) are cleared when read and new interrupts which are pending during the read cycle are held until after the cycle is completed. One, two, or three bits can be set when reading Register C. Each utilized flag bit should be examined when read to ensure that no interrupts are lost.

The second flag bit usage method is with fully enabled interrupts. When an interrupt flag bit is set and the corresponding interrupt enable bit is also set, the  $\overline{\text{IRQ}}$  pin is asserted low.  $\overline{\text{IRQ}}$  is asserted as long as at least one of the three interrupt sources has its flag and enable bits both set. The IRQF bit in Register C is set one whenever the  $\overline{\text{IRQ}}$  pin is being driven low. Determination that the RTC initiated an interrupt is accomplished by reading Register C. A logic one in bit 7 (IRQF bit) indicates that one or more interrupts have been initiated by the DS12C887. The act of reading Register C clears all active flag bits and the IRQF bit.

## OSCILLATOR CONTROL BITS

When the DS12C887 is shipped from the factory, the internal oscillator is turned off. This feature prevents the lithium energy cell from being used until it is installed in a system. A pattern of 010 in bits 4 through 6 of Register A will turn the oscillator on and enable the countdown chain. A pattern of 11X will turn the oscillator on, but holds the countdown chain of the oscillator in reset. All other combinations of bits 4 through 6 keep the oscillator off.

## SQUARE WAVE OUTPUT SELECTION

Thirteen of the 15 divider taps are made available to a 1-of-15 selector, as shown in the block diagram of Figure 1. The first purpose of selecting a divider tap is to generate a square wave output signal on the SQW pin. The RS0–RS3 bits in Register A establish the square wave output frequency. These frequencies are listed in Table 1. The SQW frequency selection shares its 1-of-15 selector with the periodic interrupt generator. Once the frequency is selected, the output of the SQW pin can be turned on and off under program control with the square wave enable bit (SQWE).

## PERIODIC INTERRUPT SELECTION

The periodic interrupt will cause the  $\overline{\text{IRQ}}$  pin to go to an active state from once every 500ms to once every 122 $\mu$ s. This function is separate from the alarm interrupt which can be output from once per second to once per day. The periodic interrupt rate is selected using the same Register A bits which select the square wave frequency (see Table 1). Changing the Register A bits affects both the square wave frequency and the periodic interrupt output. However, each function has a separate enable bit in Register B. The SQWE bit controls the square wave output. Similarly, the periodic interrupt is enabled by the PIE bit in Register B. The periodic interrupt can be used with software counters to measure inputs, create output intervals, or await the next needed software function.

## PERIODIC INTERRUPT RATE AND SQUARE WAVE OUTPUT FREQUENCY

Table 2

EXT. REG. B E32K	SELECT BITS REGISTER A				$t_{PI}$ PERIODIC INTERRUPT RATE	SQW OUTPUT FREQUENCY
	RS3	RS2	RS1	RS0		
0	0	0	0	0	None	None
0	0	0	0	1	3.90625 ms	256 Hz
0	0	0	1	0	7.8125 ms	128 Hz
0	0	0	1	1	122.070 $\mu$ s	8.192 kHz
0	0	1	0	0	244.141 $\mu$ s	4.096 kHz
0	0	1	0	1	488.281 $\mu$ s	2.048 kHz
0	0	1	1	0	976.5625 $\mu$ s	1.024 kHz
0	0	1	1	1	1.953125 ms	512 Hz
0	1	0	0	0	3.90625 ms	256 Hz
0	1	0	0	1	7.8125 ms	128 Hz
0	1	0	1	0	15.625 ms	64 Hz
0	1	0	1	1	31.25 ms	32 Hz
0	1	1	0	0	62.5 ms	16 Hz
0	1	1	0	1	125 ms	8 Hz
0	1	1	1	0	250 ms	4 Hz
0	1	1	1	1	500 ms	2 Hz

## UPDATE CYCLE

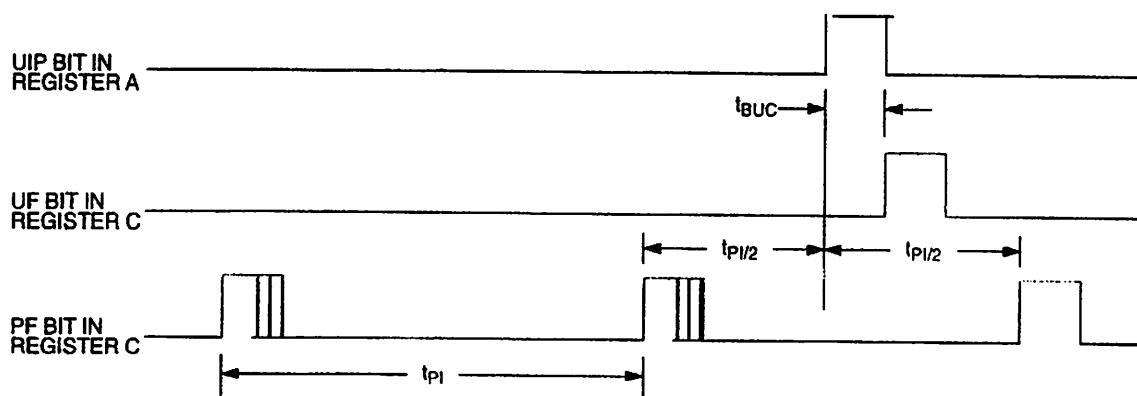
The DS12C887 executes an update cycle once per second regardless of the SET bit in Register B. When the SET bit in Register B is set to one, the user copy of the double buffered time, calendar, and alarm bytes is frozen and will not update as the time increments. However, the time countdown chain continues to update the internal copy of the buffer. This feature allows time to maintain accuracy independent of reading or writing the time, calendar, and alarm buffers and also guarantees that time and calendar information is consistent. The update cycle also compares each alarm byte with the corresponding time byte and issues an alarm if a match or if a "don't care" code is present in all three positions.

There are three methods that can handle access of the real time clock that avoid any possibility of accessing inconsistent time and calendar data. The first method uses the update-ended interrupt. If enabled, an interrupt occurs after every update cycle that indicates that over 999 ms are available to read valid time and date information. If this interrupt is used, the IRQF bit in Register C should be cleared before leaving the interrupt routine.

A second method uses the update-in-progress bit (UIP) in Register A to determine if the update cycle is in progress. The UIP bit will pulse once per second. After the UIP bit goes high, the update transfer occurs 244 $\mu$ s later. If a low is read on the UIP bit, the user has at least 244 $\mu$ s before the time/calendar data will be changed. Therefore, the user should avoid interrupt service routines that would cause the time needed to read valid time/calendar data to exceed 244 $\mu$ s.

The third method uses a periodic interrupt to determine if an update cycle is in progress. The UIP bit in Register A is set high between the setting of the PF bit in Register C (see Figure 3). Periodic interrupts that occur at a rate of greater than  $t_{BUC}$  allow valid time and date information to be reached at each occurrence of the periodic interrupt. The reads should be complete within  $1 ( t_{PI/2} + t_{BUC} )$  to ensure that data is not read during the update cycle.

## UPDATE-ENDED AND PERIODIC INTERRUPT RELATIONSHIP Figure 3



$t_{PI}$  = PERIODIC INTERRUPT TIME INTERNAL PER TABLE 1

$t_{BUC}$  = DELAY TIME BEFORE UPDATE CYCLE = 244  $\mu$ s

**ABSOLUTE MAXIMUM RATINGS**

Voltage on Any Pin Relative to Ground	-0.3V to +7.0V
Operating Temperature	0° to 70°C
Storage Temperature	-40°C to +70°C
Soldering Temperature	260°C for 10 seconds (See Note 7)

\* This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

**RECOMMENDED DC OPERATING CONDITIONS (0°C to 70°C)**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Power Supply Voltage	V <sub>CC</sub>	4.5	5.0	5.5	V	1
Input Logic 1	V <sub>IH</sub>	2.3		V <sub>CC</sub> +0.3	V	1
Input Logic 0	V <sub>IL</sub>	-0.3		0.8	V	1

**DC ELECTRICAL CHARACTERISTICS (0°C to 70°C; V<sub>CC</sub> = 5.0V ± 10%)**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Average V <sub>CC</sub> Power Supply Current	I <sub>CC1</sub>		7	15	mA	2
Input Leakage	I <sub>IL</sub>	-1.0		+1.0	μA	3
I/O Leakage	I <sub>OL</sub>	-1.0		+1.0	μA	4
Input Current	I <sub>MOT</sub>	-1.0		+500	μA	3
Output @ 2.4V	I <sub>OH</sub>	-1.0			mA	1,5
Output @ 0.4V	I <sub>OL</sub>			4.0	mA	1
Write Protect Voltage	V <sub>TP</sub>	4.0	4.25	4.5	V	

**CAPACITANCE (t<sub>A</sub> = 25°C)**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Capacitance	C <sub>IN</sub>			5	pF	
Output Capacitance	C <sub>OUT</sub>			7	pF	

**AC ELECTRICAL CHARACTERISTICS** (0°C to 70°C; VCC = 5.0V ± 10%)

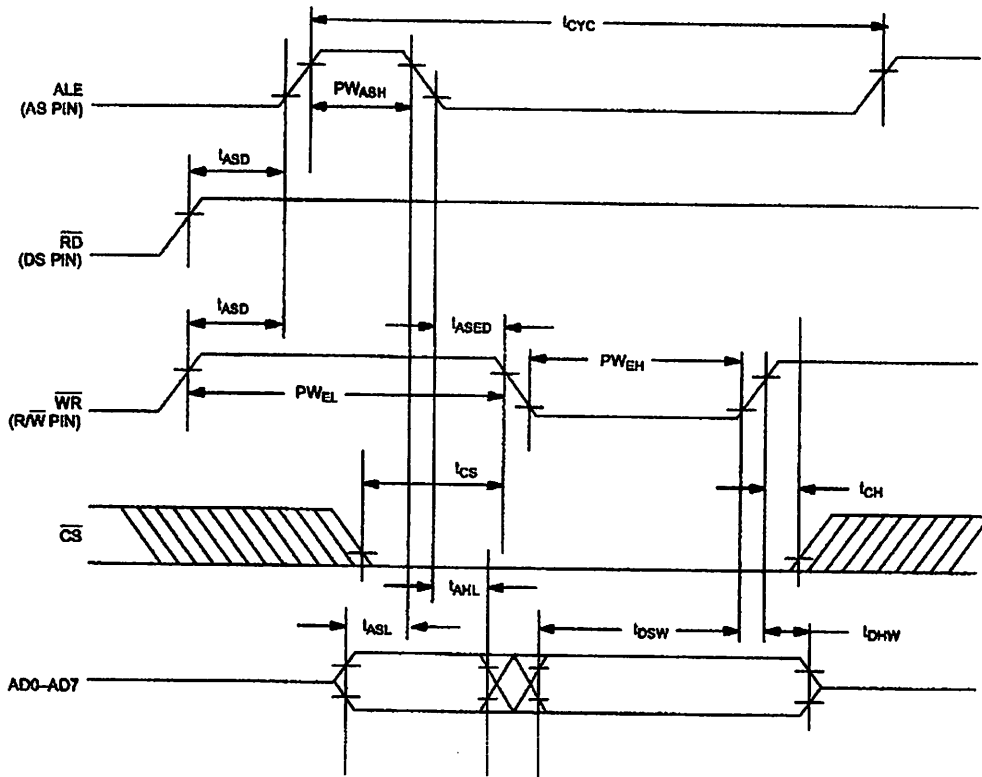
PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Cycle Time	t <sub>CYC</sub>	385		DC	ns	
Pulse Width, DS/E Low or RD/WR High	PW <sub>EL</sub>	150			ns	
Pulse Width, DS/E High or RD/WR Low	PW <sub>RH</sub>	125			ns	
Input Rise and Fall	t <sub>R</sub> , t <sub>F</sub>			30	ns	
R/ $\overline{W}$ Hold Time	t <sub>RWH</sub>	10			ns	
R/ $\overline{W}$ Setup Time Before DS/E	t <sub>RWS</sub>	50			ns	
Chip Select Setup Time Before DS, $\overline{WR}$ , or $\overline{RD}$	t <sub>CS</sub>	20			ns	
Chip Select Hold Time	t <sub>CH</sub>	0			ns	
Read Data Hold Time	t <sub>DHR</sub>	10		80	ns	
Write Data Hold Time	t <sub>DHW</sub>	0			ns	
Mux'ed Address Valid Time to ALE Fall	t <sub>ASL</sub>	30			ns	
Mused Address Hold Time to ALE Fall	t <sub>AHL</sub>	10			ns	
Delay Time DS/E to AS/ALE Rise	t <sub>ASD</sub>	20			ns	
Pulse Width AS/ALE High	PW <sub>ASH</sub>	60			ns	
Delay Time, AS/ALE to DS/E Rise	t <sub>ASED</sub>	40			ns	
Output Data Delay Time from DS/E or $\overline{RD}$	t <sub>DDR</sub>	20		120	ns	6
Data Setup Time	t <sub>DSW</sub>	100			ns	
Reset Pulse Width	t <sub>RWL</sub>	5			μs	
$\overline{IRQ}$ Release from DS	t <sub>IRDS</sub>			2	μs	
$\overline{IRQ}$ Release from $\overline{RESET}$	t <sub>IRR</sub>			2	μs	

**NOTES:**

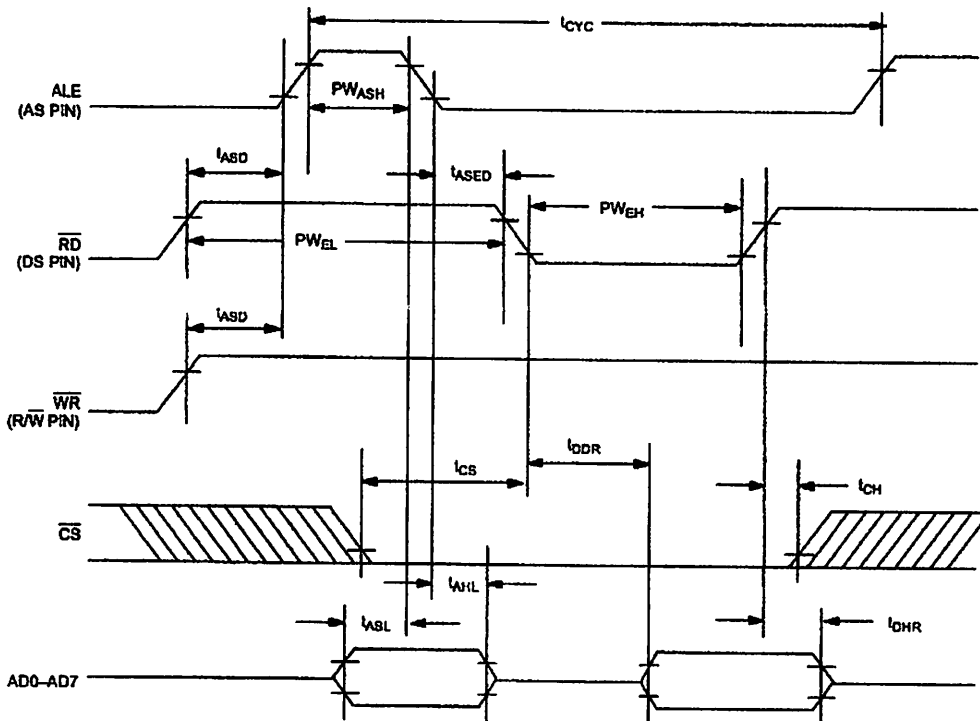
- . All voltages are referenced to ground.
- . All Outputs are open.
- . The MOT pin has an internal pull-down of 20KΩ.
- . Applies to the AD0-AD7 pins, the  $\overline{IRQ}$  pin, and the SQW pin when each is in a high impedance state.
- . The  $\overline{IRQ}$  pin is open drain.
- . Measured with a load as shown in Figure 4.
- . Real-Time Clock Modules can be successfully processed through conventional wave-soldering techniques as long as temperature exposure to the lithium energy source contained within does not exceed +85°C. Post solder cleaning with water washing techniques is acceptable, provided that ultrasonic vibration is not used. Such cleaning can damage the crystal.



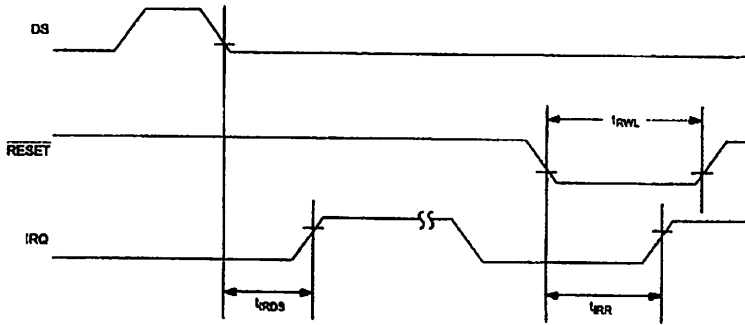
**DS12C887 BUS TIMING FOR INTEL INTERFACE WRITE CYCLE**



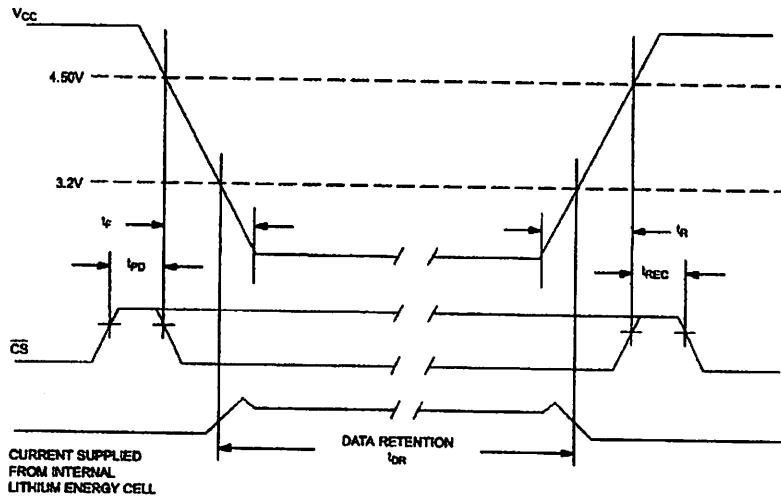
**DS12C887 BUS TIMING FOR INTEL INTERFACE READ CYCLE**



**DS12C887 IRQ RELEASE DELAY TIMING**



**POWER DOWN / POWER UP TIMING**



**POWER DOWN / POWER UP TIMING**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
$\overline{\text{CS}}$ at $V_{\text{IH}}$ before Power-Down	$t_{\text{PD}}$			0	$\mu\text{s}$	
$V_{\text{CC}}$ slew from 4.5V to 0V ( $\overline{\text{CS}}$ at $V_{\text{IH}}$ )	$t_{\text{F}}$ $4.0 \leq V_{\text{CC}} \leq 4.5\text{V}$	300			$\mu\text{s}$	
$V_{\text{CC}}$ slew from 0V to 4.5V ( $\overline{\text{CS}}$ at $V_{\text{IH}}$ )	$t_{\text{R}}$	100			$\mu\text{s}$	
$\overline{\text{CS}}$ at $V_{\text{IH}}$ after Power-Up	$t_{\text{REC}}$	20		200	ms	
Expected Data Retention	$t_{\text{DR}}$	10			years	10,11

**( $t_{\text{A}}=25^{\circ}\text{C}$ )**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Expected Data Retention	$t_{\text{DR}}$	10			years	10,11

**Note:**

The real time clock will keep time to an accuracy of  $\pm 1$  minute per month during data retention time for the period of  $t_{\text{DR}}$ .

**Warning:**

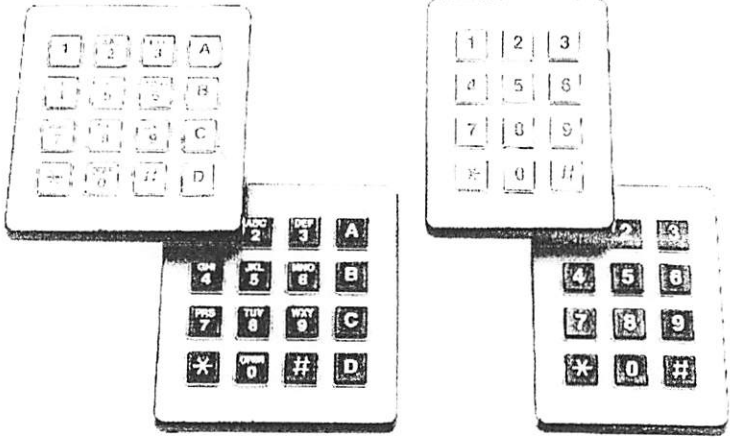
Under no circumstances are negative undershoots, of any amplitude, allowed when device is in battery back-up mode.



**SERIES 96**  
Conductive Rubber

**FEATURES**

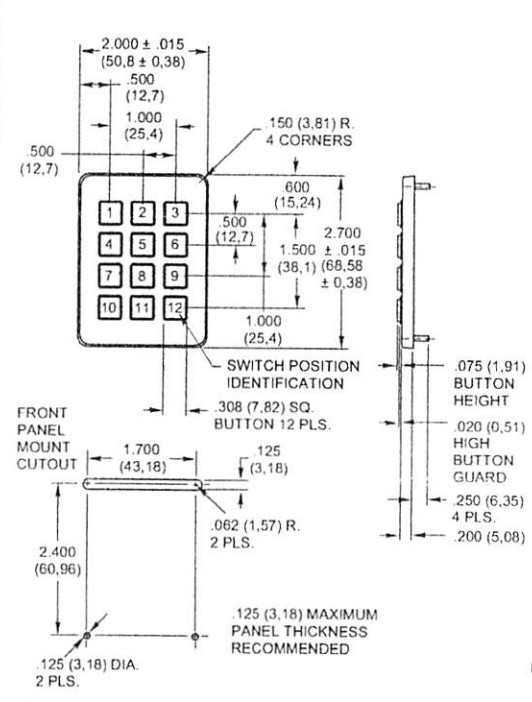
- Quality, Economical Keyboards
- Easily Customized Legends
- Matrix Circuitry
- Backlit and Shielded Options Available
- Termination Mates With Standard Connectors
- Tactile Feedback to Operator
- 1,000,000 Operations per Button
- Compatible With High Resistance Logic Inputs



The Series 96 is Grayhill's most economical 3x4 and 4x4 keypad family. The contact system utilizes conductive rubber to mate the appropriate PC board traces. Offered in matrix circuitry, with shielded and backlit options. Built with quality component parts, the Series 96 is subjected to our rigid statistical process control to insure that it meets our reliability standards.

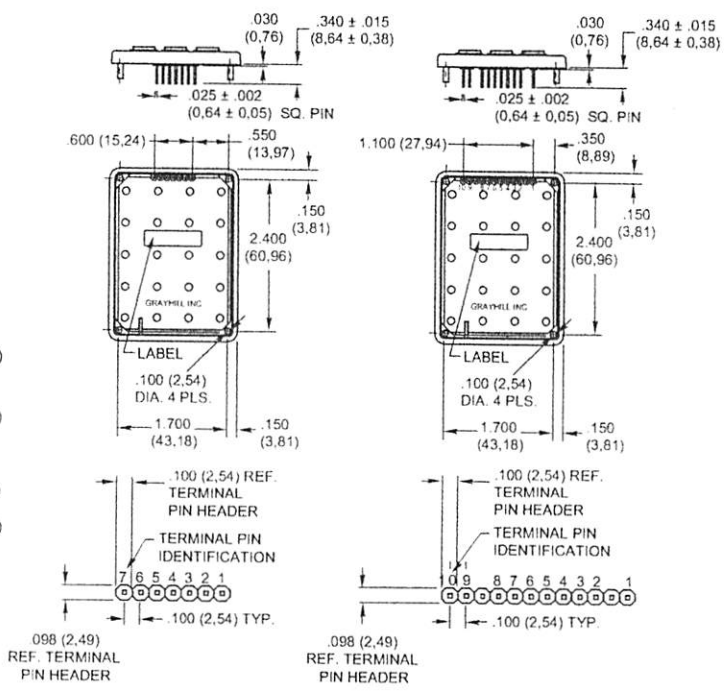
**DIMENSIONS** In inches (and millimeters)

**3x4 Front Mount Keyboard**



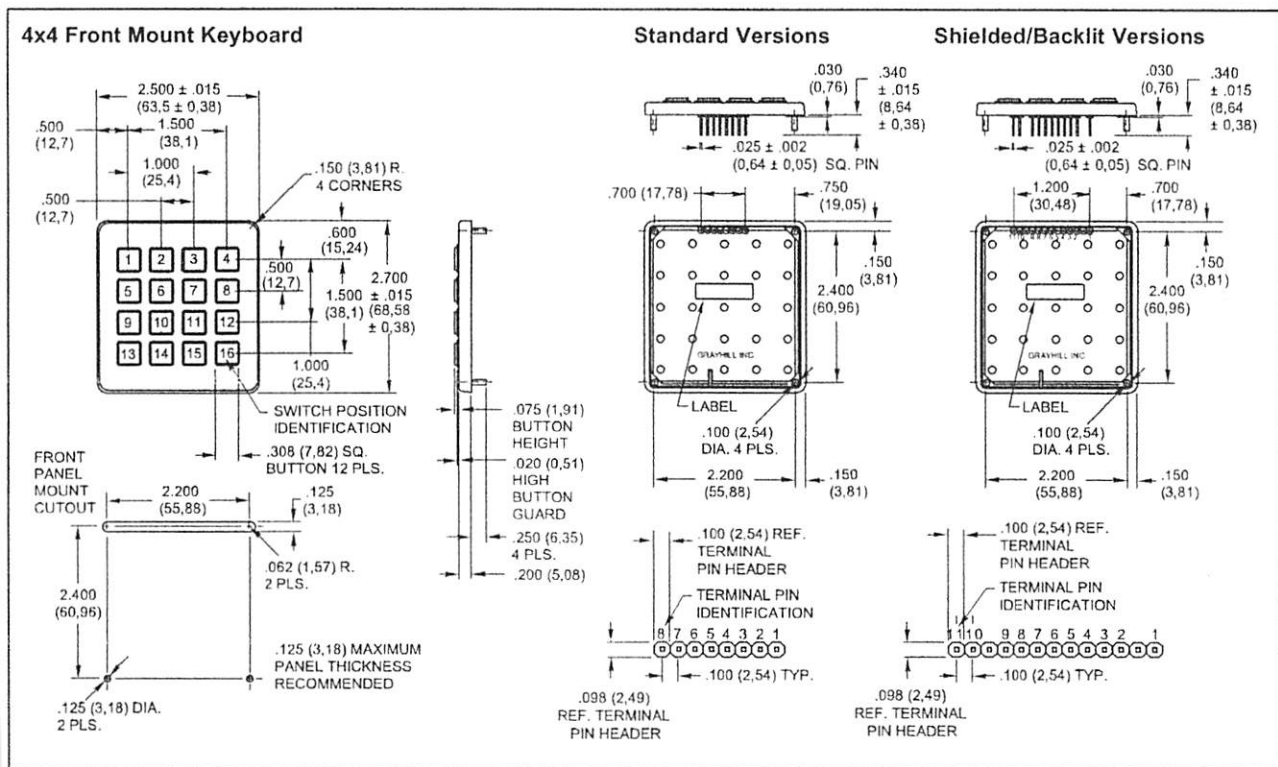
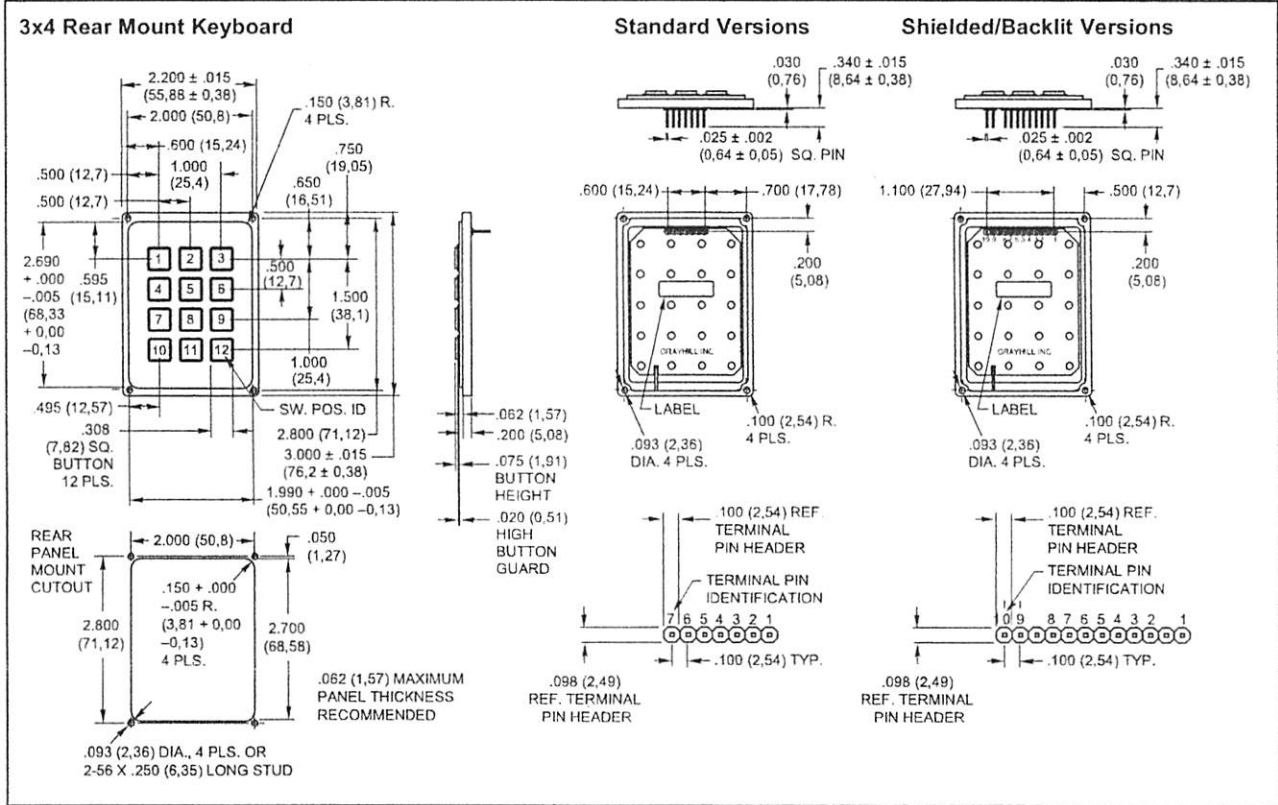
**Standard Versions**

**Shielded/Backlit Versions**



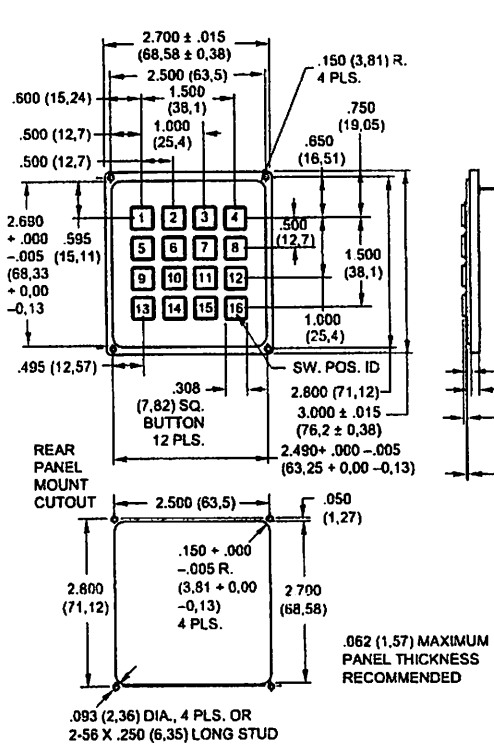
# Standard Keypads

## DIMENSIONS In inches (and millimeters)



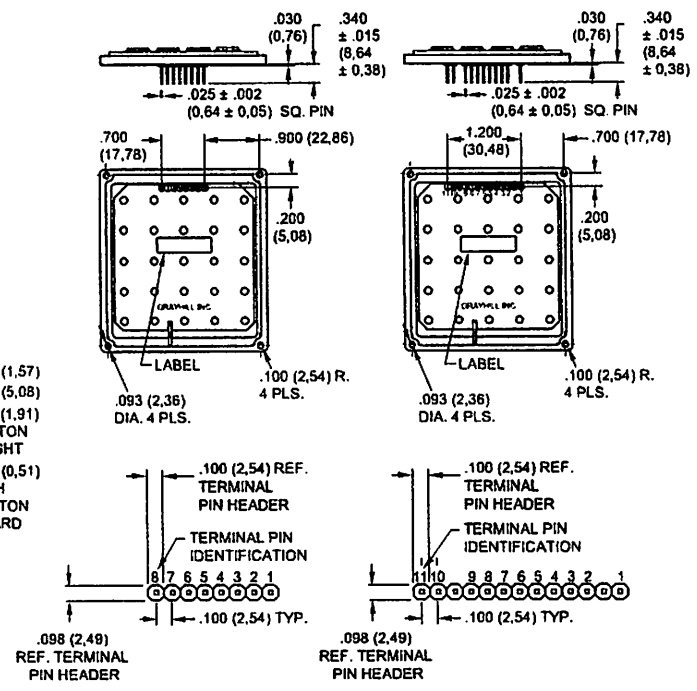
**DIMENSIONS** In inches (and millimeters)

**4x4 Rear Mount Keyboard**



**Standard Versions**

**Shielded/Backlit Versions**



**CODE AND TRUTH TABLES**

Dots in the chart indicate connected terminals when switch is closed. Terminals are identified on the keyboard.

**12 Button Keypads**

BUTTON LOCATION	MATRIX CODES																	
	Standard				Shielded/Backlit													
1	.	.	.	.	.	.	.	.	.	.	.	.	.					
2	.	.	.	.	.	.	.	.	.	.	.	.	.					
3	.	.	.	.	.	.	.	.	.	.	.	.	.					
4	.	.	.	.	.	.	.	.	.	.	.	.	.					
5	.	.	.	.	.	.	.	.	.	.	.	.	.					
6	.	.	.	.	.	.	.	.	.	.	.	.	.					
7	.	.	.	.	.	.	.	.	.	.	.	.	.					
8	.	.	.	.	.	.	.	.	.	.	.	.	.					
9	.	.	.	.	.	.	.	.	.	.	.	.	.					
10	.	.	.	.	.	.	.	.	.	.	.	.	.					
11	.	.	.	.	.	.	.	.	.	.	.	.	.					
12	.	.	.	.	.	.	.	.	.	.	.	.	.					
	5	6	7	8	1	2	3	4	6	7	8	2	3	4	5	1	9	10
	TERMINAL LOCATION																	

Shielded keypad = Shielded  
Backlit keypad = NC  
Shielded and backlit keypad = Shielded

Shielded keypad = NC  
Backlit keypad = EL Panel 1  
Shielded and backlit keypad = EL Panel 1

Shielded keypad = NC  
Backlit keypad = EL Panel 2  
Shielded and backlit keypad = EL Panel 2

**16 Button Keypads**

BUTTON LOCATION	MATRIX CODES																			
	Standard				Shielded/Backlit															
1	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
2	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
3	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
4	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
5	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
6	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
7	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
8	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
9	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
10	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
11	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
12	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
13	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
14	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
15	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
16	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.	.				
	5	6	7	8	1	2	3	4	6	7	8	9	2	3	4	5	1	10	11	
	TERMINAL LOCATION																			

Shielded keypad = Shielded  
Backlit keypad = NC  
Shielded and backlit keypad = Shielded

Shielded keypad = NC  
Backlit keypad = EL Panel 1  
Shielded and backlit keypad = EL Panel 1

Shielded keypad = NC  
Backlit keypad = EL Panel 2  
Shielded and backlit keypad = EL Panel 2

## Standard Keypads

### SPECIFICATIONS

#### Rating Criteria

Rating at 12 Vdc: 5 milliamps for .5 seconds  
 Contact Bounce: < 12 milliseconds  
 Contact Resistance: < 100 ohms (at stated operating force)  
 Voltage Breakdown: 250 Vac between components  
 Mechanical Operation Life: 1,000,000 operations per key  
 Insulation Resistance: > 10<sup>12</sup> ohms @ 500 Vdc  
 Push Out Force Per Pin: 5 lbs.

#### Operating Features

Travel: .040 minimum  
 Operating Force: 175 ± 40 grams  
 Operating Temperature: -30°C to +80°C

#### Material and Finishes

Terminal Pin: Phosphor bronze, solder-plated  
 PC Board: FR-4 glass cloth epoxy  
 Keypad: Silicone rubber, durometer 50 ± 5  
 Housing: ABS, cycolac "KJW"  
 Housing Color: Black

### Shielding Effectiveness

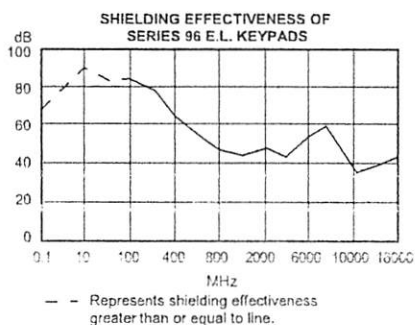
Results shown are typical for a standard Grayhill Series 84S keyboard. A conductive gasket will generally increase the shielding, depending on the size and shape of the gasket and its material. Data derived for E-Field Radiation.

#### Test Method:

Measurements were made with the keyboard mounted to a brass plate, which in turn was mounted to a shielded enclosure containing the receiving equipment. A signal generator provided the frequency source that was radiated from the transmitting antenna to the enclosed receiving antenna. The spacing between antennas was maintained constant throughout the frequency range. The effectiveness rating is determined by establishing a reference reading without obstruction between the two antennas and determining the difference between that reading and the test setup reading.

#### Note:

When measured in actual equipment, shielding effectiveness is determined by many factors. This method accurately represents the shielding effectiveness of the Grayhill Series 84S under ideal test conditions.



Frequency M Hz	Rating in dB
0.1	≥ 66.2
10	> 94.8
100	90.5
400	64.2
800	42.3
2,000	40.5
6,000	33.1
10,000	34.4
18,000	37.0

### STANDARD LEGENDS

Available through Grayhill Distributors

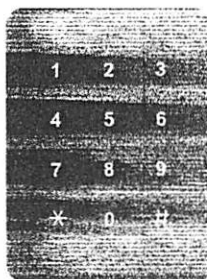
To order one of the configurations below, use the dash number shown here; select the keypad size and code, and order the part number with the appropriate legend dash number.



-102



-006



-152



-056

### ORDERING INFORMATION

Grayhill Series Number  
 Keyboard Size: A = 3x4, B = 4x4  
 Circuitry: B2 = Matrix (terminal pin header)

96AB2-102-FS-EL

#### E.L. Panel Backlighting Option

EL = Backlit, Blank = Non-backlit

#### EMI/RFI Shielding Option

S = Shielded, Blank = Non-shielded

Mounting Option: F = Front panel mount, R = Rear panel mount

#### Standard Legend Choices

12 Position legends

102 = Black legends on a white button

152 = White legends on a black button

16 Position legends

006 = Black legends on a white button

056 = White legends on a black button

Available from your local Grayhill Distributor.

For prices and discounts, contact a local Sales Office, an authorized local Distributor or Grayhill.

# Designing an LCD Dot Matrix Display Interface

National Semiconductor  
 Application Note 350  
 Bob Lutz  
 May 1988



Designing an LCD Dot Matrix Display Interface

The MM58201 is a CMOS LCD driver capable of driving a multiplexed display of up to 192 segments (24 segment columns by 8 backplanes). The number of backplanes being driven is programmable from one to eight. Data to be displayed is sent to the chip serially and stored in an internal RAM. An external resistor and capacitor control the

frequency of the driving signals to the LCD. The MM58201 can also be programmed to accept the oscillator output and backplane signals of another MM58201 for cascading purposes. The displayed data may also be read serially from the on-chip RAM. A simplified functional block diagram of the MM58201 is shown in Figure 1.

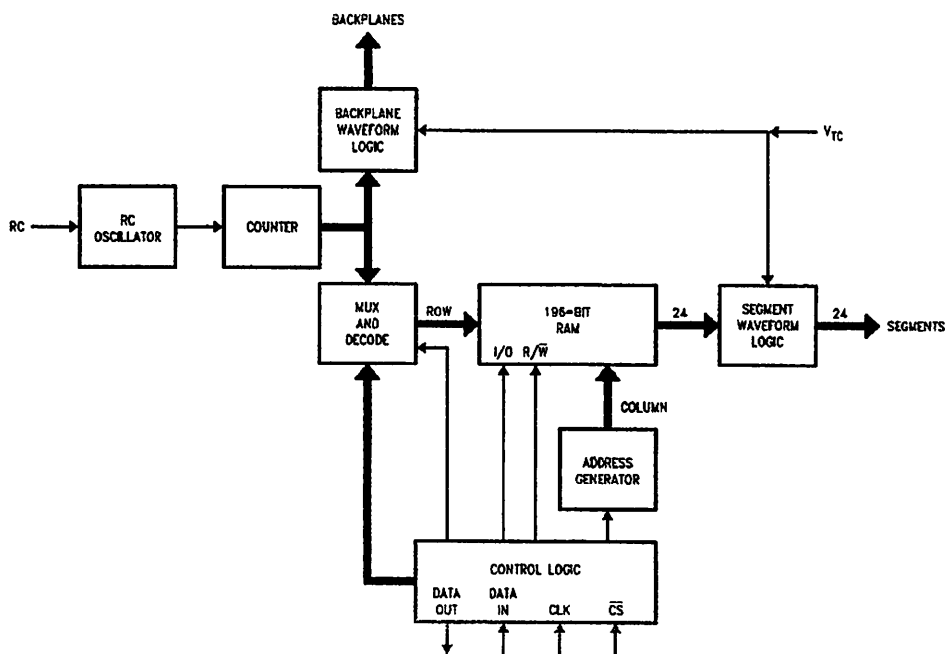


FIGURE 1. MM58201 Functional Diagram

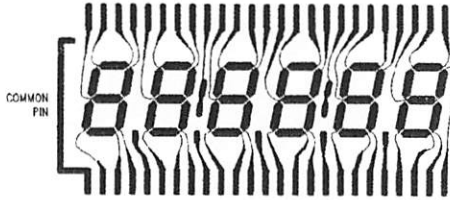
TL/B/5606-1

AN-350

## BACKGROUND

LCD displays have become very popular because of their ultra-low power consumption and high contrast ratio under high ambient light levels. Typically an LCD has a backplane that overlaps the entire display area and multiple segment lines that each overlap just one segment or descriptor. This means that a separate external connection is needed for every segment or descriptor as shown in *Figure 2*. For a display with many segments such as a dot matrix display, the number of external connections could easily grow to be very large.

Unlike other display technologies that respond to peak or average voltage and current, LCDs are sensitive to the rms voltage between the backplane and given segment location. Also, any DC bias across this junction would cause an irreversible electrochemical action that would shorten the life of the display. A typical LCD driving signal is shown in *Figure 3*. The backplane signal is simply a symmetrical square wave. The individual segment outputs are also square waves, either in phase with the backplane for an "off" segment or out of phase for an "on" segment. This causes a  $V_{rms}$  of zero for an "off" segment and a  $V_{rms}$  of  $+V$  for an "on" segment.



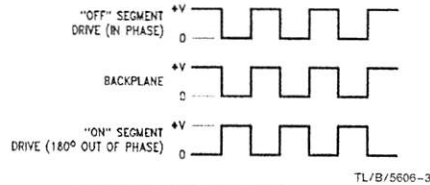
TL/B/5606-2

FIGURE 2. Typical LCD Pin Connections

One way to reduce the number of external connections is to multiplex the display. An example of this could be an LCD with its segments arranged as intersections of an X-Y grid. A driver to control a matrix like this would be fairly straightforward for an LED display. However, it is more complex for an LCD because of the DC bias restriction.

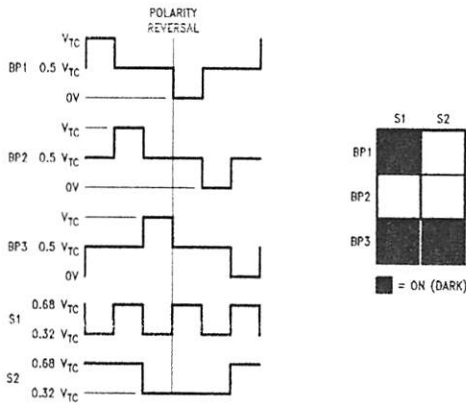
A multiplexed LCD driver must generate a complex set of output signals to insure that an "on" segment sees an rms voltage greater than the display's turn-on voltage and that an "off" segment sees an rms voltage less than the display's turn-off voltage. The driver must also insure that there is no DC bias.

One pattern that can accomplish this is shown as an example in *Figure 4*. This is the pattern that the MM58201 uses. The actual  $V_{rms}$  of an "on" segment and an "off" segment is shown in *Figure 5*. If there are eight backplanes, the  $V_{rms}$  (ON) =  $0.2935 \times V_{TC}$  and the  $V_{rms}$  (OFF) =  $0.2029 \times V_{TC}$ . It can be seen in *Figure 6* that as the number of backplanes increases, the difference between  $V_{rms}$  (ON) and  $V_{rms}$  (OFF) becomes less. Refer to the specifications of the LCD to determine exactly what  $V_{rms}$  is required.



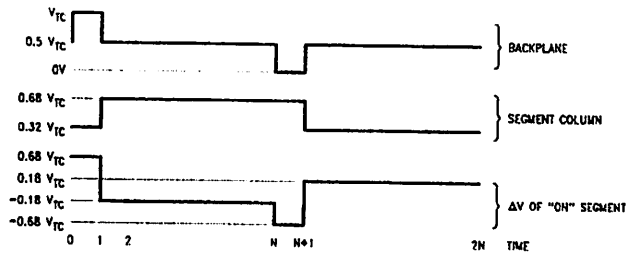
TL/B/5606-3

FIGURE 3. Drive Signals from a Direct Connect LCD Driver



TL/B/5606-4

FIGURE 4. Example of Backplane and Segment Patterns

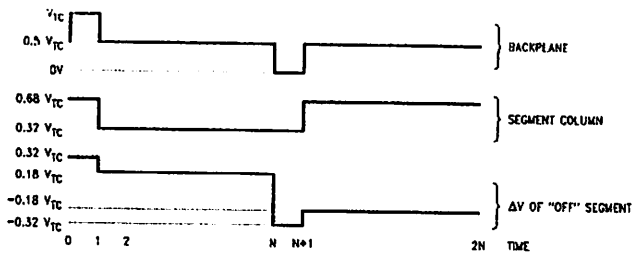


TL/B/5606-5

$$\begin{aligned}
 V_{rms} (ON) &= \left( \frac{1}{T} \int_0^T v^2(t) dt \right)^{1/2} \\
 &= \left( \frac{1}{N} \left[ \int_0^1 (0.68 V_{TC})^2 dt + \int_1^N (-0.18 V_{TC})^2 dt \right] \right)^{1/2} \\
 &= \left( \frac{1}{N} V_{TC}^2 [0.4624 + 0.0324(N-1)] \right)^{1/2} \\
 &= V_{TC} \left[ \frac{0.4624 + 0.0324(N-1)}{N} \right]^{1/2}
 \end{aligned}$$

N = number of backplanes

**a. Analysis of Vrms (ON)**



TL/B/5606-6

$$\begin{aligned}
 V_{rms} (OFF) &= \left( \frac{1}{T} \int_0^T v^2(t) dt \right)^{1/2} \\
 &= \left( \frac{1}{N} \left[ \int_0^1 (0.32 V_{TC})^2 dt + \int_1^N (-0.18 V_{TC})^2 dt \right] \right)^{1/2} \\
 &= \left( \frac{1}{N} V_{TC}^2 [0.1024 + 0.0324(N-1)] \right)^{1/2} \\
 &= V_{TC} \left[ \frac{0.1024 + 0.0324(N-1)}{N} \right]^{1/2}
 \end{aligned}$$

N = number of backplanes

**b. Analysis of Vrms (OFF)**

$$V_{TC} = 1/2 \left[ \frac{V_{rms} (OFF)}{\left( \frac{0.1024 + 0.0324(N-1)}{N} \right)^{1/2}} + \frac{V_{rms} (ON)}{\left( \frac{0.4624 + 0.0324(N-1)}{N} \right)^{1/2}} \right]$$

MUST BE GREATER THAN \_\_\_\_\_

TL/B/5606-7

Example: If N = 8  
 and Vrms (OFF) = 1.8V  
 and Vrms (ON) = 2.2V  
 then V<sub>TC</sub> = 7.5V

**FIGURE 5**

## FUNCTIONAL DESCRIPTION

### Connecting an MM58201 to an LCD

The backplane and segment outputs of the MM58201 connect directly to the backplane and segment lines of the LCD. These outputs are designed to drive a display with a total "on" capacitance of up to 2000 pF. This is especially important for the backplane outputs, as it is usually the backplanes that have the most capacitance. As the capacitance of the output lines increases, the DC offset between a backplane and segment signal may increase. Most LCD displays specify that a maximum offset of 50 mV is acceptable. For backplane capacitance under 2000 pF the MM58201 guarantees an offset of less than 10 mV.

If the LCD display to be used has 24 segments per backplane or less, then each MM58201 should be configured as a "master" so that each one will generate its own set of backplane signals. However, if the LCD display has more than 24 segments per backplane, more than one MM58201 will be needed for each backplane. To synchronize the driving signals there must be one "master" chip and then an additional "slave" chip for every 24 segments after the first 24. When a chip is configured as a "slave" it does not generate its own backplane signals. It simply synchronizes itself to the backplane signals generated by a "master" chip by sensing the BP1 signal. An example of both an all "master" configuration and a "master-slave" configuration will be shown later.

### Voltage Control Pin and Circuitry

The voltage presented at the  $V_{TC}$  pin determines the actual voltage that is output on the backplane and segment lines. These voltages are shown in Figure 7.  $V_{TC}$  should be set with respect to  $V_{rms}$  (ON) and  $V_{rms}$  (OFF) and can be calculated as shown in Figure 5.

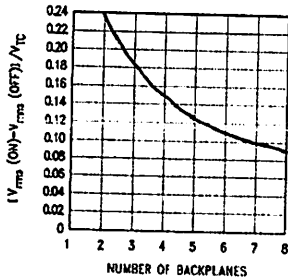


FIGURE 6.  $\Delta V_{rms} / V_{TC}$

TL/B/5606-8

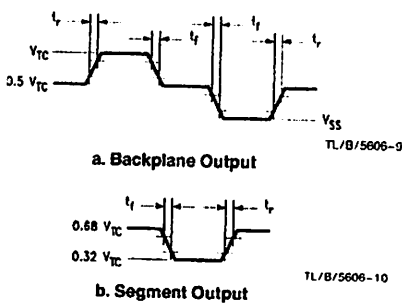


FIGURE 7. Output Voltages

Since the input impedance of  $V_{TC}$  may vary between 10 k $\Omega$  and 30 k $\Omega$ , the output impedance of the voltage reference at  $V_{TC}$  should be relatively low. One example of a  $V_{TC}$  driver is shown in Figure 8. To put the MM58201 in a standby mode, bring  $V_{TC}$  to  $V_{SS}$  (ground). This will blank out the display and reduce the supply current to less than 300  $\mu A$ .

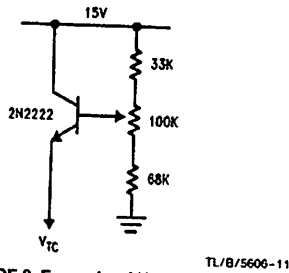


FIGURE 8. Example of  $V_{TC}$  Driver

TL/B/5606-11

### RC Oscillator

This oscillator works with an external resistor tied to  $V_{DD}$  and an external capacitor tied to  $V_{SS}$ . The frequency of oscillation is related to the external R and C by:

$$f_{osc} = 1/1.25 RC \pm 30\%$$

The value of the external resistor should be in the range from 10 k $\Omega$  to 1 M $\Omega$ . The value of the external capacitor should be less than 0.005  $\mu F$ .

The oscillator generates the timing required for multiplexing the LCD. The frequency of the oscillator is 4N times the refresh rate of the display, where N is the number of backplanes programmed. Since the refresh rate should be in the range from 32 Hz to 100 Hz, the oscillator frequency should be:

$$128N < f_{osc} < 400N$$

If the frequency is too slow, there will be a noticeable flicker in the display. If the frequency is too fast, there will be a loss of contrast between segments and an increase in power consumption.

### Serial Input and Output

Data is sent to the MM58201 serially through the DATA IN pin. Each transmission must consist of 30 bits of information, as shown in Figure 9. The first five bits are the address, MSB first, of the first column of LCD segments that are to be changed. The next bit is a read or write flag. The following 24 bits are the actual data to be displayed.

The address specifies the first LCD column that is going to be affected. The columns are numbered as shown in Figure 10. Data is always written in three column chunks. Twenty-four bits of data must always be sent, even if some of the backplanes are not in use. The starting column can be any number between one (00000) and twenty-four (10111). If column 23 or 24 is specified the displayed data will wrap around to column 1.

If the R/W bit is a "0" then the specified columns of the LCD will be overwritten with the new data. If the bit is a "1" then the data displayed in the specified columns will be available serially at the DATA OUT pin and the display will not be changed.



### TYPICAL APPLICATIONS

One application of the MM58201 is a general purpose display to show graphic symbols and text. This type of display could be used in an electronic toy or a small portable computer or calculator. One such display is shown in *Figure 12*. This display consists of four separate LCD displays that are built into one housing. Each separate LCD display has 8 backplanes and 24 segment lines. The entire display will require four MM58201s to control it.

The circuit diagram of this application is shown in *Figure 14*. Each separate LCD display is driven by one MM58201. The backplanes are driven by the separate MM58201s and are not paralleled together. There are three common lines: CLK, DATA IN, and DATA OUT. The CLK and DATA IN are generated from an output port such as an INS8255. Four other bits of the output port generate a linear select with a different bit going to each MM58201 chip select as shown in *Figure 13*. DATA OUT is sent to one bit of an input port.

The  $V_{TC}$  driver is as described beforehand. The MM74C906 is an open drain CMOS buffer that has near regular TTL compatible inputs. This is to provide level translation from the 5V supply of the computer system to the 12V supply of the MM58201.

If I/O ports are not available, the circuit in *Figure 15* could be used as an interface between the MM58201s and a microprocessor bus.

To reduce the number of connections between the circuit and the LCD, all of the backplanes could have been driven by one MM58201 as shown in *Figure 16*. The other MM58201s would be configured as "slaves" synchronized to the one "master" MM58201. This would save 24 connections to the LCD but would increase the capacitance of the backplanes. In this application the capacitance is not a problem with either setup.

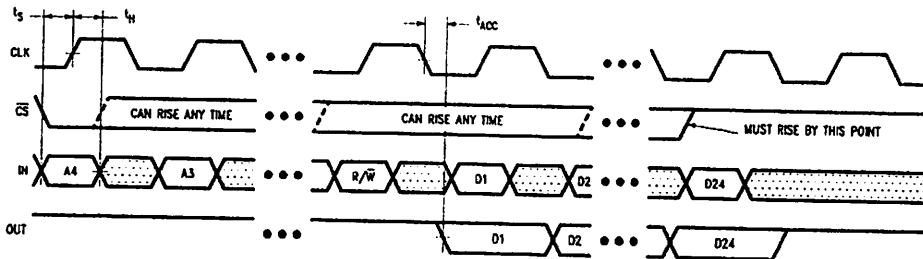


FIGURE 11. Timing of One Transmission

TL/B/5606-14

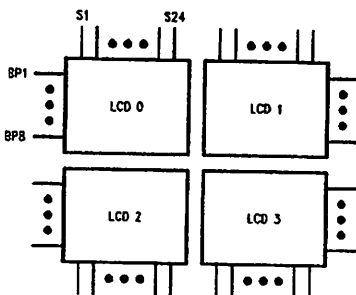


FIGURE 12. Four Separate LCD Displays Positioned to Look Like One Display

TL/B/5606-15

7	6	5	4	3	2	1	0
DATA IN	CLK	X	X	$\overline{CS4}$	$\overline{CS3}$	$\overline{CS2}$	$\overline{CS1}$

$\overline{CS4}$	$\overline{CS3}$	$\overline{CS2}$	$\overline{CS1}$	
1	1	1	0	Chip 1 Selected
1	1	0	1	Chip 2 Selected
1	0	1	1	Chip 3 Selected
0	1	1	1	Chip 4 Selected
1	1	1	1	No Chip Selected

FIGURE 13. Chip Select Scheme



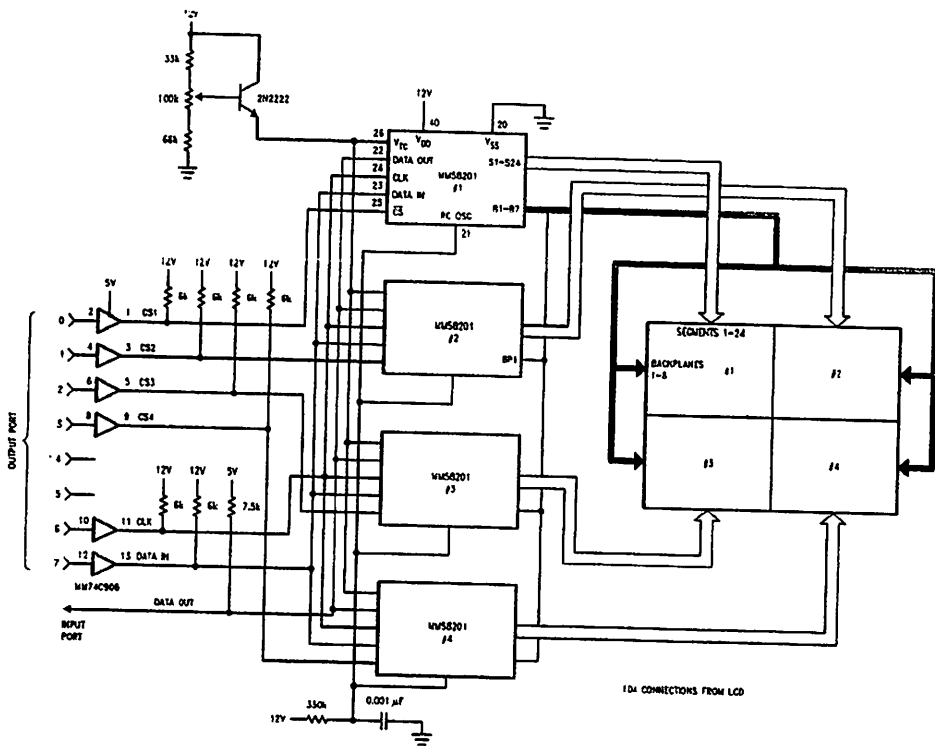


FIGURE 16. Diagram of a Master-Slave Set-Up Not Used for This Application

TL/B/5606-19

#### SOFTWARE

The real heart of this system is the software which consists of four parts. Part one is the initialization portion. This sets up the MM58201s as "masters" and programs them for 8 backplanes. It then sets up the needed pointers for the other subroutines which consist of:

- 1) GRAPH: displays pattern on LCD.
- 2) TEXT: prints ASCII characters on display.
- 3) SCROLL: scrolls whatever pattern is displayed to the right until LCD is cleared.

This application used an NSC800™ with 8080 mnemonics. It could easily be adapted for other microprocessors.

#### MAIN

This program initializes the MM58201s. It controls the sequence of display output by calling other programs.

It first sends out a "dummy" transmission to make sure that the chips are ready to respond to a valid transmission. It then programs the chips to be "masters" and to use eight backplanes.

After initialization, this program sets up the correct pointers to display a graphic symbol. First it displays the upper eight bits of it, then it displays the lower eight bits.

The words "TESTING MM58201" are then displayed. A call to scroll then causes this to scroll to the right until the screen is blank. Finally the words "END OF TEST" appear and the program ends.

The method to create a custom graphic symbol will be demonstrated in the next section.

M8090

EXTRN GRAPH,WRITE,MODE,TEXT,CURSOR,SCROLL

```
:INITIALIZE THE STACK POINTER
LXI SP,1FFFH

:INITIALIZE THE B10
:SET MODE 0 FOR PORT A
:INIT: MVI A,00H
      OUT 27H
:SET PORT A AS OUTPUT AND PORT C AS INPUT
      MVI A,0FFH
      OUT 24H           :PORT A DDR
      MVI A,00H
      OUT 26H           :PORT B DDR

:INITIALIZE THE FOUR 58201'S
      MVI A,0           :SET FOR WRITE MODE
      STA MODE
      LXI H,MASTER.    :SEND A COMPLETE TRANSMISSION TO CLEAR OUT
      MVI E,110000H    : ANY OLD CHIP SELECT.
      MVI D,00001101B
      CALL WRITE
      LXI H,MASTER
      MVI D,00001101B  :CONFIGURE CHIPS 0, 1, 2, AND 3 AS MASTERS
      CALL WRITE
      LXI H,MASTER
      MVI D,00001101B
      CALL WRITE
      LXI H,MASTER
      MVI D,00001011B
      CALL WRITE
      LXI H,MASTER
      MVI D,00001011B
      CALL WRITE
      LXI H,MASTER
      MVI D,00000111B
      CALL WRITE

:SET UP POINTER AND COUNTERS TO DISPLAY NATIONAL SEMI SYMBOL
      MVI B,21         :B HOLDS # OF COLUMNS TO CHANGE
RESTR: MVI D,0         :D HOLDS THE STARTING COLUMN NUMBER FOR UPPER HALF
      MVI E,48         :E HOLDS STARTING COLUMN NUMBER FOR LOWER HALF
DSLOOP: MOV C,D
      LXI H,NATSM1    :DISPLAY UPPER HALF OF GRAPHIC
      CALL GRAPH
      LXI H,NATSM2    :DISPLAY LOWER HALF OF GRAPHIC
      MOV C,E
      CALL GRAPH

      LXI H,OFFFFH    :PAUSE
PAUSE: DCX H
      MOV A,H
      ORA L
      JNZ PAUSE

      INR D           :INCREMENT STARTING COLUMN NUMBERS
      INR D
      INR D
      INR E
      INR E
      INR E
      MVI A,30        :DISPLAY IT UNTIL COLUMN COUNT IS 30
      CMP D
      JNZ DSLOOP

      LXI H,TEXT1     :PRINT FIRST TEXT
      MVI A,0         :ZERO THE CURSOR
      STA CURSOR
      CALL TEXT

      CALL SCROLL     :SCROLL THE TEXT

      LXI H,TEXT2     :PRINT SECOND TEXT
      MVI A,0         :ZERO THE CURSOR
      STA CURSOR
      CALL TEXT

      LXI H,OFFFFH    :PAUSE
PAUSE1: DCX H
      MVI A,2
PAUSE2: DCR A
      JNZ PAUSE2
      MOV A,H
      ORA L
      JNZ PAUSE1
```

```

LXI H,TEXT3          :PRINT THIRD TEXT
MVI A,0
STA CURSOR
CALL TEXT

RST 6                :END

TEXT1: DB "TESTING M458201 ",0
TEXT2: DB "THIS IS THE END ",0
TEXT3: DB " OF THE TEST ",0

MASTER: DB 1111B      :ADDRESS FOR MASTER
SLAVE:   DB 0111B     :ADDRESS FOR SLAVE

NATSM1: DB 0FFH, 0FFH, 0FFH, 7FH, 3FH, 9FH, 0CFH, 67H, 33H, 01H, 7FH
        DB 3FH, 9FH, 0CFH, 67H, 33H
        DB 99H, 0FFH, 0FFH, 00H, 00H
NATSM2: DB 0FFH, 0FFH, 0FFH, 0E6H, 0F3H, 0F9H, 0FCH, 0FEH, 0FFH
        DB 0E6H, 0E6H, 0F3H, 0F9H, 0FCH
        DB 0FEH, 0FFH, 0FFH, 0FFH, 0FFH, 00H, 00H
        END

```

**GRAPH**

This subroutine is the center of the software. It is the interface between the calling programs and the hardware. All I/O is generated by this subroutine.

There are two entrances to this subroutine: graph and read. Graph is the entrance used to display new data. Read is the entrance used to read data from the display.

The HL register should point to the beginning of the data to be displayed. The B register should hold the number of columns to change. This must be a multiple of three. The C register should hold the column number to start with. This must also be a multiple of three. These restrictions are to simplify the software.

The first operation is the calculation of the correct chip to enable and the column number to start within that chip. The first bit of the column address is output with the correct chip

select going low. The rest of the column address is then output with all the chip selects high. If the operation is a write, the data is sent to the display bit by bit. If the operation is a read, the data is read in bit by bit.

To create a custom graphic symbol, draw it on a grid as shown in Figure 17. Group the upper eight squares as a byte with the least significant bit at the top, counting a dark square as a one. Group the lower eight squares as a byte with the most significant bit at the bottom. Use this generated data as input lists to the graph subroutine. A good example of this is shown in the listing of main when it calls graph.

Pad the data at the end with zeros as shown to keep the number of data values a multiple of three. Remember, this is only a software restriction. A different routine could be used that would allow any number of columns to be displayed.

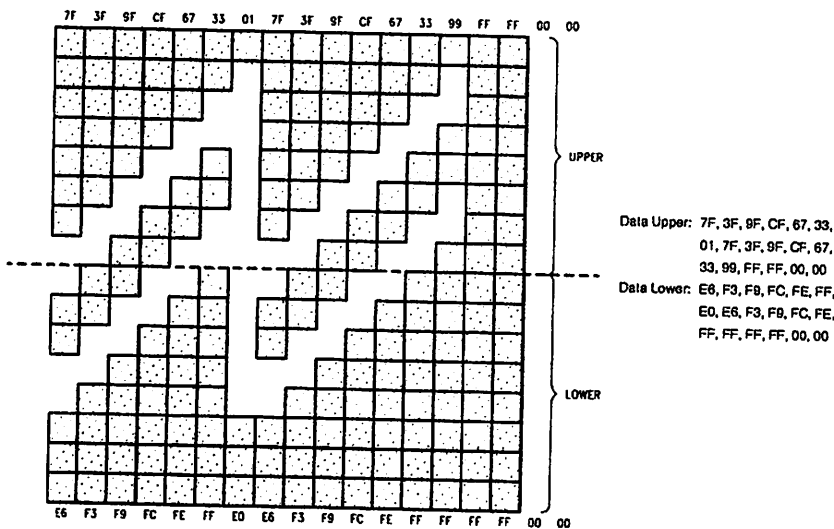


FIGURE 17. Example Graphic Symbol

TL/B/5606-20

```

M8080
PUBLIC GRAPH, READ, WRITE, MODE
:GRAPHIC DISPLAY DRIVER
:
: INPUT: HL - POINTS TO START OF DATA
:         B- # OF 8 BIT COLUMNS TO CHANGE (MUST BE MULT. OF 3)
:         C- COLUMN # TO START WITH (MUST BE MULT. OF 3)
: OUTPUT: NO REGISTERS DISTURBED
:         DATA POINTED TO IS DISPLAYED ON LCD DISPLAY.
:         COLUMNS NOT SPECIFIED ARE NOT AFFECTED.
:
READ:
:SAVE ALL STATES
    PUSH PSW
    PUSH B
    PUSH D
    PUSH H
:FLAG FOR A READ OPERATION
    MVI A,1000000B
    STA MODE
    JMP GRAPH1
GRAPH:
:SAVE ALL STATES
    PUSH PSW
    PUSH B
    PUSH D
    PUSH H
:FLAG FOR A WRITE OPERATION
    MVI A,0
    STA MODE
:CALCULATE WHICH 58201 TO ACCESS
GRAPH1: MVI D,0EEH           :START WITH CS1
ACC:    MOV A,C
        SUI 24             :SUBTRACT 24 FROM COLUMN COUNT
        JC GO              :IF CARRY IS SET THE CORRECT CHIP IS SELECTED
        MOV C,A            :REG C GETS NEW COLUMN NUMBER
        MOV A,D
        RLC                :INCREMENT THE CS TO NEXT CHIP
        MOV D,A
        JMP ACC
:MAIN LOOP
GO:     MOV E,C             :GET COLUMN NUMBER
M_LOOP: CALL WRITE         :DRAW 3 COLUMNS
        DCR B              :SUBTRACT 3 FROM COLUMN COUNT
        DCR B
        DCR B
        JZ END.G           :IF DONE, JUMP.
        MOV A,E            :ADD 3 TO ADDRESS
        ADI 3
        CPI 11000B        :IF ADDRESS NOT MAX THEN SKIP THIS
        JNZ SKIP1
        MOV A,D
        RLC                :SELECT NEXT 58201 CS
        MOV D,A
        MVI A,0
SKIP1:  MOV E,A            :SAVE NEXT ADDRESS
        JMP M_LOOP        :LOOP UNTIL DONE
END.G:  POP H              :RESTORE ALL STATES
        POP D
        POP B
        POP PSW
        RET
WRITE:
:
: DISPLAY 3 COLUMNS OF DATA
: INPUT: HL- POINTS TO START OF DATA
:         E - ADDRESS
:         D - OUTPUT CS
: OUTPUT: HL <- HL + 3
:SAVE ALL STATES
    PUSH PSW
    PUSH B
    PUSH D
START:  MVI A,0000111B :ISOLATE CS IN REG D
        ANA D
        MOV D,A
        MOV A,E          :GET ADDRESS BITS AT HIGH END OF BYTE
        RLC
        RLC
        MOV E,A

```

```

:OUTPUT FIVE ADDRESS BITS WITH CHIP SELECT
MVI C,5
W.LOOP: MOV A,E
        RLC                                :ROTATE ADDRESS
        MOV E,A
        MVI A,10000000B
        ANA E                                :GET MSB
        ORA D                                :MERGE WITH CHIP SELECT
        CALL DISPLY
        DCR C                                :DEC ADDRESS BIT COUNTER
        JNZ W.LOOP                          :LOOP UNTIL ADDRESS IS OUT

:SIGNAL FOR A READ OR WRITE
LDA MODE
ORI 00001111B
CALL DISPLY
JP DISO                                :JUMP IF THIS IS A WRITE

:READ THE DATA
MVI B,3                                :3 BYTES OF DATA
READ1: MVI C,B                            :8 BITS PER BYTE
        MVI D,0                            :CLEAR DATA BYTE
READ2: IN 22H                             :GET A BIT OF DATA
        ANI 00000001B                       :MASK OFF UNWANTED BITS
        ORA D                                :MERGE WITH DATA BYTE
        RRC                                :ROTATE DATA
        MOV D,A
        MVI A,00001111B                       :SET UP 58201 TO READ NEXT BIT
        CALL DISPLY
        DCR C                                :LOOP UNTIL DONE WITH BYTE
        JNZ READ2
        MOV M,D
        INX H                                :INCREMENT BYTE POINTER
        DCR B                                :LOOP UNTIL DONE WITH ALL BYTES
        JNZ READ1

:RESTORE STATES
POP D
POP B
POP PSW
RET

:DISPLAY THE DATA
DISO: MVI B,3                            :3 BYTES OF DATA
DIS1: MVI C,8                            :8 BITS PER BYTE
        MOV D,M
DIS2: MOV A,D                             :ROTATE DATA
        RRC
        MOV D,A
        ANI 10000000B                       :GET NEXT BIT
        ORI 00001111B                       :SET CS
        CALL DISPLY                         :OUTPUT A BIT OF DATA
        DCR C
        JNZ DIS2                            :LOOP UNTIL DONE WITH BYTE
        INX H
        DCR B
        JNZ DIS1                            :LOOP UNTIL DONE WITH 3 BYTES

:RESTORE STATES
POP D
POP B
POP PSW
RET

DISPLY:
:DISPLAY ROUTINE
: INPUT: A - DATA AND CHIP SELECT
: BIT 7 - DATA
: BITS 0-3 - CHIP SELECT
: OUTPUT: NO REGISTERS DISTURBED
: OUTPUT ONE BIT TO 58201
PUSH PSW                                :SAVE STATES
ANI 10001111B                            :MASK OFF UNWANTED BITS
OUT 20H                                  :SET UP DATA AND CHIP SELECT
ORI 01000000B                            :CLOCK HIGH
OUT 20H
ANI 10111111B                            :CLOCK LOW
POP PSW                                  :RESTORE STATES
RET

MODE: DS 1
END

```

## TEXT

This subroutine will take the ASCII text pointed to by HL and display it on the LCD starting at the column pointed to by the memory location CURSOR. The data should end with a zero. CURSOR should be in the range of 0-15 as this is the extent of this LCD display. The first operation is the calculation of the offset into the ASCII table of the first character. Thirty-two is subtracted from the ASCII number because

the table starts with a space character. This result is then multiplied by six because the data to be displayed is six bytes long. We now have the offset into the table. The character is displayed on the LCD. This operation is repeated until all the characters have been displayed.

A custom font can be generated using the same technique as that used to create a custom graphic symbol.

```
        NSO80
        EXTRN GRAPH
        PUBLIC TEXT, LET
                TR, CURSOR

TEXT:
:DISPLAY A CHARACTER STRING ON LCD DISPLAY
:
: INPUT: HL-POINTS TO BEGINNING OF STRING
:        CURSOR-CURRENT CURSOR POSITION
: OUTPUT: CURSOR <= CURSOR + LENGTH OF STRING
:        NO REGISTERS DISTURBED

        PUSH PSW                :SAVE STATES
        PUSH H
T.LOOP: MOV A,M                  :CHECK FOR END OF STRING
        CPI 0
        JZ T.FIN
        CALL LETTR              :PRINT LETTER
        INX H
        JMP T.LOOP
T.FIN:  POP H                    :LOOP UNTIL DONE
        POP PSW                 :RESTORE STATES
        RET

LETTR:
:DISPLAY AN ASCII CHARACTER ON LCD DISPLAY
:
: INPUT: A-CHARACTER TO DISPLAY
:        CURSOR-CURRENT CURSOR LOCATION (0 - 95)
: OUTPUT: CURSOR <= CURSOR + 1
:        NO REGISTERS DISTURBED

:SAVE STATES
        PUSH PSW
        PUSH B
        PUSH D
        PUSH H

:SET UP HL TO POINT TO CORRECT DATA
        LXI H,ASCII              :HL POINTS TO BASE ADDRESS
        MVI B,0                  :BC GETS ASCII OFFSET MINUS A CONSTANT
        SUI 20H
        MOV C,A
        CALL MULT                 :MULTIPLY OFFSET BY 6 (DOUBLE PRECISION)
        DAD B                    :HL POINTS TO CORRECT CHARACTER DATA
        LDA CURSOR               :MULTIPLY CURSOR BY 6 TO GET COLUMN NUMBER
        MOV B,A
        ADD B
        ADD B
        ADD B
        ADD B
        ADD B
        MOV C,A
        MVI B,6                  :EACH CHARACTER IS SIX COLUMNS WIDE
        CALL GRAPH               :DISPLAY THE CHARACTER
        LDA CURSOR               :INCREMENT CURSOR
        INR A
        CPI 16                   :CHECK FOR END OF LCD DISPLAY
        JNZ T.END
        MVI A,0                  :IF SO, RESET TO ZERO
T.END:  STA CURSOR

:RESTORE STATES
        POP H
        POP D
        POP B
        POP PSW
        RET
```

```

MULT:
: MULTIPLY BC REG BY SIX
: INPUT: BC - MULTPLICAND
: OUTPUT: BC <= BC * 6
: NO REGISTERS DISTURBED

PUSH PSW
MOV H,B
MOV L,C
DAD B
DAD B
DAD B
DAD B
MOV B,H
MOV C,L
POP H
POP PSW
RET

```

```

CURSOR: DS 1
ASCII: DS 0,0,0,0,0,0,0
:SPACE
:1 DS 0,95,95,0,0,0
:2 DS 0,7,0,7,0,0
:3 DS 20,127,20,127,20,0
:4 DS 36,42,127,42,18,0
:5 DS 35,19,8,100,98,0
:6 DS 54,73,102,32,80,0
:7 DS 0,0,7,0,0,0
:8 DS 0,28,34,65,0,0
:9 DS 0,53,34,28,0,0
:0 DS 34,20,127,20,34,0
:1 DS 8,8,82,8,8,0
:2 DS 0,84,48,0,0,0
:3 DS 8,8,8,8,8,0
:4 DS 0,96,96,0,0,0
:5 DS 32,16,8,4,2,0
:6 DS 62,81,73,69,62,0
:7 DS 0,66,127,64,0,0
:8 DS 128,73,73,73,70,0
:9 DS 34,66,73,73,64,0
:0 DS 15,8,8,128,8,0
:1 DS 39,69,69,69,67,0
:2 DS 62,73,73,73,48,0
:3 DS 1,97,17,9,7,0
:4 DS 54,73,73,73,54,0
:5 DS 8,9,9,126,0
:6 DS 0,84,84,0,0,0
:7 DS 96,54,84,0,0,0
:8 DS 8,20,34,65,0,0
:9 DS 20,20,20,20,20,0
:0 DS 0,66,34,20,8,0
:1 DS 2,1,68,16,2,0
:2 DS 62,66,93,89,78,0
:3 DS 124,19,17,18,124,0
:4 DS 127,73,73,73,84,0
:5 DS 62,66,66,66,34,0
:6 DS 127,66,66,66,62,0
:7 DS 127,73,73,65,65,0
:8 DS 127,9,9,1,1,0
:9 DS 62,66,66,61,14,0
:0 DS 127,8,8,8,127,0
:1 DS 0,66,127,66,0,0
:2 DS 32,64,64,64,63,0
:3 DS 127,8,20,34,66,0
:4 DS 127,64,64,64,64,0
:5 DS 127,2,12,2,127,0
:6 DS 127,4,8,16,127,0
:7 DS 62,66,66,66,62,0
:8 DS 127,9,9,9,6,0
:9 DS 62,66,81,33,94,0
:0 DS 127,9,25,41,70,0
:1 DS 34,69,73,81,34,0
:2 DS 1,1,127,1,1,0
:3 DS 63,64,64,64,63,0
:4 DS 31,92,64,32,91,0
:5 DS 127,32,24,32,127,0
:6 DS 99,20,8,20,99,0
:7 DS 3,4,120,4,3,0
:8 DS 97,81,73,69,67,0
:9
:0
:1
:2

```

END

## SCROLL

This subroutine will scroll whatever is displayed on the LCD to the right until the screen is clear. It first reads in three columns of data. It then writes three columns of data with the HL pointer shifted by one byte. This will shift the displayed data by one column. This is repeated until the

entire LCD has been shifted by one column. Then the entire operation is repeated until all the displayed data is shifted off the screen.

This subroutine could easily be adapted to scroll the display to the left if desired.

```
NS080
PUBLIC SCROLL
EXTRN READ,GRAPH
```

```
SCROLL:
:SCROLLS DISPLAY TO THE RIGHT UNTIL CLEAR
: INPUT: NONE
: OUTPUT: NO REGISTERS ARE CHANGED
: SCREEN IS SCROLLED UNTIL CLEAR

:SAVE ALL STATES
PUSH PSW
PUSH B
PUSH D
PUSH H

:SET UP ALL THE POINTERS
MVI D,96
REPEAT: MVI A,0          :LOOP UNTIL SCREEN IS CLEAR (96 CYCLES)
        STA BUFFER      :CLEAR FIRST BYTE IN BUFFER
        MVI B,3         :READ 3 COLUMNS ALWAYS
        MVI C,0         :START WITH COLUMN ZERO

:READ THE DATA
L.READ: LXI H,BUFFER+1  :SET HL TO POINT TO BUFFER+1
        CALL READ       :SET HL TO SHIFT THE DATA
        LXI H,BUFFER    :REDRAW THE SHIFTED DATA
        CALL GRAPH

:MOVE LAST COLUMN OF LAST READ INTO FIRST COLUMN OF NEXT WRITE
LDA BUFFER+3
STA BUFFER

:UPDATE COUNTERS
MOV A,C                :INCREMENT COLUMN NUMBER
ADI 3
MOV C,A
CPI 96                 :CHECK IF DONE WITH ONE CYCLE
JNZ L.READ
DCR D                  :DECREMENT LOOP COUNT
JNZ REPEAT             :LOOP UNTIL DONE WITH ALL CYCLES

:RESTORE STATES
POP H
POP D
POP B
POP PSW
RET

BUFFER: DS 4

END
```

**OTHER APPLICATIONS**

There are many different types of LCDs that can be controlled by the MM58201. Some of these are shown in Figure 18.

Up to 24 seven-segment digits can be controlled by one MM58201. The software to control a multiplexed seven-segment display is not too much different from that of the previous application. The software is simpler because only one MM58201 is needed instead of four. A logic diagram for a six-digit multiplexed seven-segment LCD display is shown in Figure 19 and the software to control it is in listing 5.

Given a string of numbers to display, this subroutine simply looks up the data it needs from a look-up table and stores this data in a buffer. After every three digits, the subroutine sends this data to the MM58201 to be displayed. The digit backplanes are wired backward in groups of three to simplify the software. The subroutines that this subroutine uses are very similar to the equivalent subroutines in the LCD dot matrix application. Since there is only one MM58201, the software is simpler. There is no need to calculate which MM58201 chip select to enable.

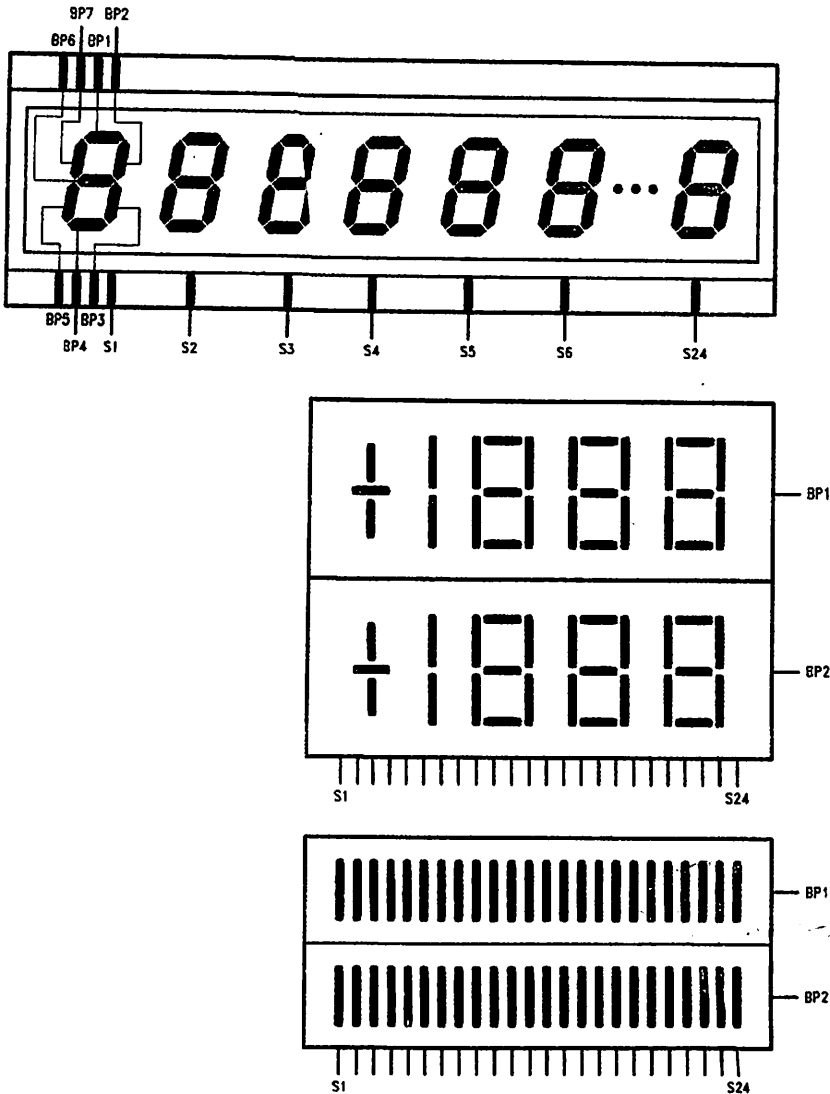


FIGURE 18. Typical LCD Connections to the MM58201

TL/G/5606-21



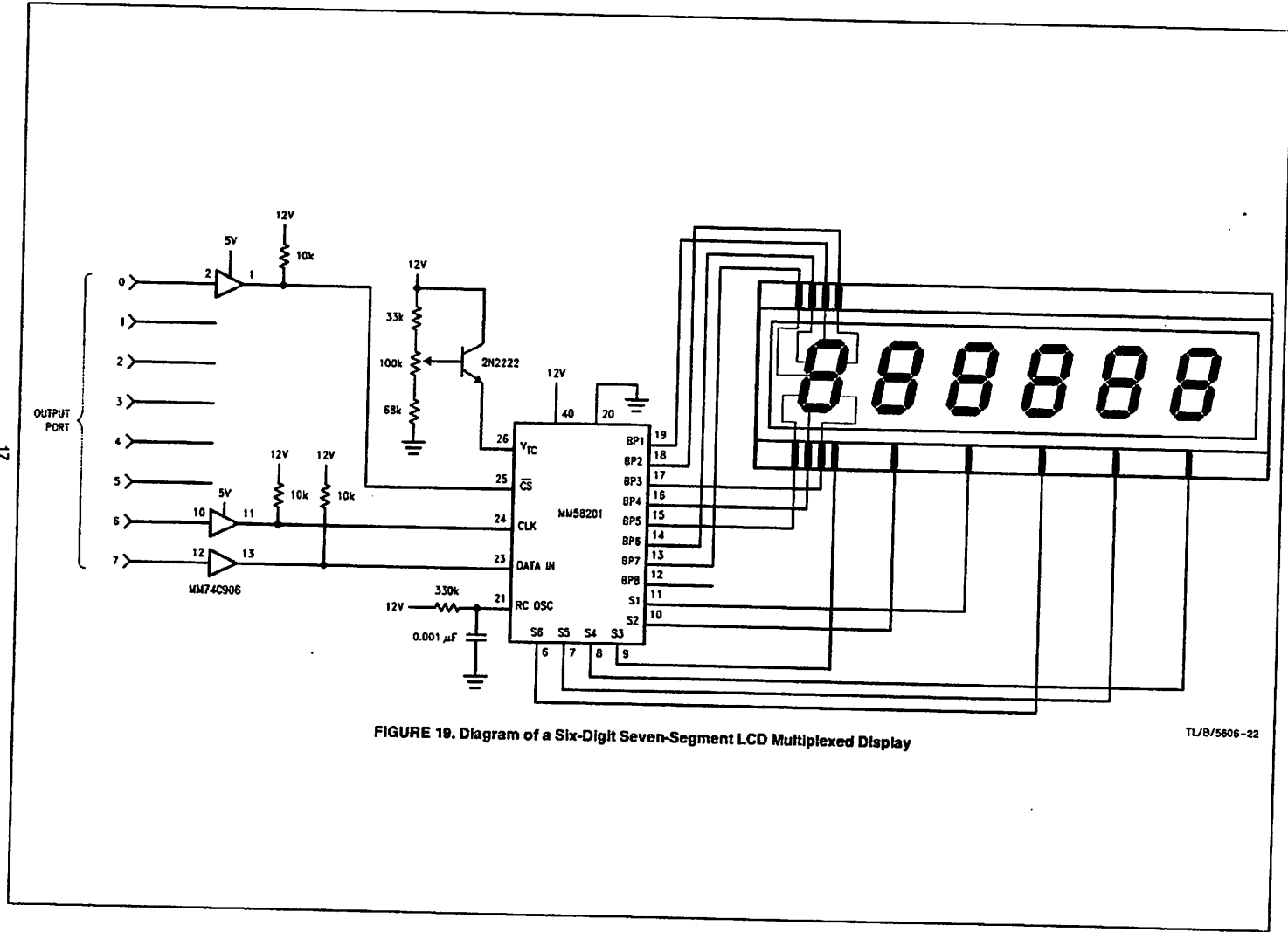


FIGURE 19. Diagram of a Six-Digit Seven-Segment LCD Multiplexed Display

TLB/5606-22

```

W3020
:INITIALIZE THE 810
  MV A,0
  OUT 27H
  MVI A,OFFH
  OUT 24H

  LXI BC,TEST
  MVI E,6
  CALL NUMBER
  RST 6

TEST:  DB 1,2,3,4,5,6

:SUBROUTINE TO DISPLAY NUMERALS ON LCD DISPLAY
: INPUT  BC-POINTS TO BCD DATA STRING
:        E -LENGTH OF DATA STRING (MULTIPLE OF 3)
: OUTPUT -NO REGISTERS DISTURBED
:        -DATA STRING IS DISPLAYED
:
NUMBER: PUSH PSW           :SAVE STATES
        PUSH B
        PUSH D
        PUSH H

DIG3:  MVI D,3             :LOOP FOR 3 DIGITS
LOOP:  LDAX B
        LXI H,TABLE       :CALCULATE ADDRESS INTO TABLE
        ADD L
        MOV L,A
        MVI A,OOH
        ADC H
        MOV H,A

        MOV A,H           :GET OUTPUT DATA FROM TABLE
        PUSH PSW

        LXI H,DATA       :STORE INTO DATA BUFFER
        MOV A,L
        ADD D
        MOV L,A
        DCR L
        POP PSW
        MOV M,A

        INX B             :INCREMENT POINTER TO DATA STRING
        DCR E             :DECREMENT # OF DIGITS
        DCR D             :DECREMENT 3 DIGIT COUNT
        JNZ LOOP         :IF NOT THIRD DIGIT THEN LOOP BACK

        LXI H,DATA
        CALL WRITE       :DISPLAY THESE THREE DIGITS

        MOV A,E           :CHECK FOR LAST DIGIT OF DATA STRING
        ANA A
        JNZ DIG3

        POP H             :RESTORE STATES
        POP D
        POP B
        POP PSW
        RET

WRITE:
: DISPLAY 3 DIGITS
: INPUT  HL-POINTS TO START OF DATA
:        E -COLUMN ADDRESS
: OUTPUT -NO REGISTERS DISTURBED
:
        PUSH PSW         :SAVE STATES
        PUSH B
        PUSH D
        PUSH H

        MOV A,E           :GET ADDRESS BITS AT HIGH END OF BYTE
        RLC
        RLC
        MOV E,A

```

```

:OUTPUT FIVE ADDRESS BITS
MVI C,3
W.LOOP: MOV A,E
        RLC
        MOV E,A           :ROTATE ADDRESS
        MVI A,10000000B  :GET MSB & ENABLE CHIP SELECT BIT
        ANA E
        CALL OUT        :OUTPUT BIT WITH CHIP SELECT
        DCR C
        JNZ W.LOOP      :LOOP UNTIL ADDRESS IS OUT

:SIGNAL FOR A WRITE
MVI A,00H
CALL OUT           :OUTPUT A ZERO BIT

:OUTPUT THE DATA
MVI B,3
DIS1:  MVI C,B         :3 BYTES OF DATA
        MOV D,N        :8 BITS PER BYTE
DIS2:  MOV A,D         :ROTATE DATA
        RRC
        MOV D,A
        ANI 10000000B  :GET NEXT BIT
        ORI 00000001B  :DISABLE CHIP SELECT
        CALL OUT
        DCR C
        JNZ DIS2      :LOOP UNTIL DONE WITH BYTE
        INX H
        DCR B
        JNZ DIS1      :LOOP UNTIL DONE WITH 3 BYTES

        POP H          :RESTORE STATES
        POP D
        POP B
        POP PSW
        RET

OUT:
:SUBROUTINE TO OUTPUT ONE BIT TO THE MM58201
: INPUT A -DATA BIT IN MSB POSITION
: OUTPUT -NO REGISTERS DISTURBED
: -OUTPUT ONE BIT TO 58201

        PUSH PSW
        OUT 20H
        ORI 01000000B  :CLOCK HIGH
        OUT 20H
        ANI 10111111B  :CLOCK LOW
        OUT 20H
        POP PSW
        RET

DATA: DS 3
TABLE: DB 00111111B, 00000110B, 01011011B, 01001111B
        DB 01100110B, 01101101B, 01111101B, 00000111B
        DB 01111111B, 01101111B

```

END

#### SUMMARY

The MM58201 makes it easy to interface a multiplexed LCD display to a microprocessor. It is simply a matter of connecting the display and the microprocessor to the chip, choosing a value for  $V_{CT}$ , then interfacing your program to use the

subroutines listed here or similar ones. Multiplexed LCDs are the perfect way to cut down on display interconnections while still taking advantage of the LCD's low power consumption and high contrast ratio—and the MM58201 makes them easy to use.

**LIFE SUPPORT POLICY**

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



**National Semiconductor Corporation**  
 1111 West Bardin Road  
 Arlington, TX 76017  
 Tel: 1(800) 272-9959  
 Fax: 1(800) 737-7016

**National Semiconductor Europe**  
 Fax: (+49) 0-180-530 85 85  
 Email: crtwg@tevm2.nsc.com  
 Deutsch Tel: (+49) 0-180-530 85 85  
 English Tel: (+49) 0-180-532 78 32  
 Français Tel: (+49) 0-180-532 83 58  
 Italiano Tel: (+49) 0-180-534 16 80

**National Semiconductor Hong Kong Ltd.**  
 13th Floor, Straight Block,  
 Ocean Centre, 5 Canton Rd.  
 Tsimshatsui, Kowloon  
 Hong Kong  
 Tel: (852) 2737-1600  
 Fax: (852) 2736-9960

**National Semiconductor Japan Ltd.**  
 Tel: 81-043-299-2309  
 Fax: 81-043-298-2408

National does not assume any responsibility for use of any circuitry described, no circuit patents are listed and National reserves the right at any time without notice to change said circuitry and specifications.

# LM124/LM224/LM324/LM324M

## Low Power Quad Operational Amplifiers

### General Description

The LM124 series consists of four independent, high gain, internally frequency compensated, operational amplifiers which were designed specifically to operate from a wide range of power supply voltages and to require only a single power supply. The quiescent current is independent of the power supply voltage.

Application areas include: signal processing, instrumentation, and all the conventional op amp applications. The LM124 series can be more easily implemented in digital systems. For example, the LM124 series can be used in digital systems to interface electronics without requiring the additional power supplies.

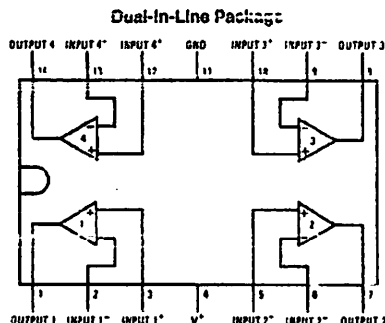
### Unique Characteristics

- In the linear mode the input common-mode voltage range includes ground and swings to ground, even though operated from only a single power supply voltage
- The unity gain cross frequency is temperature compensated
- The input bias current is also temperature compensated

### Advantages

- Common-mode input voltage range includes ground
- Wide power supply range: Single supply 3V to 32V or dual supply  $\pm 1.5V$  to  $\pm 16V$
- Low input offset voltage and offset current
- Input bias current is temperature compensated
- Differential input voltage range extends to the power supply voltage

### Connection Diagrams

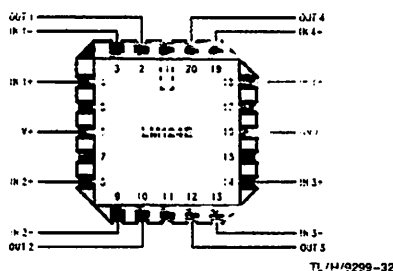


TL/H/9299-1

#### Top View

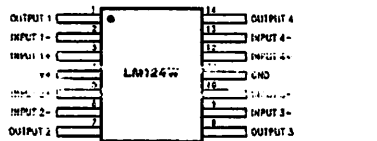
Order Number LM124J, LM124AJ, LM124J/883\*\*, LM124AJ/883\*, LM224J, LM224AJ, LM224J/883\*\*, LM224AJ/883\*, LM324AM, LM2902\*\*, LM324M, LM324M/883\*\*  
See NS Package Number J14A, M14A or N14A

\*LM124A available per JMS3510/11006  
\*\*LM124 available per JMS3510/11005



TL/H/9299-32

Order Number LM124AE/883\*\* or LM124AJE/883\*  
See NS Package Number E88A



TL/H/9299-33

Order Number LM124AW/883\*\* or LM124AJW/883\*  
See NS Package Number W14B

LM124/LM224/LM324/LM324M Low Power Quad Operational Amplifiers

## Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications. (Note 9)

	LM124/LM224/LM324 LM124A/LM224A/LM324A	LM2902	LM124/LM224/LM324 LM124A/LM224A/LM324A	LM2902
Supply Voltage, V <sup>+</sup>	32V	26V	-65°C to +150°C	-65°C to +150°C
Differential Input Voltage	32V	26V	Lead Temperature (Soldering, 10 seconds)	260°C
Input Voltage	-0.3V to +32V	-0.3V to -26V	Soldering Information	260°C
Input Current			Dual-In-Line Package	
V <sub>IN</sub> < 0.3V (Note 3)	50 mA	50 mA	Soldering (10 seconds)	260°C
Power Dissipation (Note 1)			Small Outline Package	
Maximum Power Dissipation	1130 mW	1130 mW	Vapor Phase (60 seconds)	215°C
Maximum Power Dissipation (Soldered Package)	1260 mW	1260 mW	Infrared (15 seconds)	220°C
Maximum Power Dissipation (Through-Hole Package)	800 mW	800 mW	See A-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.	
Electrostatic Discharge (ESD) Sensitivity to Human Body Model (HBM)			ESD Sensitivity (Note 10)	2kV
Operating Temperature Range	Continuous	Continuous		
Storage Temperature Range	0°C to +70°C	-40°C to +85°C		
	-25°C to +85°C			
	-55°C to +125°C			

Electrical Characteristics V<sup>+</sup> = 5.0V (Note 4), unless otherwise stated

Conditions	LM124A		LM224A		LM324A		LM124/LM224		LM324		LM2902		Units
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage (Note 5) T <sub>A</sub> = 25°C	1	2	3	2	3	2	2	5	2	7	2	7	mV
Input Bias Current (I <sub>B</sub> ) (V <sub>IN</sub> = 0V, V <sub>OUT</sub> = 0V, T <sub>A</sub> = 25°C)	20	50	40	80	5	10	45	50	5	200	40	50	nA
Input Bias Current (I <sub>B</sub> ) (V <sub>IN</sub> = 0V, V <sub>OUT</sub> = 0V, T <sub>A</sub> = 55°C)	2	10	2	15	5	10	3	30	5	5	5	10	nA
Common-Mode Voltage Range (LM2902: 2.0V to 26V, LM124/LM224: 2.0V to 32V)	V <sup>+</sup> - 1.5		0		V <sup>+</sup> - 1.5		0		V <sup>+</sup> - 1.5		0		V
Output Current Sinking Capability (V <sub>OUT</sub> = 0V, V <sub>IN</sub> = 0V, T <sub>A</sub> = 25°C)	1.5	3	1.5	3	1.5	3	1.5	3	1.5	3	1.5	3	mA
Output Current Sinking Capability (V <sub>OUT</sub> = 0V, V <sub>IN</sub> = 0V, T <sub>A</sub> = 55°C)	0.7	1.2	0.7	1.2	0.7	1.2	0.7	1.2	0.7	1.2	0.7	1.2	mA
Output Resistance (R <sub>OUT</sub> ) (V <sub>OUT</sub> = 0V, V <sub>IN</sub> = 0V, T <sub>A</sub> = 25°C)	9	100	50	100	5	100	50	100	5	100	25	100	Ω
Output Resistance (R <sub>OUT</sub> ) (V <sub>OUT</sub> = 0V, V <sub>IN</sub> = 0V, T <sub>A</sub> = 55°C)	9	15	70	80	5	15	70	80	5	15	50	70	Ω
Output Resistance (R <sub>OUT</sub> ) (V <sub>OUT</sub> = 0V, V <sub>IN</sub> = 0V, T <sub>A</sub> = 125°C)	5	100	65	100	5	100	65	100	5	100	50	100	Ω

**Electrical Characteristics**  $V^+ = -1.5.0V$  (Note 4) unless otherwise stated (Continued)

Parameter	Conditions	LM124A		LM224A		LM324A		LM124/LM224		LM324		LM2002		Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Amplifier-to-Amplifier Coupling (Note 8)	$f = 1 \text{ kHz to } 20 \text{ kHz}, T_A = 25^\circ\text{C}$ (Input Referenced)	-120		-120		-120		-120		-120		-120		dB
Output Current	Source $V_{IN}^+ = 1V, V_{IN}^- = 0V,$ $V_{CC} = 15V, V_O = 2V, T_A = 25^\circ\text{C}$	20	40	20	40	20	40	20	40	20	40	20	40	mA
	Sink $V_{IN}^+ = 1V, V_{IN}^- = 0V,$ $V_{CC} = 15V, V_O = 2V, T_A = 25^\circ\text{C}$	10	20	10	20	10	20	10	20	10	20	10	20	mA
	$V_{IN}^+ = 1V, V_{IN}^- = 0V,$ $V_{CC} = 15V, V_{IC} = 200 \text{ mV}, T_A = 25^\circ\text{C}$	12	50	12	50	12	50	12	50	12	50	12	50	$\mu\text{A}$
Short Circuit to Ground	$V_{CC} = 15V, T_A = 25^\circ\text{C}$	40	60	40	60	40	60	40	60	40	60	40	60	mA
Output Offset Voltage		4		4		5		7		9		10		mV
Common-Mode Rejection Ratio	$f = 1 \text{ kHz}$	70		70		70		70		70		70		dB
Power Consumption	$V_{CC} = 15V, V_{IC} = 1V$	30		30		75		100		150		200		$\mu\text{A}$
Frequency Response	$f = 1 \text{ kHz}$	10	200	10	200	10	300	10		10		10		Hz
Load Regulation	$V_{CC} = 15V$	40	100	40	100	40	200	40	300	40	500	40	500	mA
Power Dissipation	$V_{CC} = 15V, T_A = 25^\circ\text{C}$	1	$V^+ - 2.0$	1	$V^+ - 2.0$	1	$V^+ - 2.0$	1	$V^+ - 2.0$	1	$V^+ - 2.0$	1	$V^+ - 2.0$	W
Propagation Delay	$t_{pd} = 1V$	5		25		10		5		5		15		ns
Settling Time	$R_L = 2 \text{ k}\Omega$	6		26		10		6		16		20		ns
	$R_L = 1 \text{ k}\Omega$	7	25	27	20	10	20	10	20	17	20	20	20	ns
	$R_L = 1 \text{ }\Omega$	20		20		20		5	20	20		20		ns

## Electrical Characteristics $V^+ = +5.0V$ (Note 4) unless otherwise stated (Continued)

Parameter	Conditions	LM124A			LM224A			LM324A			LM124/LM224			LM324			LM2902			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Output Current	Source	$V_{IN}^+ = +1V, V_{IN}^- = 0V, V^+ = 15V$			10	20		10	20		10	20		10	20		10	20		mA
	Sink	$V_{IN}^- = +1V, V_{IN}^+ = 0V, V^+ = 15V$			10	15		5	8		5	8		5	8		5	8		

Note 1: For operating at high temperatures, the LM324/LM324A/LM2902 must be derated based on a +125°C maximum junction temperature and a thermal resistance of 88°C/W which applies for the device soldered in a printed circuit board, operating in a still air ambient. The LM224/LM224A and LM124/LM124A can be derated based on a +150°C maximum junction temperature. The dissipation is the total of all four amplifiers—use external resistors, where possible, to allow the amplifier to saturate or to reduce the power which is dissipated in the integrated circuit.

Note 2: Short circuits from the output to  $V^+$  can cause excessive heating and eventual destruction. When considering short circuits to ground, the maximum output current is approximately 40 mA independent of the magnitude of  $V^+$ . At values of supply voltage in excess of +15V, continuous short-circuits can exceed the power dissipation ratings and cause eventual destruction. Destructive dissipation can result from simultaneous shorts on all amplifiers.

Note 3: This input current will only exist when the voltage at any of the input loads is driven negative. It is due to the collector-base junction of the input PNP transistors becoming forward biased and thereby acting as input diode clamp. In addition to this diode action, there is also lateral NPN parasitic transistor action on the IC chip. This transistor action can cause the output voltages of the op amps to rise to the  $V^+$  voltage level (or to ground for a large overdrive) for the time duration that an input is driven negative. This is not destructive and normal output states will re-establish when the input voltage, which was negative, returns to a value greater than -0.3V (at 25°C).

Note 4: These specifications are limited to -55°C ≤  $T_A$  ≤ +125°C for the LM124/LM124A. With the LM224/LM224A, all temperature specifications are limited to -25°C ≤  $T_A$  ≤ +85°C. The LM2902 specifications are limited to -40°C ≤  $T_A$  ≤ +85°C.

Note 5:  $V_{IN}^- = 0V$  with  $V^+$  from 5V to 30V and over the full input common-mode range (0V to  $V^+ - 1.5V$ ) for LM2902,  $V^+$  from 5V to 26V.

Note 6: The distortion of the input current is due to the PNP input stage. This current is essentially constant, independent of the state of the output so no loading effects on the input lines.

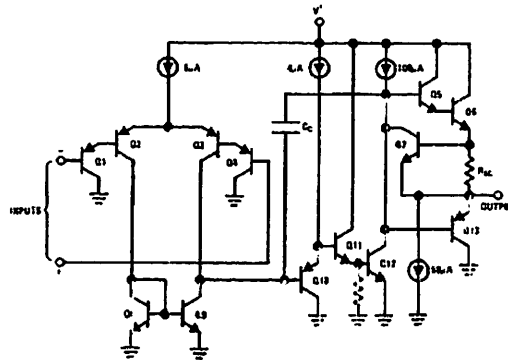
Note 7: The input common-mode voltage of the input ground should not be allowed to go negative by more than 0.3V (at 25°C). The upper end of the common-mode voltage range is  $V^+ - 1.7V$  (at 25°C) but either 4 bits.

Note 8: The output of the differential pair is not originating via stray capacitance between these external parts. This typically can be set and adjusted by the capacitor.

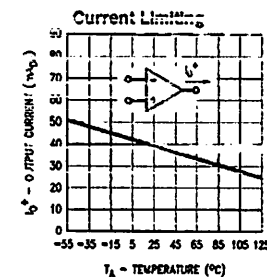
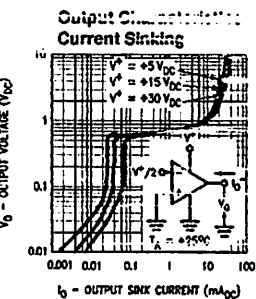
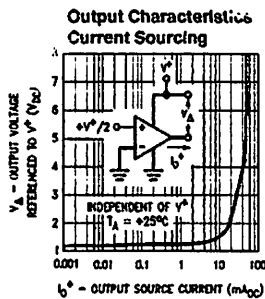
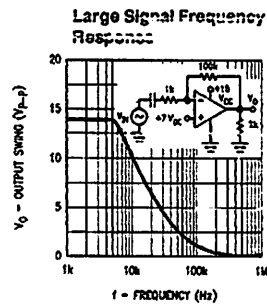
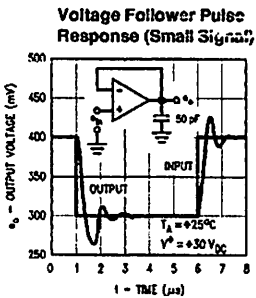
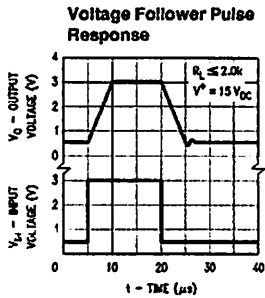
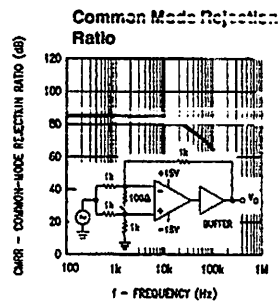
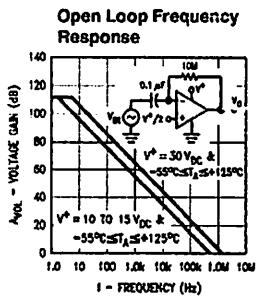
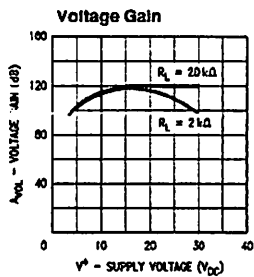
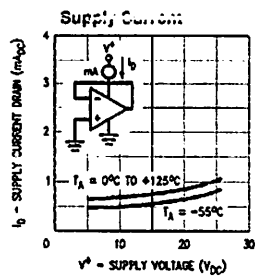
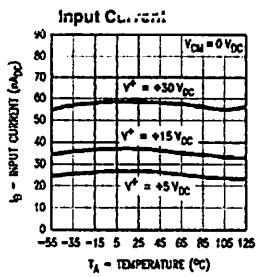
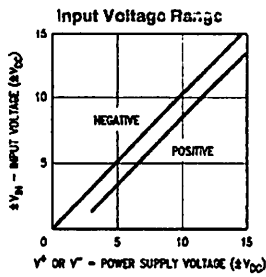
Note 9: For the LM124, LM224, LM324, and LM2902 refer to RETS124X for LM124 military specifications.

Note 10: For the LM124, LM224, LM324, and LM2902 refer to RETS124X for LM124 military specifications.

Note 11: For the LM124, LM224, LM324, and LM2902 refer to RETS124X for LM124 military specifications.

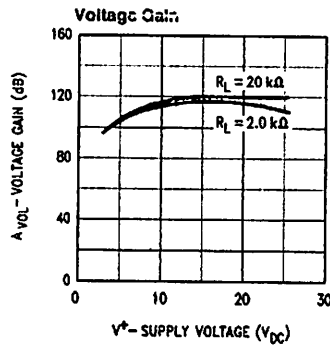
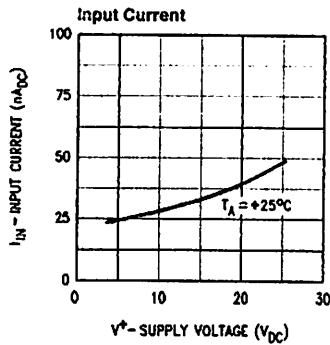


# Typical Performance Characteristics



TL/H/0209-3

## Typical Performance Characteristics



TL/H/0209-4

## Application Hints

The LM124 series are op amps which operate with a single power supply voltage, have two differential inputs and remain in the linear mode with an input common mode voltage of 0 V<sub>DC</sub>. These amplifiers operate over a wide range of power supply voltage with little change in performance characteristics. At 25°C differential operation is possible down to a minimum supply voltage of 1.0 V.

The pinouts of the package have been designed to simplify PC board layouts. Inverting inputs are adjacent to output for all of the amplifiers and the output pins are placed at the corners of the package (pins 1, 4, 8, and 11). Precautions should be taken to insure that the power supply for the integrated circuit is not inadvertently connected to a test socket as an unlimited current source. A reverse-biased diode within the IC could cause fusion of the internal conductors and result in a defective unit.

Large differential input voltages can be applied, provided and, as input differential voltage protection diodes are not needed, no large input currents result from large differential input voltages. The differential input voltage can be larger than  $V^+$  without damaging the device. Protection should be provided to prevent the input from going to a negative mode.

To reduce the power supply drain, the amplifier can be operated in class A or class B in a large signal mode. The output can be connected to both source and sink loads. The output can be connected to both NPN and PNP external output load terminals and can be used to extend the power capability of the device output pins. The output voltage drop above ground to bias the external output load transistor for output current sinking applications.

For ac applications, where the output is connected to the output of the amplifier, a resistor should be connected to the output of the amplifier to ground to increase the bias current and prevent crossover distortion.

Capacitive loads must be applied directly to the output of the amplifier and should be connected using the smallest value possible to vary unity gain cut-off frequency. Edge-coupled loads can be used to reduce the risk of oscillation.

The bias network of the device determines a certain current through the output stage. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

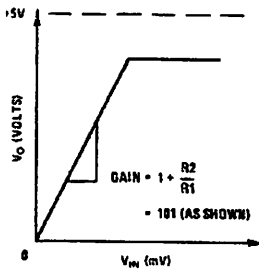
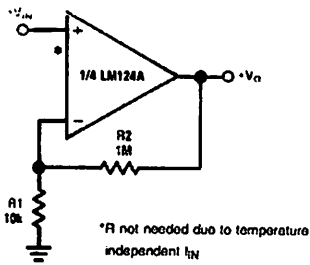
Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

Output short-circuit current is greater than the quiescent current. The output current is limited by the output stage.

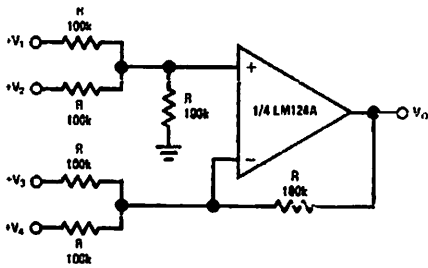
# Typical Single Supply Applications

## Non-Inverting DC Gain (Input $V_{IN} < 0.1 V_{DC}$ )



TL/H/9299-5

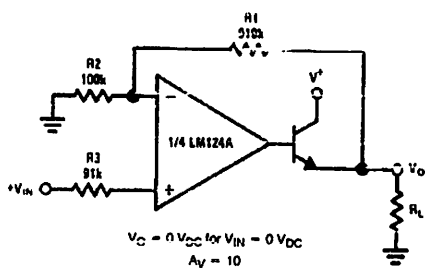
## DC Summing Amplifier ( $V_{INS} \geq 0 V_{DC}$ and $V_O \leq V_{DC}$ )



TL/H/9299-6

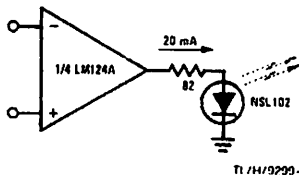
Where:  $V_O = V_1 + V_2 - V_3 - V_4$   
 $(V_1 + V_2) \geq (V_3 + V_4)$  to keep  $V_O > 0 V_{DC}$

## Power Amplifier



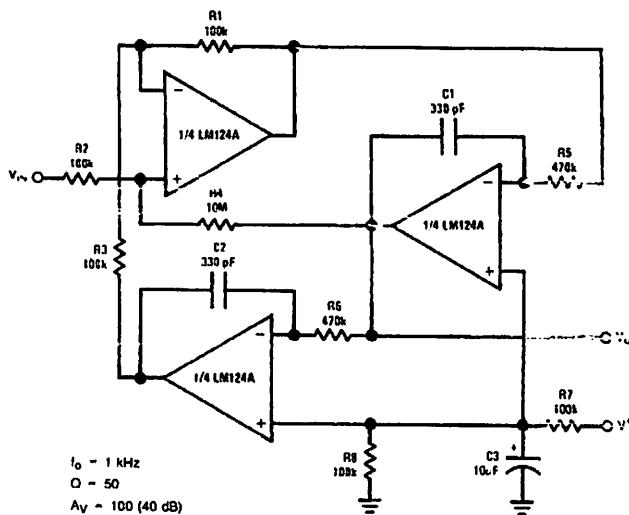
TL/H/9299-7

## LED Driver



TL/H/9299-8

## "BI-QUAD" RC Active Bandpass Filter

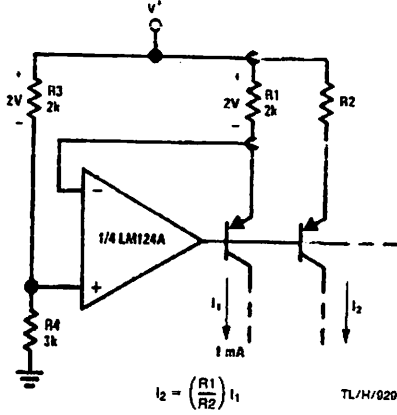


$f_o = 1 \text{ KHz}$   
 $Q = 50$   
 $A_V = 100 \text{ (40 dB)}$

TL/H/9299-9

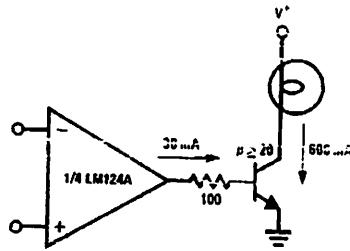
Typical Single-Supply Applications (Continued)

Fixed Current Source



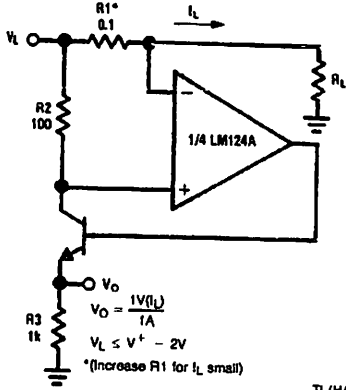
TL/H/9299-10

Lamp Driver



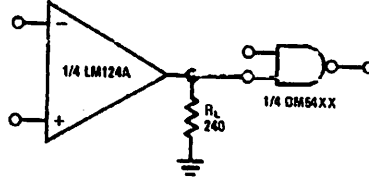
TL/H/9299-11

Current Monitor



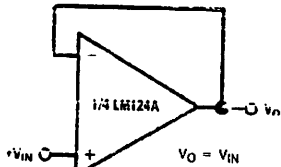
TL/H/9299-12

Driving TTL



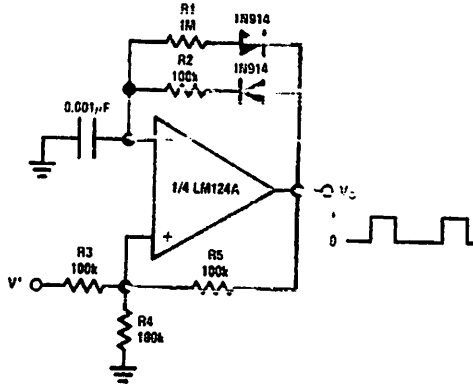
TL/H/9299-13

Voltage Follower



TL/H/9299-14

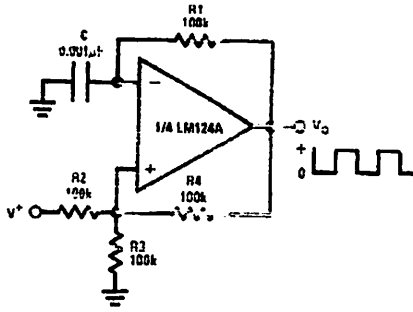
Pulse Generator



TL/H/9299-15

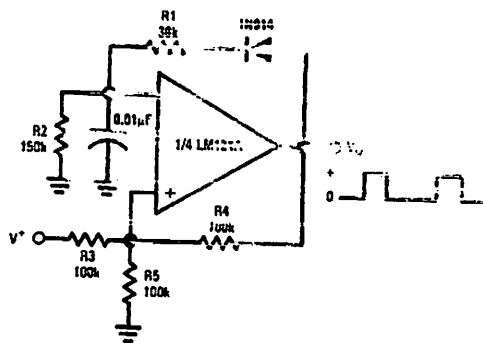
# Typical Single-Supply Applications (0.5 V<sub>CC</sub> (MINIMUM))

## Squarewave Generator



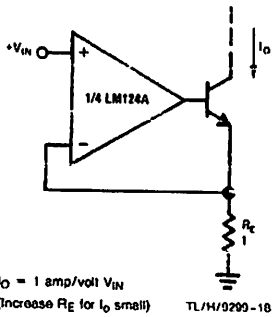
TL/H/9299-16

## Pulse Generator



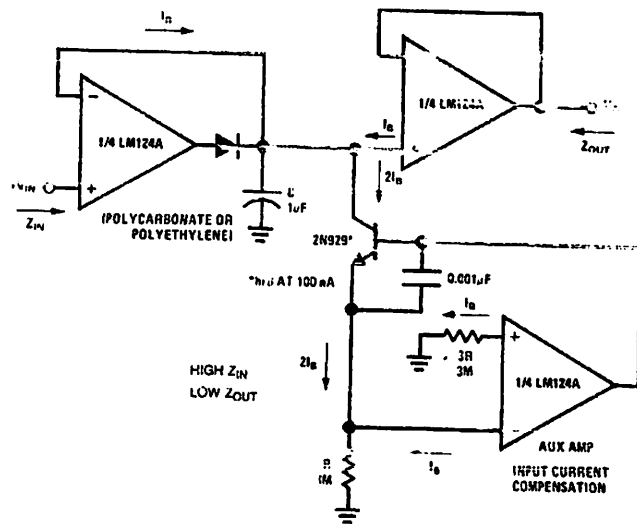
TL/H/9299-17

## High Compliance Current Sink



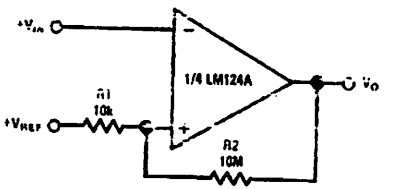
TL/H/9299-18

## Low Distortion Current Source



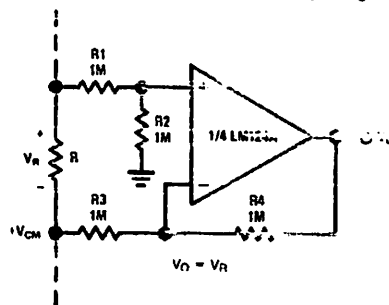
TL/H/9299-19

## Comparator with Hysteresis



TL/H/9299-20

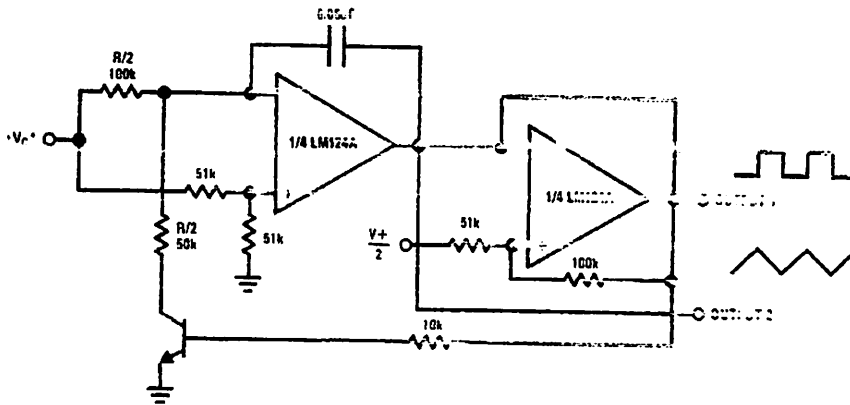
## Ground Referencing a Differential Input Signal



TL/H/9299-21

## Typical Single Supply Applications (0 to 5.0 VDC)

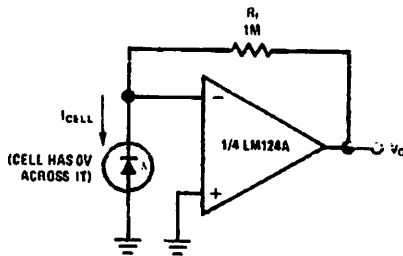
### Voltage Controlled Oscillator



\*Wide control voltage range:  $0 \text{ VDC} \leq V_C \leq 2 (V^+ - 1.5 \text{ VDC})$

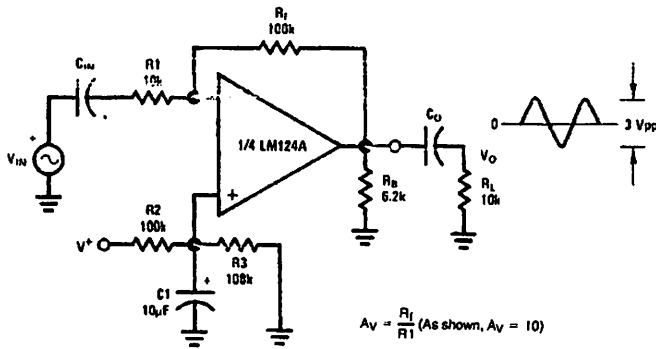
TL/H/9299-22

### Photo Voltaic-Cell Amplifier



TL/H/9299-23

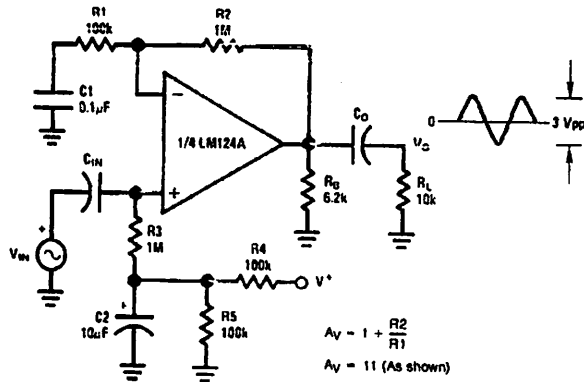
### AC Coupled Inverting Amplifier



TL/H/9299-24

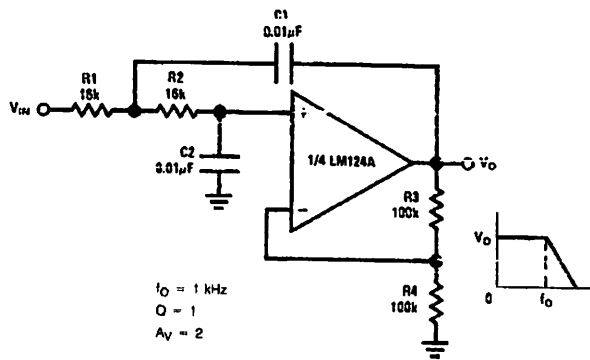
# Typical Single Supply Applications (5.0V V<sub>CC</sub>)

## AC Coupled Non-Inverting Amplifier



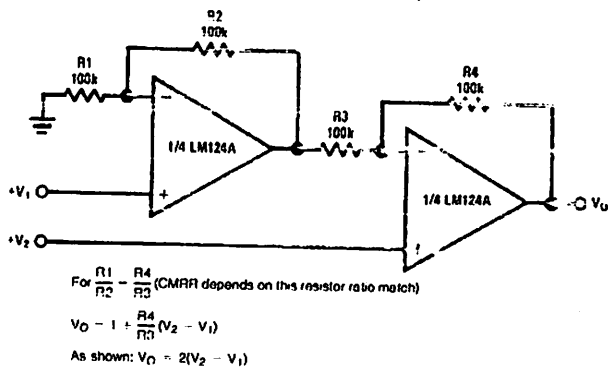
TL/H/9299-25

## DC Coupled Low-Pass RC Active Filter



TL/H/9299-26

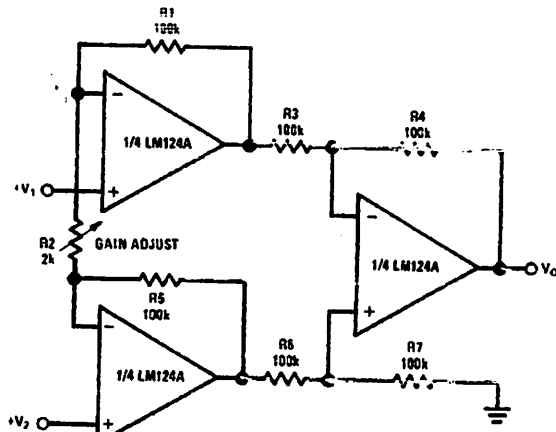
## High Input Z, DC Differential Amplifier



TL/H/9299-27

Typical Single Supply Applications

High Input Z<sub>in</sub> DC Instrumentation Amplifier



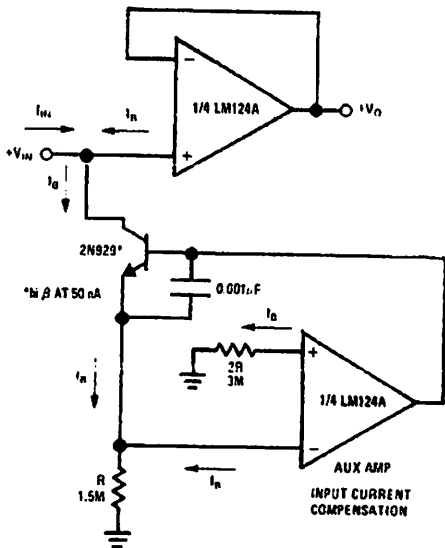
If  $R1 = R5$  &  $R3 = R4 = R6 = R7$  (CMRR depends on match)

TL/H/9299-28

$$V_0 = 1 + \frac{2R1}{R2} (V_2 - V_1)$$

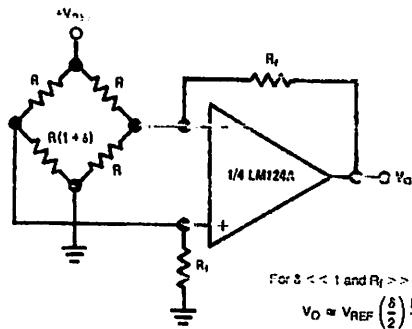
As shown  $V_0 = 101 (V_2 - V_1)$

Using Symmetrical Amplifiers to Reduce Input Current



TL/H/9299-29

Bridge Current Amplifier



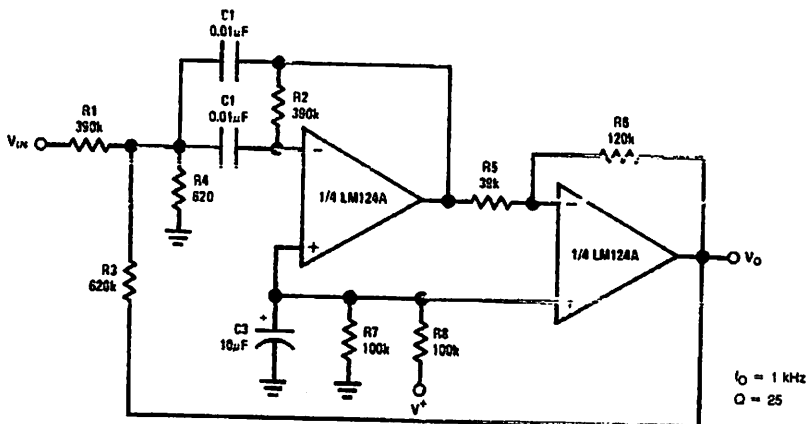
For  $\delta \ll 1$  and  $R_f \gg R$

$$V_0 \approx V_{REF} \left( \frac{\delta}{2} \right) \frac{R_f}{R}$$

TL/H/9299-30

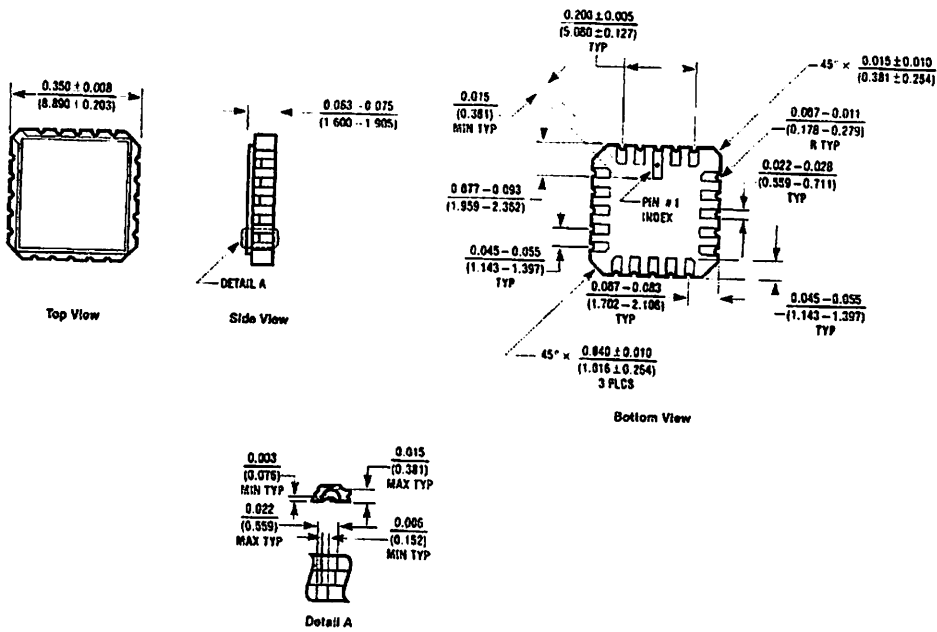
# Typical Single Supply Applications (V<sub>CC</sub> = 5.0 VDC)

## Bandpass Active Filter



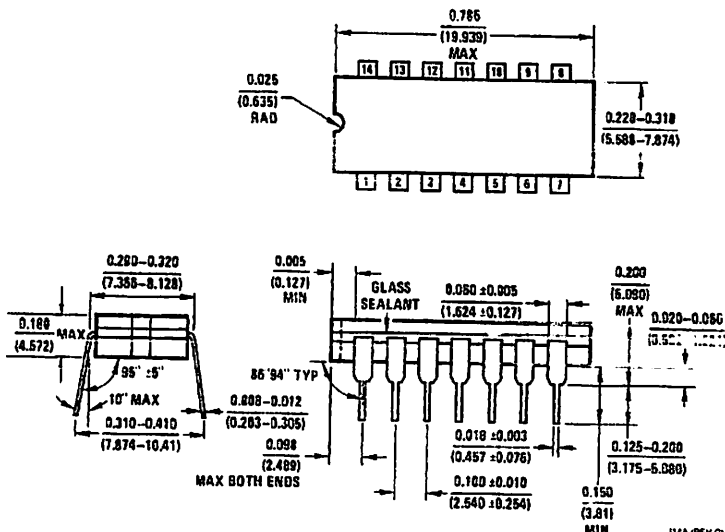
TL/H/0200-31

**Physical Dimensions** (inches (millimeter))



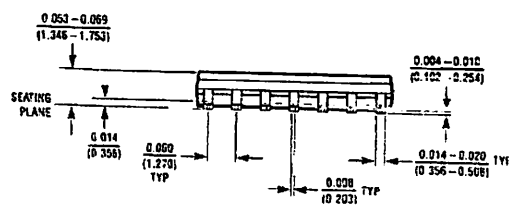
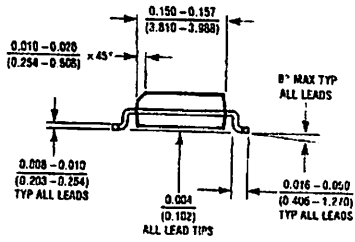
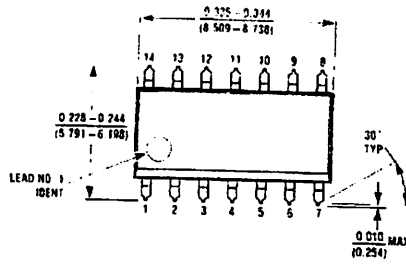
**Leadless Chip Carrier Package**  
 Order Number LM124AE/853 or LM124AE/000  
 NS Package Number E2CA

EXCA REV F

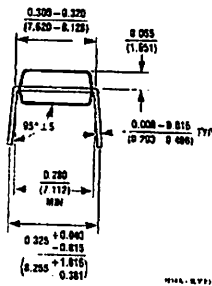
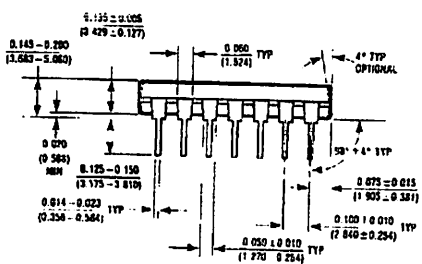
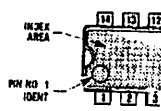
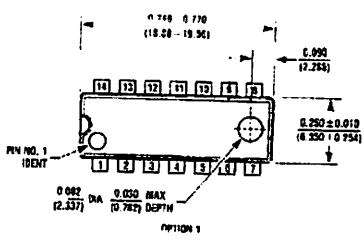


**Ceramic Dual-In-Line Package (DIP)**  
 Order Number LM124J, LM124AJ, LM124AJ/883, LM124J/883, LM124J, LM124AJ or LM124J  
 NS Package Number J14A

**Physical Dimensions** (millimeters preferred)



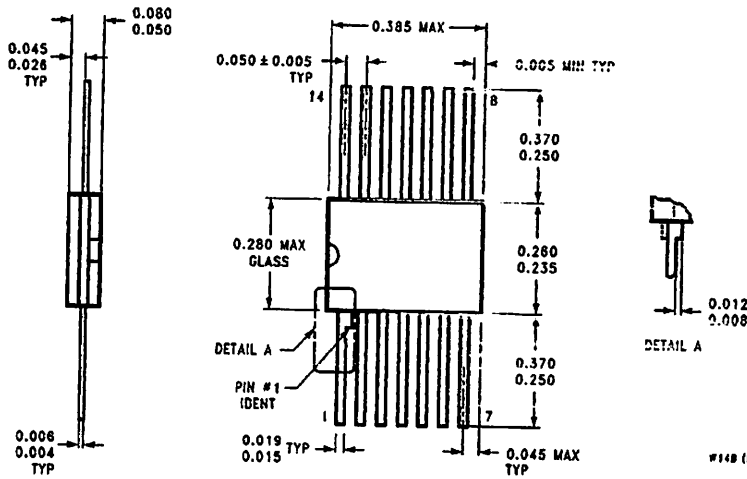
**S.O. Package (M)**  
 Order Number LM324M, LM324AM or LM324AMM  
 NS Package Number N14A



**Molded Dual-In-Line Package (M)**  
 Order Number LM324M, LM324AM or LM324AMM  
 NS Package Number N14A

**LM124/LM224/LM324/LM2902  
Low Power Quad Operational Amplifiers**

**Physical Dimensions**



**Ceramic Flatpak Package**  
**Order Number LM124AW/002 or LM224AW/002**  
**NS Package Number W14B**

**LIFE SUPPORT POLICY**

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION, AS DEFINED:

- Life support devices or systems which:
  - are intended for surgical implant into the body, or
  - support or sustain life, and
  - whose failure to perform, when used in accordance with instructions for use provided in the accompanying literature, could be reasonably expected to result in a significant injury to the user.

DE: (Germany) expected to cause the failure of the life support device or system, or the injury or death of a person.



**National Semiconductor Corporation**  
 1111 West Bardin Road  
 Irving, TX 76017  
 Tel: 1(800) 272-9959  
 Fax: 1(800) 737-7018

**National Semiconductor Europe**  
 Fax: (+49) 0-180-532 33 58  
 Email: cnwgo@lornix.com  
 Deutsch Tel: (+49) 0-180-532 33 58  
 English Tel: (+49) 0-180-532 33 58  
 Français Tel: (+49) 0-180-532 33 58  
 Italiano Tel: (+49) 0-180-534 15 80

**National Semiconductor Hong Kong Ltd.**  
 Tel: (852) 2737-1600  
 Fax: (852) 2737-1601

**National Semiconductor Japan Ltd.**  
 Tel: 03-5620-5000

© 1994 National Semiconductor Corporation. All rights reserved. National Semiconductor reserves the right to change said drawings and specifications without notice.

## SS9013

### 1W Output Amplifier of Potable Radios in Class B Push-pull Operation.

- High total power dissipation. ( $P_T=625\text{mW}$ )
- High Collector Current. ( $I_C=500\text{mA}$ )
- Complementary to SS9012
- Excellent  $h_{FE}$  linearity.



TO-92  
1. Emitter 2. Base 3. Collector

### NPN Epitaxial Silicon Transistor

#### Absolute Maximum Ratings $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{CBO}$	Collector-Base Voltage	40	V
$V_{CEO}$	Collector-Emitter Voltage	20	V
$V_{EBO}$	Emitter-Base Voltage	5	V
$I_C$	Collector Current	500	A
$P_C$	Collector Power Dissipation	625	W
$T_J$	Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature	-55 ~ 150	$^\circ\text{C}$

#### Electrical Characteristics $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$BV_{CBO}$	Collector-Base Breakdown Voltage	$I_C=100\mu\text{A}, I_E=0$	40			V
$BV_{CEO}$	Collector-Emitter Breakdown Voltage	$I_C=1\text{mA}, I_B=0$	20			V
$BV_{EBO}$	Emitter-Base Breakdown Voltage	$I_E=100\mu\text{A}, I_C=0$	5			V
$I_{CBO}$	Collector Cut-off Current	$V_{CB}=25\text{V}, I_E=0$			100	nA
$I_{EBO}$	Emitter Cut-off Current	$V_{EB}=3\text{V}, I_C=0$			100	nA
$h_{FE1}$	DC Current Gain	$V_{CE}=1\text{V}, I_C=50\text{mA}$	64	120	202	
$h_{FE2}$		$V_{CE}=1\text{V}, I_C=500\text{mA}$	40	120		
$V_{CE}(\text{sat})$	Collector-Emitter Saturation Voltage	$I_C=500\text{mA}, I_B=50\text{mA}$		0.16	0.6	V
$V_{BE}(\text{sat})$	Base-Emitter Saturation Voltage	$I_C=500\text{mA}, I_B=50\text{mA}$		0.91	1.2	V
$V_{BE}(\text{on})$	Base-Emitter On Voltage	$V_{CE}=1\text{V}, I_C=10\text{mA}$	0.6	0.67	0.7	V

#### $h_{FE}$ Classification

Classification	D	E	F	G	H
$h_{FE1}$	64 ~ 91	78 ~ 112	96 ~ 135	112 ~ 166	144 ~ 202

# Typical Characteristics

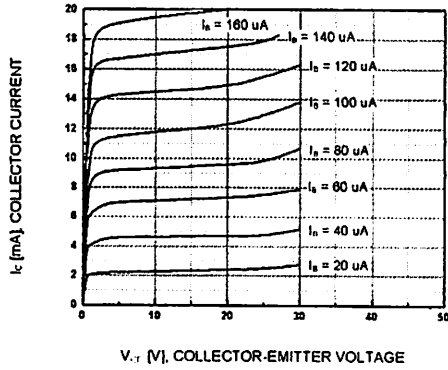


Figure 1. Static Characteristic

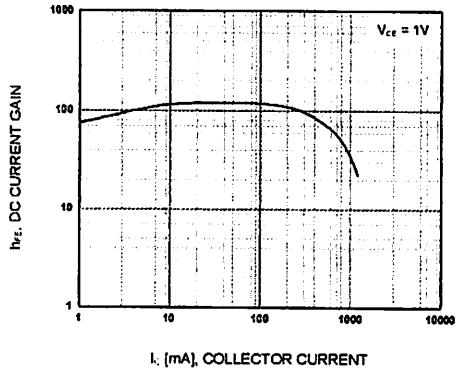


Figure 2. DC current Gain

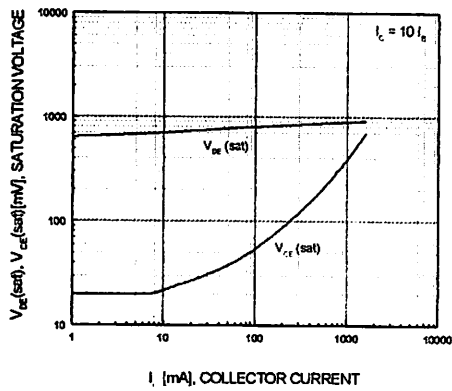


Figure 3. Base-Emitter Saturation Voltage  
Collector-Emitter Saturation Voltage

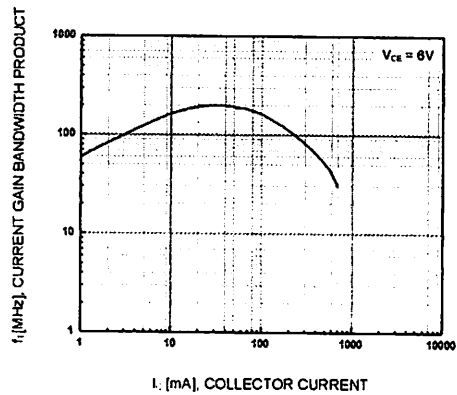
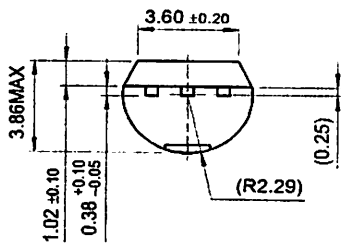
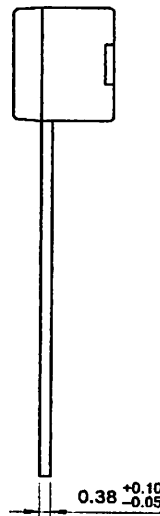
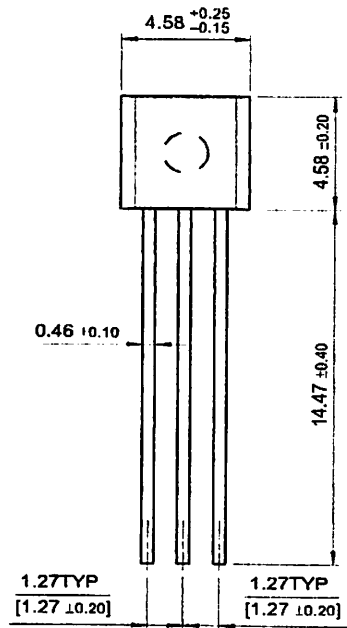


Figure 4. Current Gain Bandwidth Product

# Package Demensions

SS9013

## TO-92



Dimensions in Millimeters

## TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE <sub>x</sub> ™	FAST®	OPTOPLANAR™	STAR*POWER™
Bottomless™	FAST <sub>r</sub> ™	PACMAN™	Stealth™
CoolFET™	FRFET™	POP™	SuperSOT™-3
CROSSVOLT™	GlobalOptoisolator™	Power247™	SuperSOT™-6
DenseTrench™	GTO™	PowerTrench®	SuperSOT™-8
DO <sub>M</sub> E™	HiSeC™	QFET™	SyncFET™
EcoSPARK™	ISOPLANAR™	QS™	TruTranslation™
E <sup>2</sup> C <sub>MOS</sub> ™	LittleFET™	QT Optoelectronics™	TinyLogic™
EnSigna™	MicroFET™	Quiet Series™	UHC™
FACT™	MICROWIRE™	SLIENT SWITCHER®	UltraFET®
FACT Quiet Series™	OPTOLOGIC™	SMART START™	VCX™

STAR\*POWER is used under license

## DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

## LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

### FEATURES

#### Ultrahigh Speed

5,500 V/ $\mu$ s Slew Rate, 4 V Step,  $G = +2$

545 ps Rise Time, 2 V Step,  $G = +2$

#### Large Signal Bandwidth

440 MHz,  $G = +2$

320 MHz,  $G = +10$

#### Small Signal Bandwidth (-3 dB)

1 GHz,  $G = +1$

700 MHz,  $G = +2$

Settling Time 10 ns to 0.1%, 2 V Step,  $G = +2$

#### Low Distortion Over Wide Bandwidth

##### SFDR

-44 dBc @ 150 MHz,  $G = +2$ ,  $V_O = 2$  V p-p

-41 dBc @ 150 MHz,  $G = +10$ ,  $V_O = 2$  V p-p

##### 3rd Order Intercept (3IP)

26 dBm @ 70 MHz,  $G = +10$

18 dBm @ 150 MHz,  $G = +10$

#### Good Video Specifications

Gain Flatness 0.1 dB to 75 MHz

0.01% Differential Gain Error,  $R_L = 150 \Omega$

0.01° Differential Phase Error,  $R_L = 150 \Omega$

#### High Output Drive

175 mA Output Load Drive

10 dBm with -38 dBc SFDR @ 70 MHz,  $G = +10$

#### Supply Operation

+5 V to  $\pm 5$  V Voltage Supply

14 mA (Typ) Supply Current

### APPLICATIONS

Pulse Amplifier

IF/RF Gain Stage/Amplifiers

High Resolution Video Graphics

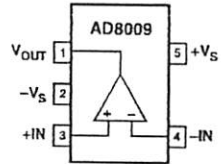
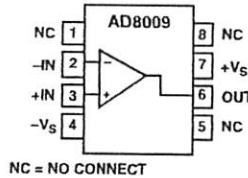
High Speed Instrumentations

CCD Imaging Amplifier

### FUNCTIONAL BLOCK DIAGRAMS

8-Lead Plastic SOIC (SO-8)

5-Lead SOT-23 (RT-5)



NC = NO CONNECT

### PRODUCT DESCRIPTION

The AD8009 is an ultrahigh speed current feedback amplifier with a phenomenal 5,500 V/ $\mu$ s slew rate that results in a rise time of 545 ps, making it ideal as a pulse amplifier.

The high slew rate reduces the effect of slew rate limiting and results in the large signal bandwidth of 440 MHz required for high resolution video graphic systems. Signal quality is maintained over a wide bandwidth with worst case distortion of -40 dBc @ 250 MHz ( $G = +10$ , 1 V p-p). For applications with multitone signals such as IF signal chains, the third order Intercept (3IP) of 12 dBm is achieved at the same frequency. This distortion performance coupled with the current feedback architecture make the AD8009 a flexible component for a gain stage amplifier in IF/RF signal chains.

The AD8009 is capable of delivering over 175 mA of load current and will drive four back terminated video loads while maintaining low differential gain and phase error of 0.02% and 0.04° respectively. The high drive capability is also reflected in the ability to deliver 10 dBm of output power @ 70 MHz with -38 dBc SFDR.

The AD8009 is available in a small SOIC package and will operate over the industrial temperature range -40°C to +85°C. The AD8009 is also available in an SOT-23-5 and will operate over the commercial temperature range 0°C to 70°C.

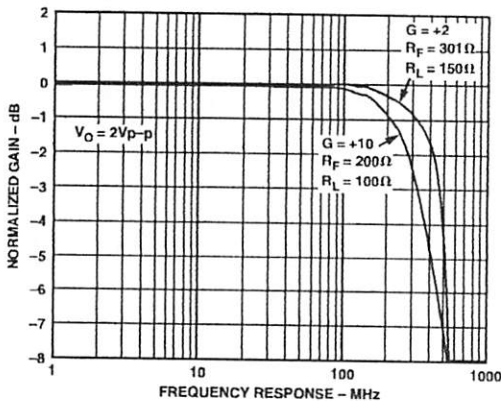


Figure 1. Large Signal Frequency Response;  $G = +2$  and  $+10$

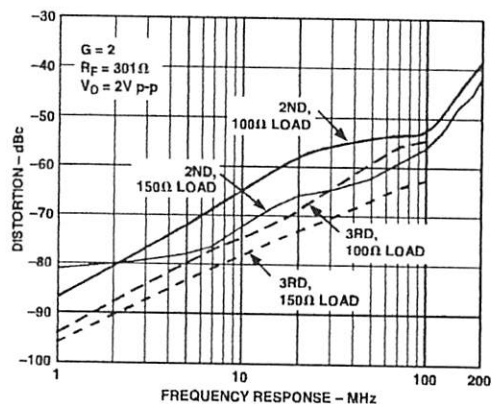


Figure 2. Distortion vs. Frequency;  $G = +2$

REV. D

Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices.

# AD8009—SPECIFICATIONS

(@  $T_A = 25^\circ\text{C}$ ,  $V_S = \pm 5\text{ V}$ ,  $R_L = 100\ \Omega$ , for R Package:  $R_F = 301\ \Omega$  for  $G = +1, +2$ ,  $R_F = 200\ \Omega$  for  $G = +10$ , for RT Package:  $R_F = 332\ \Omega$  for  $G = +1$ ,  $R_F = 226\ \Omega$  for  $G = +2$  and  $R_F = 191\ \Omega$  for  $G = +10$ , unless otherwise noted.)

Model	Conditions	AD8009AR/JRT			Unit
		Min	Typ	Max	
<b>DYNAMIC PERFORMANCE</b>					
-3 dB Small Signal Bandwidth, $V_O = 0.2\text{ V p-p}$	R Package		1000		MHz
	RT Package		845		MHz
	$G = +1, R_F = 301\ \Omega$				
Large Signal Bandwidth, $V_O = 2\text{ V p-p}$	$G = +1, R_F = 332\ \Omega$				MHz
	$G = +2$	480	700		MHz
	$G = +10$	300	350		MHz
	$G = +2$	390	440		MHz
Gain Flatness 0.1 dB, $V_O = 0.2\text{ V p-p}$	$G = +10$	235	320		MHz
	$G = +2$	45	75		MHz
Slew Rate	$G = +2, R_L = 150\ \Omega$	4500	5500		V/ $\mu\text{s}$
Settling Time to 0.1%	$G = +2, R_L = 150\ \Omega, 4\text{ V Step}$		10		ns
	$G = +10, 2\text{ V Step}$		25		ns
Rise and Fall Time	$G = +2, R_L = 150\ \Omega, 4\text{ V Step}$		0.725		ns
<b>HARMONIC/NOISE PERFORMANCE</b>					
SFDR $G = +2, V_O = 2\text{ V p-p}$	5 MHz		-74		dBc
	70 MHz		-53		dBc
	150 MHz		-44		dBc
$G = +10, V_O = 2\text{ V p-p}$	5 MHz		-58		dBc
	70 MHz		-41		dBc
	150 MHz		-41		dBc
Third Order Intercept (3IP) W.R.T. Output, $G = +10$	70 MHz		26		dBm
	150 MHz		18		dBm
	250 MHz		12		dBm
Input Voltage Noise	$f = 10\text{ MHz}$		1.9		nV/ $\sqrt{\text{Hz}}$
Input Current Noise	$f = 10\text{ MHz}, +\text{In}$		46		pA/ $\sqrt{\text{Hz}}$
	$-\text{In}$		41		pA/ $\sqrt{\text{Hz}}$
Differential Gain Error	NTSC, $G = +2, R_L = 150\ \Omega$		0.01	0.03	%
	$R_L = 37.5\ \Omega$		0.02	0.05	%
Differential Phase Error	NTSC, $G = +2, R_L = 150\ \Omega$		0.01	0.03	Degrees
	$R_L = 37.5\ \Omega$		0.04	0.08	Degrees
<b>DC PERFORMANCE</b>					
Input Offset Voltage			2	5	mV
	$T_{\text{MIN}}-T_{\text{MAX}}$			7	mV
Offset Voltage Drift			4		$\mu\text{V}/^\circ\text{C}$
-Input Bias Current			50	150	$\pm\mu\text{A}$
	$T_{\text{MIN}}-T_{\text{MAX}}$		75		$\pm\mu\text{A}$
+Input Bias Current			50	150	$\pm\mu\text{A}$
	$T_{\text{MIN}}-T_{\text{MAX}}$		75		$\pm\mu\text{A}$
Open Loop Transresistance		90	250		k $\Omega$
	$T_{\text{MIN}}-T_{\text{MAX}}$		170		k $\Omega$
<b>INPUT CHARACTERISTICS</b>					
Input Resistance	+Input		110		k $\Omega$
	-Input		8		$\Omega$
Input Capacitance	+Input		2.6		pF
Input Common-Mode Voltage Range			3.8		$\pm\text{V}$
Common-Mode Rejection Ratio	$V_{\text{CM}} = \pm 2.5$	50	52		dB
<b>OUTPUT CHARACTERISTICS</b>					
Output Voltage Swing		$\pm 3.7$	$\pm 3.8$		V
Output Current	$R_L = 10\ \Omega, P_D\text{ Package} = 0.7\text{ W}$	150	175		mA
Short Circuit Current			330		mA
<b>POWER SUPPLY</b>					
Operating Range		+5		$\pm 6$	V
			14	16	mA
Quiescent Current	$T_{\text{MIN}}-T_{\text{MAX}}$			18	mA
Power Supply Rejection Ratio	$V_S = \pm 4\text{ V to } \pm 6\text{ V}$	64	70		dB

Specifications subject to change without notice.

**ABSOLUTE MAXIMUM RATINGS<sup>1</sup>**

Supply Voltage	12.6 V
Internal Power Dissipation <sup>2</sup>	
Small Outline Package (R)	0.75 Watts
Input Voltage (Common Mode)	$\pm V_S$
Differential Input Voltage	$\pm 3.5$ V
Output Short Circuit Duration	Observe Power Derating Curves
Storage Temperature Range R Package	-65°C to +125°C
Operating Temperature Range (A Grade)	-40°C to +85°C
Operating Temperature Range (J Grade)	0°C to 70°C
Lead Temperature Range (Soldering 10 sec)	300°C

**NOTES**

<sup>1</sup>Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

<sup>2</sup>Specification is for device in free air:  
 8-Lead SOIC Package:  $\theta_{JA} = 155^\circ\text{C/W}$ .  
 5-Lead SOT-23 Package:  $\theta_{JA} = 240^\circ\text{C/W}$ .

**MAXIMUM POWER DISSIPATION**

The maximum power that can be safely dissipated by the AD8009 is limited by the associated rise in junction temperature. The maximum safe junction temperature for plastic encapsulated devices is determined by the glass transition temperature of the plastic, approximately 150°C. Exceeding this limit temporarily may cause a shift in parametric performance due to a change in the stresses exerted on the die by the package. Exceeding a junction temperature of 175°C for an extended period can result in device failure.

While the AD8009 is internally short circuit protected, this may not be sufficient to guarantee that the maximum junction temperature (150°C) is not exceeded under all conditions. To ensure proper operation, it is necessary to observe the maximum power derating curves.

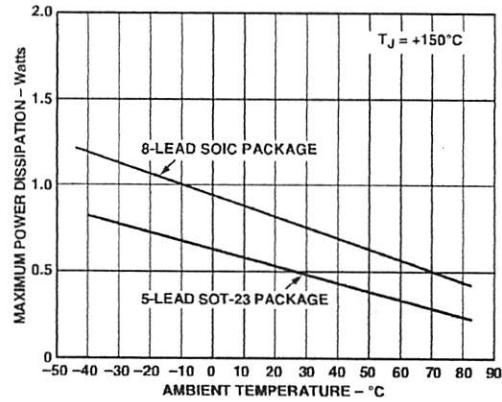


Figure 3. Plot of Maximum Power Dissipation vs. Temperature

**ORDERING GUIDE**

Model	Temperature Range	Package Description	Package Option	Branding Information
AD8009ACHIPS	-40°C to +85°C	Dic		
AD8009AR	-40°C to +85°C	8-Lead SOIC	SO-8	
AD8009AR-REEL	-40°C to +85°C	8-Lead SOIC	13" Tape and Reel	
AD8009AR-REEL7	-40°C to +85°C	8-Lead SOIC	7" Tape and Reel	
AD8009JRT-REEL	0°C to 70°C	5-Lead SOT-23	13" Tape and Reel	HKJ
AD8009JRT-REEL7	0°C to 70°C	5-Lead SOT-23	7" Tape and Reel	HKJ
AD8009-EB		Evaluation Board	SO-8	

**CAUTION**

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD8009 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high-energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



# AD6009—Typical Performance Characteristics

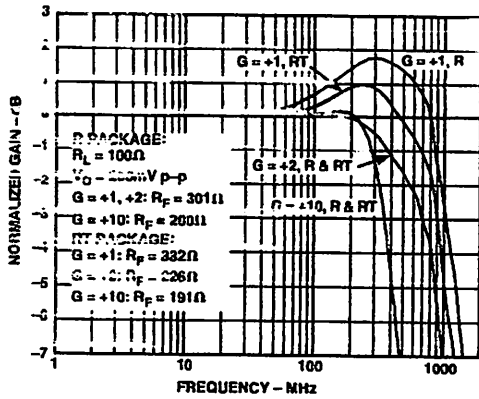


Figure 4. Frequency Response;  $G = +1, +2, +10, R$  and  $RT$  Packages

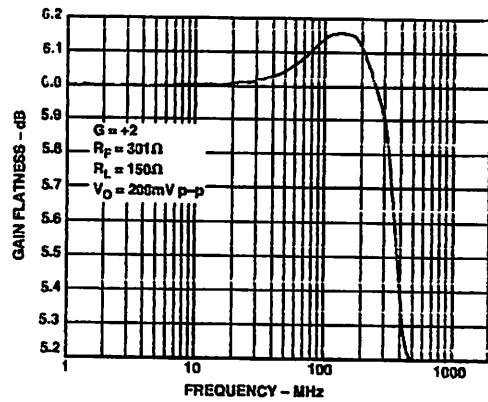


Figure 7. Gain Flatness;  $G = +2$

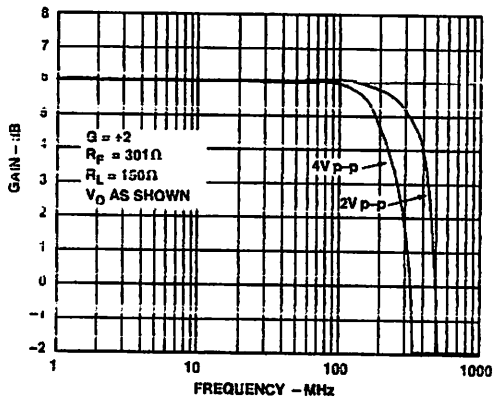


Figure 5. Large Signal Frequency Response;  $G = +2$

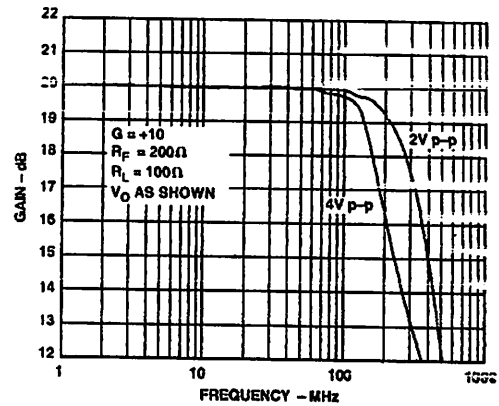


Figure 8. Large Signal Frequency Response,  $G = +10$

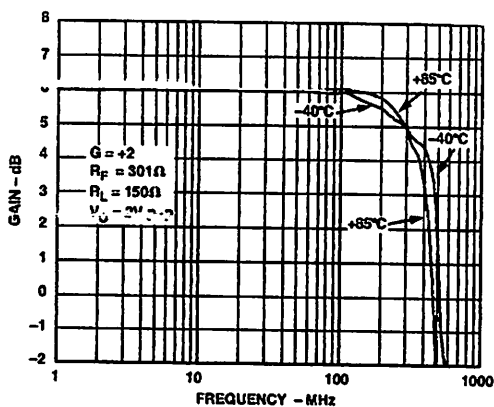


Figure 6. Large Signal Frequency Response vs. Temperature;  $G = +2$

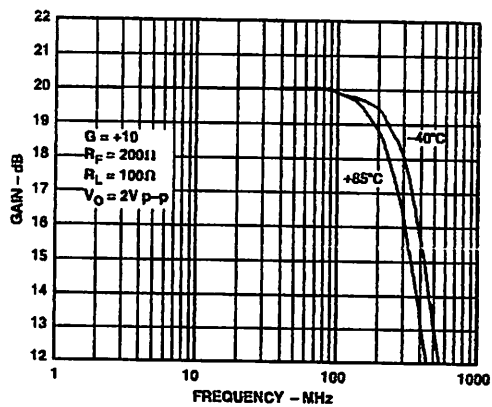


Figure 9. Large Signal Frequency Response vs. Temperature;  $G = +10$

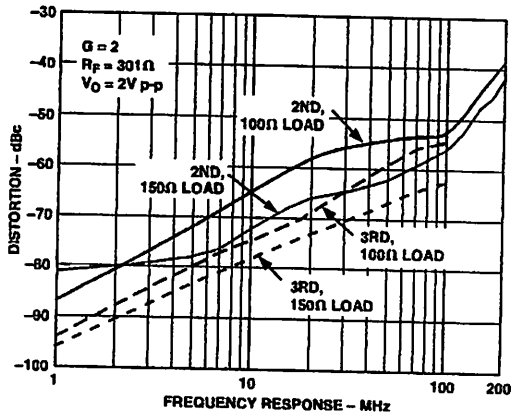


Figure 10. Distortion vs. Frequency;  $G = +2$

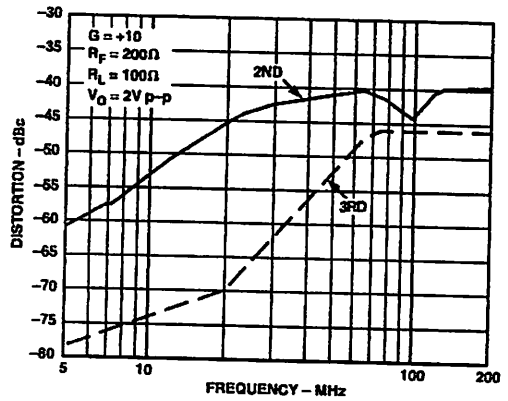


Figure 13. Distortion vs. Frequency;  $G = +10$

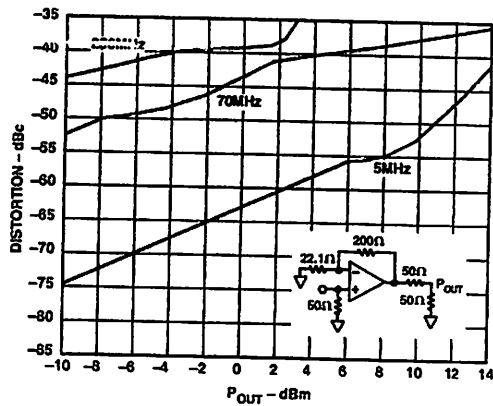


Figure 11. 2nd Harmonic Distortion vs.  $P_{OUT}$ ; ( $G = +10$ )

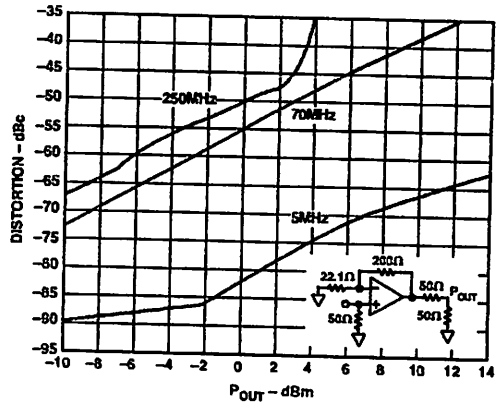


Figure 14. 3rd Harmonic Distortion vs.  $P_{OUT}$ ; ( $G = +10$ )

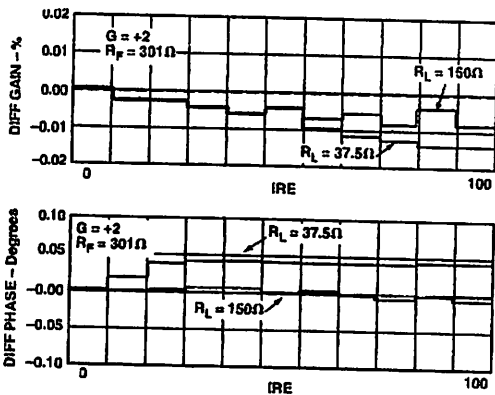


Figure 12. Differential Gain and Phase

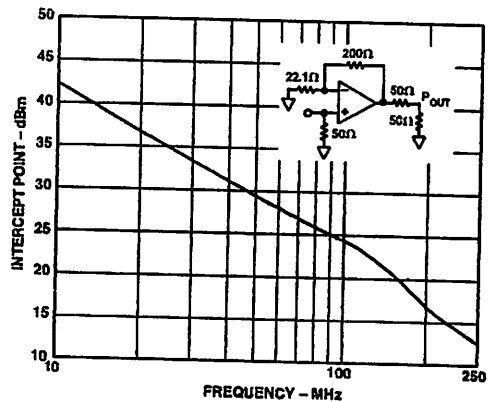


Figure 15. Two Tone, 3rd Order IMD Intercept vs. Frequency;  $G = +10$

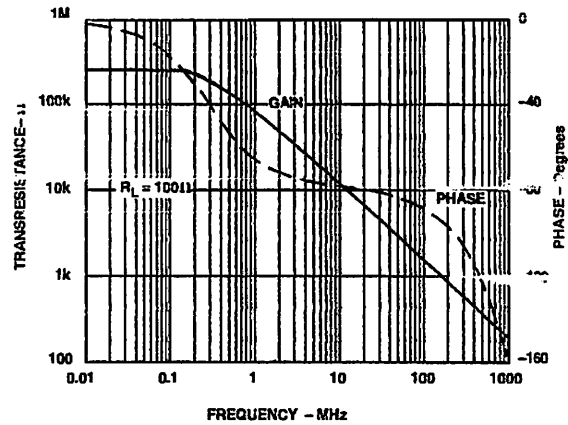


Figure 16. Transresistance and Phase vs. Frequency

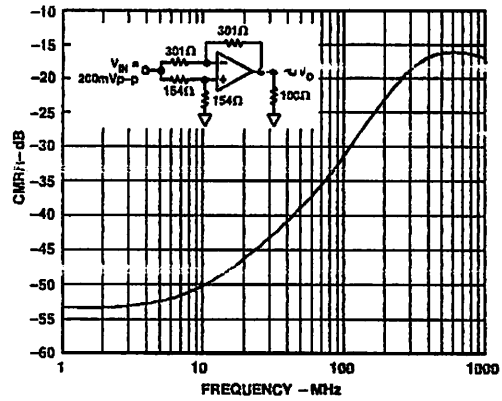


Figure 19. CMRR vs. Frequency

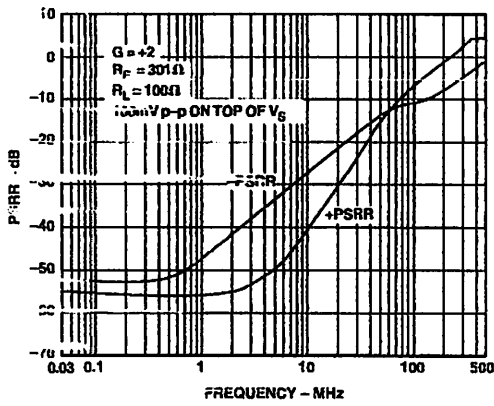


Figure 17. PSRR vs. Frequency

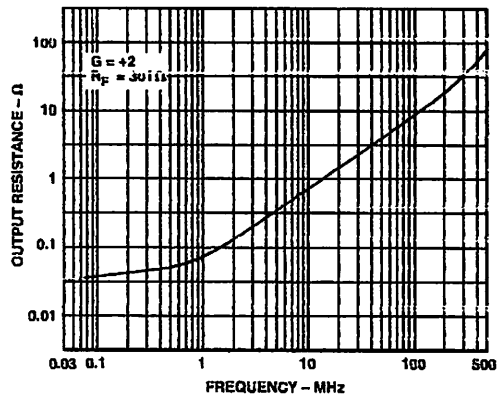


Figure 20. Output Resistance vs. Frequency

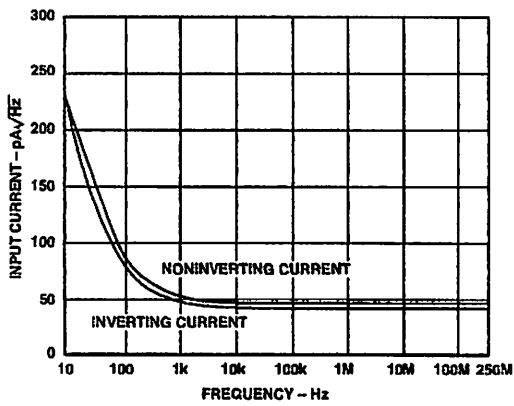


Figure 18. Current Noise vs. Frequency

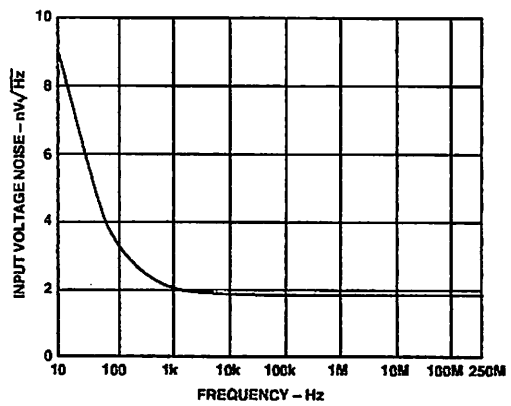


Figure 21. Voltage Noise vs. Frequency

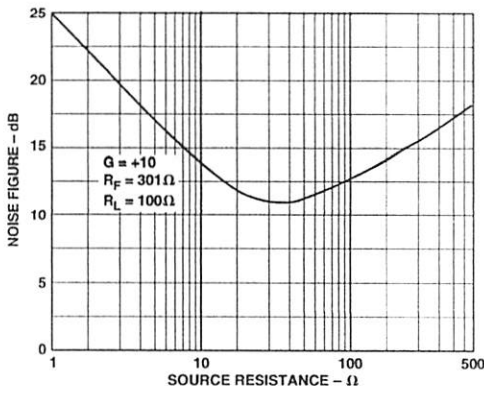


Figure 22. Noise Figure

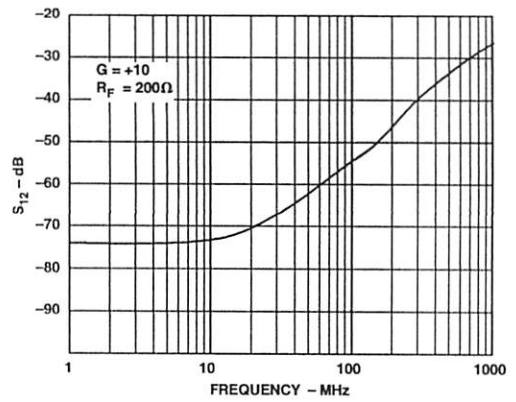


Figure 25. Reverse Isolation ( $S_{12}$ );  $G = +10$

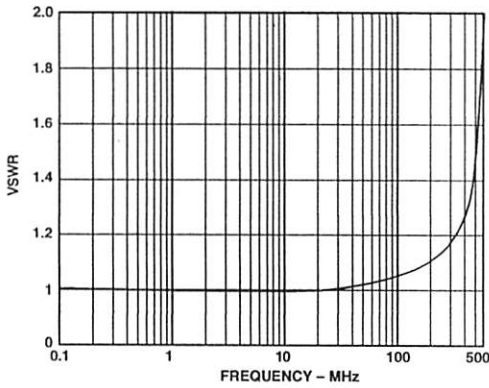


Figure 23. Input VSWR;  $G = +10$

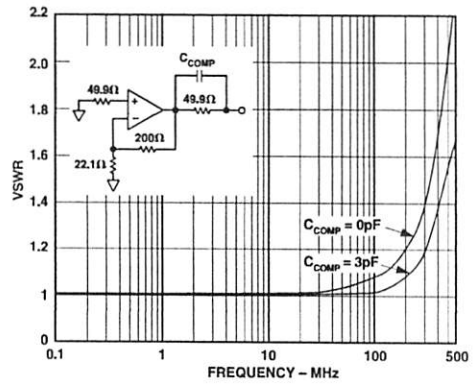


Figure 26. Output VSWR;  $G = +10$

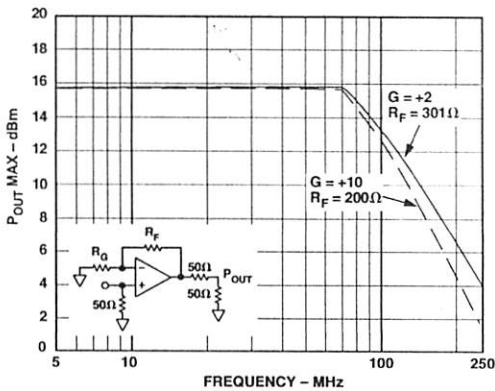


Figure 24. Maximum Output Power vs. Frequency

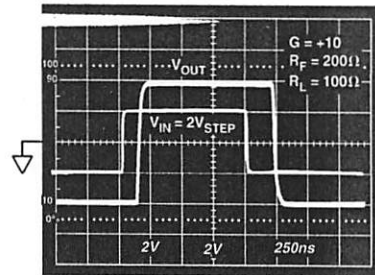


Figure 27. Overdrive Recovery;  $G = +10$

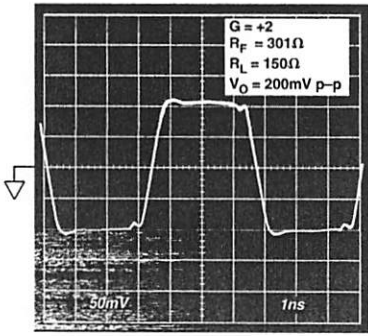


Figure 28. Small Signal Transient Response;  $G = +2$

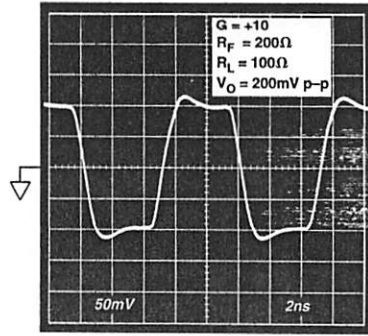


Figure 31. Small Signal Transient Response;  $G = +10$

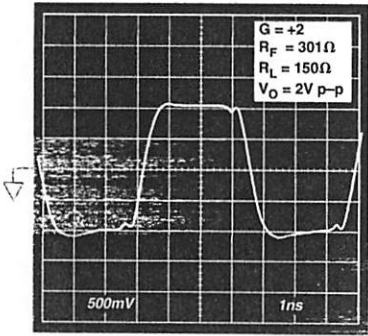


Figure 29. 2 V Transient Response;  $G = +2$

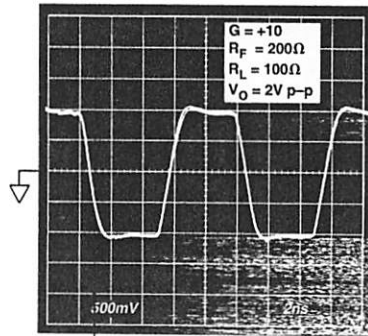


Figure 32. 2 V Transient Response;  $G = +10$

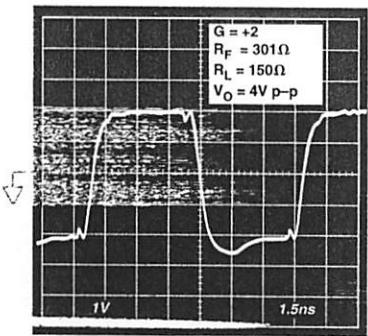


Figure 30. 4 V Transient Response;  $G = +2$

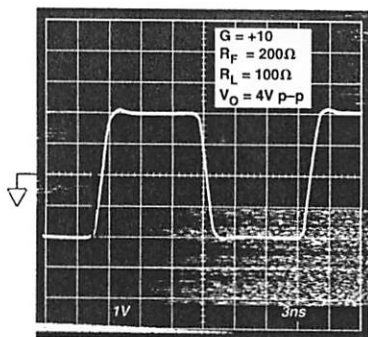


Figure 33. 4 V Transient Response;  $G = +10$

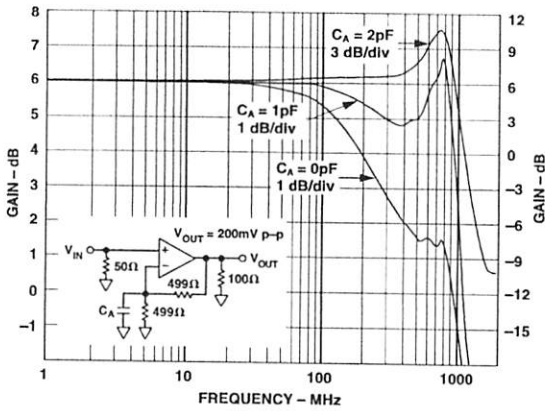


Figure 34. Small Signal Frequency Response vs. Parasitic Capacitance

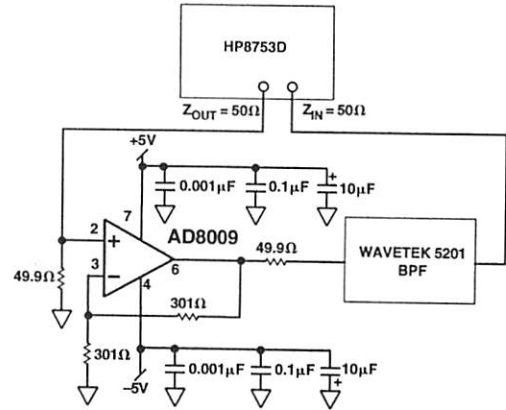


Figure 36. AD8009 Driving a Bandpass RF Filter

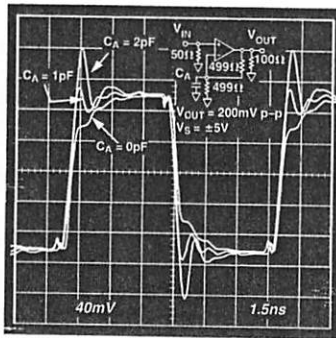


Figure 35. Small Signal Pulse Response vs. Parasitic Capacitance

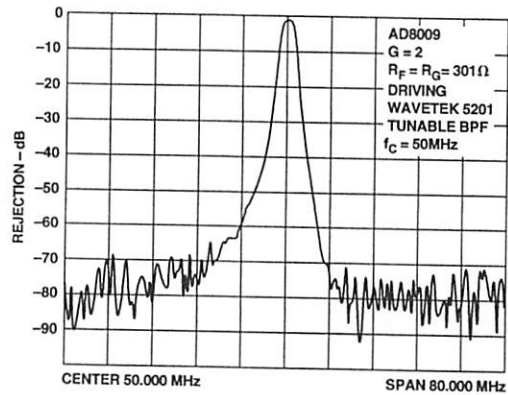


Figure 37. Frequency Response of Bandpass Filter Circuit

**APPLICATIONS**

All current feedback op amps are affected by stray capacitance on their -INPUT. Figures 34 and 35 illustrate the AD8009's response to such capacitance.

Figure 34 shows the bandwidth can be extended by placing a capacitor in parallel with the gain resistor. The small signal response corresponding to such an increase in capacitance/bandwidth is shown in Figure 35.

As a practical consideration, the higher the capacitance on the -INPUT to GND, the higher  $R_F$  needs to be to minimize peaking/ringing.

**RF Filter Driver**

The output drive capability, wide bandwidth and low distortion of the AD8009 are well suited for creating gain blocks that can drive RF filters. Many of these filters require that the input be driven by a 50  $\Omega$  source, while the output must be terminated in 50  $\Omega$  for the filters to exhibit their specified frequency response.

Figure 36 shows a circuit for driving and measuring the frequency response of a filter, a Wavetek 5201 Tunable Band Pass Filter that is tuned to a 50 MHz center frequency. The HP8753D network provides a stimulus signal for the measurement. The analyzer has a 50  $\Omega$  source impedance that drives a cable that is terminated in 50  $\Omega$  at the high impedance noninverting input of the AD8009.

The AD8009 is set at a gain of two. The series 50  $\Omega$  resistor at the output, along with the 50  $\Omega$  termination provided by the filter and its termination, yield an overall unity gain for the measured path. The frequency response plot of Figure 37 shows the circuit to have an insertion loss of 1.3 dB in the pass band and about 75 dB rejection in the stop band.

# AD8009

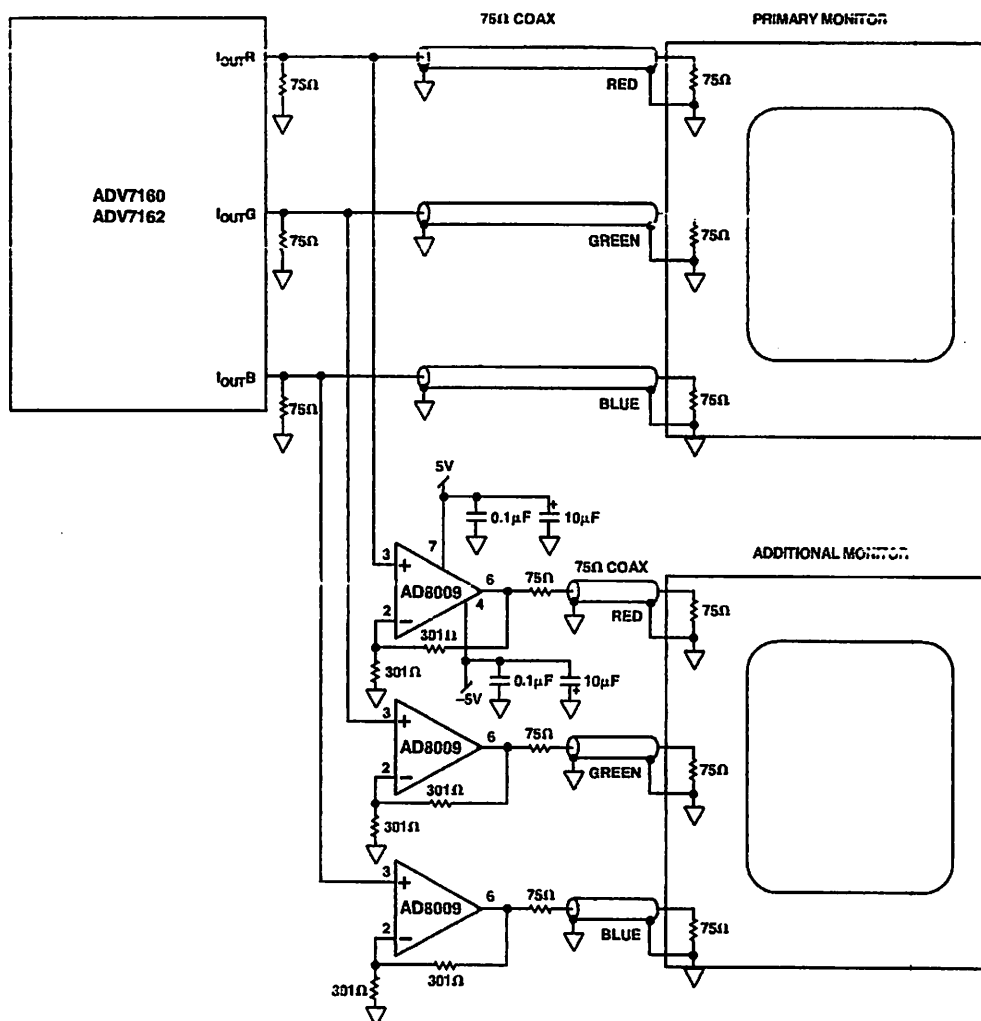


Figure 36. Driving an Additional High Resolution Monitor Using Three AD8009s

## RGB Monitor Driver

High resolution computer monitors require very high full power bandwidth signals to maximize their display resolution. The RGB signals that drive these monitors are generally provided by a current-out RAMDAC that can directly drive a 75 Ω doubly terminated line.

There are times when the same output wants to be delivered to additional monitors. The termination provided internally by each monitor prohibits the ability to simply connect a second monitor in parallel with the first. Additional buffering must be provided.

Figure 38 shows a connection diagram for two high resolution monitors being driven by an ADV7160 or ADV7162, a 220 MHz (mega-pixel per second) triple RAMDAC. This pixel rate requires a driver whose full power bandwidth is at least half the pixel rate or 110 MHz. This is to provide good resolution for a worst case signal that swings between zero scale and full scale on adjacent pixels.

The primary monitor is connected in the conventional fashion with a 75 Ω termination to ground at each end of the 75 Ω cable. Sometimes this configuration is called "doubly terminated" and is used when the driver is a high output impedance current source.

For the additional monitor, each of the RGB signals close to the RAMDAC output is applied to a high input impedance, noninverting input of an AD8009 that is configured for a gain of +2. The outputs each drive a series 75 Ω resistor, cable and termination resistor in the monitor that divides the output signal by two, thus providing an overall unity gain. This scheme is referred to as "back termination" and is used when the driver is a low output impedance voltage source. Back termination requires that the voltage of the signal be double the value that the monitor sees. Double termination requires that the output current be double the value that flows in the monitor termination.

### Driving a Capacitive Load

A capacitive load, like that presented by some A/D converters, can sometimes be a challenge for an op amp to drive depending on the architecture of the op amp. Most of the problem is caused by the pole created by the output impedance of the op amp and the capacitor that is driven. This creates extra phase shift that can eventually cause the op amp to become unstable.

One way to prevent instability and improve settling time when driving a capacitor is to insert a resistor in series between the op amp output and the capacitor. The feedback resistor is still connected directly to the output of the op amp, while the series resistor provides some isolation of the capacitive load from the op amp output.

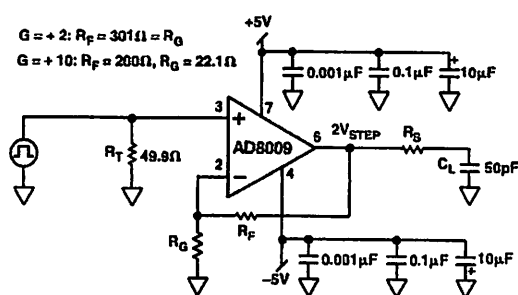


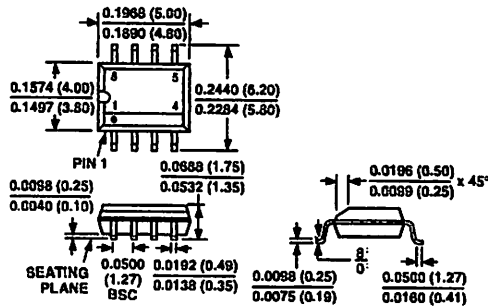
Figure 39. Capacitive Load Drive Circuit

Figure 39 shows such a circuit with an AD8009 driving a 50 pF load. With  $R_S = 0$ , the AD8009 circuit will be unstable. For a gain of +2 and +10, it was found experimentally that setting  $R_S$  to 42.2  $\Omega$  will minimize the 0.1% settling time with a 2 V step at the output. The 0.1% settling time was measured to be 40 ns with this circuit.

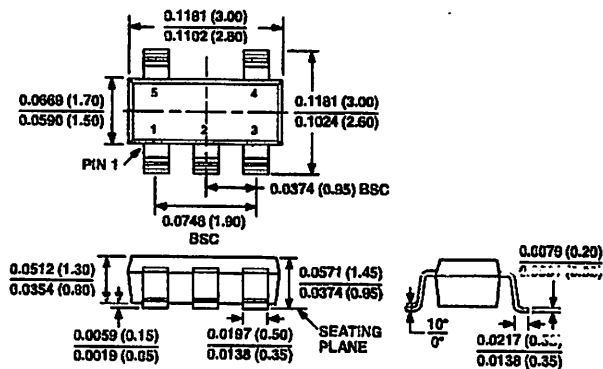
For smaller capacitive loads, a smaller  $R_S$  will yield optimal settling time, while a larger  $R_S$  will be required for larger capacitive loads. Of course, a larger capacitance will always require more time for settling to a given accuracy than a smaller one, and this will be lengthened by the increase in  $R_S$  required. At best, a given RC combination will require about 7 time constants by itself to settle to 0.1%, so a limit will be reached where too large a capacitance cannot be driven by a given op amp and still meet the system's required settling time specification.

**OUTLINE DIMENSIONS**  
Dimensions shown in inches and (mm).

**8-Lead SOIC  
(SO-8)**



**5-Lead Plastic Surface Mount (SOT-23)  
(RT-5)**



C01011s-0-10/00 (rev. D)

PRINTED IN U.S.A.